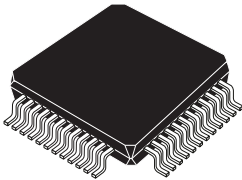


Automotive 3-Phase motor gate driver unit



TQFP48 (exposed pad down)

Features



- AEC-Q100 qualified
- Full ISO26262 compliant, ASIL-D systems ready
- VDH motor supply voltage range from 4.5 V to 75 V for working in single (12 V systems), double (24 V systems) and 48 V battery applications
- 3.3 V internal supply voltage generated from 5 V on VDD pin
- Digital I/O compatible to 3.3 V/5 V logics
- 6 separate N-channel FET pre-drivers:
 - dedicated source connection to each FET
 - the device can withstand -14 V to 95 V on motor connection pins
 - 0% to 100% duty cycle operation support
 - dedicated PWM input pin for each gate driver
- 3 differential high accuracy current monitors for ground referred current measurements:
 - ADC/DAC architecture
 - SPI adjustable Gain Factor and Output Offset
 - built-in error calibration
 - the device can withstand -14 V to 6 V on input sensing pins
 - SPI readable current measurement
 - 0 to 4.6 V DAC output dynamic range
- 3 real time phase voltage monitor channels:
 - SPI programmable phase voltage feedback;
 - SPI readable phase duty cycle measurement;
- 32-bit - 10 MHz SPI interface with 5-bit CRC and 1bit frame counter for internal setting, self-test and full diagnostics
- Protection and diagnostic:
 - SPI programmable VDS diagnostic and protection in on-state
 - SPI programmable Dead Time protection
 - SPI programmable Shoot-through diagnostic and protection
 - Open load, short to GND and short to battery diagnostic in off-state
 - Over-temperature diagnostic and protection with SPI programmable warning flag
 - SPI readable Tj measurement
 - Ground loss diagnostic
 - System clock monitoring
 - Power supply pins VDD, VDH, VBP over-voltage and under-voltage diagnostic
 - FET driver supply VPRE and VCP under-voltage and over-voltage diagnostic
 - SPI Window Watchdog
 - Fault status flag output

Product status link

L9908

Product summary

| Order code | Package | Packing |
|------------|------------------------|-----------|
| L9908 | TQFP48 (exp. pad down) | Tray |
| L9908-TR | | Tape&Reel |

Application

- EPS – Electronic Power Steering
- HVAC Blowers – Heating, ventilation, and air conditioning
- Engine Cooling Fans
- Electronic Brake Booster
- EWP, EFP, EOP

Description

L9908 is a gate driver unit (GDU) for controlling 6 N-channel FETs for brushless motors in automotive applications.

Each one of the 3 half bridge drivers channels (HS/LS couples) can be independently configured allowing different load driving and is able to withstand -14 V to 95 V excursion on motor's pins.

Through 6 dedicated parallel inputs the pre-driver stages can be controlled independently supporting duty cycle operations from 0% to 100% and allowing to implement all kinds of electric motor control strategy. A dedicated combination of regulators, charge pumps and bootstrap circuits allows L9908 to be suitable to operate in passenger, commercial or hybrid vehicles.

Safe operation of half bridges is ensured by shoot-through diagnosis, dead-time, short to battery, short to ground and open load detection plus a real time phase voltage monitoring.

L9908 is equipped with 3 independent high accuracy current monitor channels with SPI-configurable input differential voltage ranges for ground referenced current measurements, with 5 V/3.3 V output dynamic range compatibility.

L9908 implements diagnostics on external and internal supply, ground level, internal temperature.

A 32-bit out of frame SPI-slave interface is implemented for communication up to 10 MHz between L9908 and uC. SPI communication is safe-guarded by 5-bit CRC, 1bit frame counter, frame length check and an SPI-configurable Window Watchdog.

1 Block diagram and pin description

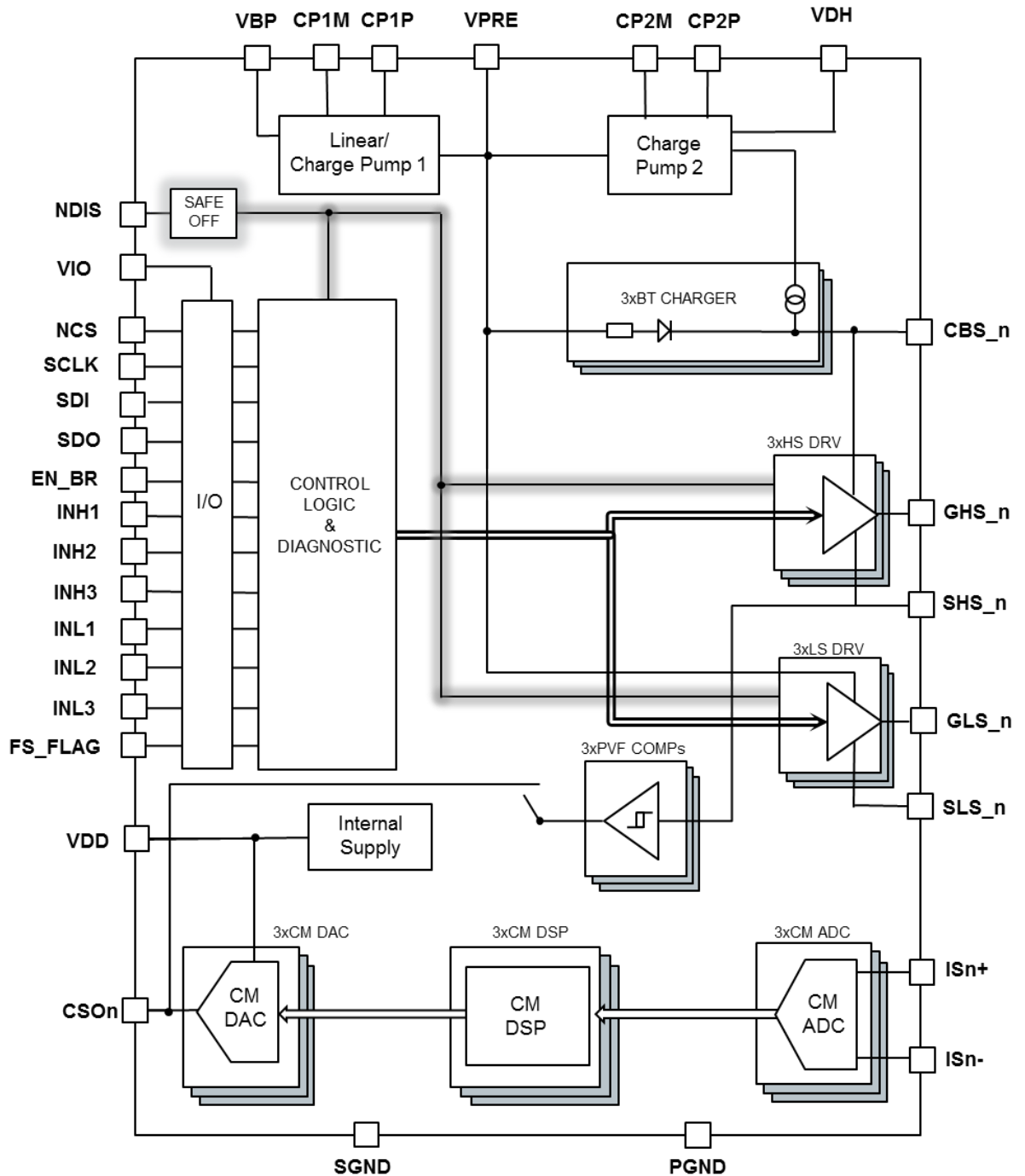
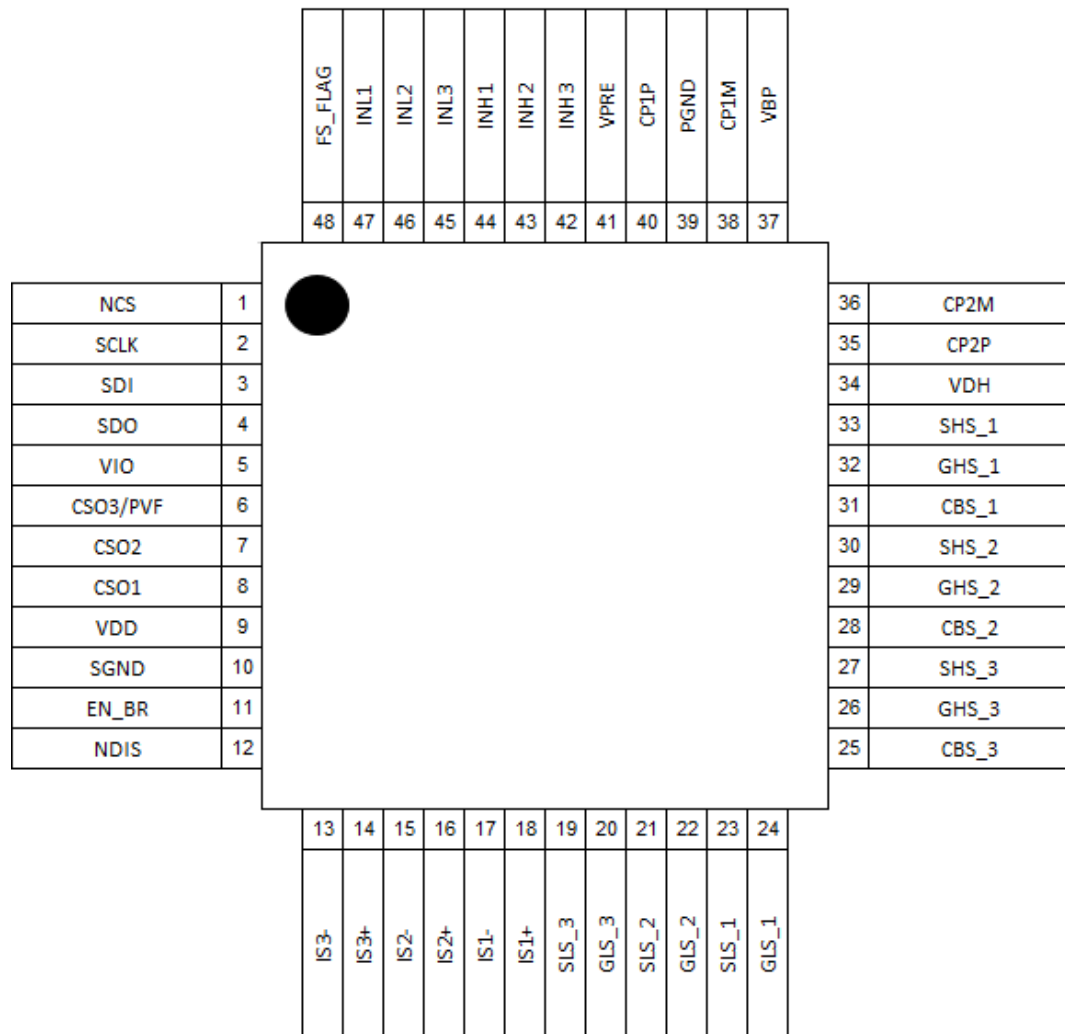
Figure 1. Block diagram


Figure 2. Pin connection diagram (top view)


Legenda: I = Input, O = Output, P = Power Supply, G = Ground, I/O = Input/Output

Table 1. Pin list description

| Pin # | Pin name | Description | Pin type | Class |
|-------|----------|---|----------|-------|
| 1 | NCS | SPI Chip Select Input (Active LOW) | I | Local |
| 2 | SCLK | SPI Serial Clock Input | I | Local |
| 3 | SDI | SPI Serial Data Input | I | Local |
| 4 | SDO | SPI Serial Data Output | O | Local |
| 5 | VIO | Power supply for digital output | P | Local |
| 6 | CSO3/PVM | Current monitor 3 analog output. Phase voltage feedback output | O | Local |
| 7 | CSO2 | Current monitor 2 analog output | O | Local |
| 8 | CSO1 | Current monitor 1 analog output | O | Local |
| 9 | VDD | Power supply input for internal circuitry and current monitors analog output (CSOn) | P | Local |
| 10 | SGND | Signal Ground (Analog, Digital, Reference) | G | Local |
| 11 | EN_BR | Bridge Enable Input (Active HIGH) | I | Local |

| Pin # | Pin name | Description | Pin type | Class |
|-------|----------|---|----------|--------|
| 12 | NDIS | Safe switch-off activation Input (Active LOW) | I | Local |
| 13 | IS3- | Current monitor 3 negative input | I | Local |
| 14 | IS3+ | Current monitor 3 positive input | I | Local |
| 15 | IS2- | Current monitor 2 negative input | I | Local |
| 16 | IS2+ | Current monitor 2 positive input | I | Local |
| 17 | IS1- | Current monitor 1 negative input | I | Local |
| 18 | IS1+ | Current monitor 1 positive input | I | Local |
| 19 | SLS_3 | Source connection of LS FET, phase 3 | I/O | Local |
| 20 | GLS_3 | Gate connection of LS FET, phase 3 | I/O | Local |
| 21 | SLS_2 | Source connection of LS FET, phase 2 | I/O | Local |
| 22 | GLS_2 | Gate connection of LS FET, phase 2 | I/O | Local |
| 23 | SLS_1 | Source connection of LS FET, phase 1 | I/O | Local |
| 24 | GLS_1 | Gate connection of LS FET, phase 1 | I/O | Local |
| 25 | CBS_3 | Bootstrap capacitor of HS, phase 3 | I/O | Local |
| 26 | GHS_3 | Gate connection of HS FET, phase 3 | I/O | Local |
| 27 | SHS_3 | Source connection of HS FET, phase 3 | I/O | Global |
| 28 | CBS_2 | Bootstrap capacitor of HS, phase 2 | I/O | Local |
| 29 | GHS_2 | Gate connection of HS FET, phase 2 | I/O | Local |
| 30 | SHS_2 | Source connection of HS FET, phase 2 | I/O | Global |
| 31 | CBS_1 | Bootstrap capacitor of HS, phase 1 | I/O | Local |
| 32 | GHS_1 | Gate connection of HS FET, phase 1 | I/O | Local |
| 33 | SHS_1 | Source connection of HS FET, phase 1 | I/O | Global |
| 34 | VDH | Drain connection of HS FETs | P | Global |
| 35 | CP2P | Charge Pump 2 positive input of fly capacitance | I/O | Local |
| 36 | CP2M | Charge Pump 2 negative input of fly capacitance | I/O | Local |
| 37 | VBP | Pre-regulation stage power supply | P | Global |
| 38 | CP1M | Charge Pump 1 negative input of fly capacitance | I/O | Local |
| 39 | PGND | Power Ground (Charge Pump 1 and 2) | G | Local |
| 40 | CP1P | Charge Pump 1 positive input of fly capacitance | I/O | Local |
| 41 | VPRE | Pre-regulated voltage for HS/LS Vgs driving | I/O | Local |
| 42 | INH3 | PWM command for HS, phase 3 (Active HIGH) | I | Local |
| 43 | INH2 | PWM command for HS, phase 2 (Active HIGH) | I | Local |
| 44 | INH1 | PWM command for HS, phase 1 (Active HIGH) | I | Local |
| 45 | INL3 | PWM command for LS, phase 3 (Active HIGH) | I | Local |
| 46 | INL2 | PWM command for LS, phase 2 (Active HIGH) | I | Local |
| 47 | INL1 | PWM command for LS, phase 1 (Active HIGH) | I | Local |
| 48 | FS_FLAG | Fault status flag output (Active LOW) | O | Local |
| | Exp. PAD | Cooling pad not electrically connected. Connect to GND plane on PCB | | |

Safety Related pin NDIS and EN_BR have the following characteristics:

Table 2. Safety related digital input pins functional partitioning

| Pins | Default State | Description |
|-------|--|---|
| NDIS | Type B – Internal Resistance Pull-down | SPI Pin (SPI communication related pin) |
| EN_BR | Type B – Internal Resistance Pull-down | SPI Pin (SPI communication related pin) |

Table 3. NDIS and EN_BR electrical characteristics

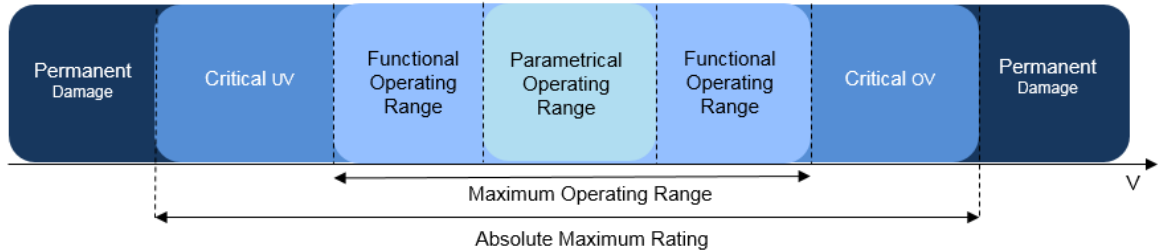
| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|--------------|-------------------------|----------------|------|-----|-----|------|----------------|
| NDIS_II_th | NDIS Input Low Level | | -0.3 | - | 0.8 | V | - |
| NDIS_hI_th | NDIS Input High Level | | 2 | - | 65 | V | - |
| T_ndis_fit | NDIS filtering time | | 1 | 2.5 | 5 | µs | Analog filter |
| NDIS_in_ipd | NDIS Pull Down Current | NDIS = VIO | -65 | -40 | -15 | µA | - |
| EN_BR_II_th | EN_BR Input Low Level | | -0.3 | - | 0.8 | V | - |
| EN_BR_hI_th | EN_BR Input High Level | | 2 | - | 65 | V | - |
| T_en_br_fit | EN_BR filtering time | | 1 | 2.5 | 5 | µs | Digital filter |
| EN_BR_in_ipd | EN_BR Pull Down Current | EN_BR = VIO | -65 | -40 | -15 | µA | - |

The state of Safety control pins EN_BR and NDIS is echoed into dedicated SPI readable bits **EN_BR_ECHO** and **NDIS_ECHO** in the register **GEN_STATUS2**.

2 Absolute maximum ratings

In the following section the voltage ranges of each pin are described by dividing them into three categories: Functional Operating Range, Parametrical Operating Range and Absolute maximum rating.

Figure 3. Pin voltage ranges



2.1 Maximum Operating Range (MOR)

2.1.1 Functional Operating Range

Within these operating ranges the part operates as specified in the circuit description, electrical characteristics are guaranteed only in the parametrical operating range, between these two ranges parametrical deviation may occur. The device may not operate properly if functional operating range conditions are exceeded. Once taken beyond the functional operative ratings and returned back within, the part will recover with no damage or degradation (provided that AMR range is not exceeded). All analog and digital voltages are related to the potential at signal ground SGND. All currents are assumed to be positive when current flows into the pin.

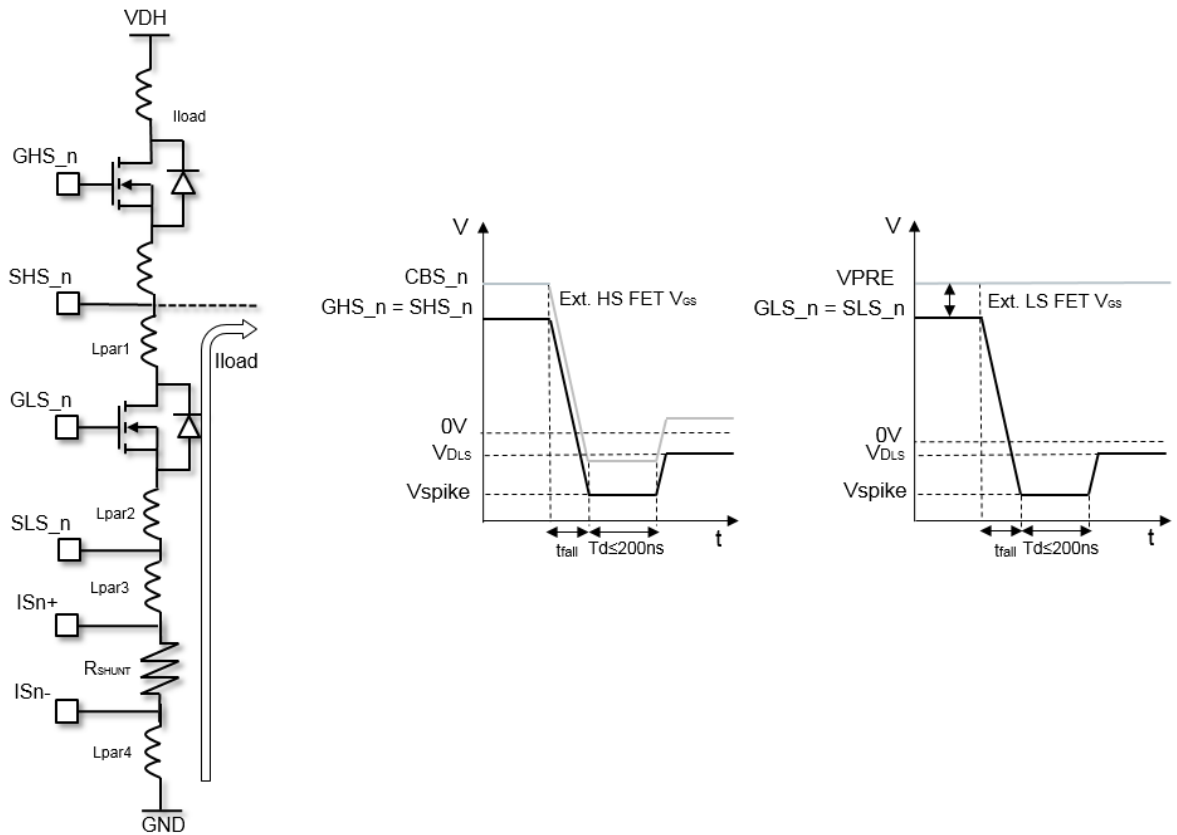
Table 4. Functional operating conditions

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|---------------------------|---|---------------|-----|---------|------|-------------------|
| Power Supply | | | | | | |
| VBP_MOR | VBP: voltage range | VBP UV | - | VBP OV | V | Thermally limited |
| VBP_MOR_PU | VBP: voltage range for power up | VBP UV + HYST | - | | V | Power-Up |
| VDH_MOR | VDH: voltage range | VDH UV | - | VDH OV | V | - |
| VDH_MOR_PU | VDH: voltage range for power up | VDH UV + HYST | - | | V | Power-Up |
| VDD_MOR | VDD: voltage range | VDD UV | - | VDD OV | V | - |
| VDD_MOR_PU | VDD: voltage range for power up | VDD UV + HYST | - | | V | Power-Up |
| VIO_MOR | VIO: voltage range | 2.5 | - | 5.5 | V | - |
| Gate Driver Supply | | | | | | |
| d_CP1P_CP1M_MOR | CP1P - CP1M: Charge Pump1 external capacitance terminals differential voltage | VPRE UV | - | VPRE OV | V | - |
| VPRE_MOR | VPRE: voltage range | VPRE UV | - | VPRE OV | V | - |
| d_CP2P_CP2M_MOR | CP2P - CP2M: Charge Pump2 external capacitance terminals differential voltage | VPRE UV | - | VPRE OV | V | - |

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|-------------------------|--|--------------------|-----|------------------------------------|------|---|
| Gate Drivers | | | | | | |
| d_CBSN_SHSN_MOR_BT1_MOR | CBS _n – SHS _n : differential voltage between CBS _n and SHS _n | VPRE UV | - | VPRE OV | V | Charge through BT charge limiter 1 only [n=1,2,3] |
| d_CBSN_SHSN_MOR_BT2_MOR | CBS _n – SHS _n : differential voltage between CBS _n and SHS _n | BT_lim2_vlim (MIN) | - | BT_lim2_vlim (MAX) | V | Charge through BT charge limiter 2 only [n=1,2,3] |
| d_GHSN_SHSN_MOR | GHS _n – SHS _n : differential voltage between GHS _n and SHS _n | 0 | - | CBS _n -SHS _n | V | [n=1,2,3] |
| SHSN_MOR | SHS _n : voltage range | -12 | - | VDH +12 | V | [n=1,2,3] |
| d_GLSN_SLSN_MOR | GLS _n – SLS _n : differential voltage between GLS _n and SLS _n | 0 | - | VPRE-SLS _n | V | [n=1,2,3] |
| d_SLSN_MOR | SLS _n : voltage range | -12 | - | 2 | V | [n=1,2,3] |
| Current Monitors | | | | | | |
| ISN_MOR | ISn+ – ISn-: differential voltage between ISn+ and ISn- | -0.3 | - | 0.3 | V | [n=1,2,3] |
| ISN_MOR | ISn+/ISn-: common mode voltage range | -2 | - | 2 | V | [n=1,2,3] |
| CSON_MOR | CSON: voltage range | 0 | - | VDD-0.4 | V | [n=1,2,3] |
| Digital I/O | | | | | | |
| DO_MOR | SDO, PVM, FS_FLAG: voltage range | 0 | - | VIO | V | - |
| DI_MOR | NCS, SCLK, SDI, EN_BR, NDIS, INHn, INLn: voltage range | 0 | - | VIO | V | [n=1,2,3] |

Note: *undershoot spikes at motor's phase (SHS_n) take place when the high side is switched off and the load current must flow through the low-side freewheeling diode.*

Figure 4. 14 V pulse scenario - applicative condition



The negative peak voltage reached during such a transition can be described by the following formula:

$$SHS_n(\text{peak}) = V_{d_peak} + (L_{PAR_TOT}) \frac{dI_{LOAD}}{t_{fall}} + (R_{shunt} + R_{PAR_TOT}) I_{load} \quad (1)$$

$$SHS_n(\text{peak}) \approx (L_{PAR_TOT}) \frac{dI_{LOAD}}{t_{fall}} \quad (2)$$

The first term V_{d_peak} is the transient peak voltage of the LS FET body diode, the second is due to transient response of the parasitic inductances between SHS_n and GND while the third is related to path resistance drop. Given the maximum current conducted, the application shall limit the maximum undershoot peak voltage by minimizing the ratio:

$$\frac{L_{PAR_TOT}}{t_{fall}} \quad (3)$$

(Ex: if $I_{load} = 100$ A then $L_{PAR_TOT} = 4$ nH then t_{fall} must be kept higher than 33 ns)

The above-mentioned considerations also apply to SHS_n positive pulse which takes place when the inverter is working in generator mode.

2.1.2 Parametrical Operating Range

Within these operating ranges the part operates as specified and without parameter deviations. The device may show parameters deviation if parametrical operating conditions are exceeded.

Once taken beyond the operative ratings and returned back within, the part will recover with no damage or degradation (provided that AMR range is not exceeded). All analog and digital voltages are related to the potential at signal ground SGND. All currents are assumed to be positive when current flows into the pin.

Table 5. Parametrical operating conditions

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|---------------------|---|---------------------------|------|-----|------|------|-----------------------|
| Power Supply | | | | | | | |
| VBP_MOR_PAR | VBP: voltage range | - | 4.5 | - | 36 | V | - |
| VBP_MOR_PAR_EXT1 | VBP: extended voltage range 1 | t ≤ 15 min Tamb = 25°C | 36 | - | 48 | V | Jump Start Pulse |
| VBP_MOR_PAR_EXT2 | VBP: extended voltage range 2 | t ≤ 400 ms Tamb = 25°C | 48 | - | 60 | V | Load Dump Pulse |
| VDD_MOR_PAR_CSON | VDD: voltage range (CSON related parameter) | - | 4.85 | 5 | 5.15 | V | - |
| VDD_MOR_PAR | VDD: voltage range | - | 4.5 | 5 | 5.5 | V | - |
| VIO_MOR_PAR | VIO: voltage range | - | 2.5 | - | 5.5 | V | - |
| VPRE_MOR_PAR | VPRE: voltage range | - | 7 | - | 15 | V | - |
| VDH_MOR_PAR | VDH: voltage range | - | 4.5 | - | 52 | V | - |
| VDH_MOR_PAR_EXT1 | VDH: extended voltage range 1 | t ≤ 60 min Tamb = 25°C | 52 | - | 60 | V | Long Term Overvoltage |
| VDH_MOR_PAR_EXT2 | VDH: extended voltage range 2 | t ≤ 40 ms Tamb = 25°C | 60 | - | 70 | V | Transient Overvoltage |

Note: All parameters are guaranteed and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

2.2 Absolute Maximum Ratings (AMR)

Maximum ratings are absolute ratings; exceeding any one of these values may cause permanent damage to the integrated circuit. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. All analog and digital voltages are related to the potential at signal ground SGND. All currents are assumed to be positive when current flows into the pin.

Table 6. Absolute maximum ratings

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|---------------------------|--|------------------------------|------|-----|-------------------|------|--------------------------------|
| Power Supply | | | | | | | |
| VBP_AMR_DC | VBP: DC voltage range | - | -0.3 | - | 65 ⁽¹⁾ | V | - |
| VBP_AMR_AC | VBP: transient voltage range | t ≤ 400 ns; IVBP ≤ 500 mA | -1 | - | 65 ⁽¹⁾ | V | Not subject to production test |
| VDH_AMR_DC | VDH: DC voltage range. | - | -0.3 | - | 75 ⁽²⁾ | V | - |
| VDH_AMR_AC | VDH: transient voltage range. | t ≤ 400 ns; IVDH ≤ 500 mA | -1 | - | 90 | V | Not subject to production test |
| d_VDH_VBP_AMR | VDH - VBP Differential voltage between VDH and VBP | - | -65 | - | 75 | V | - |
| VDD_AMR | VDD: voltage range | - | -0.3 | - | 20 | V | - |
| VIO_AMR | VIO: voltage range | - | -0.3 | - | 20 | V | - |
| Gate Driver Supply | | | | | | | |
| CP1M_AMR | CP1M: voltage range | - | -0.3 | - | 65 | V | - |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|---------------------|---|-----------------------------------|--------------------|-----|--------------------|------|--|
| d_VBP_CP1M_AMR | VBP - CP1M: Charge Pump1 external differential voltage between VBP and CP1M | - | -0.3 | - | 65 | V | - |
| CP1P_AMR | CP1P: voltage range | - | -0.3 | - | 20 | V | - |
| d_CP1P_CP1M_AMR | CP1P - CP1M: Charge Pump1 external capacitance terminals differential voltage | - | -65 | - | 20 | V | - |
| d_VBP_CP1P_AMR | VBP - CP1P: Charge Pump1 external differential voltage between VBP and CP1P | - | -20 | - | 65 | V | - |
| d_VPRE_CP1P_AMR | VPRE – CP1P: Charge Pump1 external differential voltage between VPRE and CP1P | - | -0.3 | - | 20 | V | - |
| VPRE_AMR | VPRE: voltage range | - | -0.3 | - | 20 | V | - |
| CP2M_AMR | CP2M: voltage range | - | -0.3 | - | 75 | V | - |
| d_VPRE_CP2M_AMR | VPRE – CP2M: Charge Pump2 external differential voltage between VPRE and CP2M | - | -75 | - | 20 | V | - |
| CP2P_AMR | CP2P: voltage range | - | -0.3 | - | 95 | V | - |
| d_CP2P_CP2M_AMR | CP2P – CP2M: Charge Pump2 external capacitance terminals differential voltage | - | -20 | - | 75 | V | - |
| d_VPRE_CP2P_AMR | VPRE – CP2P: Charge Pump2 external differential voltage between VPRE and CP2P | - | -75 | - | 20 | V | - |
| d_VDH_CP2P_AMR | VDH – CP2P: Charge Pump2 external differential voltage between VDH and CP2P | - | -95 | - | 0.3 | V | - |
| d_VDH_VPRE_SHSN_AMR | VDH+VPRE-SHS_n: constraint on simultaneous voltage on VDH, VPRE and SHS_n/GHS_n | - | - | - | 100 ⁽³⁾ | V | [n=1,2,3] Application information |
| Gate Drivers | | | | | | | |
| CBS_AMR_DC_RES | CBS_n: DC voltage range in RESET | VDD < VDD UV + HYST | -0.3 | - | 95 | V | [n=1,2,3] |
| CBS_AMR_DC | CBS_n: DC voltage range | VDD ≥ VDD UV + HYST | -7 ⁽¹⁾ | - | 95 | V | [n=1,2,3] |
| CBS_AMR_AC | CBS_n: transient voltage range | VDD ≥ VDD UV + HYST t ≤ 200 ns | -14 ⁽¹⁾ | - | 95 | V | [n=1,2,3] Not subject to production test |
| d_CBSN_CP2P_AMR | CBS_n - CP2P: differential voltage between CBS_n and CP2P terminals | - | -95 | - | 20 | V | [n=1,2,3] |
| GHS_N_AMR_DC_RES | GHS_n: DC voltage range in RESET | VDD < VDD UV + HYST | -0.3 | - | 95 | V | [n=1,2,3] |
| GHS_N_AMR_DC | GHS_n: DC voltage range | VDD ≥ VDD UV + HYST | -7 | - | 95 | V | [n=1,2,3] |
| GHS_N_AMR_AC | GHS_n: transient voltage range | VDD ≥ VDD UV + HYST t ≤ 200 ns | -14 | - | 95 | V | [n=1,2,3] Not subject to production test |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|--------------------|---|-----------------------------------|------------------|-----|-----|------|--|
| SHS_N_AMR_DC_RES | SHS_n: DC voltage range in RESET | VDD < VDD UV + HYST | -0.3 | - | 95 | V | [n=1,2,3] |
| SHS_N_AMR_DC | SHS_n: DC voltage range | VDD ≥ VDD UV + HYST | -7 | - | 75 | V | [n=1,2,3] |
| SHS_N_AMR_AC | SHS_n: transient voltage range | VDD ≥ VDD UV + HYST t ≤ 200 ns | -14 | - | 95 | V | [n=1,2,3] Not subject to production test |
| SHS_N_AMR_SR | SHS_n: transient slew rate | SR ≤ 1V/ns | - | - | 20 | V | [n=1,2,3] Not subject to production test |
| d_CBSN_GHSN_AMR | CBS_n - GHS_n: differential voltage between CBS_n and GHS_n terminals | - | -0.3 | - | 20 | V | [n=1,2,3] |
| d_CBSN_SHSN_AMR | CBS_n - SHS_n: Differential voltage between CBS_n and SHS_n | - | -0.3 | - | 20 | V | [n=1,2,3] |
| d_GHSN_SHSN_AMR_DC | GHS_n - SHS_n: Differential DC voltage between GHS_n and SHS_n | - | -0.3 | - | 20 | V | [n=1,2,3] |
| d_GHSN_SHSN_AMR_AC | GHS_n - SHS_n: Differential transient voltage between GHS_n and SHS_n | t ≤ 200 ns; IGHS_n ≤ -2A | -2 | - | 20 | V | [n=1,2,3] Not subject to production test |
| d_VDH_SHSN_AMR_RES | VDH - SHS_n: Differential voltage between VDH and SHS_n in RESET | VDD < VDD UV + HYST | -0.3 | - | 95 | V | - |
| d_VDH_SHSN_AMR | VDH - SHS_n: Differential voltage between VDH and SHS_n | VDD ≥ VDD UV + HYST | -14 | - | 95 | V | [n=1,2,3] |
| GLS_N_AMR_RES | GLS_n: DC voltage range in RESET | VDD < VDD UV + HYST | -0.3 | - | 95 | V | [n=1,2,3] |
| GLS_N_AMR | GLS_n: DC voltage range | VDD ≥ VDD UV + HYST | -7 | - | 20 | V | [n=1,2,3] |
| GLS_N_AMR_AC | GLS_n: transient voltage range | VDD ≥ VDD UV + HYST t ≤ 200 ns | -14 | - | 20 | V | [n=1,2,3] Not subject to production test |
| SLS_N_AMR_DC_RES | SLS_n: DC voltage range in RESET | VDD < VDD UV + HYST | -0.3 | - | 95 | V | [n=1,2,3] |
| SLS_N_AMR_DC | SLS_n: DC voltage range | VDD ≥ VDD UV + HYST | -7 | - | 20 | V | [n=1,2,3] |
| SLS_N_AMR_AC | SLS_n: transient voltage range | VDD ≥ VDD UV + HYST t ≤ 200 ns | -14 | - | 20 | V | [n=1,2,3] Not subject to production test |
| d_VPRE_GLSN_AMR | VPRE - GLS_n: Differential voltage between VPRE and GLS_n | - | -0.3 | - | 35 | V | [n=1,2,3] |
| d_VPRE_SLSN_AMR | VPRE - SLS_n: Differential voltage between VPRE and SLS_n | - | -0.3 | - | 35 | V | [n=1,2,3] |
| d_GLSN_SLSN_AMR_DC | GLS_n - SLS_n: Differential voltage between GLS_n and SLS_n | - | 0 ⁽¹⁾ | - | 20 | V | [n=1,2,3] |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-------------------------|--|--|-------------------|-----|-----|------|--|
| d_GLSN_SLSN_AMR_AC | GLS_n - SLS_n: Differential voltage between GLS_n and SLS_n | $t \leq 200 \text{ ns}$; $I_{GLS_n} \leq -2 \text{ A}$ | -2 ⁽¹⁾ | - | 20 | V | [n=1,2,3] Not subject to production test |
| Current Monitors | | | | | | | |
| IS_AMR_DC_RES | ISn+/ISn-: DC voltage range in RESET | $V_{DD} < V_{DD} \text{ UV} + \text{HYST}$ | -0.3 | - | 20 | V | [n=1,2,3] |
| IS_AMR_DC | ISn+/ISn-: DC common mode voltage range | $V_{DD} \geq V_{DD} \text{ UV} + \text{HYST}$ | -7 | - | 20 | V | [n=1,2,3] |
| IS_AMR_AC | ISn+/ISn-: transient common mode voltage range | $V_{DD} \geq V_{DD} \text{ UV} + \text{HYST}$ $t \leq 200 \text{ ns}$ | -14 | - | 20 | V | [n=1,2,3] Not subject to production test |
| d_ISMPN_ISMN_AMR | ISn+ - ISn-: Differential voltage between ISn+ and ISn- | - | -5 | - | 5 | V | [n=1,2,3] |
| d_VPRE_IS_AMR | VPRE - ISn+/ISn-: Differential voltage between VPRE and ISn+/ISn- | - | 0 | - | 40 | V | [n=1,2,3] Not subject to production test |
| IS_AMR_SR | ISn+/ISn-: common mode transient slew rate | $SR \leq 1 \text{ V/ns}$ | - | - | 20 | V | [n=1,2,3] Not subject to production test |
| CSON_AMR | CSON: voltage range | - | -0.3 | - | 20 | V | [n=1,2,3] |
| d_VIO_CSON_AMR | VIO – CSON: differential voltage between VIO supply and CSON outputs | - | -0.3 | - | 20 | V | [n=1,2,3] |
| SPI Interface | | | | | | | |
| NCS_AMR | NCS: voltage range | - | -0.3 | - | 20 | V | - |
| SCLK_AMR | SCLK: voltage range | - | -0.3 | - | 20 | V | - |
| SDI_AMR | SDI: voltage range | - | -0.3 | - | 20 | V | - |
| SDO_AMR | SDO: voltage range | - | -0.3 | - | 20 | V | - |
| Digital I/O | | | | | | | |
| d_VIO_SDO_AMR | VIO – SDO: differential voltage between VIO supply and SDO outputs | - | -0.3 | - | 20 | V | - |
| d_VIO_PVF_AMR | VIO – PVF: differential voltage between VIO supply and PVF outputs | - | -20 | - | 20 | V | - |
| d_VIO_FSFLAG_AMR | VIO – FS_FLAG: differential voltage between VIO supply and FS_FLAG outputs | - | -0.3 | - | 20 | V | - |
| PVF_AMR | PVF: voltage range | - | -0.3 | - | 20 | V | - |
| FS_FLAG | FS_FLAG: voltage range | - | -0.3 | - | 20 | V | - |
| INHn_AMR | INHn: voltage range | - | -0.3 | - | 20 | V | [n=1,2,3] |
| INLn_AMR | INLn: voltage range | - | -0.3 | - | 20 | V | [n=1,2,3] |
| EN_BR_AMR | EN_BR: voltage range | - | -0.3 | - | 65 | V | - |
| NDIS_AMR | NDIS: voltage range | - | -0.3 | - | 65 | V | - |
| Grounds | | | | | | | |
| GND_AMR | SGND, PGND | - | -0.6 | - | 0.6 | V | - |

1. 36 V AMR over life-time. 48 V \geq AMR \geq 36 V for Jump Start transient pulse E-02 as defined in LV 124 standard and AMR \geq 48 V for Load Dump Test B transient pulse as defined in ISO 16750-2 standard.

- 52 V AMR over life-time. $60\text{ V} \geq \text{AMR} \geq 52\text{ V}$ for E48-01a transient pulse, $\text{AMR} \geq 60\text{ V}$ for E48-02 transients pulse as defined in VDA_320/LV 148 standard.
- The maximum voltage drop experienced by internal structures has to be limited to 100V in order to avoid damages. The HS pre-driver stage may experience together the maximum voltage and the minimum voltage all over L9908 respectively imposed by CP2 output voltage or CBS_n and SHS_n negative pulses. HS pre-driver then must be protected by ensuring that the absolute maximum voltage on CP2 or on CBS_n never takes place simultaneously with the absolute minimum voltage on SHS_n so that: $\text{VDH} * \text{VPRE} - \text{SHS}_n \leq 100\text{ W}$

Note: Integrated protection and diagnostics are designed to prevent device damage under the fault conditions defined in the functional description. Fault conditions are considered to be out of normal operating range. Protection functions are not designed for a continuous repetitive operation.

2.3 ESD resistivity

Table 7. ESD resistivity (pin level)

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-------------|----------------------------------|-------------------------|------|-----|-----|------|----------|
| HBM_LOC_ESD | HBM (Local Pins) ⁽¹⁾ | All pins ⁽²⁾ | -2 | - | 2 | kV | Class 2 |
| HBM_GLO_ESD | HBM (Global Pins) ⁽¹⁾ | VBP, VDH, SHS_n | -4 | - | 4 | kV | Class 3A |
| CDM_ESD | CDM ⁽¹⁾ | All pins | -500 | - | 500 | V | Class C3 |
| CDM_COR_ESD | CDM ⁽¹⁾ | Corner pins | -750 | - | 750 | V | Class C4 |
| LUT | Latch Up ⁽³⁾ | All pins | -100 | - | 100 | mA | - |

- According to AEC-Q100-011
- Pins are all GND connected together.
- According to AEC-Q100-004

2.4 Temperature ranges and thermal data

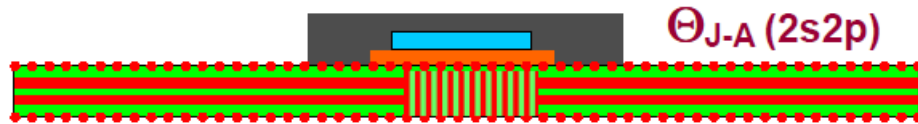
Table 8. Temperature ranges and thermal data

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|-----------------------------------|--|-----|-----|-----|------|--|
| T _{amb} | Operating temperature (ECU environment) | -40 | - | 150 | °C | - |
| T _j ⁽¹⁾ | Operating junction temperature | -40 | - | 150 | °C | - |
| T _j | Extended operating junction temperature | -40 | - | 175 | °C | 200h over life time |
| T _{sto} | Storage temperature | -55 | - | 150 | °C | |
| R _{thJA} ⁽²⁾ | Thermal resistance junction-to-ambient | - | 31 | - | °C/W | Homogeneous internal power distribution ⁽³⁾ |
| R _{thJcb} ⁽²⁾ | Thermal resistance junction-to-case-bottom | - | 2.1 | - | °C/W | Homogeneous internal power distribution |

- All parameters are guaranteed and tested, in the temperature range $T_j -40 \div 150^\circ\text{C}$ unless otherwise specified. The device is still operative and functional at higher temperatures (up to $T_j 175^\circ\text{C}$). Device functionality at high temperature is guaranteed by bench validation, electrical parameters are guaranteed by correlation with ATE tests at reduced temperature and adjusted limits (if needed).
- Not subject to production test, guaranteed by design.
- R_{thJA} value is retrieved according to Jedec JESD51-2,-5,-7 guideline with a 2s2p board.

Figure 5. 2s2p PCB with thermal vias

➤ 2s2p PCB + vias



Note: In "2s2p", the "s" suffix stands for "Signal" and the number before indicates how many PCB layers are dedicated to signal wires. The "p" suffix stands for "Power" and the number before indicates how many PCB layers are dedicated to power planes.

3 Current consumption

Table 9. Quiescent current consumption in reset mode

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|---------|---|---|-----|-----|-----|---------------|
| IQ_VBP1 | Quiescent consumption for VBP in reset mode | VBP = 14 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ VDD = 0 V | - | 0.5 | 15 | μA |
| IQ_VBP2 | Quiescent consumption for VBP in reset mode | VBP = 14 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ VDD = 0 V | - | 1.3 | 15 | μA |
| IQ_VBP3 | Quiescent consumption for VBP in reset mode | VBP = 60 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ VDD = 0 V | - | 2.2 | 15 | μA |
| IQ_VBP4 | Quiescent consumption for VBP in reset mode | VBP = 60 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ VDD = 0 V | - | 4.6 | 15 | μA |
| IQ_VDH1 | Quiescent consumption for VDH in reset mode | VDH = 14 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ VDD = 0 V | - | 0.3 | 15 | μA |
| IQ_VDH2 | Quiescent consumption for VDH in reset mode | VDH = 14 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ VDD = 0 V | - | 1 | 15 | μA |
| IQ_VDH3 | Quiescent consumption for VDH in reset mode | VDH = 60 V, $40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ VDD = 0 V | - | 0.8 | 15 | μA |
| IQ_VDH4 | Quiescent consumption for VDH in reset mode | VDH = 60 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ VDD = 0 V | - | 2.5 | 15 | μA |
| IQ_VIO1 | Quiescent consumption for VIO in reset mode | VIO = 5 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ VDD = 0 V | - | 5 | 15 | μA |
| IQ_VIO2 | Quiescent consumption for VIO in reset mode | VIO = 5 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ VDD = 0 V | - | 6 | 15 | μA |

Table 10. Mean current consumptions in normal mode

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|--------------|---|--|-----|-----|-----|------|
| INORMAL_VBP1 | Mean Current consumption for VBP in normal mode | VBP = 14 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 2.5 | 20 | mA |
| INORMAL_VBP2 | Mean Current consumption for VBP in normal mode | VBP = 14 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 2.5 | 20 | mA |
| INORMAL_VBP3 | Mean Current consumption for VBP in normal mode | VBP = 60 V, $-40^{\circ}\text{C} \leq T_j < 25^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 2.5 | 20 | mA |
| INORMAL_VBP4 | Mean Current consumption for VBP in normal mode | VBP = 60 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 2.5 | 20 | mA |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|--------------|---|---|-----|-----|-----|------|
| INORMAL_VDH1 | Mean Current consumption for VDH in normal mode | VDH = 14 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 3.5 | 15 | mA |
| INORMAL_VDH2 | Mean Current consumption for VDH in normal mode | VDH = 14 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 3.5 | 15 | mA |
| INORMAL_VDH3 | Mean Current consumption for VDH in normal mode | VDH = 60 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 3.5 | 15 | mA |
| INORMAL_VDH4 | Mean Current consumption for VDH in normal mode | VDH = 60 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 3.5 | 15 | mA |
| INORMAL_VDD1 | Mean Current consumption for VDD in normal mode | VDD = 5.5 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 23 | 40 | mA |
| INORMAL_VDD2 | Mean Current consumption for VDD in normal mode | VDD = 5.5 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 25 | 40 | mA |
| INORMAL_VIO1 | Mean Current consumption for VIO in normal mode | VIO = 5 V, $-40^{\circ}\text{C} \leq T_j \leq 25^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 2 | 4 | mA |
| NORMAL_VIO2 | Mean Current consumption for VIO in normal mode | VIO = 5 V, $25^{\circ}\text{C} < T_j \leq 150^{\circ}\text{C}$ Default Configuration and HBn_DIS=0 INLn=INHn=0, SHS_n=0 [n=1,2,3] | - | 2.5 | 4 | mA |

4 Functional safety

4.1 Safe states

To reach the safety requirements of the system, the following safe states are supported by L9908, with a different associated priority level:

- SAFE-OFF due to CLK1_TIME_OUT or NDIS='0'. Priority Level = 1
- SAFE-HIZ. Priority Level = 2
- SAFE-OFF due to STD Fault detection except INT_RST or Configurable fault with related FRC set as 00. Priority Level = 3
- SAFE-DIS. Priority Level = 4

In case of simultaneous safe state activation requests with different safe states required, the safe state reached by L9908 is determined by the highest priority level.

Note:

- *Priority is descending, 1 = higher priority.*
- *SAFE – OFF by NDIS assertion has the highest priority all over.*

4.1.1 SAFE-OFF

When SAFE-OFF is active the gate driver unit is disabled by forcing the three Half Bridges in a tristate mode so that VGHS_n-VSHS_n = 0 V actively, VGLS_n-VSLSn = HIZ and by disabling the Gate Drive Supply block (CP1_EN = CP2_EN = 0).

SAFE-OFF is activated by default if the following conditions are verified:

- STD Fault detection except INT_RST
- CLK1_TIME_OUT
- Configurable fault with related FRC set as 00
- NDIS = 0

4.1.2 SAFE-DIS

When SAFE-DIS is active the gate driver unit is disabled by forcing the three Half Bridges in a tristate mode so that VGHS_n-VSHS_n and VGLS_n-VSLSn are kept tight to 0 V actively.

SAFE-DIS is activated by default if the following conditions are verified:

- VPRE UV fault detection
- Configurable fault with related FRC set as 01
- EN_BR = 0

4.1.3 SAFE-HIZ

When SAFE-HIZ is active the gate driver unit is disabled by forcing the driver output in a tristate mode so that VGHS_n-VSHS_n and VGLS_n-VSLSn = HIZ.

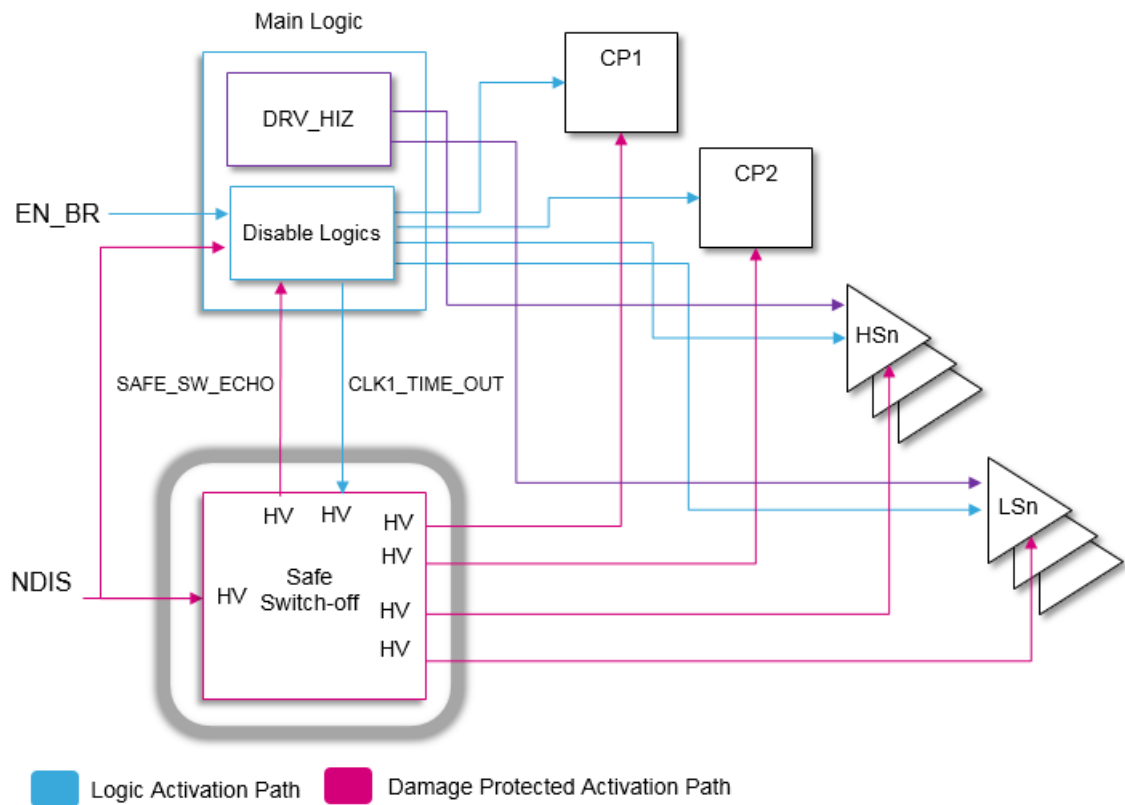
SAFE-HIZ is activated by default if the following conditions are verified:

- Fault detection which generates INT_RST
- SW_RST
- No STD faults present & HBn_DIS = 0 [n = 1,2,3] & STD DRV_HIZ = 1

4.2 Safe state activation

Depending on the safe state its activation is performed through one between two separate paths.

Figure 6. Safe states activation paths



Logic activation path: safe state activation is carried out entirely by the main logic.

This path is used to develop:

- SAFE HIZ (except if determined by CLK1_TIME_OUT)
- SAFE DIS
- SAFE OFF

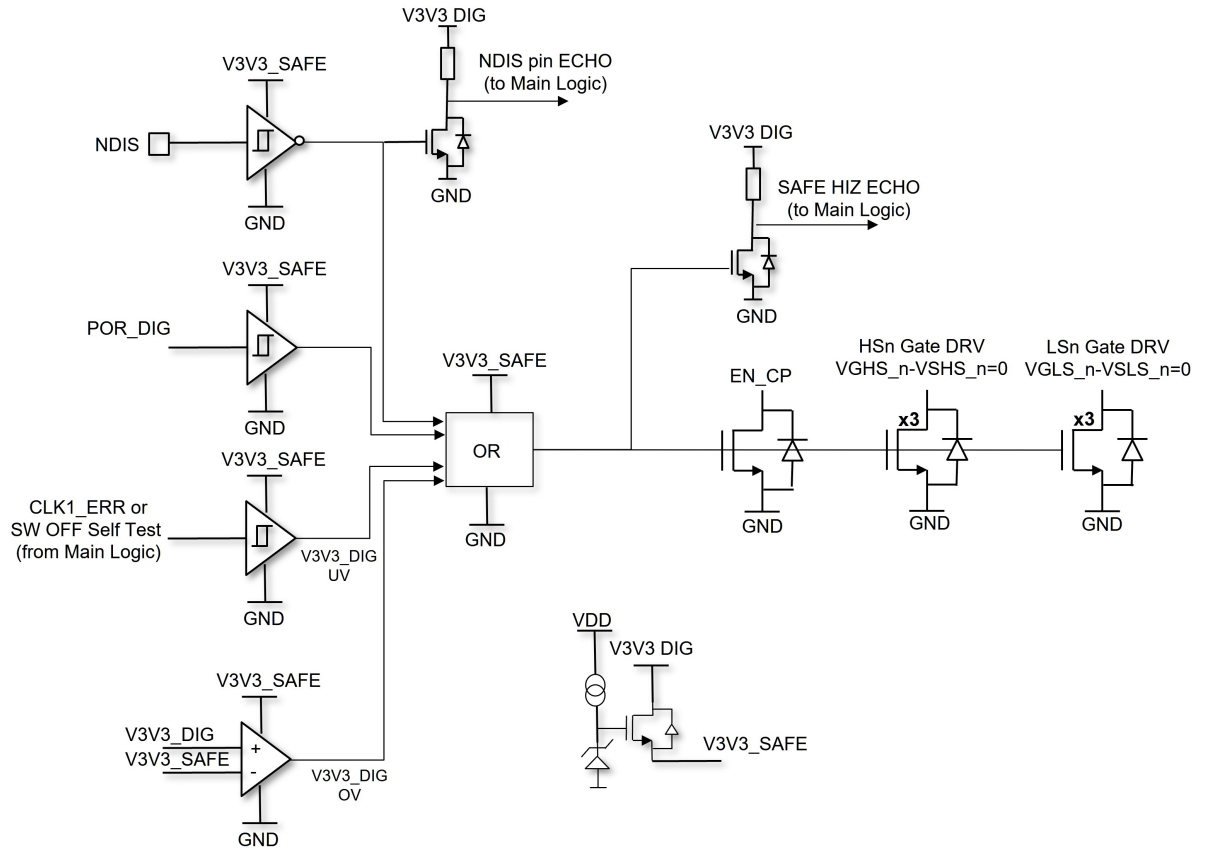
Damage protected activation path: in case of device failure where internal main logic integrity is compromised L9908 implements an isolated Safe Switch Off structure which allows to activate an isolated Safe Switch Off structure which can be activated through a separated path.

This path is used to develop:

- SAFE OFF (only if determined by NDIS = 0)
- CLK1_TIME_OUT

The Safe State activation through the damage protected path is signaled by setting the dedicated SPI read only bit SAFE_STATE (GEN_STATUS1[2]).

Figure 7. Damage protected activation simplified structure



5 Functional description

5.1 Internal supply

5.1.1 VDD power supply

The internal supply rails for analog and digital circuitries on L9908 are generated from the VDD pin which is the main power input. Additionally VDD is used as reference voltage for Current Measurement Analog output (CSO Buffers).

5.1.2 Internal supply monitor

Each internal supply voltage level (V3V3_ANA/DIG) is monitored by means of a dedicated UV and an OV diagnosis. Abnormal behavior on internal supply level will cause the generation of a POR (Power on Reset) event that consequently sends L9908 into a RESET state. Hysteresis on thresholds and filtering time are implemented.

If $V3V3_ANA/DIG \leq V3V3_uv_th$ occurs for an interval longer than $T_por_htol_flt$, INT_RST flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by an SPI command. POR_ANA/DIG is set low and internal reset is triggered.

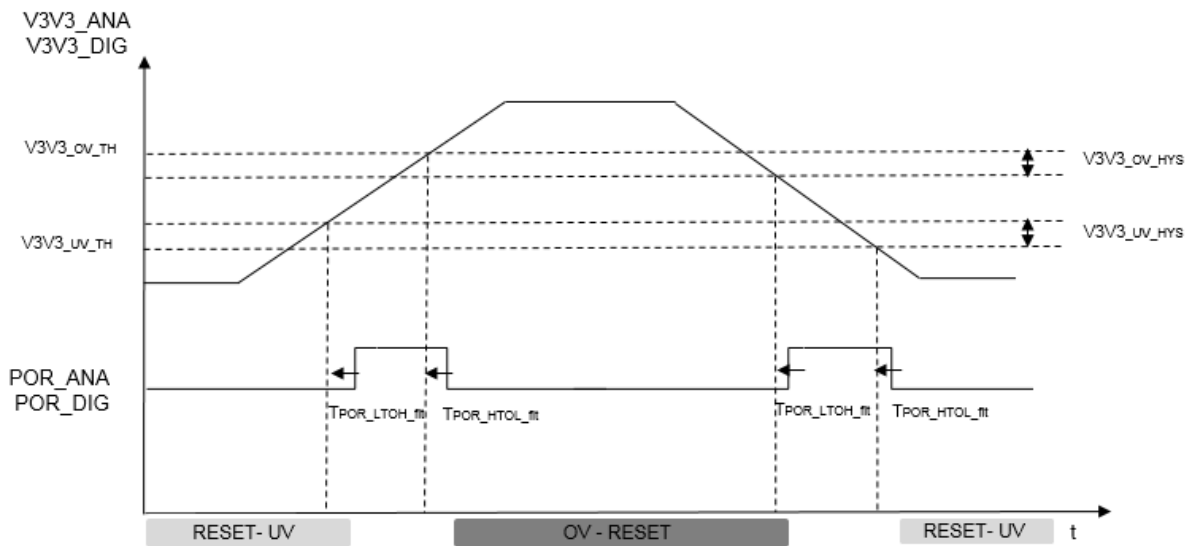
If $V3V3_ANA/DIG \geq V3V3_ov_th$ occurs for an interval longer than $T_por_htol_flt$, INT_RST flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by an SPI command. POR_ANA/DIG is set low and internal reset is triggered. OV/UV Resets related to V3V3 internal reference are represented in Figure 8.

The internal supply monitor is safety relevant and then a self-check procedure is implemented.

Note: All parameters are guaranteed and tested in the voltage ranges specified in Table 5 unless otherwise specified. Where not specified parametrical operating range equals functional operating range.

Table 11. Internal power supply electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|----------------|--|-------|------|-------|------|-------------------------------|
| VBG_vout | Bandgap output voltage | 1.188 | 1.2 | 1.212 | V | - |
| V3V3_vout | V3V3_ANA/DIG output voltage | 3.2 | 3.3 | 3.34 | V | - |
| V3V3_uv_th | V3V3_ANA/DIG under-voltage threshold | 2.65 | 2.73 | 2.93 | V | Comparator output Low to High |
| V3V3_uv_hys | V3V3_ANA/DIG under-voltage hysteresis | 35 | 45 | 56 | mV | - |
| V3V3_ov_th | V3V3_ANA/DIG over-voltage threshold | 3.6 | 3.7 | 3.9 | V | Comparator output Low to High |
| V3V3_ov_hys | V3V3_ANA/DIG over-voltage hysteresis | - | 0 | - | mV | - |
| V3V3_pre_vout | V3V3_PRE output voltage | 2.7 | 3.35 | 3.55 | V | - |
| T_por_ltoh_flt | POR_V3V3 Low to High state filter time | 3.2 | 4.8 | 7.3 | μs | Analog filter |
| T_por_htol_flt | POR_V3V3 High to Low state filter time | 5.4 | 8.3 | 13.5 | μs | Analog filter |

Figure 8. Internal supply operative range


5.1.3 VDD monitor

VDD voltage level is monitored by means of dedicated UV and an OV diagnosis. Hysteresis on thresholds and filtering time are implemented.

If $VDD \leq VDD_{uv_th}$ occurs for an interval longer than $T_{por_htol_fit}$, INT_RST flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by SPI command. POR_ANA is set low and internal reset is triggered.

If $VDD \geq VDD_{ov_th}$ occurs for an interval longer than T_{vdd_ov} , VDD_OV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by SPI command.

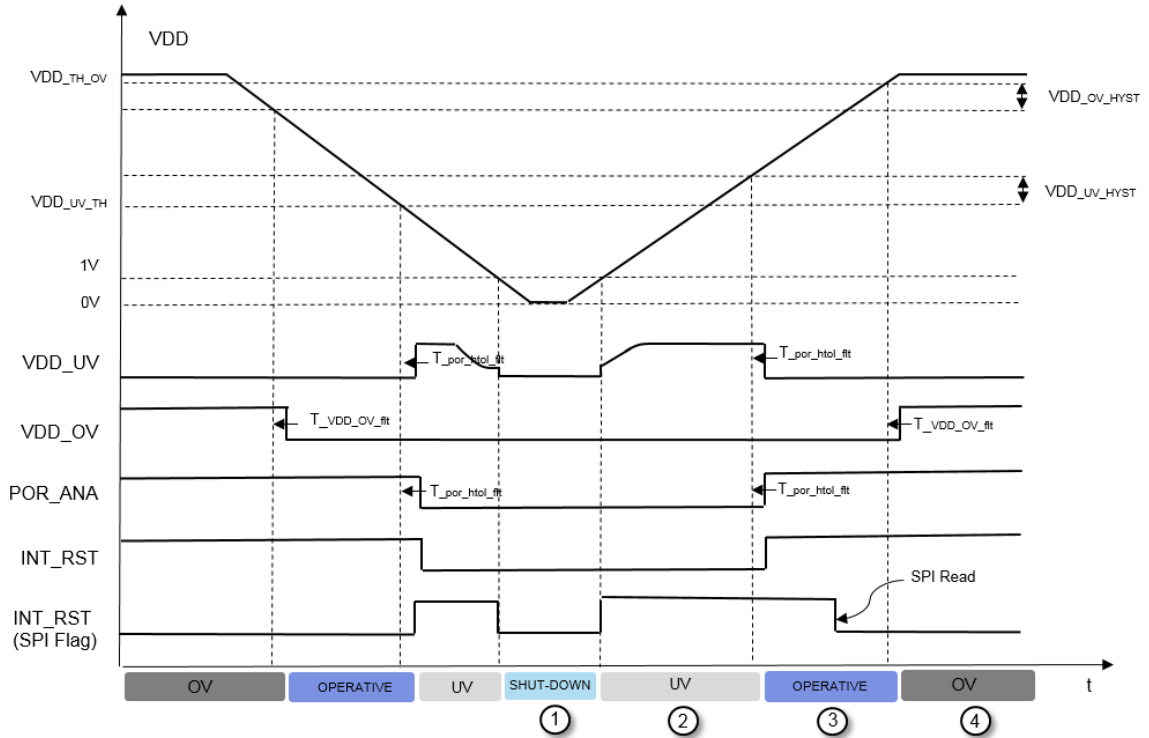
Device's functional ranges related to VDD level are represented in Figure 9.

The operative VDD monitor is safety relevant and then a self-check procedure is implemented.

Note: All parameters are guaranteed and tested in the voltage ranges reported in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Table 12. VDD monitor electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|--------------|--|------|------|------|---------|-------------------------------|
| VDD_uv_th | VDD under-voltage threshold | 3.95 | 4.05 | 4.15 | V | Comparator output Low to High |
| VDD_uv_hys | VDD under-voltage hysteresis | 135 | - | 165 | mV | |
| VDD_ov_th | VDD over-voltage threshold | 5.5 | - | 6 | V | Comparator output Low to High |
| VDD_ov_hys | VDD over-voltage hysteresis | 120 | 170 | 220 | mV | |
| T_vdd_ov_fit | VDD over-voltage detection filter time | 1 | - | 5 | μ s | Digital filter |

5.1.3.1 VDD functional ranges
Figure 9. VDD functional ranges


Where:

1. $0V \leq VDD \leq 1V$
L9908 is shut-down. Internal supply and reference voltage/currents levels are shutdown.
2. $1V \leq VDD \leq VDD_{uv_th} + VDD_{uv_hyst}$
VDD is in under-voltage and L9908 is sent into RESET mode. Internal supply and reference voltage/currents levels are degraded. Internal registers are under reset.
3. $VDD_{uv_th} \leq VDD \leq VDD_{ov_th}$
Internal supply and reference voltage/currents are available. Internal registers are out of reset. (if no STD faults are detected and NDIS='1' the device is in NORMAL mode).
4. $VDD_{ov_th} \leq VDD$
VDD is in over-voltage and L9908 sent into safe state. The internal supply and reference voltage/currents are available. Internal registers are out of reset.

5.2 Internal resets (INT_RST, CFG_RST)

L9908 implements two different reset states following two different reset signals INT_RST and CFG_RST.

- INT_RST (active LOW) is the main internal reset signal; when active it resets the whole logic system.
This signal is generated via the reset logic by supervising Internal Supply Monitor, VDD Monitor and ICM outputs: if a fault is verified the internal reset is activated.
The internal INT_RST can be alternatively triggered through an activation key written into a dedicated SPI register SW_RESET_KEY.

Table 13. SW reset activation register

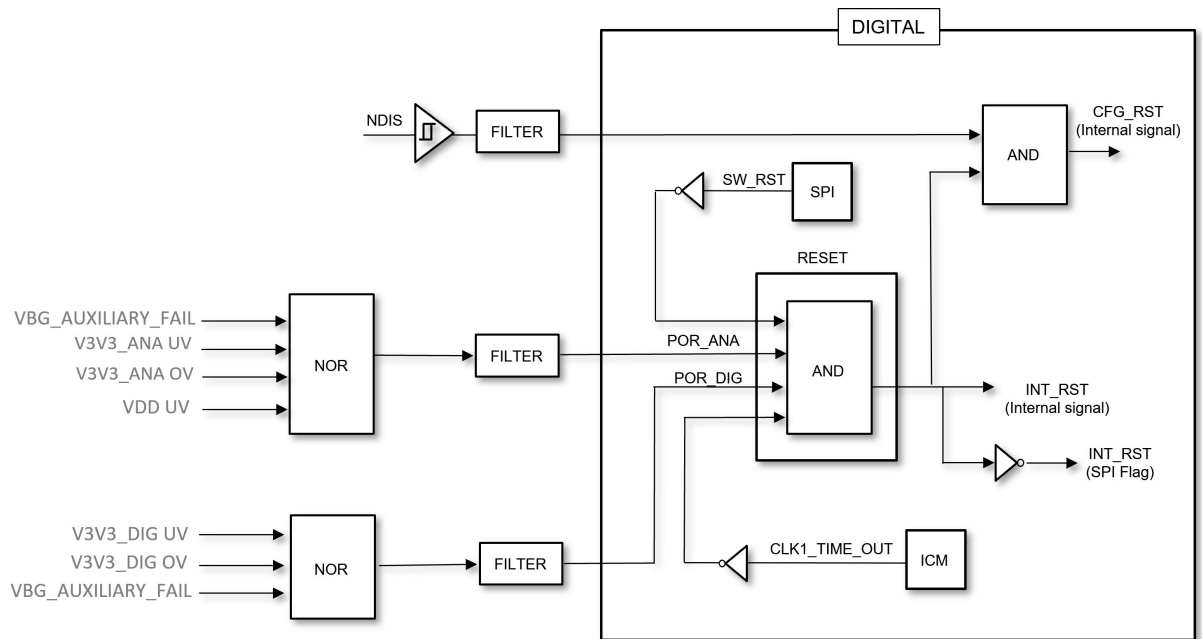
| SW_RESET_KEY <7:0> | Description |
|--------------------|---------------------|
| 0xCC | SW Reset Activation |

- CFG_RST (active LOW) is the reset signal configuration register.
This signal is generated via the reset logic by supervising the NDIS pin status level: if a '0' logic level is detected for a time interval greater than T_ndis_fit the reset is activated.

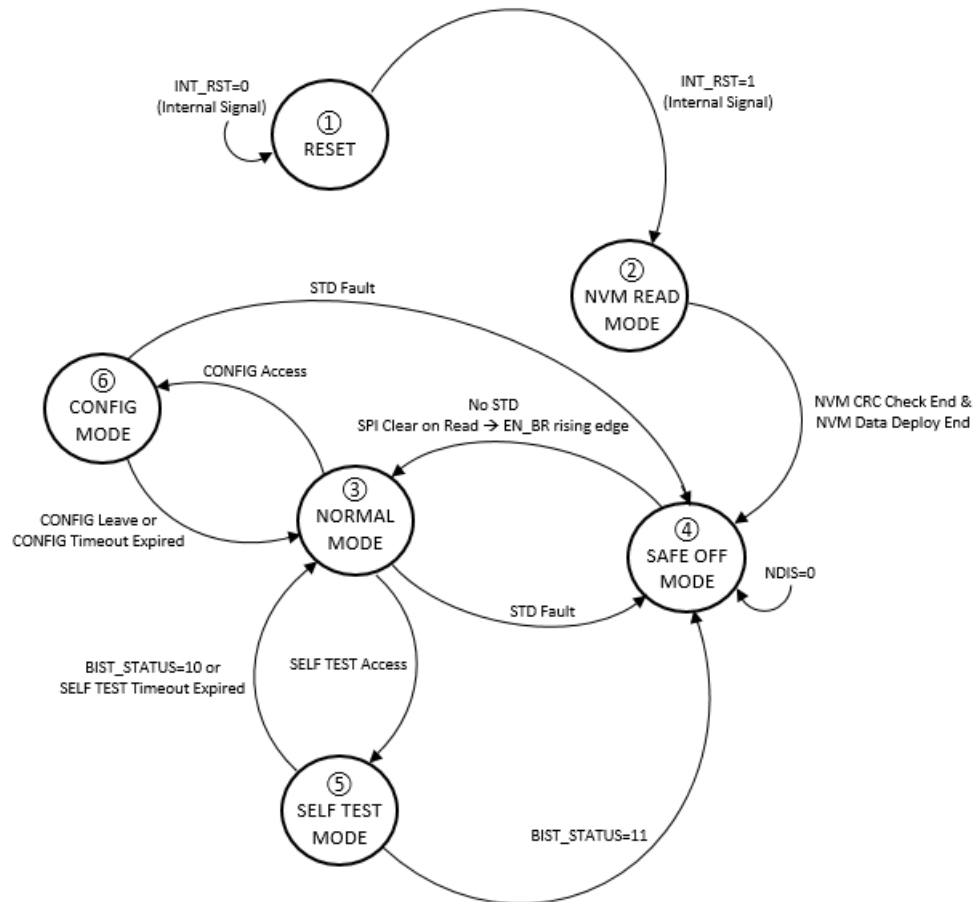
Table 14. Internal resets sources and filtering

| Condition | Action | Filter timer for Reset |
|----------------------|---------------------|------------------------|
| NDIS='0' | CFG_RST=0 | T_ndis_fit |
| UV on V3V3_ANA | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| UV on V3V3_DIG | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| OV on V3V3_ANA | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| OV on V3V3_DIG | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| UV on BG MAIN | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| UV on BG AUXILIARY | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| UV on VDD | CFG_RST=0 INT_RST=0 | T_por_ltoh_fit |
| CLK1 timeout (stuck) | CFG_RST=0 INT_RST=0 | ICM Timeout |
| SW Reset SPI frame | CFG_RST=0 INT_RST=0 | NA |

Figure 10. Internal reset logic simplified block diagram



5.3 Device operation state machine

Figure 11. Device operational state machine


Where:

1. RESET MODE

Internal supply and reference voltage/currents levels are degraded or shutdown. Main logic is under reset (INT_RST = '0', Internal signal). All functions are disabled:

- Gate Driver Supply stage and Half Bridge Gate Drivers stage are shutdown (SAFE-HIZ)
- Current Monitors chains and monitoring units are shutdown
- SPI Read/Write operations are not available

The device persists in this state as long as INT_RST='0' (Internal signal).

2. NVM READ MODE

Internal supply and reference voltage/currents are available possibly exceeding spec parametrical ranges. Main logic is out of reset (INT_RST = '1', Internal signal). Main functions are disabled:

- Gate Driver Supply stage disabled
- Half Bridge Gate Drivers stages are in HIZ mode while LS Half Bridge Gate Drivers stages are shutdown (SAFE-HIZ)
- Current Monitors chains and monitoring units are disabled
- SPI Read is available while SPI Write is disabled

In this mode a CRC check on NVM data is first performed:

- If no CRC error is detected the NVM content is deployed into main logic register
- If a CRC error is detected the related main logic registers are reset to default values (all '0') and NVM_CRC_FAIL flag is set to '1'

Note: All parameters are guaranteed and tested in the voltage ranges reported in [Table 5](#) unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Table 15. Power up/down timings

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|--------|--------------------------------|-----|-----|-----|------|--------------------------------|
| T_nvm | NVM data deploy & CRC duration | - | - | 2 | ms | Not subject to production test |

3. NORMAL MODE

Internal supply and reference voltage/currents are available and within spec ranges. Main logic is out of reset (INT_RST = '1', Internal signal). Main functions:

- Half Bridge Gate Drivers status depends on disable logic assessment (Functional or SAFE_DIS)
- Gate Driver Supply stage status depends on configuration
- Current Monitors chains and monitoring units status depend on configuration
- SPI Read/Write operations are available

4. SAFE OFF MODE

Internal supply and reference voltage/currents are available and within spec ranges. Main logic is out of reset (INT_RST = '1', Internal signal). Main functions:

- Gate Driver Supply stage is disabled
- HS and LS state are in SAFE_OFF or SAFE_HIZ depending on fault reaction as described in [Table 17](#)
- Current Monitors chains and monitoring units status depend on configuration
- SPI Read/Write operations are available

5. SELF TEST MODE

Internal supply and reference voltage/currents are available and within spec ranges. Main logic is out of reset (INT_RST = '1', Internal signal). Main functions:

- Gate Driver Supply stage depends on disable logic assessment
- Half Bridge Gate Drivers are disabled (SAFE-DIS)
- Current Monitors chains and monitoring units status depend on configuration
- SPI Read is available while SPI Write is disabled

6. CONFIG MODE

Internal supply and reference voltage/currents are available and within spec ranges. Main logic is out of reset (INT_RST = '1', Internal signal). Main functions:

- Half Bridge Gate Drivers status depends on disable logic assessment (Functional or SAFE_DIS)
- Gate Driver Supply stage status depends on configuration
- Current Monitors chains and monitoring units status depend on configuration
- SPI Read/Write operations are available

Three SPI readable flags are present to read-back the operational state machine status according to the following table:

Table 16. Operation mode status bits

| OPERATION_MODE2 | OPERATION_MODE1 | OPERATION_MODE0 | Description |
|-----------------|-----------------|-----------------|----------------|
| 0 | 0 | 0 | RESET Mode |
| 0 | 0 | 1 | NVM Read Mode |
| 0 | 1 | 0 | SAFE OFF Mode |
| 0 | 1 | 1 | NORMAL Mode |
| 1 | 0 | 0 | CFG Mode |
| 1 | 0 | 1 | SELF TEST Mode |
| 1 | 1 | 0 | RESET Mode |
| 1 | 1 | 1 | RESET Mode |

Table 17. Device operation modes summary

| Operation Mode | Logic Core | Gate Driver Supply | HS/LS Pre-drivers | Current Monitors | Diagnosis | SPI Access |
|----------------|------------|--------------------|-----------------------|------------------|---------------|------------|
| RESET | Reset | Disabled | SAFE_HIZ | Disabled | Disabled | Disabled |
| NVM READ | Functional | Disabled | SAFE_HIZ | Disabled | Disabled | Read |
| SELF TEST | Functional | As configured | SAFE_DIS | As configured | As configured | Read |
| SAFE OFF | Functional | Disabled | SAFE_OFF/ SAFE_HIZ | Disabled | As configured | Read/Write |
| CONFIG | Functional | As configured | Functional/SAFE_DIS | As configured | As configured | Read/Write |
| NORMAL | Functional | As configured | Functional/SAFE_DIS | As configured | As configured | Read/Write |

5.4 Configuration mode

The L9908 default configuration can be modified by properly writing the SPI configuration registers.

Configuration registers are divided into three categories depending on their functional safety relevance:

- Safety Relevant Registers (SRR): the content of these registers is protected by a two-step LOCK mechanism: CONFIG mode access procedure and a masking related to Half Bridges status (EN_BR = 0 or HBn_DIS = 1 with n = 1, 2, 3). The content is then protected by a cyclic 5-bit CRC check.
- Safety Latent Registers (SLR): the content of these registers is protected by a one-step LOCK mechanism: CONFIG mode access procedure. The content has no CRC protection.
- Non-safety Registers (NSR): the content of these registers can be accessed directly in NORMAL Mode and has no CRC protection.

Correct SRR modification is safety relevant and then a CRC check on their bit is performed continuously by a dedicated state machine. CRC check is performed sequentially over the 11 bits content of shadow register, LSB first. The 5-bit CRC is calculated using the following polynomial expression over bit 5-15:

$$g(x) = x^5 + x^2 + 1 \quad (4)$$

The initial value to be used is 11111 (0x1F).

Example:

- Input word: [000.0000.0100] (0x004)
- Computed CRC: [0.1011] (0XB)
- Resulting frame: [0000.0000.1000.1011] (0X8B)

If a CRC violation on one or more SRR the SR_CRC_FAIL flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

5.4.1 Configuration mode activation

An accidental SRR and SLR change must be avoided therefore a finite state machine is implemented to access the CONFIG mode.

The CONFIG mode access state machine is composed by 2 sequential states, the passage from a state to the next one is carried out by the acknowledgment of a dedicated UNLOCK frames sequence to be written in the SPI register CFG_EN_UNLOCK (UNLOCK1 key: 0x55 → UNLOCK2 key: 0x33).

The correct completion of the CONFIG Mode procedure gives access to SLR. Access to SRR is further masked until EN_BR = 0 or HBn_DIS = 1 [n = 1, 2, 3].

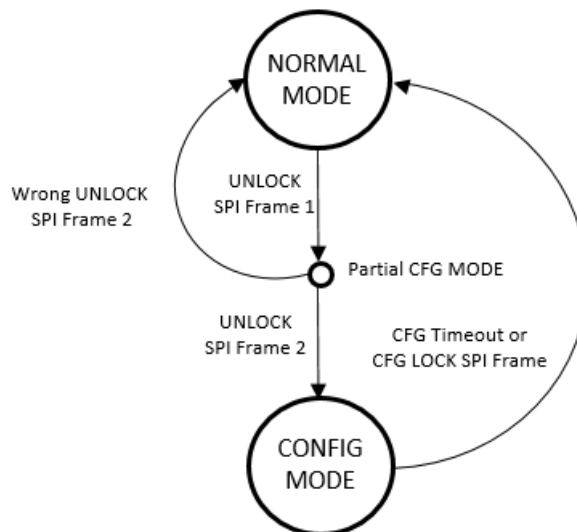
Table 18. CONFIG mode activation register

| CFG_EN_UNLOCK <7:0> | Description |
|---------------------|--------------------|
| 0x55 → 0x33 | CONFIG Mode Access |
| 0xAA | CONFIG Mode Exit |

Note:

- SRR and SLR configuration will become effective the next clock cycle after the completed writing operation.
- Write attempts on SRR and SLR are ignored as long as the previous requirements aren't met.
- Write attempts on Read Only (RO) registers are ignored, no matter if the register is NSR, SLR or SRR.

Figure 12. CONFIG mode state machine



The configuration mode is left by a dedicated LOCK frame (LOCK key: 0xAA) to be written in the SPI register CFG_EN_UNLOCK, which confirms the written changes and locks them on writing. The configuration mode is also left automatically after the CONFIG mode time-out expiration: if no correct LOCK SPI frame is detected within T_cgf_time_out, the CONFIG mode is left.

Note:

All parameters are guaranteed and tested in the voltage ranges reported in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Table 19. CFG timeout

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|----------------|-------------------|-----|-----|-----|------|--------------------------------|
| T_cgf_time_out | CFG Mode Time-out | - | 100 | - | ms | Not subject to production test |

5.5 Self-test mode

A built-in self-test (BIST) procedure is implemented to check safety relevant circuitries both in digital core and in the analog monitor circuits on L9908.

The target of core logic self-test is to check the correct functionality of the Internal Clock Monitor.

The target of the analog monitor is to check the correct functionality of the comparators involved in the safety relevant monitors and of the Safety Switch Off path.

To allow a certain amount of freedom the block on which the self-test procedure runs can be configured by setting a dedicated SPI frame.

Note:

- During Self-Test of the SW OFF path SAFE-OFF state is activated
- In case of BIST_STATUS = 11 (BIST check failure), the device is sent in SAFE_OFF Mode; re-engage procedure can be performed only by issuing a SW_RESET command

Table 20. Self-test selection bits

| SELF_TEST_CFG4 | SELF_TEST_CFG3 | SELF_TEST_CFG2 | SELF_TEST_CFG1 | SELF_TEST_CFG0 | Description |
|----------------|----------------|-----------------|----------------|----------------|-----------------------------|
| OND LS | OND HS | Supply Monitors | SW OFF Path | Clock Monitor | Self-Test Not Active |
| 0 | 0 | 0 | 0 | 0 | |
| 1 | 1 | 1 | 1 | 1 | Self-Test Active (Defaults) |

Note:

Supply Monitors include: Internal Supply, VDD, VPRE, VCP, VBP, VDH and GLM.

Self-Test procedure is developed in different steps in the following order:

- Clock Monitor
- Supply Monitor & OND_LS & OND_HS
- SW OFF Path

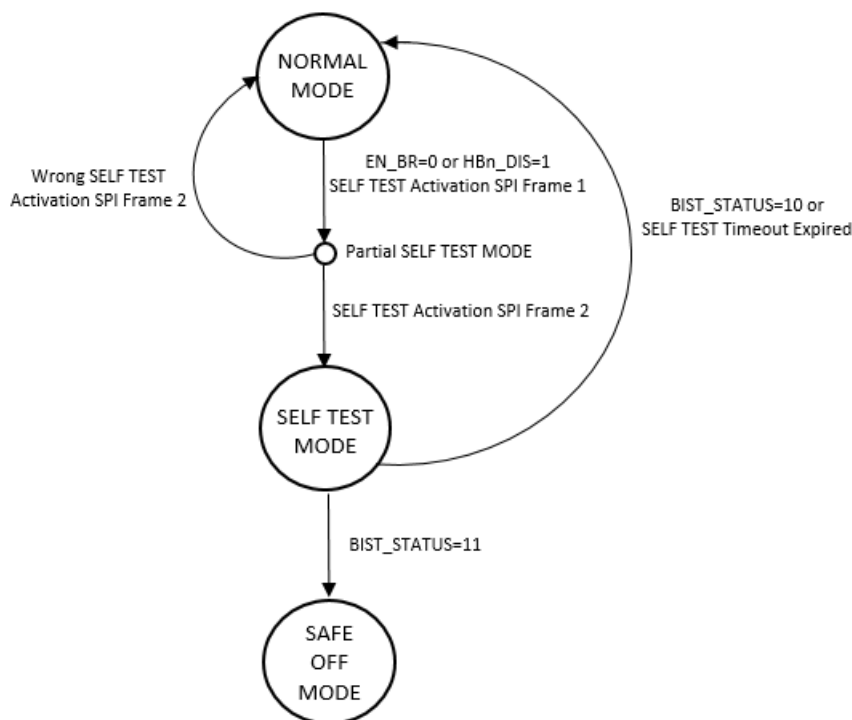
5.5.1 Self-test activation

When Self-Test procedure is active, safety related analog and digital parts are under test, thus are not functional; this implies that Self-Test procedure can be activated only when no actuation is applied to half bridges: HBn_DIS = 1 [n = 1, 2, 3] or EN_BR = 0.

Accidental Self-Test procedure activation must be avoided therefore a finite state machine is implemented. The Self-Test activation state machine is composed by 2 sequential states, the passage from a state to the next one is carried out by a correct Self-Test activation SPI frame sequence to be written in the SPI register BIST_KEY (SELF-TEST1 key: 0x55 → SELF-TEST 2 key: 0x33).

Table 21. Self-test mode activation register

| BIST_KEY <7:0> | Description |
|----------------|-----------------------|
| 0x55à0x33 | SELF TEST Mode Access |

Figure 13. Self-test mode state machine (NORMAL MODE)


Note: Self-Test procedure shall be activated only when the L9908 is supplied within its Functional Operating Range otherwise the self-check may fail.

Two SPI readable flags are present in the register **GEN_STATUS1** to read-back the BIST state machine activation status according to the following table:

Table 22. Self-test procedure status bits

| SELF_TEST_STATUS1 | SELF_TEST_STATUS0 | Description |
|-------------------|-------------------|------------------------------------|
| 0 | 0 | SELF TEST stop |
| 0 | 1 | SELF TEST running |
| 1 | 0 | SELF TEST finished with NO Failure |
| 1 | 1 | SELF TEST finished with Failure |

The self-test mode is left when procedure ends or after the Self-Test Time-out expiration: after accessing self-test mode a timeout is started, when the timeout expires, it is aborted.

Note: All parameters are guaranteed and tested in the voltage ranges reported in [Table 5](#) unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Table 23. Self-test timings and timeout

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|---------------------|------------------------------|------|------|------|------|--------------------------------|
| T_hwsc | Self-Test procedure duration | 0.65 | - | 0.75 | ms | Not subject to production test |
| T_selftest_time_out | SELF TEST Mode Time-out | 0.77 | 0.88 | 0.99 | ms | Not subject to production test |

5.6 Fault Handling Management (FHM)

The fault set is divided into two main categories based on the required corrective actions:

- STD (Shutdown Faults): this set includes faults which are highly dangerous for the IC or the application and that needs a quick corrective action to avoid harming;
- WRN (Warnings): this set includes all those faults against which the application and the device are tolerant and the corrective action can be waived or delayed.

L9908 allows a certain degree of fault management customization a subset of available enabled faults can be configured by setting the proper FHC registers.

Table 24. Fault summary

| Fault Flag | Source Diagnosis | Self-Check | Failure Reaction | Fault Description |
|---|-------------------------|------------|--------------------------------|---|
| INT_RST=1 | Internal Supply Monitor | Yes | RESET | Under-voltage on V3V3_ANA |
| INT_RST=1 | Internal Supply Monitor | Yes | RESET | Under-voltage on V3V3_DIG |
| INT_RST=1 | Internal Supply Monitor | Yes | RESET | Over-voltage on V3V3_ANA |
| INT_RST=1 | Internal Supply Monitor | Yes | RESET | Over-voltage on V3V3_DIG |
| INT_RST=1 | VDD Monitor | Yes | RESET | Under-voltage on VDD |
| VDD_OV=1 | VDD Monitor | Yes | SAFE-OFF | Over-voltage on VDD |
| INT_RST=1 | ICM | Yes | RESET & SAFE_OFF | Main clock stuck violation |
| CLK1_ERR=1 CLK2_ERR=1 CLK2_TIME_OUT=1 | ICM | No | Flag only (NORMAL) | Oscillators mismatch or auxiliary clock stuck violation |
| PGND_LOSS=1 AGND_LOSS=1 DGND_LOSS=1 | GLM | Yes | Flag only (NORMAL) | Loss of power or signal grounds |
| OTM_SD=1 | OTM | No | SAFE-OFF | Thermal shutdown |
| OTM_WR=1 | OTM | No | Flag only (NORMAL) | Thermal warning |
| STDn_PWM =1 [n=1,2,3] | STD on PWM | No | Ignore overlapping PWM command | Shoot through on half bridge n (PWM input) |
| STDn_VGS =1 [n=1,2,3] | STD on VGS | No | Configurable | Shoot through on half bridge n (Ext. FET Vgs) |
| HSn_STG = 1 [n=1,2,3] | OND | Yes | Configurable | Short to ground on SHS_n |
| LSn_STB=1 [n=1,2,3] | OND | Yes | Configurable | Short to battery on SHS_n |
| HS2_OFD=1 LSn_OFD=0 [n=1,2,3] | OFD | Yes | Flag only (NORMAL) | Short to ground on one or multiple motor phase |
| HS2_OFD=0 LSn_OFD=1 [n=1,2,3] | OFD | Yes | Flag only (NORMAL) | Short to battery on one or multiple motor phase |
| HS2_OFD=0 LSn_OFD=011,101,100 [n=1,2,3] | OFD | Yes | Flag only (NORMAL) | Open connection on motor phase 1,2,3 |

| Fault Flag | Source Diagnosis | Self-Check | Failure Reaction | Fault Description |
|-----------------|-------------------------|------------|------------------------------|---------------------------------|
| VDH_UV=1 | MBM | Yes | Configurable | Under-voltage at VDH pin |
| VDH_OV=1 | MBM | Yes | Configurable | Over-voltage at VDH pin |
| VPRE_UV=1 | VPRE Monitor | Yes | Auto-retry | Under-voltage at VPRE pin |
| VPRE_OV=1 | VPRE Monitor | Yes | SAFE-OFF | Over-voltage at VPRE pin |
| VCP_UV=1 | VCP Monitor | Yes | Flag only (NORMAL) | Under-voltage at CP2 output |
| VCP_OV=1 | VCP Monitor | Yes | Flag only (NORMAL) | Over-voltage at CP2 output |
| VBP_UV=1 | VBP Monitor | Yes | Configurable | Under-voltage at VBP pin |
| VBP_OV=1 | VBP Monitor | Yes | Configurable | Over-voltage at VBP pin |
| WDT_DATA_fail=1 | WDT | NA | SAFE-OFF | Watchdog reset failure |
| WDT_OVF_fail=1 | WDT | NA | SAFE-OFF | Watchdog time-out failure |
| SPI_ERR=1 | SPI CRC Check | NA | Ignore Frame | SPI CRC Check failure |
| SPI_ERR=1 | SPI FC Check | NA | Ignore Frame | SPI FC Check failure |
| SPI_ERR=1 | SPI Clock Counter Check | NA | Ignore Frame | SPI Clock Counter Check failure |
| NVM_CRC_FAIL=1 | NVM Data CRC Check | NA | SAFE-OFF Load default values | NVM Data CRC Check |
| CFG_CRC_FAIL=1 | SRR Data CRC Check | NA | SAFE-OFF | SRR Data CRC Check |
| BIST_STATUS=11 | BIST | NA | SAFE-OFF | BIST Failure |

5.6.1 FHC registers

The L9908 default FHM configuration can be modified by properly writing the FHC configuration registers through the CONFIG mode. FHC are considered as SRR.

5.6.1.1 Fault Reaction Configuration (FRC)

For each one of the fault listed in Table 24 two configuration bits allow to define whether the corrective action shall be automatically developed by the device itself or it can be waived.

Table 25. Fault Reaction Configuration bits

| <FLT_REF>_REACT_CFG1 | <FLT_REF>_REACT_CFG0 | Description |
|----------------------|----------------------|---|
| 0 | 0 | Full SW Off – disable all HB drivers and CPs, device goes in SAFE-OFF mode (Default) ⁽¹⁾ |
| 0 | 1 | Reduced Operation Mode – disable failing HB only, device remains in NORMAL mode ⁽²⁾ |
| 1 | 0 | Flag only – down-rate fault to simple warning, device remains in NORMAL mode ⁽³⁾ |
| 1 | 1 | Flag only – down-rate fault to simple warning, device remains in NORMAL mode ⁽³⁾ |

1. *Fault danger for the application is considered high, the corrective action shall be taken as soon as it is detected by the device itself by disabling all half bridges and charge pumps.*
2. *Fault danger for the application is considered high, the corrective action shall be taken as soon as it is detected by the device itself by disabling only the half bridge on which the fault is present still allowing a reduced performance operation.*
3. *Fault danger for the application is considered low, the fault can be ignored with no corrective action applied nor internal or external.*

The following table details the Fault Reaction Configurations available for the different Fault events.

Table 26. Internal Managed Faults reaction details

| Fault Flag | Device Fault | Half Bridge Fault | FRC Available |
|-------------|--------------|-------------------|---------------|
| STD_VGS_n=1 | - | X | (1)(2)(3) |
| HSn_STG = 1 | - | X | (1)(2)(3) |
| LSn_STG=1 | - | X | (1)(2)(3) |
| VDH_UV=1 | X | - | (1)(3) |
| VDH_OV=1 | X | - | (1)(3) |
| VBP_UV=1 | X | - | (1)(3) |
| VBP_OV=1 | X | - | (1)(3) |

1. Fault danger for the application is considered high, the corrective action shall be taken as soon as it is detected by the device itself by disabling all half bridges and charge pumps.
2. Fault danger for the application is considered high, the corrective action shall be taken as soon as it is detected by the device itself by disabling only the half bridge on which the fault is present still allowing a reduced performance operation.
3. Fault danger for the application is considered low, the fault can be ignored with no corrective action applied nor internal or external.

Note:

- While other configurations are available for all FHC faults the configuration 01 is available only on a limited subset. In Faults that don't support such a FRC the configuration 01 is reserved.
- For VDH_UV, VDH_OV, VBP_UV, VBP_OV and CFG_CRC_FAIL the configuration 01 has the same effect as configuration 10 and 11.

5.6.1.2 Fault Output Redirection (FOR)

L9908 implements a double source of fault signaling by pin FS_FLAG and by a dedicated SPI field present in every frame.

FS_FLAG output can be configured in push-pull mode or in open-drain mode by means of the following SPI bit:

Table 27. Fault output redirection configuration bit

| FS_FLAG_CFG | Description |
|-------------|---------------------|
| 0 | Push-pull (Default) |
| 1 | Open-drain |

The pin FS_FLAG is asserted LOW and the IC_ERR flag is set to '1' if a STD fault is detected which has been configured to be redirected externally via <FLT_REF>_REDIRECT_CFG.

The pin FS_FLAG is asserted HIGH and IC_ERR flag is set to '10' when the STD failure condition disappears.

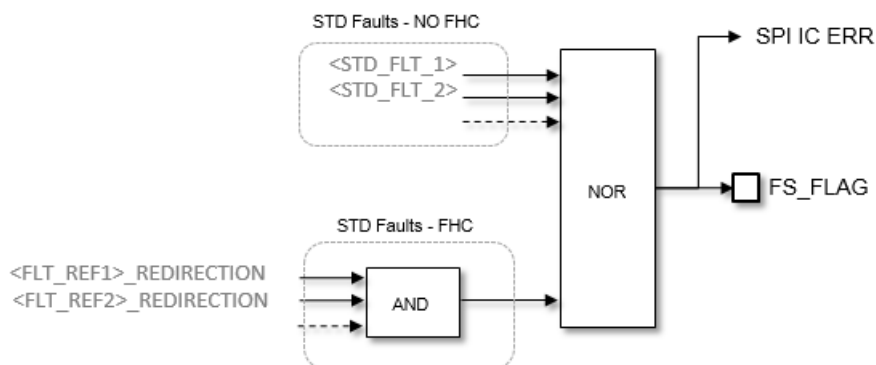
Table 28. IC_ERR status bits

| IC_ERR1 | IC_ERR0 | Description |
|---------|---------|------------------------|
| 0 | 0 | NO STD Fault (Default) |
| 0 | 1 | NO STD Fault |
| 1 | 0 | NO STD Fault |
| 1 | 1 | STD Fault |

In CONFIG mode a dedicated configuration bit is present for each one of the configurable reaction faults to mask output redirection as follows:

Table 29. Fault output redirection configuration bit

| <FLT_REF>_REDIRECT_CFG | Description |
|------------------------|--|
| 0 | Fault redirected on FS_FLAG/IC ERR (Default) |
| 1 | Fault redirection masked |

Figure 14. Fault output redirection logic simplified block diagram


5.6.2 Fault reaction scenarios

Here below are described the scenarios of each different fault case separately.

In case multiple faults take place at the same time the following priority in reaction is used:

- STD fault
- Auto-retry
- Reduced operation mode
- WRN fault

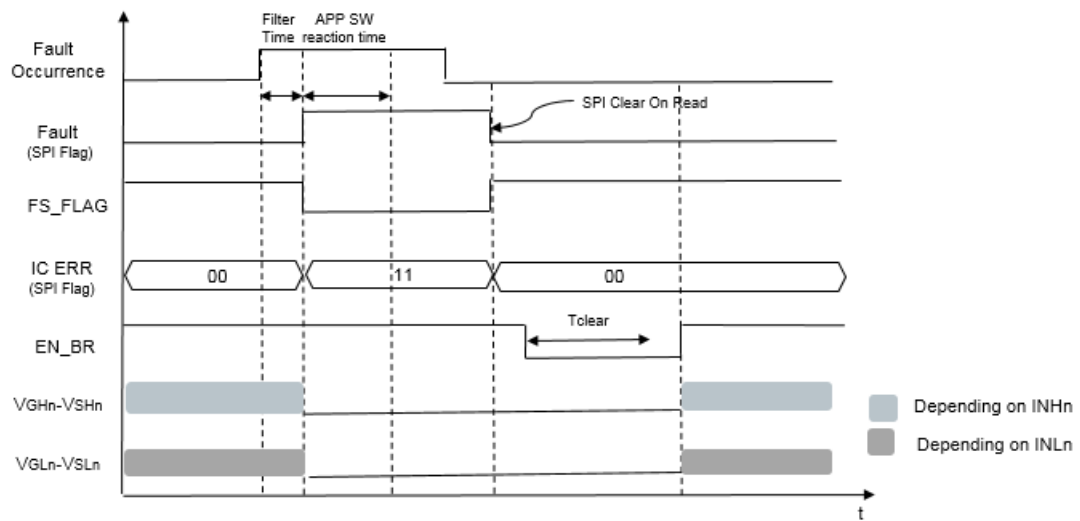
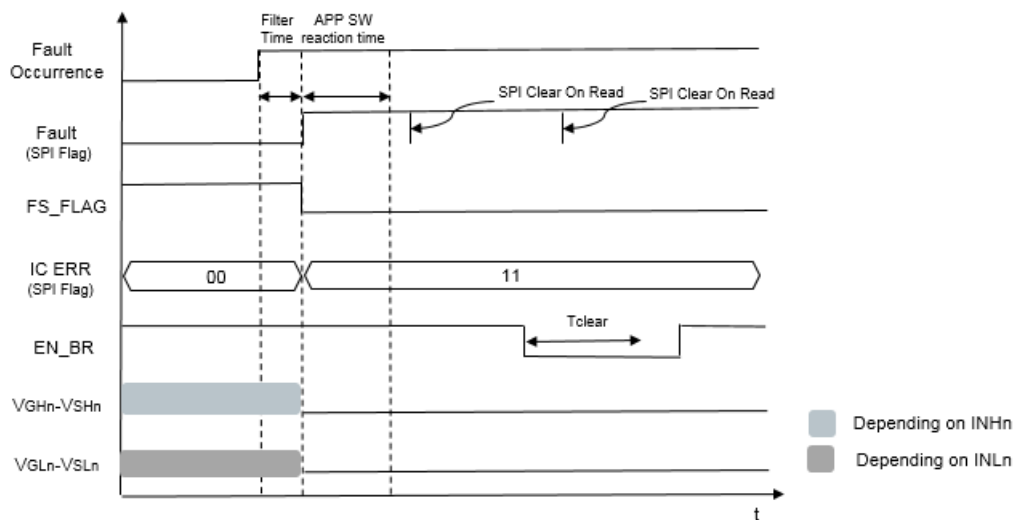
5.6.2.1 Shutdown faults

When a shutdown fault is detected, the related SPI flag is set to '1', the IC ERR bits in the SPI FRAME are set to '11' and the FS_FLAG is asserted low.

Disable logic reacts by establishing SAFE_OFF mode: all the three half bridges are disabled, with VGHS_n-VSHS_n = 0 V and VGLS_n-VSLSn = 0V [n = 1, 2, 3]. Gate Drive Supply block is disabled (SPI configuration bit HBn_DIS, CP1_EN and CP2_EN remain set as previously configured).

The SAFE_OFF mode can be left when all the following conditions are met in the following sequence:

1. STD fault is removed;
2. STD fault flag is cleared on read (action required by Application SW);
3. EN_BR is asserted low for at least T_{clear} and then asserted back high (action required by Application SW).

Figure 15. Shutdown fault - Transient fault timing diagram

Figure 16. Shutdown fault - Permanent fault timing diagram

Table 30. EN_BR minimum t_off time

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|--------------|--|-----|-----|-----|------|--------------------------------|
| EN_BR_tclear | Minimum time interval to assert low value on EN_BR | 2.5 | - | - | µs | Not subject to production test |

Note: All parameters are guaranteed, and tested, in the voltage ranges specified above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

- Note:**
- In case of BIST_STATUS=11 (BIST check failure) the device sent in SAFE_OFF Mode, re-engage procedure can be performed only by issuing a SW_REST command.
 - In case of WDT_OVF_fail = 1 or WDT_DATA_fail = 1 (WDT failure) the device sent in SAFE_OFF Mode, re-engage procedure can be performed only by issuing a WDT_RST or a SW_REST command.

5.6.2.2 Auto-retry faults

When an auto-retry fault is detected the related SPI flag is set to '1', the IC ERR bits in SPI FRAME are set to '11' and the FS_FLAG is asserted low.

Disable logic reacts disabling all the three half bridges in a tristate mode so that $V_{GHn_n}-V_{SHS_n} = 0\text{ V}$ and $V_{GLS_n}-V_{SLSn} = 0\text{ V}$ [$n = 1, 2, 3$]. State machine remains in NORMAL mode (SPI configuration bit HBn_DIS remains set as previously configured).

Safe condition is left when all the following conditions are met in the following sequence:

1. Autoretry fault is removed;
2. Autoretry fault flag is cleared on read (action required by Application SW)
3. SPI bit HBn_ACK [$n = 1,2,3$] is set '0' and then set back to '1' (action required by Application SW).

Figure 17. Auto-retry faults - Transient fault timing diagram

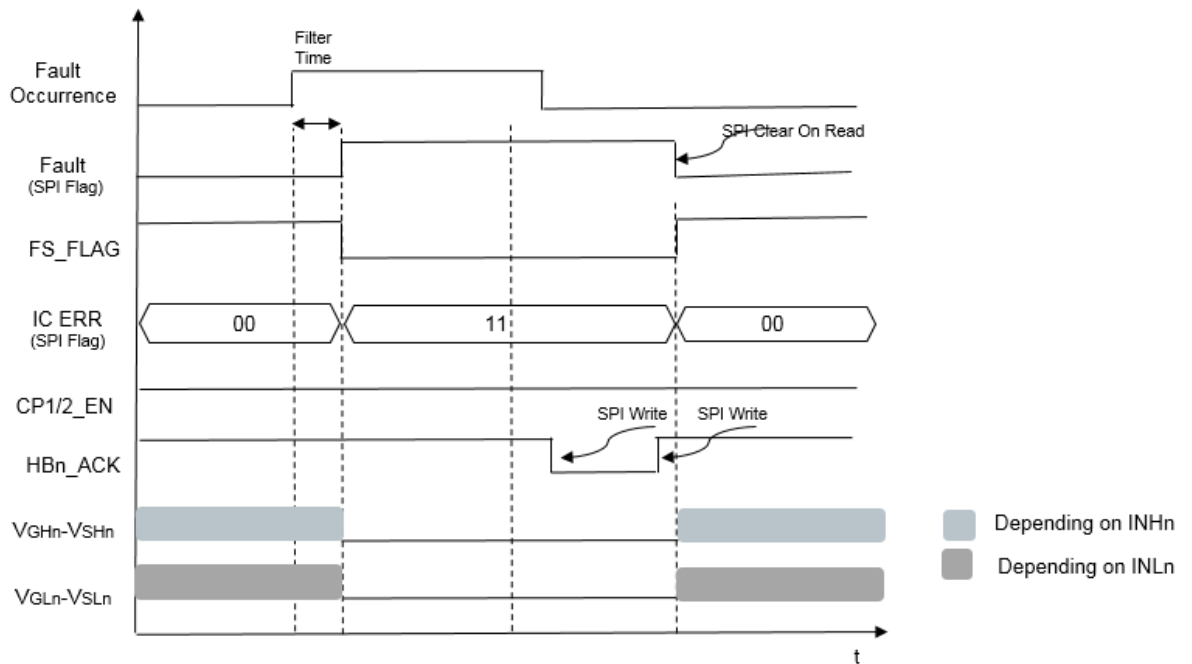
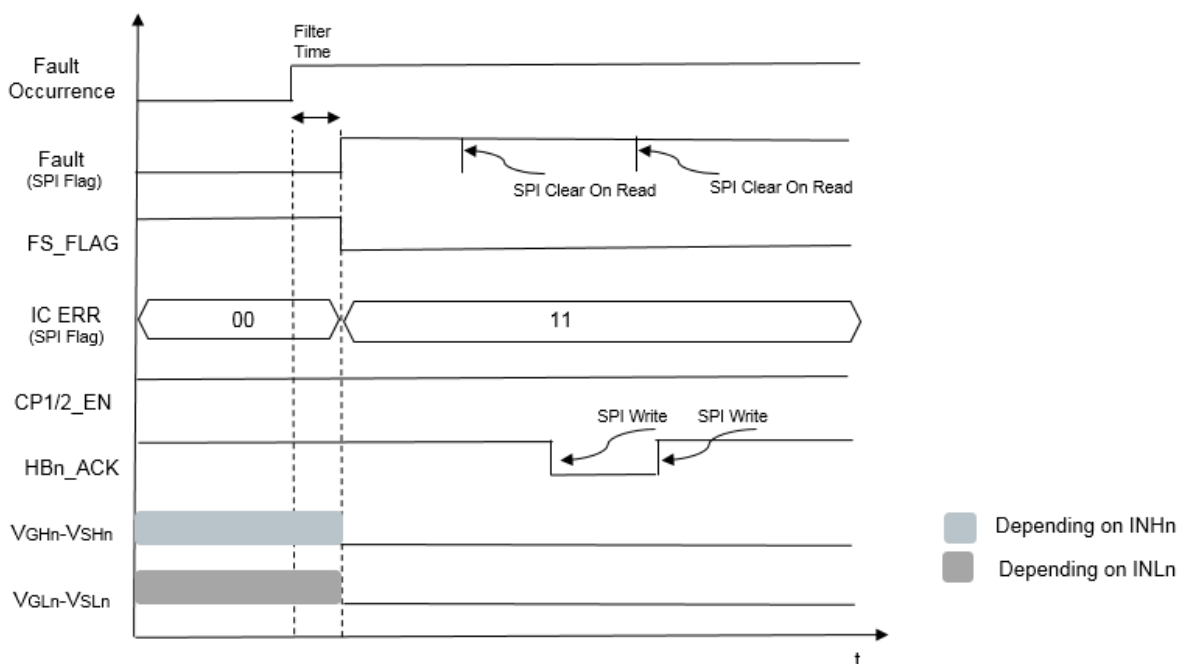


Figure 18. Auto-retry faults - Permanent fault timing diagram



5.6.2.3 Reduced operation faults

When a reduced operation fault is detected the related SPI flag is set to '1', the IC_ERR bits in SPI FRAME are set to '11' and the FS_FLAG is asserted low.

Disable logic reacts forcing the failing half bridge only in a disable mode so that $V_{GHS_n} - V_{SHS_n} = 0\text{ V}$ and $V_{GLS_n} - V_{SLSn} = 0\text{ V}$ [$n \rightarrow$ failing HB] (SPI configuration bit HBn_DIS remains set as previously configured).

Safe condition is left when all the following conditions are met in the following sequence:

1. Reduced Operation fault is removed;
2. Reduced Operation fault flag is cleared on read (action required by Application SW);
3. SPI bit HBn_ACK [$n = 1,2,3$] is set '0' and then set back to '1' (action required by Application SW).

Note: Since HBn_ACK is a Safety Latent Register (SLR) it is required to access correctly the CONFIG MODE in order to conclude correctly the recovery flow.

Figure 19. Reduced operation fault - Transient fault timing diagram

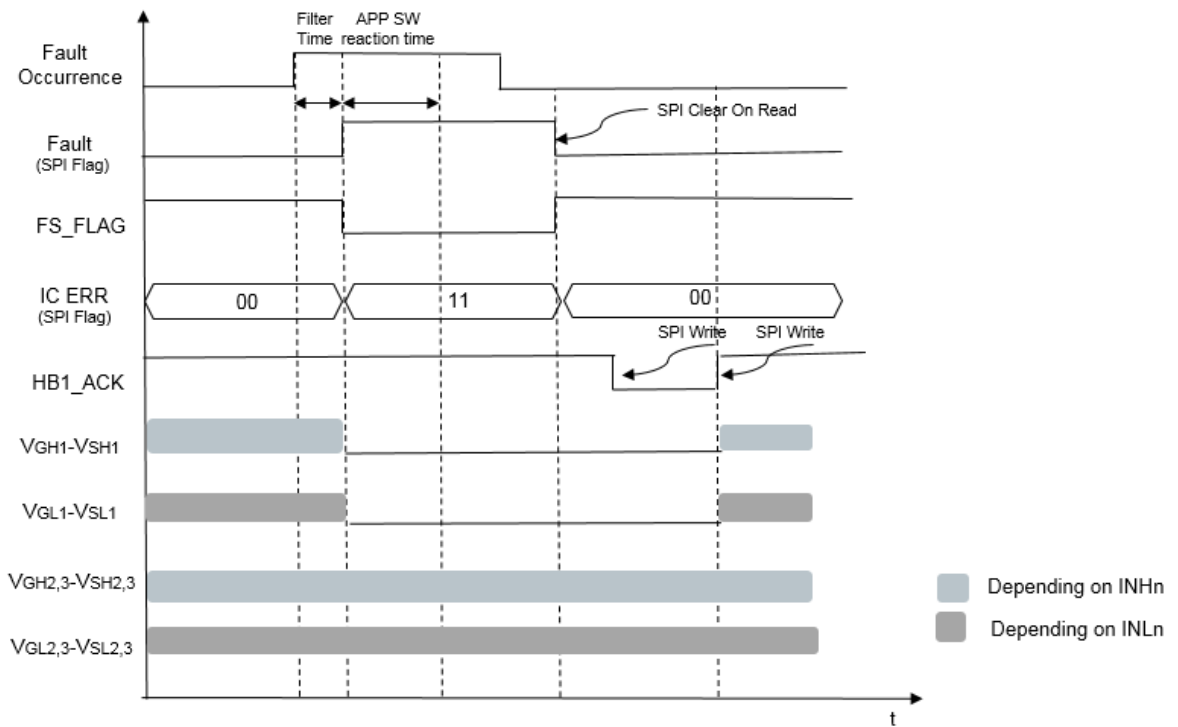
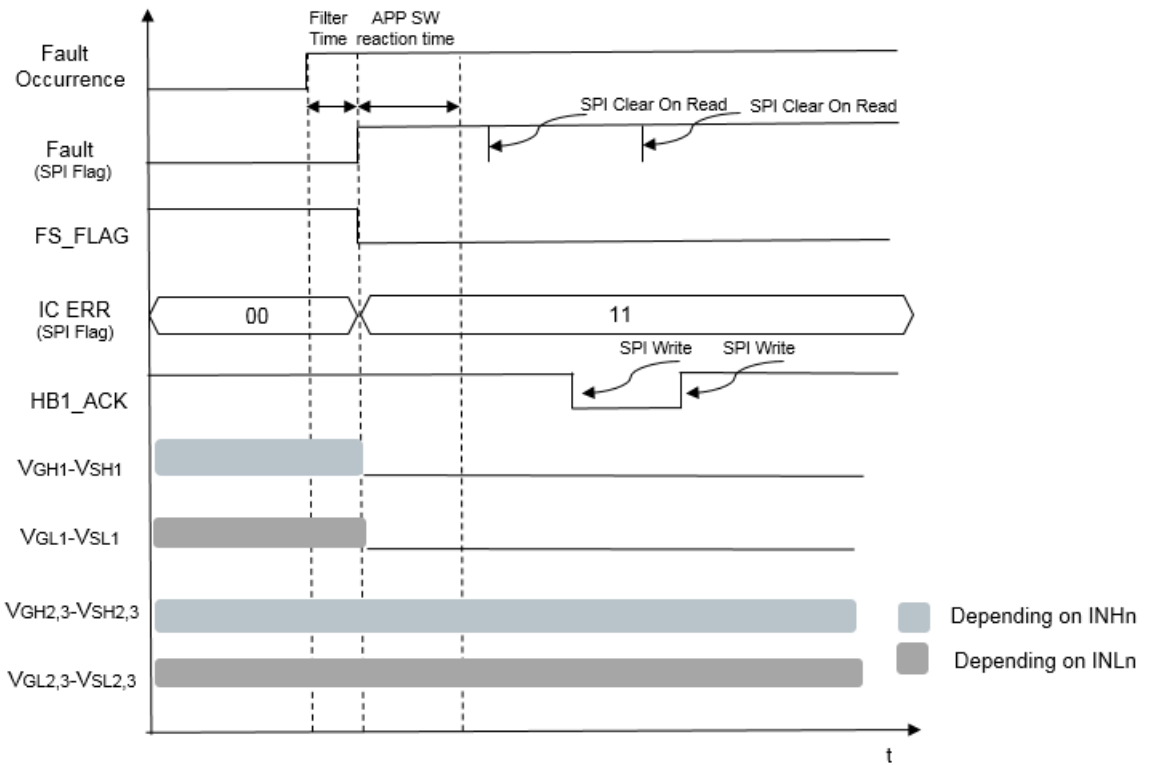


Figure 20. Reduced operation fault - Permanent fault timing diagram



5.6.2.4 Warnings

When a warning fault is detected the related SPI flag is set to '1', the IC ERR bits in SPI FRAME are left to '00' and the FS_FLAG is left asserted high.

Disable logic performs no corrective action (SPI configuration bit HBn_DIS remains set as previously configured).

Figure 21. Warning - Transient fault timing diagram

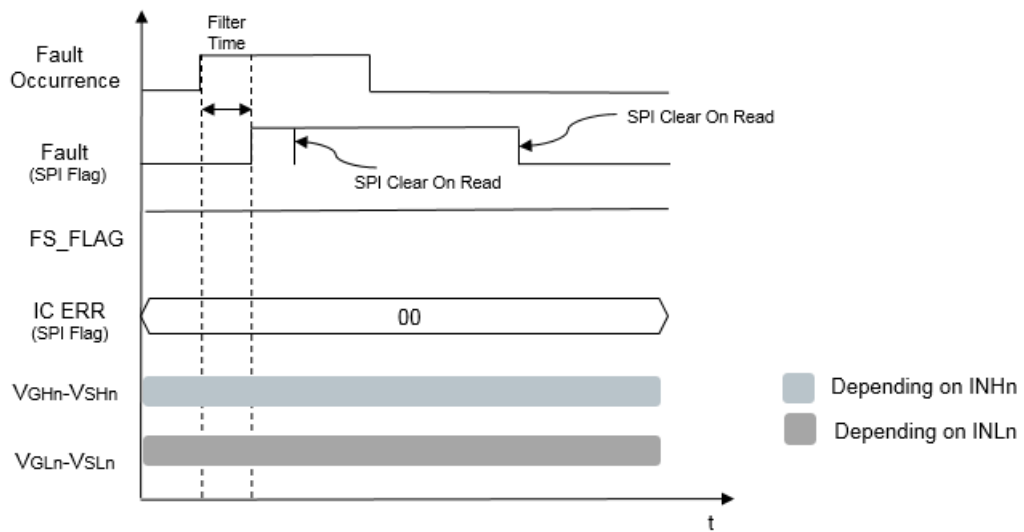
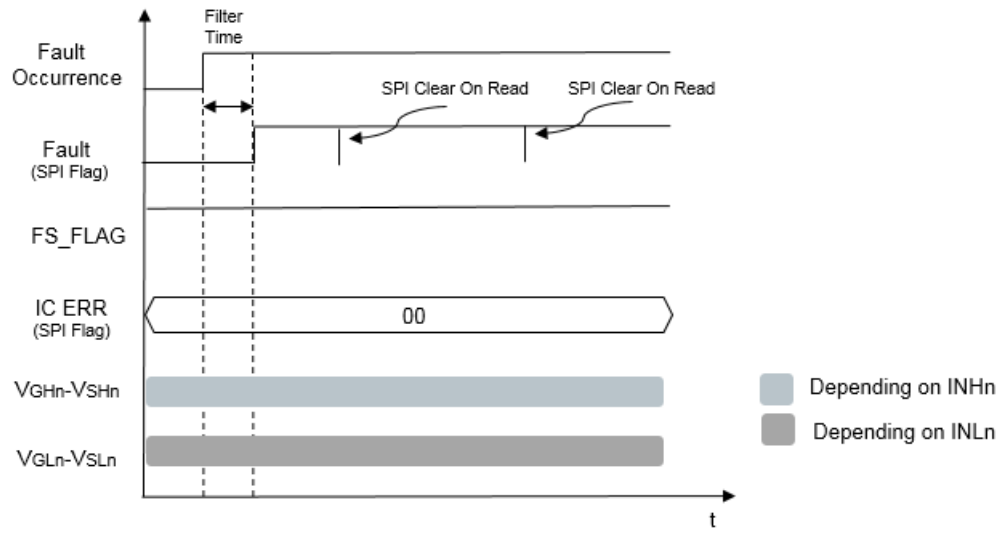


Figure 22. Warning - Permanent fault timing diagram



5.6.3 Half bridges disable logic

The enabling/disabling operation of the n-th Half Bridges is managed by a dedicated combinatory disable logic which constantly processes the following disable sources:

- HBn_DIS SPI configuration register status
- EN_BR pin status
- STD faults detection
- VPRE UV fault detection
- NDIS pin state
- Configurable reaction faults detection with related FRC set as 00 or 01

The status of the n-th disable n-th half bridge is echoed into dedicated SPI readable registers: HBn_EN_ECHO [n = 1, 2, 3].

5.6.4 Gate driver supply enable logic

The enabling/disabling operation of the Gate Driver supply unit (CP1 and CP2) is managed by a dedicated combinatory disable logic which constantly processes the following disable sources:

- **CP1_DIS & CP2_DIS SPI bits status** (within register **SAFETY_RELEVANT3**)
- STD faults detection
- NDIS pin status
- Configurable reaction faults detection with related FRC set as 00

The status of the n-th charge pump is echoed into dedicated SPI signals **CPn_EN_ECHO** [n = 1,2,3], within register **GEN_STATUS3**.

5.7 Power-Up sequences

The recommended power UP sequence should be aligned to the following flowchart.

Figure 23. Power-Up diagram

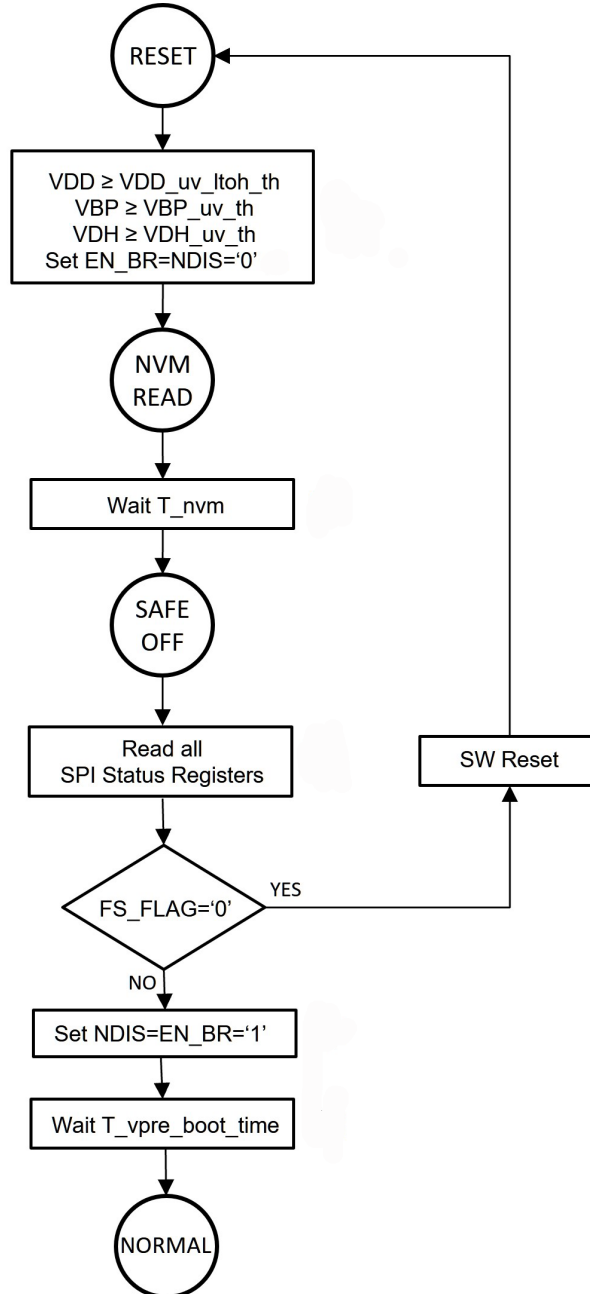
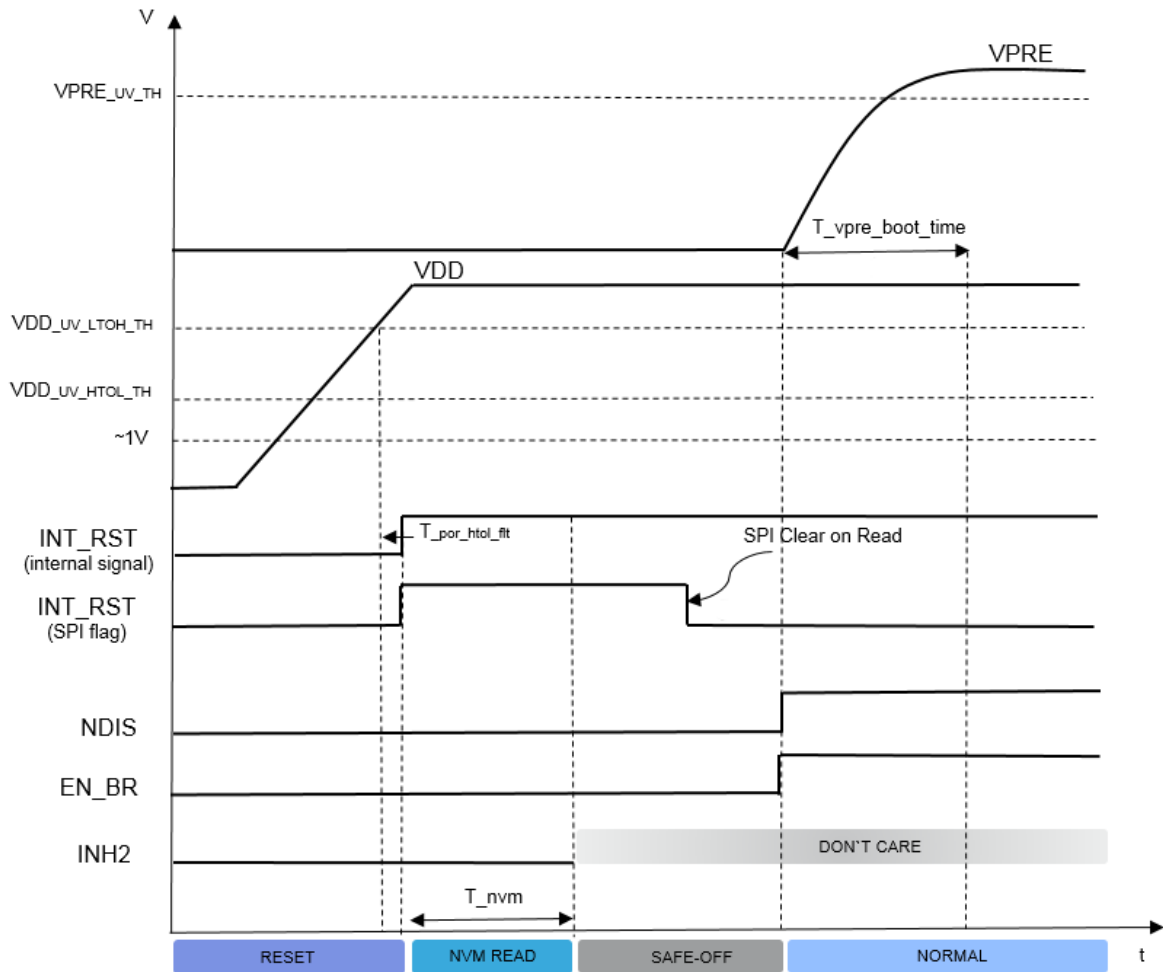


Figure 24. Recommended Power-Up sequence


5.8 Digital I/O

5.8.1 VIO power supply

The VIO power supply is a dedicated power input designed to supply the Digital Output circuitry. The voltage level applied to VIO will reflect directly onto digital output level allowing compliance with major digital I/O standards (5 V, 3.3 V).

5.8.2 Digital Input (DI)

Digital input pins on L9908 are used to transfer digital communications coming from an external source and supply domain to the internal logic and it's related to a 3.3 V domain.

Table 31. Digital input pins functional partitioning

| Pins | Default State | Description |
|------|-------------------------------------|---|
| SCLK | Type A – Internal Current Pull-down | SPI Pin (SPI communication related pin) |
| SDI | Type A – Internal Current Pull-down | SPI Pin (SPI communication related pin) |
| NCS | Type C – Internal Current Pull-up | SPI Pin (SPI communication related pin) |

| Pins | Default State | Description |
|--------------------|-------------------------------------|--|
| INHn, INLn [1,2,3] | Type A – Internal Current Pull-down | Control Loop Pins (Gate Driver control related pins) |

Table 32. Digital input electrical characteristics (Control Loop Pins)

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|---------------|--------------------------|----------------|------|-----|---------|------|--------------------------------|
| DI_in_hl_th | High input voltage range | - | 2.0 | - | VIO+0.3 | V | - |
| DI_in_ll_th | Low input voltage range | - | -0.3 | - | 0.65 | V | - |
| DI_in_hys | Input voltage hysteresis | - | 120 | 300 | 570 | mV | - |
| SPI_DI_in_ipu | Pull up current | Pin = GND | 15 | 40 | 65 | μA | Type C |
| DI_in_ipd | Pull down current | Pin = VIO | -65 | -40 | -15 | μA | Type A |
| DI_in_rpd | Pull down resistance | - | 50 | 135 | 220 | kΩ | Type B |
| DI_in_cap | Input capacitance | - | - | - | 10 | pF | Not subject to production test |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

The state of the PWM control pins INHn/INLn is echoed into dedicated SPI readable bits: **INHn_ECHO** and **INLn_ECHO** [n = 1, 2, 3], within the register **GEN_STATUS2**.

5.8.3 Digital Output (DO)

Digital output pins on L9908 are used to transfer an internal digital information to an external user whose domain is defined by the VIO voltage.

Depending on the information carried these pins can be divided into three categories:

Table 33. Digital output pins functional partitioning

| Pins | Description |
|----------|--|
| SDO | SPI Pin (SPI communication related pin) |
| CSO3/PVF | CSA phase 3 analog output/Phase voltage comparator output feedback |
| FS_FLAG | Fault Handling Pin (Fault flag output pin) |

The digital output pin interface is developed by an HV push-pull output stage supplied by VIO and a driving stage supplied by the internal V3V3_DIG reference.

Table 34. Digital output electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|----------|---------------------|--------------------------------|-----------|-----|-----|------|
| DO_in_hl | High output voltage | Iload = 1 mA | VIO-0.215 | - | VIO | V |
| DO_in_ll | Low output voltage | Iload = -1 mA | 0 | - | 0.2 | V |
| T_do_rt | Output rise time | Cload = 120 pF From 10% to 70% | - | - | 35 | ns |
| T_do_ft | Output fall time | Cload = 120 pF From 10% to 70% | - | - | 35 | ns |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.9 Internal clock

Table 35. Internal clock electrical characteristics

| Symbol | Parameter | Test condition | Min | Typ | Max | Unit |
|--------------|---------------------------------|----------------|-----|-----|-----|------|
| CLK_freq | System Clock Frequency | CLK_SSM_EN = 0 | - | 20 | - | MHz |
| CLK_freq_acc | System Clock Frequency Accuracy | CLK_SSM_EN = 0 | -5 | - | +5 | % |

5.9.1 Spread Spectrum Modulation (SSM)

L9908 clocks generator implements a frequency modulation (Spread Spectrum Modulation) feature to reduce the main logic and Charge Pumps emissions around the main frequency by spreading the power spectrum over a larger frequency range.

Table 36. Clock spread spectrum electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|---------------|--|-----|--------|-----|------|--------------------------------|
| SSM_spreading | Spread Spectrum Modulation spreading range | 1 | 3 | 5 | % | Not subject to production test |
| SSM_freq | Spread Spectrum Modulating frequency | - | 156.25 | | kHz | Not subject to production test |

Note: All parameters are guaranteed and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

The clock spread spectrum modulation function can be enabled by the dedicated SPI bit **CLK_SSM_EN** in the register **GEN_CFG1** as follows:

Table 37. Clock spread spectrum enable bit

| CLK_SSM_EN | Description |
|------------|------------------------------|
| 0 | Clock SSM Disabled (Default) |
| 1 | Clock SSM Enabled |

Note: When the clock spread spectrum is enabled the internal digital timings are affected by a timing jitter equal to the selected spread spectrum spreading range.

5.9.2 Internal Clock Monitor (ICM)

The correct operation and the precision of the internal synchronization signal are safety relevant and therefore L9908 implements a monitoring unit to detect abnormal deviation of the clock signal frequency. The monitoring unit is based on the use of two oscillators and two monitor chains (a Main one and an Auxiliary one) to avoid common-cause failures.

Each monitor chain compares the other clock period, the first one samples CLK1 by means of CLK2 and the second one samples CLK2 by means of CLK1.

If $TCLK1 \geq ICM_timeout_th$: the flag INT_RST and CLK1_TIME_OUT are set.

If $TCLK2 \geq ICM_timeout_th$: the flag CLK2_TIME_OUT is set.

The error flags remain set until the failure condition is removed and the flags are cleared by the SPI command. The correct level of clock monitor is safety relevant and then a self-check procedure is implemented on its monitor.

Table 38. Internal clock monitor electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|----------------|---|-----|-----|-----|------|-------------------------|
| ICM_err_th | ICM frequency mismatch threshold accuracy | 24 | 30 | 36 | % | Application information |
| ICM_timeout_th | ICM timeout accuracy | 30 | 50 | 70 | us | Application information |

Note: If no oscillator clock is available, the SPI data processing cannot work properly: L9908 delivers always the latest answer.

5.10 Motor Battery Monitor (MBM)

L9908 implements a monitoring unit on the voltage level of the motor's battery through the pin VDH with the purpose of detecting over-voltage events that can harm the device and under-voltage events that can prevent a correct motor driving. Hysteresis on thresholds and filtering time are implemented.

If $VDH \leq VDH_{uv_th}$ occurs for an interval longer than $T_{vdh_uv_flt}$ filtering time, VDH_UV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

If $VDH \geq VDH_{ov_th}$ occurs for an interval longer than $T_{vdh_ov_flt}$ filtering time, VDH_OV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

The correct level of motor's battery stage monitor is safety relevant and then a self-check procedure is implemented on its monitor.

The under-voltage thresholds VDH_{uv_th} can be configured by dedicated SPI bits as follows:

Table 39. Motor battery monitor UV threshold configuration bits

| VDH_UV_CFG1 | VDH_UV_CFG0 | Description |
|-------------|-------------|-------------------------|
| 0 | 0 | 12 V Systems (Defaults) |
| 0 | 1 | 24 V Systems |
| 1 | 0 | 48 V Systems |
| 1 | 1 | VDH UV Disabled |

The over-voltage threshold VDH_{ov_th} can be configured by dedicated SPI bits as follows:

Table 40. Motor battery monitor OV threshold configuration bits

| VDH_OV_CFG2 | VDH_OV_CFG1 | VDH_OV_CFG0 | Description |
|-------------|-------------|-------------|---------------------------|
| 0 | 0 | 0 | 12 V Systems 1 |
| 0 | 0 | 1 | 12 V Systems 2 |
| 0 | 1 | 0 | 24 V Systems 1 |
| 0 | 1 | 1 | 24 V Systems 2 |
| 1 | 0 | 0 | 48 V Systems 1 |
| 1 | 0 | 1 | 48 V Systems 2 |
| 1 | 1 | 0 | 48 V Systems 3 |
| 1 | 1 | 1 | 48 V Systems 4 (Defaults) |

The filter time on under/over voltage diagnosis $T_{vdh_uv_flt}$ / $T_{vdh_ov_flt}$ can be configured by dedicated SPI bits as follows:

Table 41. Motor battery monitor filtering configuration bits

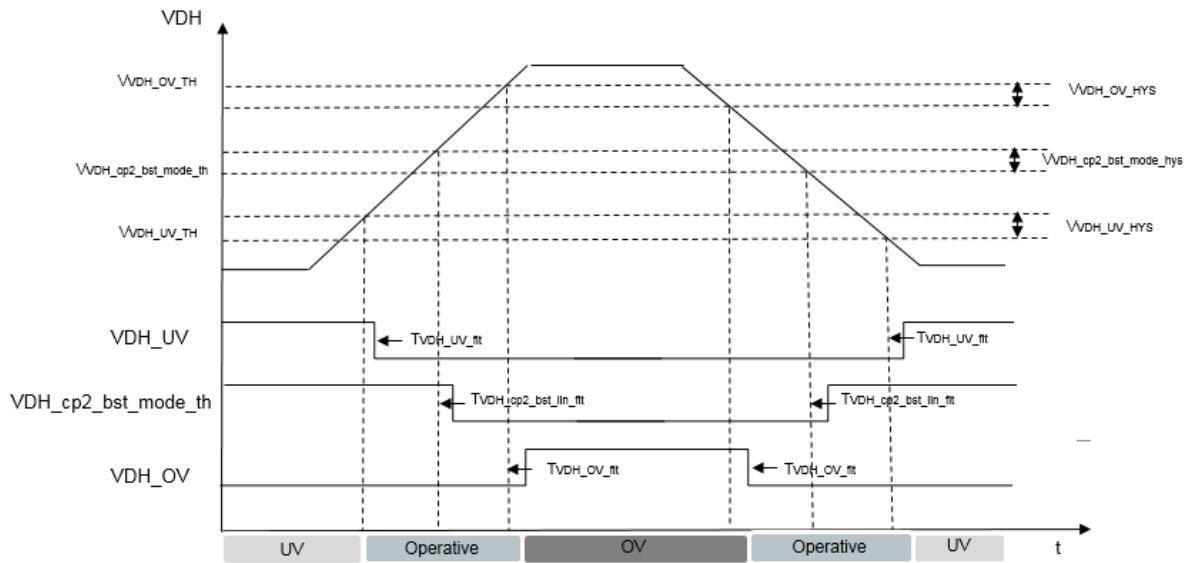
| VDH_FLT_CFG1 | VDH_FLT_CFG0 | Description |
|--------------|--------------|--------------------------|
| 0 | 0 | 12.25 μ s (Defaults) |
| 0 | 1 | 25 μ s |
| 1 | 0 | 50 μ s |
| 1 | 1 | 100 μ s |

Table 42. Motor battery monitor electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|----------------------|---|----------------|-------|-------|-------|------|-------------------------------|
| VDH_cp2_bst_mode_th | CP2 boost mode enable threshold | - | 10.3 | 10.6 | 10.9 | V | Comparator output Low to High |
| VDH_cp2_bst_mode_hys | CP2 boost mode enable hysteresis | - | 0.95 | 1.05 | 1.1 | V | - |
| VDH_cp2_bst_modeflt | CP2 boost mode enable detection filter time | - | 100 | 200 | 300 | ns | Analog Filter |
| VDH_uv_th_12v | VDH under-voltage threshold (12 V systems) | - | 4 | 4.25 | 4.5 | V | Comparator output Low to High |
| VDH_uv_th_24v | VDH under-voltage threshold (24 V systems) | - | 7.8 | 8.4 | 9 | V | Comparator output Low to High |
| VDH_uv_th_48v | VDH under-voltage threshold (48 V systems) | - | 17.3 | 18.65 | 20 | V | Comparator output Low to High |
| VDH_uv_hys | VDH under-voltage hysteresis | - | 90 | 150 | 250 | mV | - |
| VDH_ov_th1_12v | VDH over-voltage threshold (12 V systems 1) | - | 18.11 | 18.67 | 19.23 | V | Comparator output Low to High |
| V_ov_th2_12v | VDH over-voltage threshold (12 V systems 2) | - | 27.16 | 28 | 28.84 | V | Comparator output Low to High |
| VDH_ov_th1_24v | VDH over-voltage threshold (24 V systems 1) | - | 36.22 | 37.34 | 38.46 | V | Comparator output Low to High |
| VDH_ov_th2_24v | VDH over-voltage threshold (24 V systems 2) | - | 50.3 | 51.86 | 53.41 | V | Comparator output Low to High |
| VDH_ov_th1_48v | VDH over-voltage threshold (48 V systems 1) | - | 56.34 | 58.08 | 59.82 | V | Comparator output Low to High |
| VDH_ov_th2_48v | VDH over-voltage threshold (48 V systems 2) | - | 60.36 | 62.23 | 64.09 | V | Comparator output Low to High |
| VDH_ov_th3_48v | VDH over-voltage threshold (48 V systems 3) | - | 65.39 | 67.41 | 69.43 | V | Comparator output Low to High |
| VDH_ov_th4_48v | VDH over-voltage threshold (48 V systems 4) | - | 70.42 | 72.6 | 74.78 | V | Comparator output Low to High |
| VDH_ov_hys | VDH over-voltage hysteresis | - | 0.8 | 1.15 | 1.85 | V | - |
| VDH_tflt_acc | VDH Fault Detection Filter Time accuracy | CLK_SSM_EN = 0 | -15 | - | 15 | % | - |

Note: All parameters are guaranteed and tested, in the voltage ranges reported above in [Table 5](#) unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

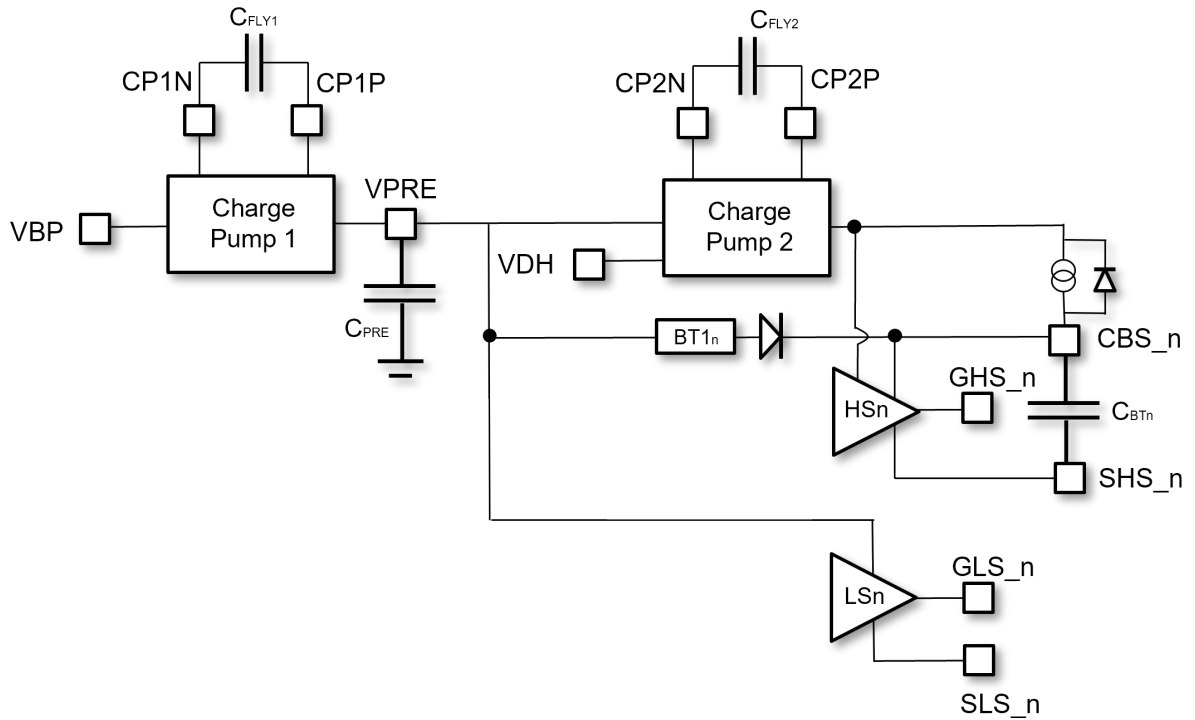
Figure 25. VDH operative range



5.11 Gate driver supply

The Ext. FET gate drivers supply on L9908 is developed by the cascaded connection of a pre-regulation stage and a supply distribution stage.

Figure 26. Ext. FET gate supply simplified block diagram



5.11.1 Pre-regulation stage

The pre-regulator stage has the purpose to generate an intermediate supply rail to be used as a reference level for the Ext. FET ON driving. This function is carried out by a current-limited Single Stage 2-Phases Dickson charge pump with external capacitance.

Charge Pump1 can be disabled by the dedicated SPI bit **CP1_DIS** within the **SAFETY_RELEVANT3** register, as follows:

Table 43. Charge pump 1 enable bit

| CP1_DIS | Description |
|---------|---------------------------------|
| 0 | Charge Pump 1 Enabled (Default) |
| 1 | Charge Pump 1 Disabled |

Table 44. Pre-regulation stage electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-----------------|--|--|-----|-----|-----|------|--------------------------------|
| CP1_iout1 | Charge Pump1 external Load Current for no VPRES_UV | 5.5 V ≤ VBP < 8 V CFLY1 = 1 μF CPRE = 4.7 μF | - | - | 40 | mA | - |
| CP1_iout2 | Charge Pump1 external Load Current for no VPRES_UV | 8 V ≤ VBP CFLY1 = 1 μF CPRE = 4.7 μF | - | - | 55 | mA | - |
| CP1_vout1 | Charge Pump1 Output Voltage | 4.5 V ≤ VB = < 5.5 V Iload ≤ 24 mA CFLY1 = 1 μF CPRE = 4.7 μF | 5.8 | - | 13 | V | (1) |
| CP1_vout2 | Charge Pump1 Output Voltage | 5.5 V ≤ VBP < 11 V Iload = 24 mA CFLY1 = 1 μF CPRE = 4.7 μF | 8 | - | 13 | V | (1) |
| CP1_vout3 | Charge Pump1 Output Voltage | 11 V ≤ VBP Iload = 36 mA CFLY1 = 1 μF CPRE = 4.7 μF | 11 | 12 | 13 | V | (1) |
| CP1_freq | Charge Pump1 Frequency | - | 180 | 200 | 220 | kHz | Not subject to production test |
| VPRES_boot_time | VPRES boot time at high battery (VBP & VDH > 10 V) | Iload ≤ 0 mA CFLY1 = 1 μF CPRE = 4.7 μF 0 V ≤ VPRES ≤ 7 V | 0.2 | - | 0.5 | ms | - |
| VPRES_boot_time | VPRES boot time at low battery (VBP & VDH < 10 V) | Iload ≤ 0 mA CFLY1 = 1 μF CPRE = 4.7 μF 0 V ≤ VPRES ≤ 7 V | 0.5 | - | 1 | ms | - |

1. Iload is the total external current out sink form VPRES equivalent to a gate charge load: Iload = (# of switching FETs) * fPWM * QgTOT.

Note: All parameters are guaranteed and tested, in the voltage ranges reported above in [Table 5](#) unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.11.2 VBP monitor

VBP voltage level is monitored by means of the dedicated UV and OV diagnosis. Hysteresis on thresholds and filtering time is implemented.

If $VBP \leq VBP_{uv_th}$ occurs for an interval longer than $T_{vbp_uv_flt}$ filtering time, the VBP_UV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

If $VBP \geq VBP_{ov_th}$ occurs for an interval longer than $T_{vbp_ov_flt}$ filtering time, the VBP_OV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

The correct operation VBP Level monitor is safety relevant and then a self-check procedure is implemented.

The under-voltage threshold VBP_{uv_th} can be configured by dedicated SPI bits within the **SAFETY_RELEVANT3** register as follows:

Table 45. VBP monitor UV threshold configuration bits

| VBP_UV_CFG1 | VBP_UV_CFG0 | Description |
|-------------|-------------|-------------------------|
| 0 | 0 | 12 V Systems (Defaults) |
| 0 | 1 | 24 V Systems |
| 1 | 0 | 48 V Systems |
| 1 | 1 | VBP UV Disabled |

The over-voltage threshold VBP_{ov_th} can be configured by dedicated SPI bits within the **SAFETY_RELEVANT2** register as follows:

Table 46. VBP monitor OV threshold configuration bits

| VBP_OV_CFG1 | VBP_OV_CFG0 | Description |
|-------------|-------------|---------------------------|
| 0 | 0 | 12 V Systems 1 |
| 0 | 1 | 12 V Systems 2 |
| 1 | 0 | 24 V Systems 1 |
| 1 | 1 | 24 V Systems 2 (Defaults) |

The filter time on under/over voltage diagnosis $T_{vbp_uv_flt}$ / $T_{vbp_ov_flt}$ can be configured by dedicated SPI bits within the **SAFETY_RELEVANT3** register as follows:

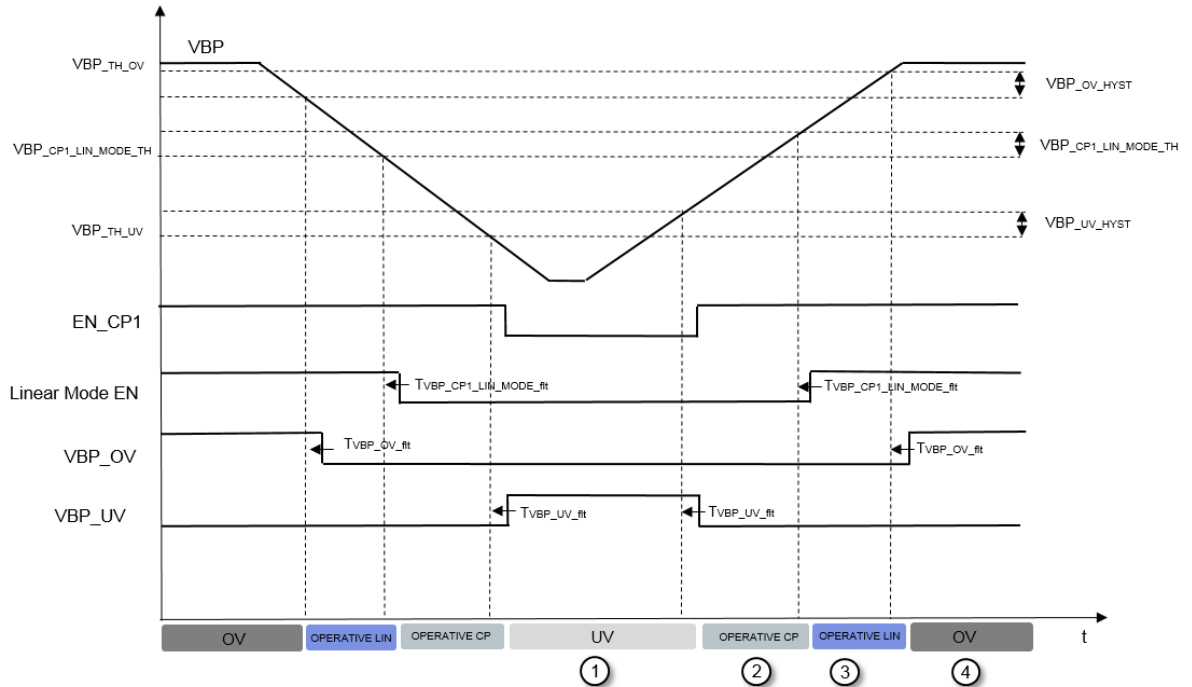
Table 47. VBP monitor filtering configuration bits

| VBP_FLT_CFG1 | VBP_FLT_CFG0 | Description |
|--------------|--------------|--------------------------|
| 0 | 0 | 12.25 μ s (Defaults) |
| 0 | 1 | 25 μ s |
| 1 | 0 | 50 μ s |
| 1 | 1 | 100 μ s |

Table 48. VBP monitor electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|----------------------|--|----------------|-------|-------|-------|------|-------------------------------|
| VBP_cp1_lin_mode_th | CP1 linear mode enable threshold | - | 10.3 | 10.6 | 10.9 | V | Comparator output Low to High |
| VBP_cp1_lin_mode_hys | CP1 linear mode enable hysteresis | - | 0.95 | 1.05 | 1.1 | V | - |
| VBP_cp1_lin_mode_fit | CP1 linear mode enable detection filter time | - | 100 | 200 | 300 | ns | Digital filter |
| VBP_uv_th_12v | VBP under-voltage threshold (12 V systems) | - | 4 | 4.25 | 4.5 | V | Comparator output Low to High |
| VBP_uv_th_24v | VBP under-voltage threshold (24 V systems) | - | 7.8 | 8.4 | 9 | V | Comparator output Low to High |
| VBP_uv_th_48v | VBP under-voltage threshold (48 V systems) | - | 17.3 | 18.65 | 20 | V | Comparator output Low to High |
| VBP_uv_hys | VBP under-voltage hysteresis | - | 90 | 150 | 250 | mV | - |
| VBP_ov_th1_12v | VBP over-voltage threshold (12 V systems 1) | - | 18.11 | 18.67 | 19.23 | V | Comparator output Low to High |
| VBP_ov_th2_12v | VBP over-voltage threshold (12 V systems 2) | - | 27.16 | 28 | 28.84 | V | Comparator output Low to High |
| VBP_ov_th1_24v | VBP over-voltage threshold (24 V systems 1) | - | 36.22 | 37.34 | 38.46 | V | Comparator output Low to High |
| VBP_ov_th2_24v | VBP over-voltage threshold (24 V systems 2) | - | 50.3 | 51.86 | 53.41 | V | Comparator output Low to High |
| VBP_ov_hys | VBP over-voltage hysteresis | - | 0.8 | 1.15 | 1.6 | V | - |
| VBP_tflt_acc | VBP Fault Detection Filter Time accuracy | CLK_SSM_EN = 0 | -15 | - | 15 | % | Digital filter |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.11.2.1 VBP functional ranges
Figure 27. VBP functional ranges


Where:

1. $VBP \leq VBP_uv_th$
 VBP is in under-voltage and L9908 is sent into the operating mode defined into the FMC registers. If set as IMF a VBP UV event automatically sets CP1_EN = 0 bit, thus disabling the CP1 stage. If set to EMF, protection mechanism is let to μC .
2. $VBP_uv_th \leq VBP \leq VBP_cp1_lin_mode_th$
 L9908 is in NORMAL Mode (operative), CP1 regulates the target voltage on VPRES by working in charge pump mode.
3. $VBP_cp1_lin_mode_th \leq VBP \leq VBP_ov_th$
 L9908 is in NORMAL Mode (operative), CP1 regulates the target voltage on VPRES by working in linear regulator mode.
4. $VBP \geq VBP_ov_th$
 VBP is in over-voltage and L9908 is sent into the operating mode defined into FMC registers.

5.11.3 VPRES monitor

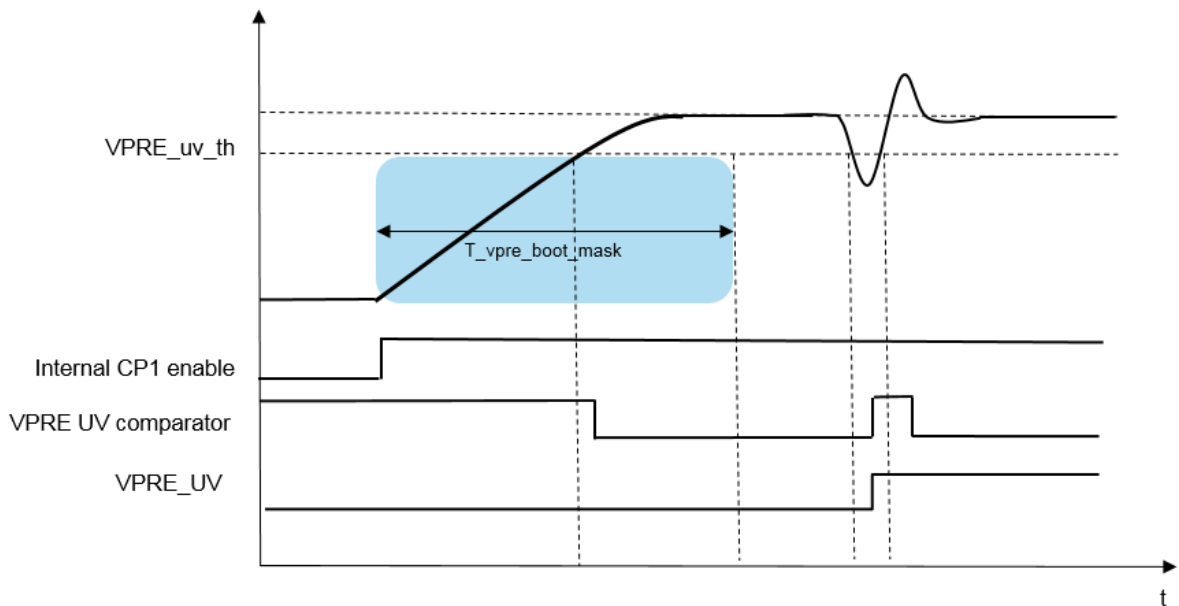
VPRES voltage level is monitored by means of dedicated UV and an OV diagnosis. Hysteresis on thresholds and filtering time is implemented.

If $VPRES \leq VPRES_uv_th$ occurs for an interval longer than $T_vpre_uv_flt$ filtering time, the VPRES_UV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

If $VPRES \geq VPRES_ov_th$ occurs for an interval longer than $T_vpre_ov_flt$ the VPRES_OV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command. The correct operation Pre-Regulator stage monitor is safety relevant and then a self-check procedure is implemented.

To avoid UV/OV detection during power up phase VPRES monitor comparators are masked for a $T_vpre_boot_mask$ filtering time, starting from each low to high transition of the internal CP1 enabling command.

Figure 28. VPRE monitor boot masking



Note: The total external capacitance applied to VPRE should be selected in order to allow a VPRE boot time always lower than VPRE boot time masking. This means that the maximum total capacitance shall be:

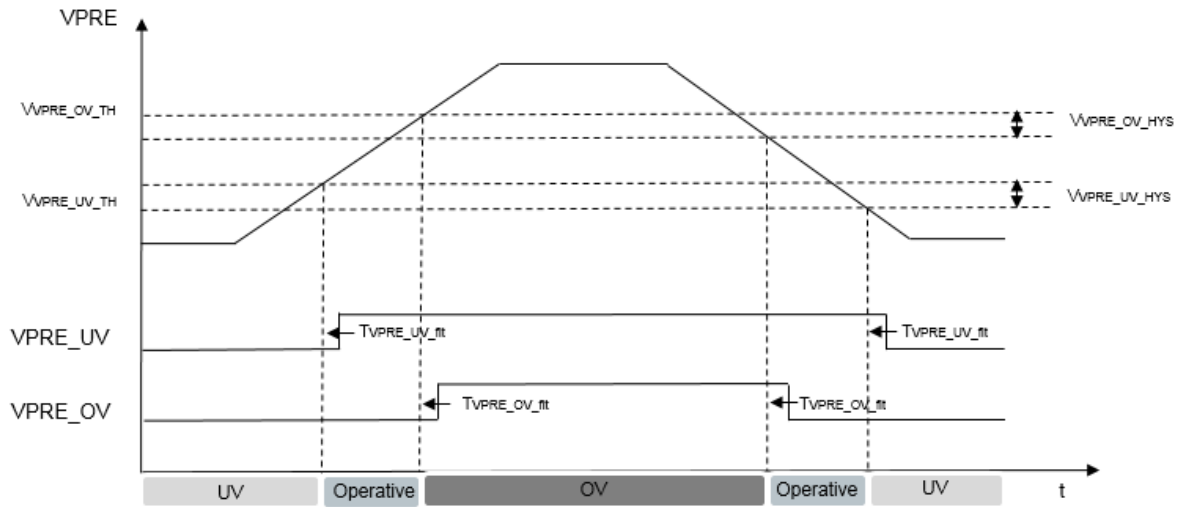
$$C_{VPRE_tot} \leq \frac{CP1_{iout_min}}{CP1_{vout_max}} T_{vpre_boot_mask_min} = 7.192 \mu F \quad (5)$$

Table 49. VPRE Monitor electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|------------------|--|------|------|------|------|-------------------------------|
| VPRE_uv_th | VPRE under-voltage threshold | 6.4 | 6.7 | 7 | V | Comparator output Low to High |
| VPRE_uv_hys | VPRE under-voltage hysteresis | 100 | - | 200 | mV | - |
| T_vpre_uvflt | VPRE under-voltage detection filter time | 1 | - | 5 | μs | Digital filter |
| VPRE_ov_th | VPRE over-voltage threshold | 14.5 | 15.5 | 16.5 | V | Comparator output Low to High |
| VPRE_ov_hys | VPRE over-voltage hysteresis | 100 | - | 250 | mV | - |
| T_vpre_ovflt | VPRE over-voltage detection filter time | 1 | - | 5 | μs | Digital filter |
| T_vpre_boot_mask | VPRE boot masking time | 1.7 | 2 | 2.3 | ms | - |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Figure 29. VPRE operative ranges



5.11.4 Supply distribution stage

The supply distribution stage has the purpose to properly deliver the pre-regulated supply to LS and HS driver.

- LS drivers are directly supplied by the VPRE voltage itself as it is referenced to GND and already conditioned to fit the Ext. FET Vgs range for a correct driving. Supply distribution stage is then absent for LS drivers.
- HS drivers cannot use directly VPRE voltage as they need this voltage to be translated above VDH for a correct Ext. FET driving. Supply distribution stage for each HS driver is then composed by the cooperation of bootstrap circuits and a dedicated Single Stage 2-Phases Dickson charge pump with external capacitance.

Charge Pump 2 (CP2) and Bootstrap Limiter 2 (BT2)

The purpose of CP2 is to guarantee a stable Vgs on HS FET during 100% (full-on) operations and to support the bootstrap supply in “high” duty cycle PWM mode by recovering the static consumption of the three HS pre-drivers in ON condition.

To carry out this function CP2 structure generates a VDH+VPRE voltage onto the internal line VCP by means of a current-limited Single Stage 2-Phases Dickson charge pump with external capacitance (the tank capacitance function of this stage is developed by the bootstrap capacitance itself).

When $VDH < VDH_{cp2_bst_mode_th}$ the CP2 will use VPRE as input in both phases, resulting in an output voltage equal to $2 \cdot VPRE$.

Charge Pump2 can be Disabled by a dedicated SPI bit **CP2_DIS** within the register **SAFETY_RELEVANT3** as follows:

Table 50. Charge pump 2 enable bit

| CP2_DIS | Description |
|---------|---------------------------------|
| 0 | Charge Pump 2 Enabled (Default) |
| 1 | Charge Pump 2 Disabled |

Table 51. Charge pump 2 electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-----------|---------------------------------|---|-----|-----|-----|------|-------------|
| CP2_iout1 | Total Charge Pump2 Load Current | $5.5\text{ V} \leq VBP \leq CP1_lin_mode_th$ CFLY2 = 1 μF SHS_n = VDH INHn = 1 | - | - | 10 | mA | [n = 1,2,3] |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|------------------|---|--|------|-----|-----|------|--------------------------------|
| CP2_iout2 | Charge Pump2 Load Current | CP1_lin_mode_th < VBP ≤ 60 V CFLY2 = 1 μF SHS_n = VDH INHn = 1 | - | - | 10 | mA | [n = 1,2,3] |
| CP2_vout1 | Charge Pump2 output voltage at CBS_n-SHS-n | 5.5 V ≤ VBP ≤ CP1_lin_mode_th CFLY2 = 1 μF SHS_n = VDH INHn = 1 | 8 | - | - | V | [n = 1,2,3] |
| CP2_vout2 | Charge Pump2 output voltage at CBS_n-SHS-n | CP1_lin_mode_th < VBP ≤ 60 V CFLY2 = 1 μF SHS_n = VDH INHn = 1 | 8 | - | - | V | [n = 1,2,3] |
| CP2_freq | Charge Pump2 Frequency | - | - | 400 | - | kHz | Not subject to production test |
| BT_lim2_ilim | BT Charge Limiter2 limitation current | SHS_n = VDH INHn = 1 | -8 | - | -1 | mA | [n = 1,2,3] |
| BT_lim2_vlim | BT Charge Limiter2 limitation voltage | SHS_n = 0 BT1_DIS = 1 | 7 | 10 | 14 | V | [n = 1,2,3] |
| CBT_boot_time_HB | CBT boot time at high battery (VBP & VDH > 10V) | SHS_n = 0 CBT = 1 μF CBS_n 0 V to 7 V | 0.25 | - | 0.5 | ms | [n=1,2,3] |
| CBT_boot_time_LB | CBT boot time at low battery (VBP & VDH < 10V) | SHS_n = 0 CBT = 1 μF CBS_n 0 V to 7 V | 0.5 | - | 1 | ms | [n=1,2,3] |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Bootstrap capacitance and Bootstrap Limiter 1 (BT1)

Bootstrap capacitance has the purpose of delivering the charge required for the external HS FET turn on translating its voltage level over VDH.

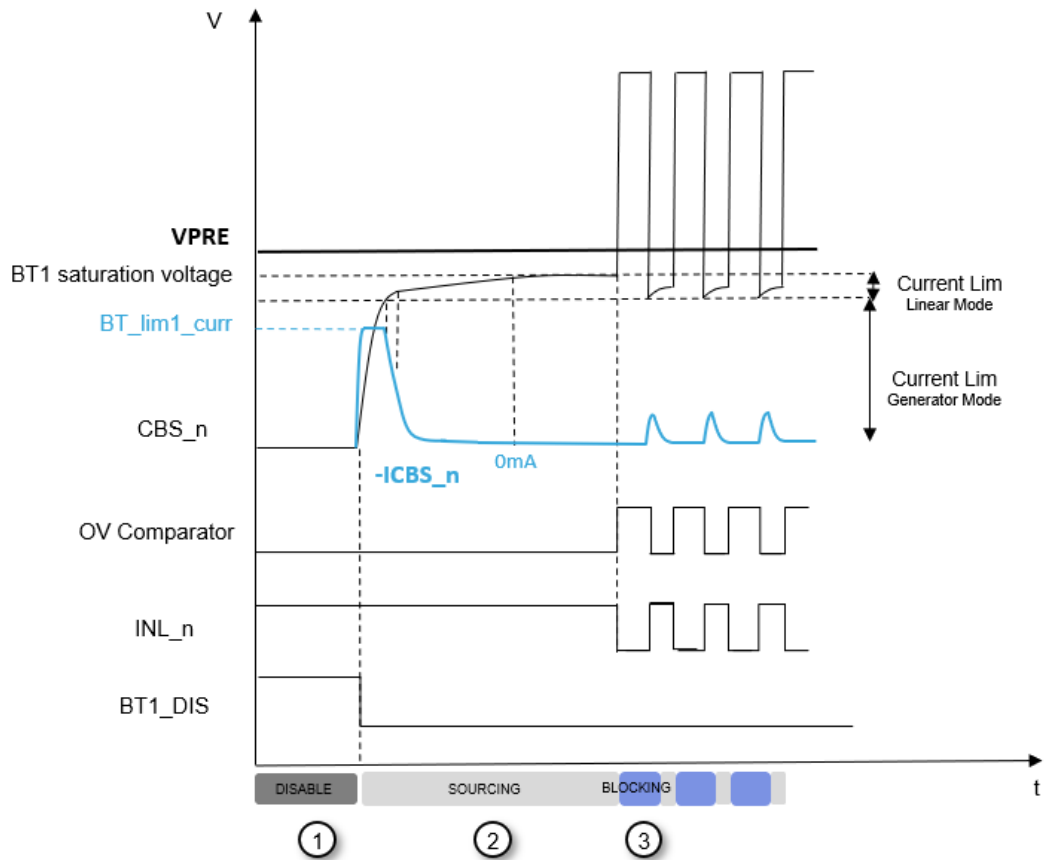
These capacitances are charged from the C_VPRE through BT1n circuitries during the n-th half bridge (1-D)*Tpwm interval (where Tpwm is the PWM period and D is the half bridge duty cycle).

BT1 develops this function by ensuring at the same time a current limitation to avoid in-rush current when CBS are depleted and an over-voltage protection during HS turn-on phases and related voltage swing.

If Bootstrap Limiter 1 is disabled the charging path from VPRE is interrupted and bootstrap capacitors must be charge by other means, e.g. from CP2. Bootstrap Limiter 1 can be disabled by the dedicated SPI bit **BT1_DIS** within the register **GEN_CFG3** as follows:

Table 52. Bootstrap limiter 1 disable bit

| BT1_DIS | Description |
|---------|---------------------------------------|
| 0 | Bootstrap Limiter 1 Enabled (Default) |
| 1 | Bootstrap Limiter 1 Disabled |

Figure 30. BT1 behavior timing diagram


Where:

1. $BT1_DIS = '1'$
 BT1 is disabled and the direct connection from VPRES to CBS_n is opened, the current flow is prevented.
2. $CBS_n - VPRES \geq BT_lim1_ov_ltoh_th$
 BT1 is enabled and CBS_n voltage is lower than the overvoltage threshold. Direct connection from VPRES to CBS_n is established and the current flow is controlled according to the current limiting feature:
 - As long as VPRES-CBS_n drop voltage is higher than the saturation mode threshold (~1.3 V) the current sourced is almost constant and equal to BT_lim1_curr;
 - When the VPRES-CBS_n drop voltage falls below the saturation threshold the output stage enters the linear operation and its behavior is assimilable to a resistance with value BT_lim1_res.

If the CBS_n voltage increases the BT_lim1_res increase until the BT_lim1_sat_drop is reached and the sourced current falls to 0 mA.
3. $CBS_n - VPRES \geq BT_lim1_ov_htol_th$
 BT1 is enabled and CBS_n voltage is higher than the overvoltage threshold. An overvoltage is detected and the connection from CBS_n to VPRES is opened to prevent the reverse current flow.

Table 53. Bootstrap Limiter 1 electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|--------------|--|------------------------------------|-----|-----|-----|----------|---|
| BT_lim1_res | BT Charge Limiter1 limitation resistance | $VPRES - CBS_n \leq 1.3\text{ V}$ | 90 | 120 | 150 | Ω | Linear Mode [n = 1,2,3] ⁽¹⁾ |
| BT_lim1_curr | BT Charge Limiter1 limitation current | $CBS_n = 0\text{ V}$ | 79 | 118 | 160 | mA | Generator Mode [n = 1,2,3] |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|------------------|---|----------------|-----|-----|-----|------|-------------|
| BT_lim1_sat_drop | BT Charge Limiter1 VRE-CBS_n drop voltage for ICBS_n = 0 mA | CBS_n = Open | 335 | 490 | 535 | mV | [n = 1,2,3] |

1. Not subject to production test. This is an equivalent resistance, its value shall be used for bootstrap charge timings estimation only.

5.11.5 VCP monitor

VCP voltage level is monitored by means of the dedicated UV and OV diagnosis. Hysteresis on thresholds and filtering time is implemented.

If $VCP \leq VCP_{uv_th}$ occurs for an interval longer than $T_{vcp_uv_flt}$ filtering time, the VCP_UV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

If $VCP \geq VCP_{ov_th}$ occurs for an interval longer than $T_{vcp_ov_flt}$ filtering time, the VCP_OV flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

To avoid UV detection during power up VCP monitor comparators are masked for a $T_{vcp_boot_mask}$ filtering time, starting from each low to high transition of the internal CP1 enabling command.

Figure 31. VCP UV boot masking

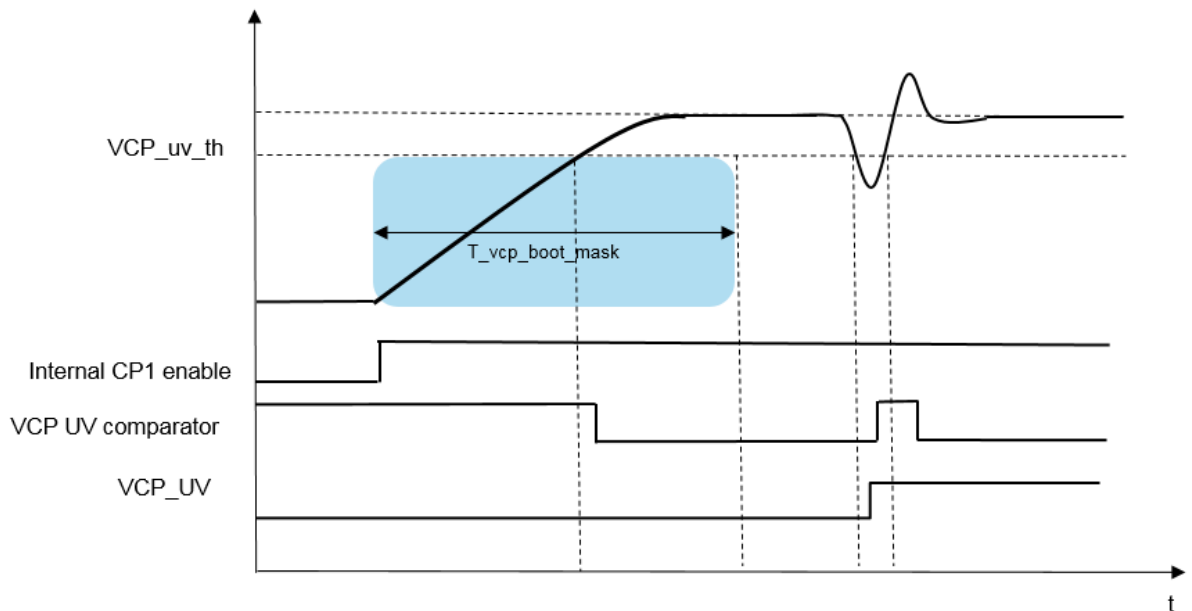
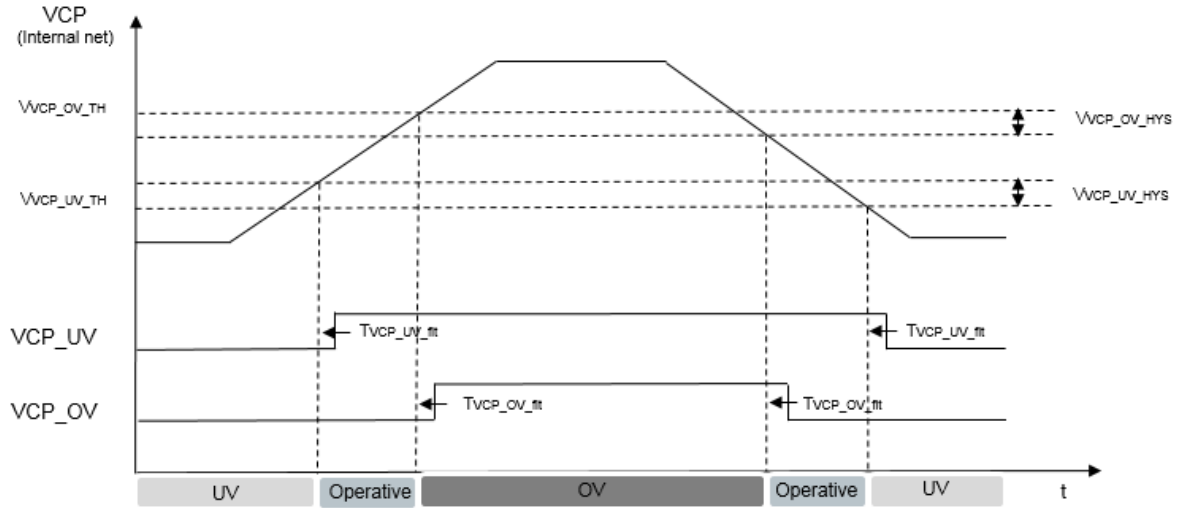


Table 54. VCP Monitor electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-----------------|---|----------------|------|------|------|------|--|
| VCP_uv_th | VCP-VDH under-voltage threshold | - | 4.5 | 5.1 | 5.8 | V | Comparator output Low to High |
| VCP_uv_hys | VCP under-voltage hysteresis | - | 200 | 300 | 400 | mV | - |
| T_vcp_uv_flt | VCP under-voltage detection filter time | CLK_SSM_EN = 0 | 10 | - | 15 | μs | Digital filter guaranteed through scan pattern |
| VCP_ov_th | VCP-VDH over-voltage threshold | - | 15.8 | 17.6 | 19.5 | V | Comparator output Low to High |
| VCP_ov_hys | VCP over-voltage hysteresis | - | 50 | 325 | 500 | mV | - |
| T_vcp_ov_flt | VCP over-voltage detection filter time | CLK_SSM_EN = 0 | 10 | - | 15 | μs | Digital filter guaranteed through scan pattern |
| T_vcp_boot_mask | VCP boot masking time | - | 1.7 | 2 | 2.3 | ms | - |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Figure 32. VCP operative range



5.12 Half bridges gate drivers

The core feature of L9908 is represented by the three identical and independent gate pre-driver stages to drive three inverter's half bridges. Each half bridge pre-driver is composed by a floating current controlled LS and HS pre-driver couple.

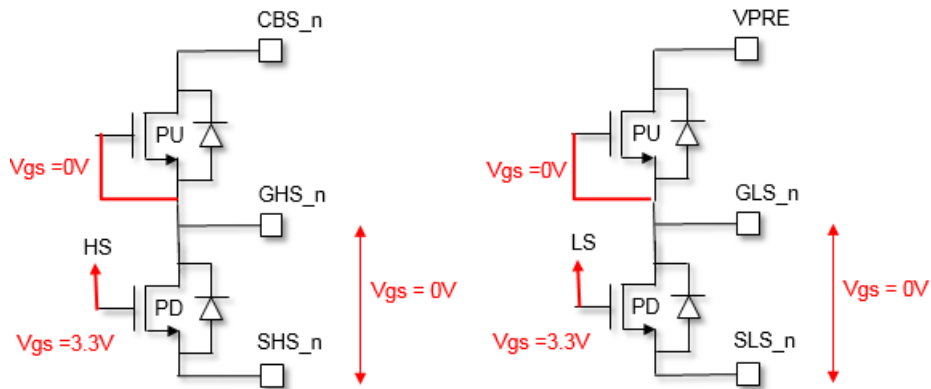
The specific n-th half bridge driver can be disabled by the dedicated SPI bit **HBn_DIS**, $n = [1,2,3]$, within the register **GEN_CFG4** as follows:

Table 55. n-th Half Bridge pre-drivers disable mode bit

| HBn_DIS | Description |
|---------|---|
| 0 | n-th HS/LS drivers is enabled (Default) |
| 1 | n-th HS/LS drivers is disabled |

When disabled the n-th half bridge driver's internal HS/LS PU stages are off while the internal HS/LS PD are on resulting in a $V_{GHS_n} - V_{SHS_n} = 0\text{ V}$ and $V_{GLS_n} - V_{SLS_n} = 0\text{ V}$.

Figure 33. Pre-drivers Disable mode behavior

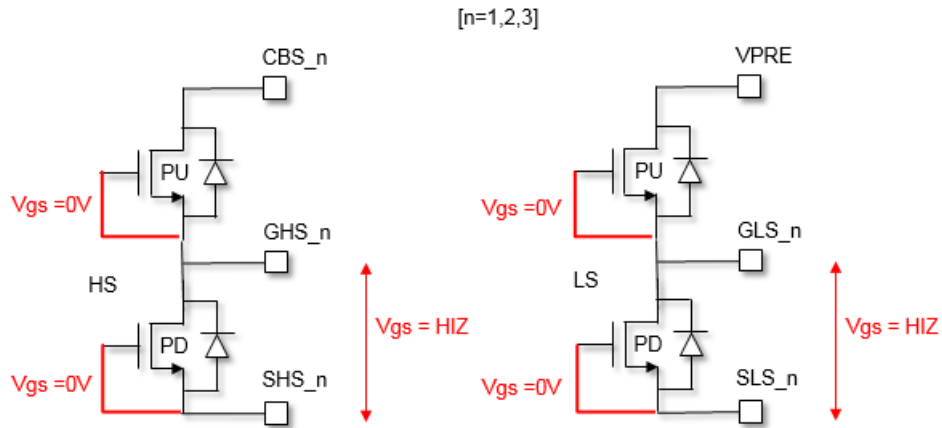


All drivers can be set in high impedance state by the dedicated SPI bit **DRV_HIZ** within the register **GEN_CFG4** as follows:

Table 56. Pre-drivers HIZ mode enable bit

| DRV_HIZ | Description |
|---------|---|
| 0 | Pre-drivers in NO high impedance |
| 1 | Pre-drivers in high impedance (Default) |

When in HIZ mode the half bridge driver's internal HS/LS PU and PD stages are both off resulting in a $V_{GHS_n} - V_{SHS_n} = \text{HIZ}$ and $V_{GLS_n} - V_{SLS_n} = \text{HIZ}$.

Figure 34. Pre-drivers HIZ mode behavior


The behavior of the driver depending on the DRV_HIZ and HBn_DIS setting reflects the following truth table:

Table 57. Pre-drivers behavior truth table

| DRV_HIZ | HBn_DIS | Description |
|---------|---------|--|
| 0 | 0 | Pre-driver enabled |
| 0 | 1 | Pre-driver disabled |
| 1 | 0 | Pre-driver in high impedance (Default) |
| 1 | 1 | Pre-driver disabled |

Note: above described condition in Disable or HIZ conditions are valid for LS drivers as long as $V_{PRE} \geq 2.6 V$ and for HS as long as $V_{DH} \geq 2.6 V$. If these conditions do not hold despite the configuration the drivers are automatically in HIZ mode and the ext. FET V_{gs} is not driven actively.

Table 58. Pre-driver timings

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|----------------|---|---|-----|-----|-----|------|---|
| DRV_pwm_freq | PWM Frequency | - | - | 20 | - | kHz | Consumption Limited ⁽¹⁾ |
| DRV_pwm_dc | HS Duty Cycle in PWM mode | - | 0 | - | 100 | % | Not subject to production test ⁽²⁾ |
| DRV_hs_on_dly | HS Pre-driver switch ON total propagation delay ($T_{logic} + T_{hs_on_dly}$) | Rload = 2 kΩ INHn*0.5 to GHS_n*0.1 SHS_n = 0 V [n = 1,2,3] | 170 | - | 400 | ns | - |
| DRV_hs_off_dly | HS Pre-driver switch OFF total propagation delay ($T_{logic} + T_{hs_off_dly}$) | Rload = 2 kΩ INHn*0.5- GHS_n*0.9 SHS_n = 0 V [n = 1,2,3] | 170 | - | 400 | ns | - |
| DRV_ls_on_dly | LS Pre-driver switch ON total propagation delay ($T_{logic} + T_{ls_on_dly}$) | Rload = 2 kΩ INLn*0.5 to GLS_n*0.1 [n = 1,2,3] | 170 | - | 400 | ns | - |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-------------------|--|---|-----|-----|-----|------|-------|
| DRV_ls_off_dly | LS Pre-driver switch OFF total propagation delay (T_logic_+T_ls_off_dly) | Rload = 2 kΩ INLn*0.5 to GLS_n*0.9 [n = 1,2,3] | 170 | - | 400 | ns | - |
| DRV_on_dly_match | Pre-drivers switch ON propagation delay matching (phase to phase) | - | 0 | - | 75 | ns | - |
| DRV_off_dly_match | Pre-drivers switch OFF propagation delay matching (phase to phase) | - | 0 | - | 75 | ns | - |
| DRV_hs_trise | HS Pre-driver rise time | Clload = 33 nF GHS_n 1 V to 7 V SHS_n = 0 V [n = 1,2,3] | 50 | - | 300 | ns | - |
| DRV_hs_tfall | HS Pre-driver fall time | Clload = 33 nF GHS_n 1 V to 7 V SHS_n = 0 V [n = 1,2,3] | 50 | - | 300 | ns | - |
| DRV_ls_trise | LS Pre-driver rise time | Clload = 33 nF GLS_n 1 V to 7 V [n = 1,2,3] | 50 | - | 250 | ns | - |
| DRV_ls_tfall | LS Pre-driver fall time | Clload = 33 nF GLS_n 1 V to 7 V [n = 1,2,3] | 50 | - | 250 | ns | - |
| DRV_on_dly_match | Pre-drivers rise time matching (phase to phase) | - | 0 | - | 20 | ns | - |
| DRV_on_dly_match | Pre-drivers fall time matching (phase to phase) | - | 0 | - | 20 | ns | - |

- The maximum allowed frequency is retrieved from the maximum average allowed current consumption from VPPE:
Where: N is the number of Ext. FETs and Qg is the FET's gate charge. So that if for example Qg = 150 nC the maximum fpwm allowed is close to 60 kHz (being Iload_max = 55 mA).
- This D.C. limitation shall be adopted to guarantee the minimum Vgs on HS FETs over the whole battery operative range.

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Figure 35. Pre-drivers delay characteristics

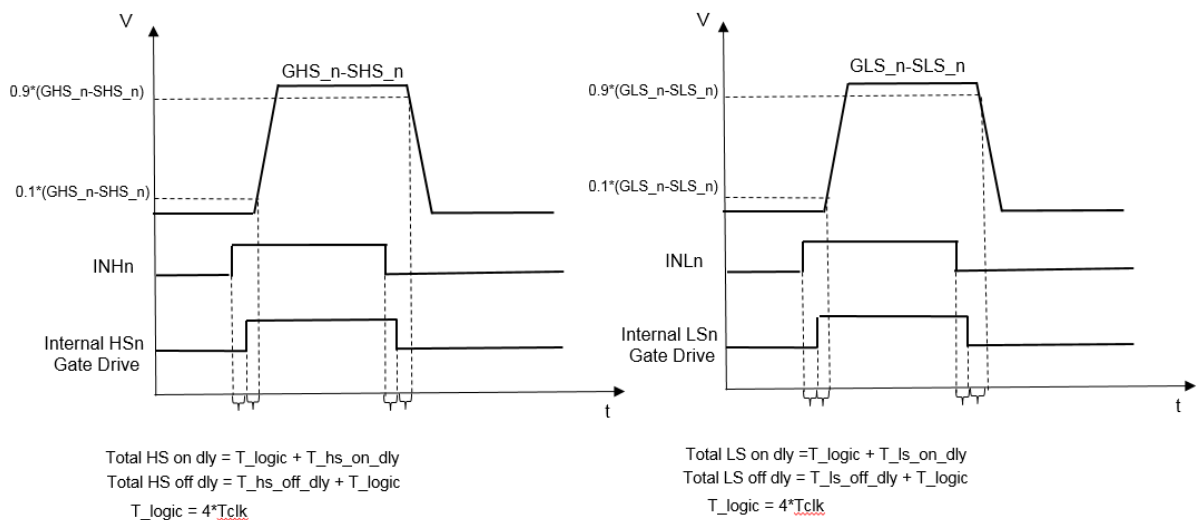
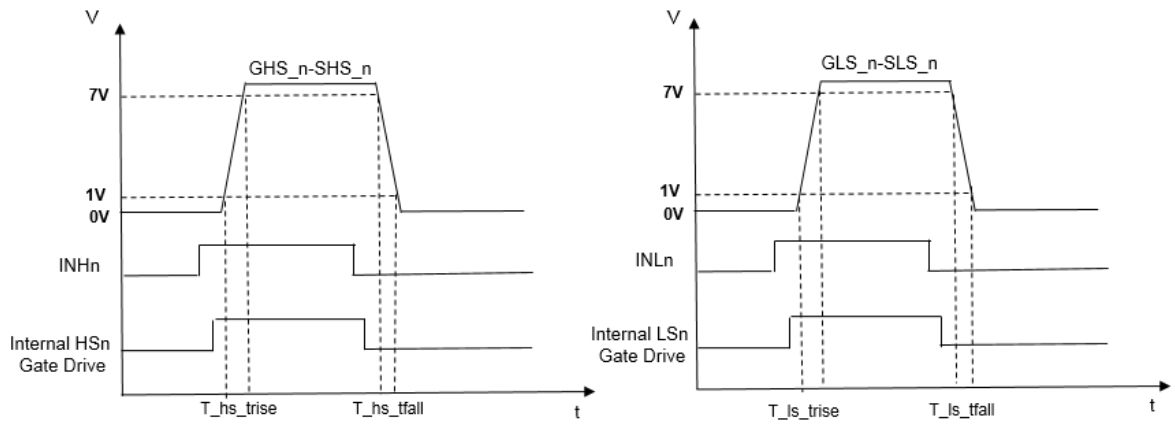


Figure 36. Pre-drivers rise/fall time characteristics

Table 59. Pre-drivers electrical characteristics

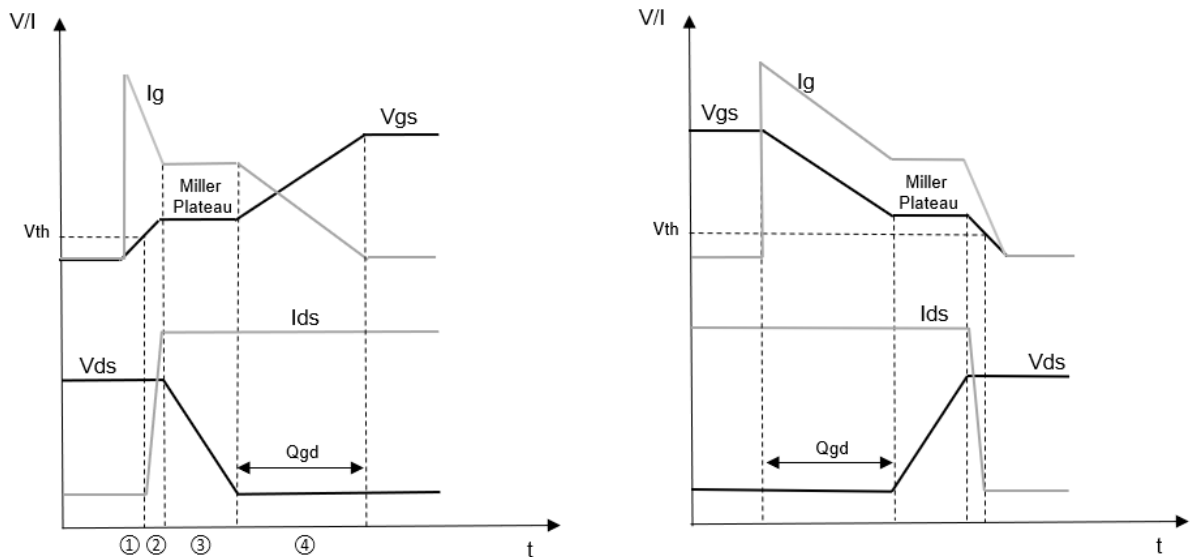
| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-------------------------|--|---|------|------|------|------|--------------------------------|
| DRV_hs_pu_iout | HS Pre-driver pull up Gate Current | VGHS_S – VSHS_n = 0 V [n = 1,2,3] | 1 | 2.2 | - | A | Not subject to production test |
| DRV_hs_pd_iout | HS Pre-driver pull down Gate Current | VGHS_S – VSHS_n = 10 V [n = 1,2,3] | 1 | 2.2 | - | A | Not subject to production test |
| DRV_ls_pu_iout | LS Pre-driver pull up Gate Current | VGLS_S – VSLS_n = 0 V [n = 1,2,3] | 1 | 2.2 | - | A | Not subject to production test |
| DRV_ls_pd_iout1 | LS Pre-driver pull down Gate Current | VGLS_S – VSLS_n = 0 V [n = 1,2,3] | 1 | 2.2 | - | A | Not subject to production test |
| DRV_hs_iout_match | HS Pre-drivers switch ON/OFF current matching (driver to driver) | - | - | - | 1 | % | - |
| DRV_ls_iout_match | LS Pre-drivers switch ON/OFF current matching (driver to driver) | - | - | - | 1 | % | - |
| DRV_hs_iout_onoff_match | HS Pre-drivers switch ON/OFF current matching (pull up to pull down) | - | - | - | 1 | % | - |
| DRV_ls_iout_onoff_match | LS Pre-drivers switch ON/OFF current matching (pull up to pull down) | - | - | - | 1 | % | - |
| DRV_hs_vout_ll | HS Pre-driver Low Level output voltage (GHS_n-SHS_n) | IGHS_n = 4 mA INHn = 0 SHS_n = 0 V [n = 1,2,3] | - | - | 130 | mV | - |
| DRV_hs_vout_ll_match | HS Pre-driver Low Level output voltage matching | - | -15 | - | 15 | mV | - |
| DRV_hs_rpd | HS Pre-driver output resistance at low state | IGHS_n = 4 mA INHn = 0 SHS_n = 0 V | 0.85 | 1.15 | 1.95 | Ω | - |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|----------------------|---|---|------|------|------|------|--------------------------------|
| | | [n = 1,2,3] | | | | | |
| DRV_ls_vout_ll | LS Pre-driver Low Level output voltage (GLS_n-SLS_n) | I _{GLS_n} = 4 mA INL _n = 0 SLS_n = 0 V [n = 1,2,3] | - | - | 200 | mV | - |
| DRV_ls_vout_ll_match | LS Pre-driver Low Level output voltage matching (GLS_n-SLS_n) | - | -15 | - | 15 | mV | - |
| DRV_ls_rpd | LS Pre-driver output resistance at low state | I _{GLS_n} = 4 mA INL _n = 0 SLS_n = 0 V [n = 1,2,3] | 0.85 | 1.15 | 1.95 | Ω | - |
| DRV_vout_ll_passive | Passive output voltage clamping (GHS_n-SHS_n, GLS_n-SLS_n) | DRV_HIZ = 1 I _{GATE} = 5 μA SHS_n = SLS_n = 0 V [n = 1,2,3] | - | - | 2 | V | - |
| DRV_hs_vout_hl | HS Pre-driver High Level output voltage | I _{GHS_n} = 4 mA INH _n = 1 [n = 1,2,3] | 7 | - | 12 | V | - |
| DRV_hs_vout_hl_match | HS Pre-driver High Level output voltage matching | - | - | - | 1 | % | - |
| DRV_hs_rpu | HS Pre-driver output resistance at high state | I _{GHS_n} = 4 mA INH _n = 1 [n = 1,2,3] | 0.85 | 1.15 | 1.95 | Ω | - |
| DRV_ls_vout_hl | LS Pre-driver High Level output voltage | I _{GLS_n} = 4 mA INL _n = 1 [n = 1,2,3] | 7 | - | 12 | V | - |
| DRV_ls_vout_hl_match | LS Pre-driver High Level output voltage matching | - | - | - | 1 | % | - |
| DRV_ls_rpu | LS Pre-driver output resistance at high state | I _{GLS_n} = 4 mA INL _n = 1 [n = 1,2,3] | 1.35 | 1.7 | 3.55 | Ω | - |
| DRV_iout_reverse | Pre-driver reverse output current | GHS_n-SHS_n = -0.6 V GLS_n-SLS_n = -0.6 V [n = 1,2,3] | 1 | - | - | A | Not subject to production test |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Note: Given the standard Ext. FET model, the currents and voltages behavior at its terminals at Turn-on/off can be described by the following piece-wise linear diagram.

Figure 37. Ext. FET Turn-on/off simplified behavior



Where:

1. The gate-source voltage (VGS) ramps up according to the time constant formed by the FET gate resistance (Rg) and input capacitance (Ciss)
2. Once the VGS reaches the threshold voltage (Vth) the current through the device starts to ramp up. The channel is supporting the full-load current and the drain-source voltage (VDS) starts decaying.
3. The VDS falls continuously to its on-state value while the VGS stays approximately constant (Miller Plateau) as well as the gate current.
4. The VGS ramps up to the value applied by the driver. This additional gate voltage fully enhances the FET channel and reaches the full RdsON.

Turn-off is the reverse of turn-on process. During turn-off, the Miller Plateau indicates the start of the rise of the VDS and the voltage of the Miller Plateau will represent the minimum required VGS to sustain the load current.

While a precise value of FET's VDS slew rates at turn-on/off requires simulations including FET and GDU model plus the board and package parasitic details a first order approximations can be used to estimate this value.

The key parameter required for the estimation is the peak current the driver can source/sink to the Ext. FET gate terminal during the turn-on/off process, so the FET VDS rise/fall time can then be approximated by:

$$t_{rise} = \frac{Q_{gd}}{I_{DRV_SOURCE_PEAK}} \quad (6)$$

$$t_{fall} = \frac{Q_{gd}}{I_{DRV_SINK_PEAK}} \quad (7)$$

Where Qgd is the Ext. FET gate-drain charge and Idrv_source/sink_peak are the predrivers Pull-up/Pull-down current. Driver peak current should not be confused with drivers Average Current which is the average current the driver is delivering over full FET switching period i.e.

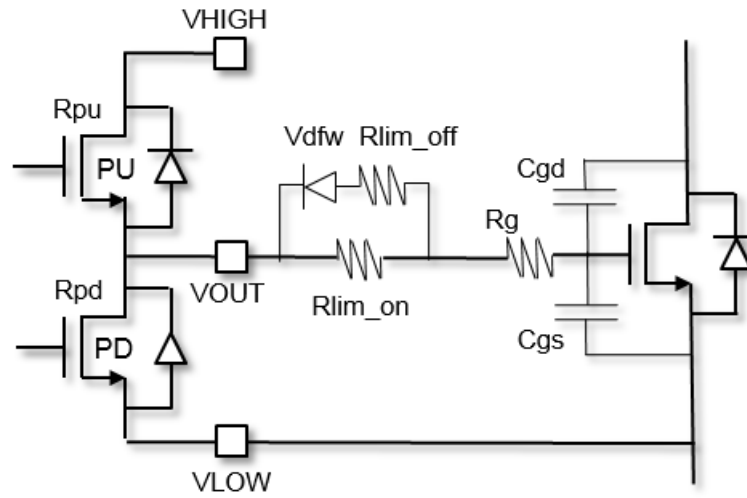
$$I_{DRV_AVERAGE} = Q_g f_{sw} \quad (8)$$

Where Qg is the Ext. FET total gate charge and fsw is the predriver switching frequency.

Output peak current limitation

Since pre-drivers output current is not programmable the peak level can be reduced by means of an external series resistances in order to achieve the following goals:

- dump ringing due to parasitic inductances/capacitances;
- dump ringing due to high voltage/current switching dv/dt, di/dt, and Ext. FET's body-diode reverse recovery charge;
- optimize the switching losses;
- reduce electromagnetic interference (EMI).

Figure 38. Pre-driver peak output current limitation circuit


The maximum PU/PD peak output currents can be estimated as follows:

$$I_{OUT_PU_PK} = \text{MIN} \left(\text{DRV_pu_iout}, \frac{V_{HIGH}}{R_{lim_on} + R_{PU} + R_g} \right) \quad (9)$$

$$I_{OUT_PD_PK} = \text{MIN} \left(\text{DRV_pu_iout}, \frac{V_{HIGH} - V_{d fw}}{R_{lim_on} \parallel R_{lim_off} + R_{PD} + R_g} \right) \quad (10)$$

Where: Vhigh is the driver's output stage supply, Vd_{fw} is the external diode forward voltage, R_g is the Ext. FET series gate resistance, and R_{lim_on/off} are the external limitation resistances.

Example: if R_g = 1.6 Ω, V_{d_{fw}} = 0.75 V, V_{HIGH} = 10 V to have maximum peak current below 0.8 A the external resistance shall be:

$$I_{OUT_PU_PK} = \frac{10V}{R_{lim_on} + 1.15\Omega + 1.6\Omega} = 0.8A \rightarrow (R_{lim_on} + 2.75\Omega) \approx 12.5\Omega$$

$$\rightarrow R_{lim_on} \approx 9.75\Omega \quad (11)$$

$$I_{OUT_PD_PK} = \frac{10V - 0.75V}{R_{lim_on} \parallel R_{lim_off} + 1.15\Omega + 1.6\Omega} = 0.8A \rightarrow (R_{lim_on} \parallel R_{lim_off} + 2.75\Omega) \approx 11.56\Omega \rightarrow 9.75\Omega \parallel R_{lim_off} \approx 8.81\Omega \rightarrow R_{lim_on} \approx 4.63\Omega \quad (12)$$

5.12.1 Ext. FET VGS monitor

The correct functionality of each six pre-drivers is monitored by a dedicated comparator that senses the difference between Gate and Source terminals of the Ext. FET.

If GHS_n-SHS_n (GLS_n-SLS_n) ≥ VGS_{TH} + VGS_{uv_hys} occurs for an interval longer than T_{vgs_fit} the VGS comparator output goes to 0 and the HSn_OFF (LSn_OFF) flag is reset. The Ext FET is considered turned-on.

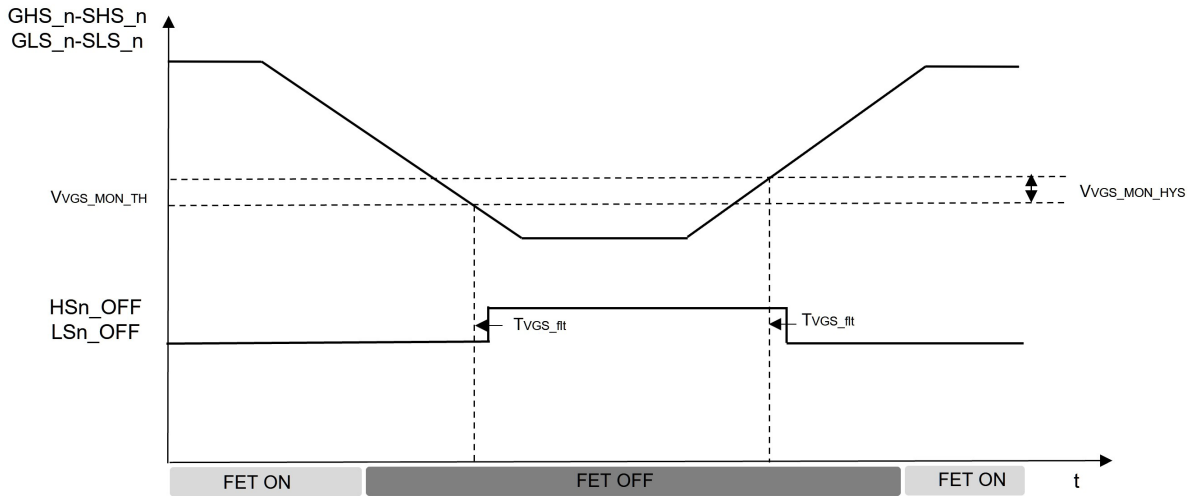
If GHS_n-SHS_n (GLS_n-SLS_n) ≤ VGS_{TH} occurs for an interval longer than T_{vgs_fit} the VGS comparator output goes to 1 and the HSn_OFF (LSn_OFF) flag is set. The Ext FET is considered turned-off.

Table 60. VGS monitor electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|--------------|-----------------------------------|-----|-----|-----|------|---------------|
| VGS_mon_th | VGS monitor threshold | 2 | 2.5 | 3 | V | - |
| VGS_uv_hys | VGS monitor hysteresis | 60 | - | 200 | mV | - |
| T_vgs_uv_fit | VGS monitor detection filter time | 200 | 230 | 300 | ns | Analog filter |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Figure 39. VGS Monitor operative ranges

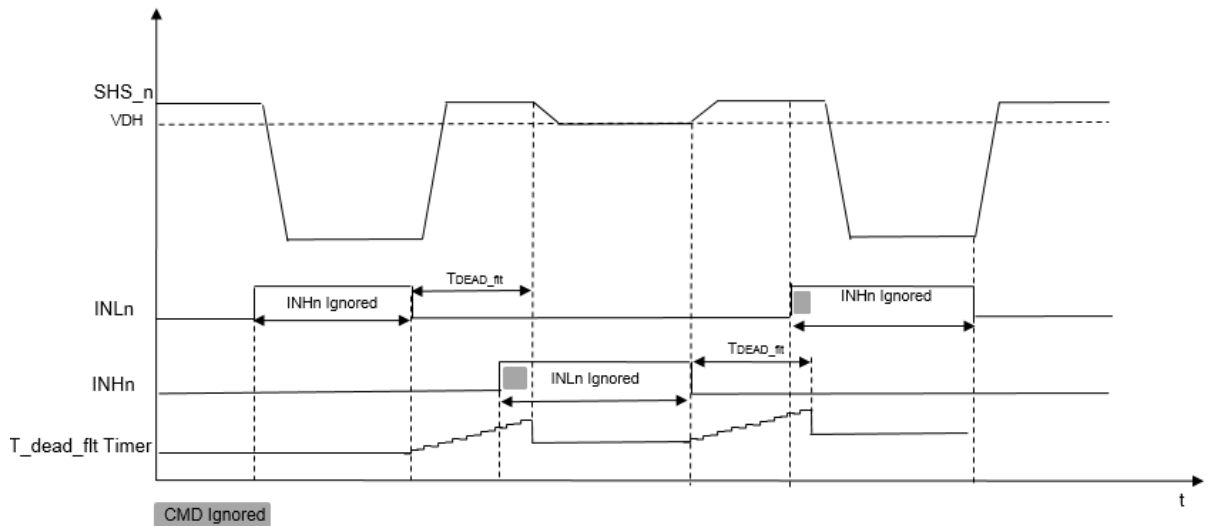


5.12.2

Dead Time Protection (DTP)

The prevention of cross-conduction due to HSn/LSn ON-phase overlap is in principle under the responsibility of the uC driving the PWM pins INHn/INLn. However, a built-in dead time protection is available. When the main logic processes a falling edge event on INHn/INLn it starts a programmable masking time interval T_{dead_fit} during which the rising edges on the opposite signal (INLn/INHn respectively) are ignored. In general a rising edge on INHn/INLn is processed only during the condition $INHn=INLn=0$ and if such a condition hold for at least a T_{dead_fit} .

Figure 40. Dead Time Protection functional operation



The T_{dead_fit} configuration can be set by the dedicated SPI signal **DTP_CFG** within the register **GEN_CFG1** as follows:

Table 61. Dead Time Protection configuration bits

| DTP_CFG2 | DTP_CFG1 | DTP_CFG0 | Description |
|----------|----------|----------|--------------------|
| 0 | 0 | 0 | 0us – DTP Disabled |
| 0 | 0 | 1 | 0.25 μ s |

| DTP_CFG2 | DTP_CFG1 | DTP_CFG0 | Description |
|----------|----------|----------|---------------------|
| 0 | 1 | 0 | 0.35 μ s |
| 0 | 1 | 1 | 0.5 μ s |
| 1 | 0 | 0 | 1 μ s – Default |
| 1 | 0 | 1 | 1.5 μ s |
| 1 | 1 | 0 | 2 μ s |
| 1 | 1 | 1 | 4 μ s |

Table 62. Dead Time Protection accuracy

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|--------------|---------------------------|----------------|-----|-----|-----|------|
| DTP_tfit_acc | Dead Time Filter accuracy | CLK_SSM_EN = 0 | -15 | | 15 | % |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.12.3 Shoot-Through Protection (STP)

Independently of the activation of DTP, L9908 implements a monitoring unit to detect the dangerous condition when HS and LS of the same half bridge are driven on at the same time. The diagnosis is performed at two levels: on the devices PWM inputs from uC (INHn/INLn) and on the Ext. FET Vgs; this allows a diagnosis coverage both on external and internal shoot-through faults.

The first diagnosis level consists in a dedicated digital counter for each half bridge PWM inputs (INHn/INLn couple) set/reset by the logic AND between INHn and INLn and integrates the time interval where the INHn and the INLn are high together.

If INHn=INLn='1' occurs for an interval longer than T_stp_pwm_fit the flag STP_PWM_n is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

In addition to STP, an interlocking protection function on INHn and INLn is implemented: when the main logic processes a rising edge event on INHn/INLn a masking on the opposite signal (INLn/INHn respectively) is applied for the entire duration of the INHn/INLn on pulse. During this interval any rising edge on the opposite signal is ignored. In case INHn/INLn rising edge is synchronous then INLn has the priority.

The interlocking protection is always active and cannot be disabled.

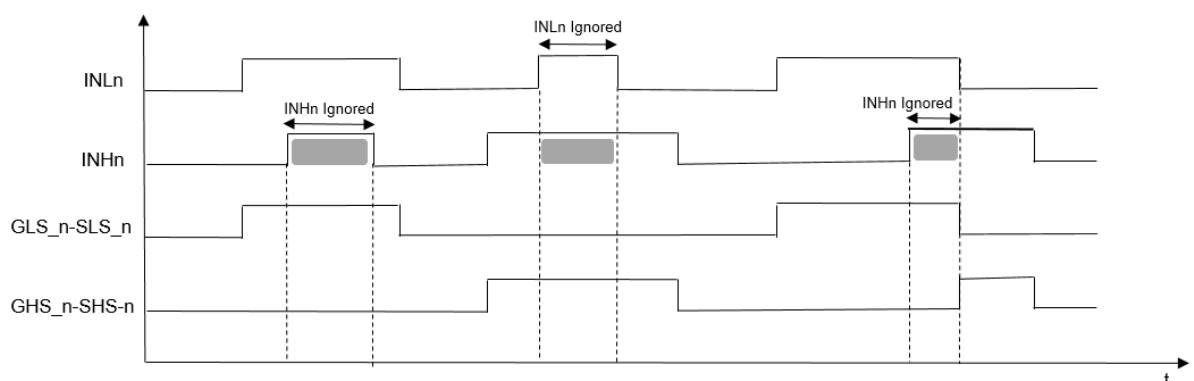
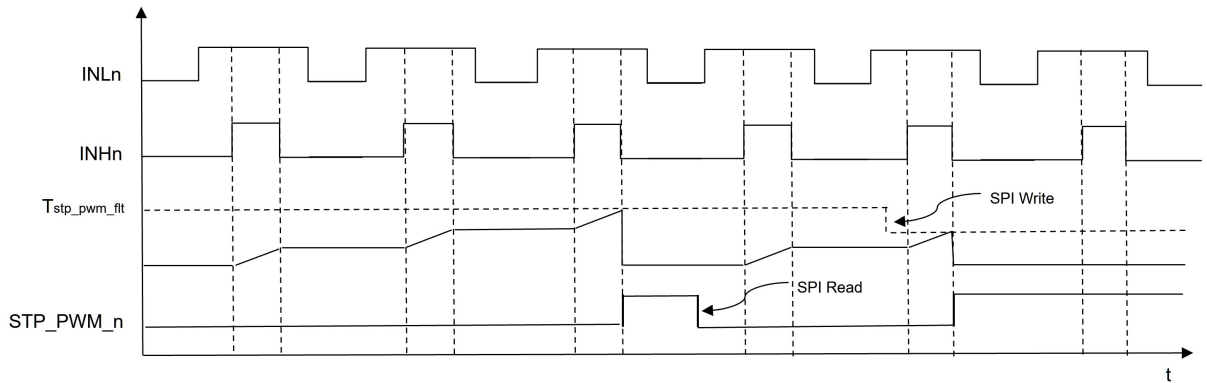
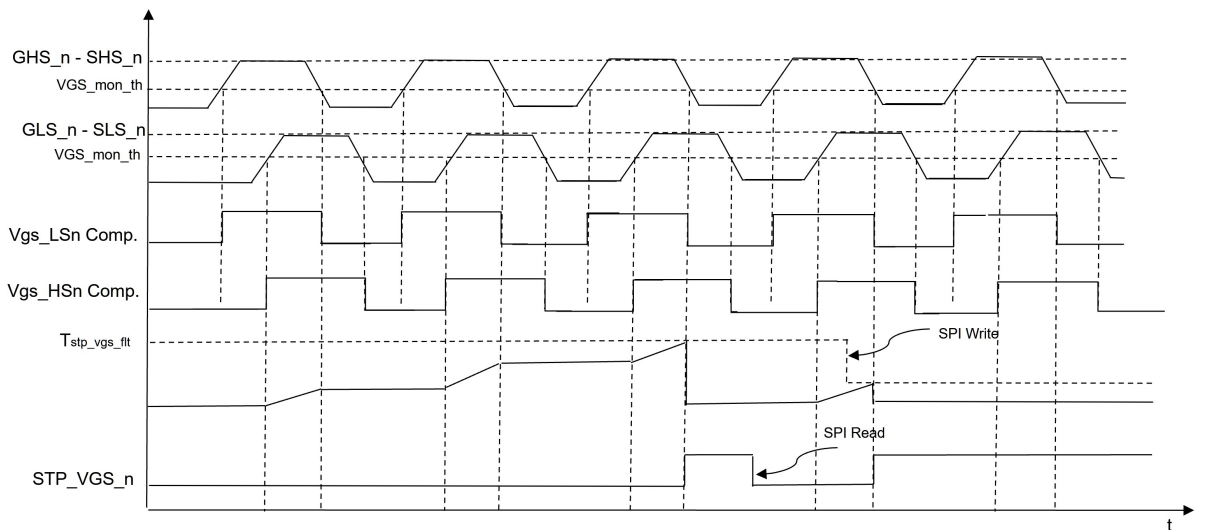
Figure 41. Interlocking protection on PWM inputs: functional operation


Figure 42. Shoot-Through diagnosis on PWM inputs: functional operation


Note: *PWM STD Filter integrates INHn/INLn timing overlap on multiple PWM periods, in this way STD Fault on PWM inputs can be detected also in case minimum timing overlaps are spread over multiple and not adjacent periods.*

The second diagnosis level consists in a dedicated digital counter for each half bridge (HS/LS couple) set/reset by the logic NOR of the HS/LS VGS comparators and integrates the time interval where the HS and the LS are on together.

If HS_n_OFF=LS_n_OFF='0' occurs for an interval longer than T_{stp_vgsflt} the flag STP_VGS_n is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

Figure 43. Shoot-through protection on Ext. FET Vgs functional operation


Note: *VGS STD Filter integrates Vgs_LSn/Vgs_HSn timing overlap on multiple PWM periods, in this way STD Fault on Ext. FET Vgs can be detected also in case minimum timing overlaps are spread over multiple and not adjacent periods.*

The STD diagnosis can be disabled on the single half bridge by a dedicated SPI bit as follows:

Table 63. Shoot-Through Protection on PWM inputs enable bit

| STPn_PWM_DIS | Description |
|--------------|---|
| 0 | Shoot-through protection on PWM input enabled (Default) |
| 1 | Shoot-through protection on PWM input disabled |

Table 64. Shoot-Through Protection on Ext. FET VGS enable bit

| STPn_VGS_DIS | Description |
|--------------|---|
| 0 | Shoot-through protection on FET Vgs enabled (Default) |
| 1 | Shoot-through protection on FET Vgs disabled |

The T_stp_fit configuration for the n-th pre-driver can be set by a dedicated SPI bit as follows:

Table 65. Shoot-Through Protection on PWM inputs filtering configuration bits

| STPn_PWM_CFG1 | STPn_PWM_CFG0 | Description |
|---------------|---------------|-------------------|
| 0 | 0 | 0.2 μs (Defaults) |
| 0 | 1 | 0.5 μs |
| 1 | 0 | 1 μs |
| 1 | 1 | 1.5 μs |

Table 66. Shoot-Through Protection on Ext. FET VGS filtering configuration bits

| STPn_VGS_CFG1 | STPn_VGS_CFG0 | Description |
|---------------|---------------|-------------------|
| 0 | 0 | 0.2 μs (Defaults) |
| 0 | 1 | 0.5 μs |
| 1 | 0 | 1 μs |
| 1 | 1 | 1.5 μs |

Table 67. Shoot-Through Protection accuracy

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|------------------|--|----------------|-----|-----|-----|------|
| STP_pwm_tflt_acc | PWM Shoot-through Filter Time accuracy | CLK_SSM_EN = 0 | -10 | - | 10 | % |
| STP_vgs_tflt_acc | VGS Shoot-through Filter Time accuracy | CLK_SSM_EN = 0 | -10 | - | 10 | % |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

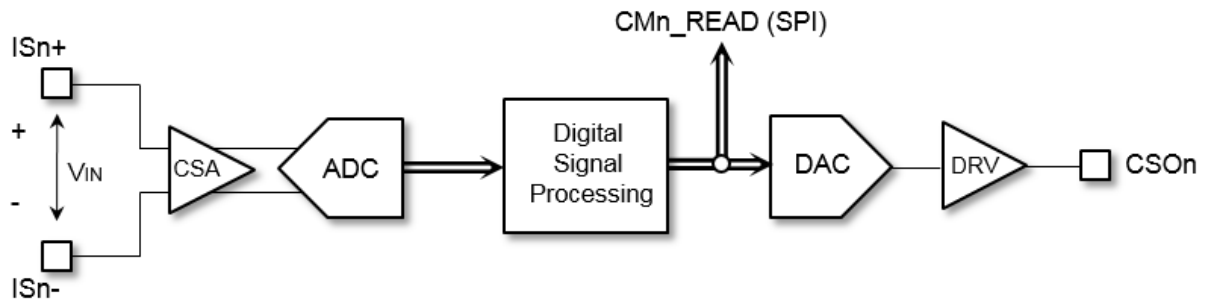
5.13 Current monitors

L9908 implements three identical and independent current monitor channels.

The motor current converted by an external shunts resistance into a differential voltage VIN is measured through the input pins Isn+ and Isn- (VIN = Isn+ - Isn-).

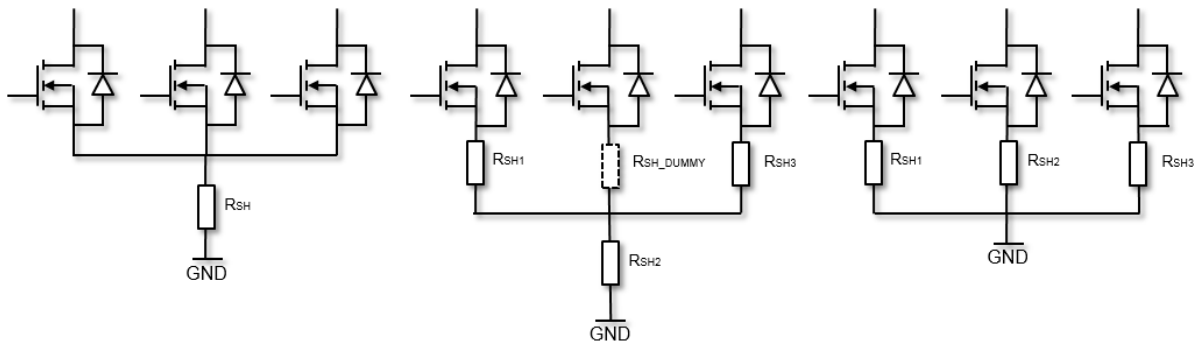
A current sense amplifier (CSA) is used to amplify the ground referenced differential voltages then converted via an internal 11-bit ADC. The current information is made available either in digital form through SPI register readout or reconverted in analog form through an 11-bit DAC at CSO_n pin.

Figure 44. n-th Current Monitor Channel simplified block diagram



Each current monitor channel can be used to measure positive or negative motor current flow through single (DC Link) or multiple (Single Leg) shunts system configurations.

Figure 45. External Shunts Configurations a) DC-Link, b) 2xSingle Leg + DC-Link, c) 3xSingle Leg



The specific n-th current monitor channel can be disabled by a dedicated SPI bit in the SAFETY_RELEVANT2 register, as follows:

Table 68. n-th Current Monitor Channel enable bit

| CSn_DIS | Description |
|---------|--|
| 0 | n-th current monitor enabled (Default) |
| 1 | n-th current monitor disabled |

When disabled, the n-th input current measurement structure is set in low consumption mode, the related DSP logic is reset and the output stage is set into high impedance state.

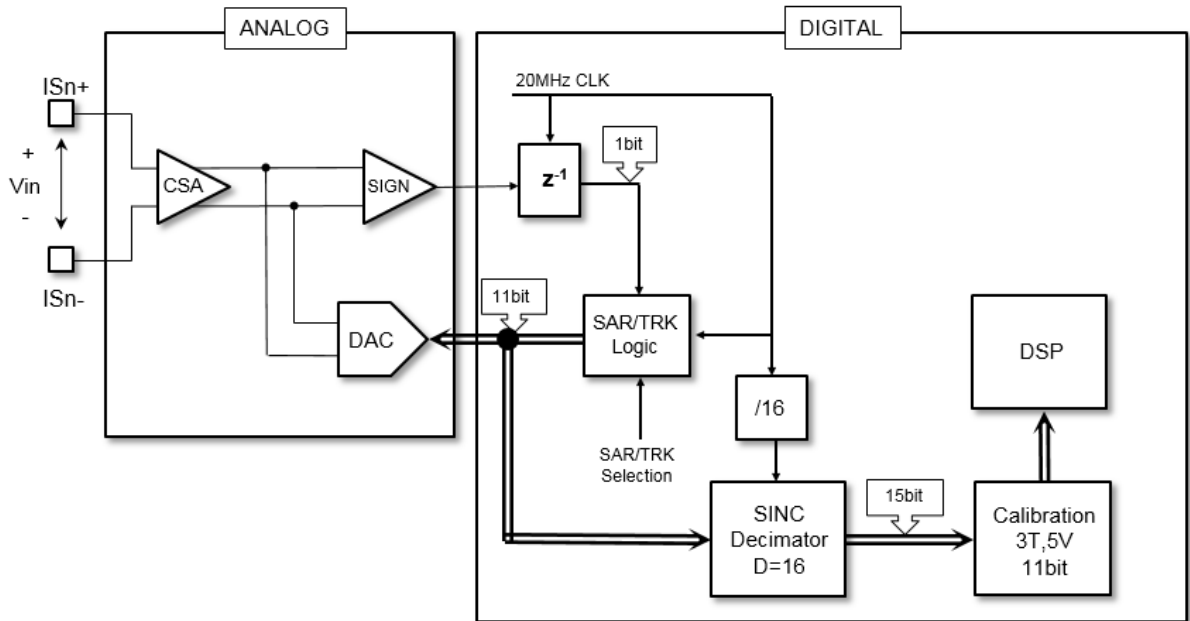
The current monitor channel consists of three main parts:

- A/D Conversion;
- Digital Signal Processing;
- D/A Conversion.

5.13.1 A/D conversion

The A/D conversion part is composed by a floating differential amplifier (CSA) that feeds an 11bits ADC.

Figure 46. A/D Conversion simplified block diagram



The differential transconductance amplifier measures the voltage across the external shunt cancelling errors due to voltage drop across the stray resistances and the offsets between the external and internal ground.

The cascaded ADC compares the differential current output from CSA with the output of an 11bit (1bit sign+10bit module) differential current steering DAC thus converting the current information in an 11 binary-coded word clocked at 20 MHz.

The DAC LSB can be configured separately for each current monitor channel by means of dedicated SPI bits in order to adjust the current monitor input range to the ADC input range as follows:

Table 69. Current Monitor input range configuration bit

| Input Range | CSMn_IN_RANGE_CFG2 | CSMn_IN_RANGE_CFG1 | CSMn_IN_RANGE_CFG0 | Description |
|-------------|--------------------|--------------------|--------------------|---|
| 0 | 0 | 0 | 0 | V _{IN_MAX} = ± 7 mV |
| 1 | 0 | 0 | 1 | V _{IN_MAX} = ±18 mV |
| 2 | 0 | 1 | 0 | V _{IN_MAX} = ±36 mV |
| 3 | 0 | 1 | 1 | V _{IN_MAX} = ±90 mV |
| 4 | 1 | 0 | 0 | V _{IN_MAX} = ±160 mV |
| 5 | 1 | 0 | 1 | V _{IN_MAX} = ±300 mV (Default) |
| - | 1 | 1 | 0 | Reserved |
| - | 1 | 1 | 1 | Reserved |

V_{IN_MAX} is the input range for which all parameters are guaranteed. Input Full Scale range is actually larger (to allow some headroom for calibration purposes), and can be calculated multiplying CM input ADC LSB (indicated in Table 70) values by 2¹¹-1.

To increase the signal to noise ratio, a successive digital process section filters the raw conversion by means of a SINC Decimation filter with a decimation factor of 16. The output digital information is then available in a 15bit length word.

Table 70. Current Monitor Input characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|---|---------------------------------------|-------------------------|------|--------|-------|------|---|
| Current Monitor Input | | | | | | | |
| CM_in_range_diff | CM differential voltage input range | CSMn_IN_RANGE_CFG = 000 | -7 | | 7 | mV | Application information ⁽¹⁾ (2) |
| | | CSMn_IN_RANGE_CFG = 001 | -18 | | 18 | | |
| | | CSMn_IN_RANGE_CFG = 010 | -36 | - | 36 | | |
| | | CSMn_IN_RANGE_CFG = 010 | -90 | | 90 | | |
| | | CSMn_IN_RANGE_CFG = 011 | -160 | | 160 | | |
| | | CSMn_IN_RANGE_CFG = 100 | -300 | | 300 | | |
| CM_in_range_cm | CM common mode voltage input range | - | -2 | - | 2 | V | Application information ⁽²⁾ |
| CM_in_ic1 | CM input current | ISn+ = ISn- = -2 V | -210 | -25 | -0.23 | mA | - |
| CM_in_ic2 | CM input current | ISn+ = ISn- = +2 V | -310 | -270 | -230 | uA | - |
| CM_in_cm_res1 | CM input common mode resistance | ISn+ = ISn- = -2 V | 9.5 | - | - | Ω | Application Information |
| CM_in_cm_res2 | CM input common mode resistance | ISn+ = ISn- = +2 V | 6.5 | - | - | kΩ | Application Information |
| CM_in_dm_res | CM input differential mode resistance | CSMn_IN_RANGE_CFG = 000 | | 0.283 | | kΩ | Application Information |
| | | CSMn_IN_RANGE_CFG = 001 | | 0.566 | | | |
| | | CSMn_IN_RANGE_CFG = 010 | - | 1.132 | | | |
| | | CSMn_IN_RANGE_CFG = 010 | | 2.831 | | | |
| | | CSMn_IN_RANGE_CFG = 011 | | 5.096 | | | |
| | | CSMn_IN_RANGE_CFG = 100 | | 9.06 | | | |
| Current Monitor Input Resolution | | | | | | | |
| CM_in_resolution | CM input ADC resolution | - | - | 11 | - | bits | Application Information |
| CM_in_lsb | CM input ADC LSB | CSMn_IN_RANGE_CFG = 000 | | 10.05 | | μV | Application information |
| | | CSMn_IN_RANGE_CFG = 001 | | 20.11 | | | |
| | | CSMn_IN_RANGE_CFG = 010 | | 40.28 | | | |
| | | CSMn_IN_RANGE_CFG = 010 | - | 100.7 | | | |
| | | CSMn_IN_RANGE_CFG = 011 | | 181.27 | | | |
| | | CSMn_IN_RANGE_CFG = 100 | | 322.26 | | | |
| Current Monitor Input Accuracy | | | | | | | |
| CM_in_gain_err | CM ADC Gain Error | - | -2 | - | 2 | % | All input ranges ⁽³⁾⁽⁴⁾ |
| CM_in_offset_err | CM ADC Input Referred Offset Error | CSMn_IN_RANGE_CFG = 000 | -2 | | 2 | mV | (4) |
| | | CSMn_IN_RANGE_CFG = 001 | -2 | | 2 | | |
| | | CSMn_IN_RANGE_CFG = 010 | -2 | - | 2 | | |
| | | CSMn_IN_RANGE_CFG = 010 | -2 | | 2 | | |
| | | CSMn_IN_RANGE_CFG = 011 | -3 | | 3 | | |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|--|--------------------------------------|-------------------------|----------------|-----|-----------|-----------|-------------------------|
| | | CSMn_IN_RANGE_CFG = 100 | -6 | | 6 | | |
| Current Monitor Input Dynamic Characteristics | | | | | | | |
| CM_in_gain_toggling | CM CSA transition time gain toggling | - | - | 26 | - | Tclk | Application Information |
| CM_in_overload_recovery | Overload Recovery Time | - | - | 36 | - | Tclk | Application Information |
| CM_in_sr | CM ADC sample rate | - | - | 20 | - | MHz | Application information |
| CM_in_rise_fall_sr | CM Input Differential Rise/Fall Time | trise, tfall | 16 | - | - | Tclk | Application Information |
| CM_in_pulse_sr | CM Input Differential Slew Rate | (V2 - V1)/tpulse | - | - | 1LSB/Tclk | mV/ μs | Application Information |
| CM_in_pulse_time | CM Input Differential pulse length | tpulse | TSYNC + 10Tclk | - | - | μs | Application Information |

1. Offset free differential input range.
2. VIN may exceed CM_in_range_diff up to the absolute maximum ratings. However, it will saturate the A/D dynamic range.
3. Ex. 1
 - CSMn_IN_RANGE_CFG:011 → CM_in_range_diff = ±90 mV
 - FSR = 180 mV
 - |ISn+ - ISn-| = 20 mV → ±20 mV*2% = ±0.4 mV
- Ex.2
 - CSMn_IN_RANGE_CFG:100 → CM_in_range_diff = ±160 mV
 - FSR = 320 mV
 - |ISn+ - ISn-| = 150 mV → ±150 mV*2% = ±3 mV
4. ADC conversion total error can be retrieved for each differential input range as follows:
 - CM_in_total_error = CM_in_gain_err + CM_in_offset_err
 - Ex1
 - CM_in_range_diff = ±90 mV
 - |ISn+ - ISn-| = 70 mV

Total ADC conversion error = ±2 mV ± (2%*70 mV) = ±2 mV ±1.4 mV. The value read by SPI will range between 70 mV-(2 mV + 1.4 mV) and 70 mV + (2 mV + 1.4 mV), which is 70 mV ± 34LSB. i.e. CSn_READ = 0x2B7 ± 0x22

Figure 47. Current Monitor input dynamic timings

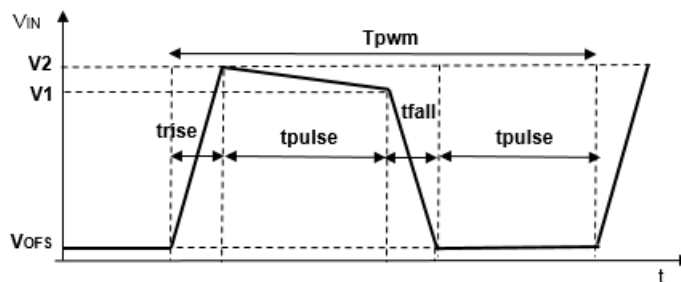


Figure 48. Current monitor input CMRR - Positive Common Mode input voltage

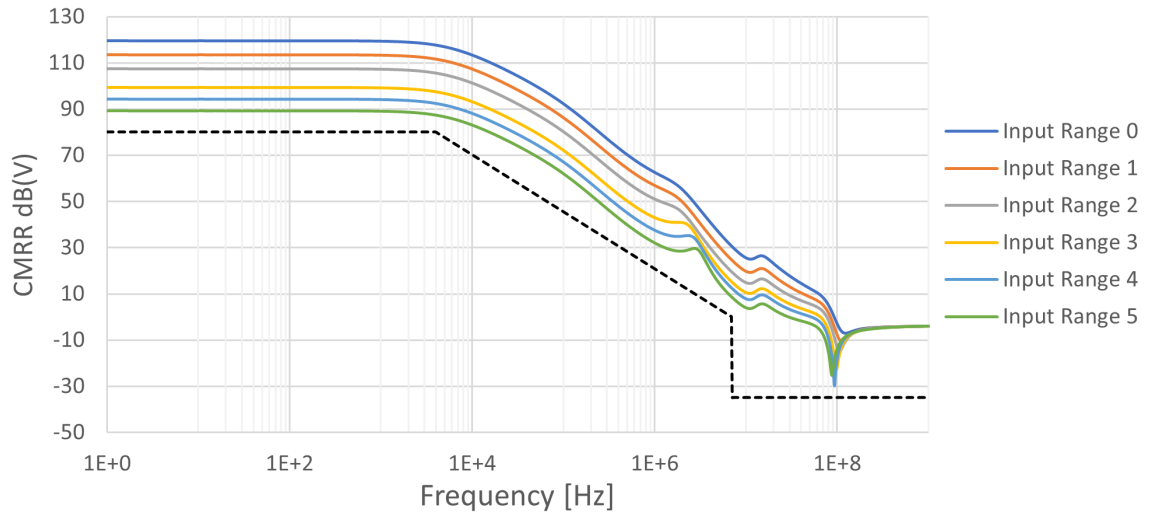
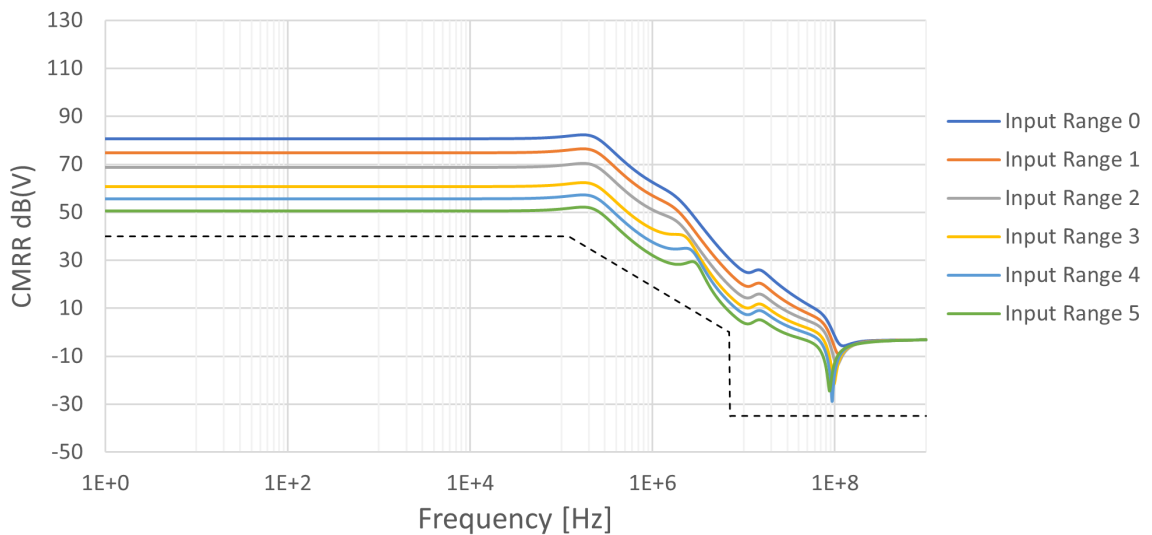


Figure 49. Current monitor input CMRR - Negative Common Mode input voltage



$$CMRRn = -20\log\left(\frac{\sqrt{CSON_{RF_RMS}^2 + CSON_{DC}^2}}{Vin_{RF_RMS}}\right) \quad (13)$$

Where:

CSON_{rf_rms} = output voltage RMS calculated taking into account only the AC component of the output voltage on the n-th CSO output.

CSON_{dc} = Output DC shift (with respect to the reference value with zero AC component).

Vin_{rf_rms} = input voltage RMS calculated taking into account only the AC component of the input voltage on n-th CM input (Vin = IS + -IS-).

Example: CSON = 200 mV (reference value without RF applied) CSON_{DC_RF} = 160 mV (DC output value with RF applied) Vin_{pp} = 4 Vpp → Vin_{RMS} = 1.4 Vrms (applied RMS RF level) CSON_{ac} = 0 (i.e. no ripple at current measurement output).

CMRR = 30.88 dB

$$CMRRn = -20\log\left(\frac{\sqrt{(0)_{AC_RMS}^2 + (-0.04)_{DC}^2}}{1.4}\right) = 30.88 \text{ dB(V)} \quad (14)$$

5.13.1.1 Conversion triggering logic

In order to improve the effectiveness of the A/D conversion and maximize the dynamic performances the current monitor ADC implements two different conversion algorithms:

- Up/Down TRK algorithm is active while SAR is disabled. TRK logic increments/decrements by 1LSB each clock cycle the DAC input depending on the sign comparator assessment. This algorithm is able to guarantee a high conversion accuracy but along with a limited input slew rate given by $1\text{LSB}/T_{\text{clk}}$;
- SAR algorithm is active while TRK is disabled. SAR logic increments/decrements by $2^{10}/2^N$ at each N clock cycle. This algorithm is effective in the fast changing signal but lacks in accuracy.

A/D conversion default algorithm is TRK; SAR conversion algorithm is launched by triggering logic assessment.

Conversion triggering logic assessment follows two different criteria:

- Command Edge Triggering;
- Auto-triggering.

Note: As long as enabled, each n -th A/D continuously converts input voltage into digital words: the conversion triggering only defines how SAR and TRK algorithms interleave to get the most accurate current conversion.

5.13.1.1.1 Command edge triggering

Command Edge Triggering criteria relies on ACT function: when the value stored in ACT n register equals the value configured in the TSYNC n register, a trigger pulse is generated and the SAR conversion is performed. SAR conversion is launched at the same time on all current monitors, synchronously.

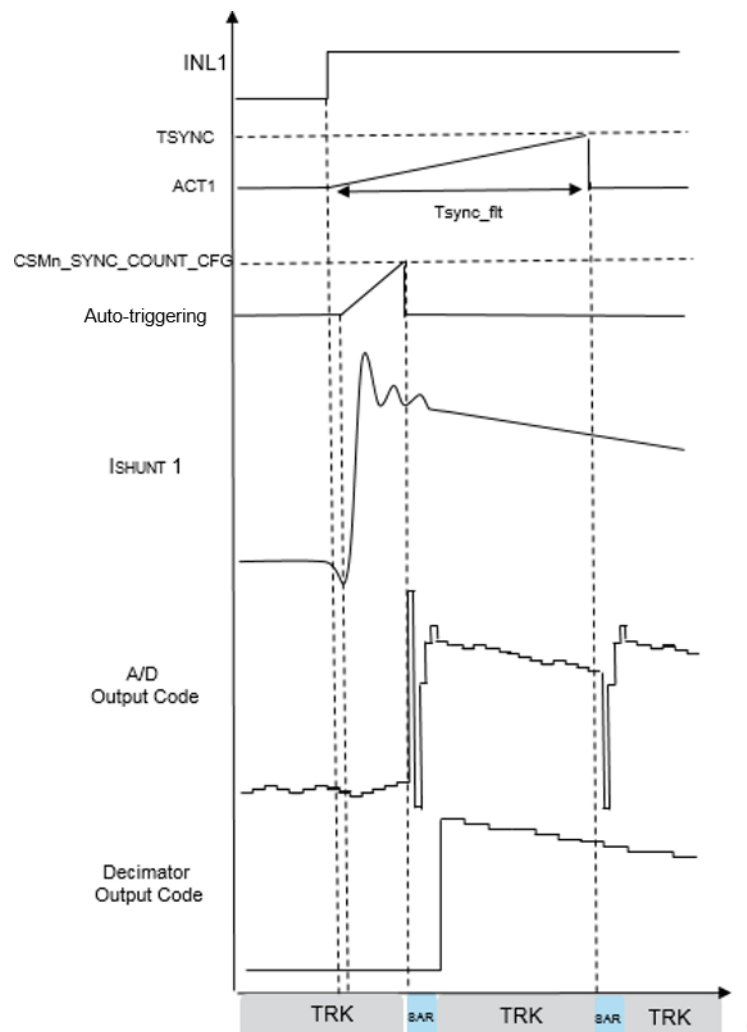
The n -th ACT to be used for sampling reference can be configured by means of the following bits:

Table 71. Command edge triggering configuration bits

| CSM_SSPV_PH_CFG1 | CSM_SSPV_PH_CFG0 | Description |
|------------------|------------------|----------------------------------|
| 0 | 0 | No synchronization |
| 0 | 1 | TSYNC based on Phase 1 (Default) |
| 1 | 0 | TSYNC based on Phase 2 |
| 1 | 1 | TSYNC based on Phase 3 |

- Note:*
- When CSM_SSPV_PH_CFG is set 00 the value output on CSOn and stored in CSn_READ correspond to the last sample value when CSM_SSPV_PH_CFG \neq 00.
 - When CSM_SSPV_PH_CFG = 01 ACT1 is used for the comparison
 - When CSM_SSPV_PH_CFG = 10 ACT2 is used for the comparison
 - When CSM_SSPV_PH_CFG = 11 ACT3 is used for the comparison

Figure 50. Command edge triggering timing diagram



The T_{sync_fit} can be set separately for each phase by the SPI signal $TSYNCn_CFG<10:0>$ in the register CHn_CFG3 , so that:

$$T_{SYNCn} = \Delta_{LSB_TSYNC} \times TSYNCn_CFG[10:0] \quad (15)$$

Being:

$$\Delta_{LSB_TSYNC} = \Delta_{ACT_lsb} \quad (16)$$

Where: Δ_{ACT_lsb} is the ACT quantization step (see Table 98).

5.13.1.1.2 Auto-triggering

Auto-triggering criteria relies on an internal counter which counts the number of clock cycles in which the Sign comparator has the same sign. When the counted value equals the value configured in the $CSMn_SYNC_COUNT_CFG$ register a trigger pulse is generated and the SAR conversion is performed. SAR conversion is launched independently on each current monitor, asynchronously.

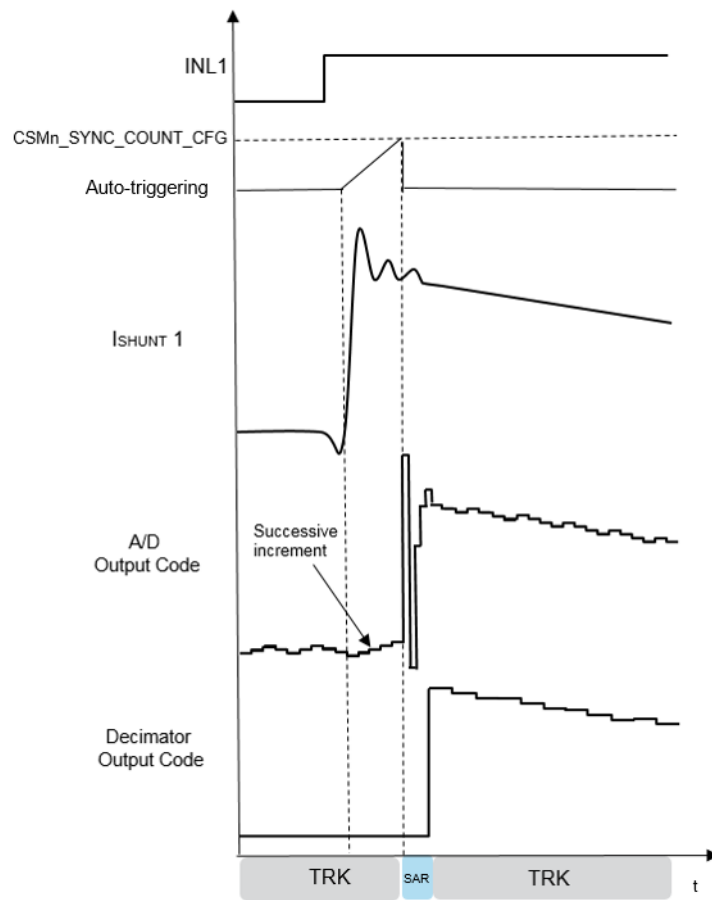
Note: Auto-triggering is always active and cannot be disabled. Its purpose is to allow A/D to promptly react in front of input voltage sharp transitions also in case Command Edge Triggering is not enabled.

SR Counter threshold can be programmed for the single current monitor through the following SPI bits:

Table 72. Synchronization counter configuration bits

| CSMn_SYNC_COUNT_CFG1 | CSMn_SYNC_COUNT_CFG0 | Description |
|----------------------|----------------------|-------------------|
| 0 | 0 | 16 Tclk (Default) |
| 0 | 1 | 24 Tclk |
| 1 | 0 | 32 Tclk |
| 1 | 1 | 40 Tclk |

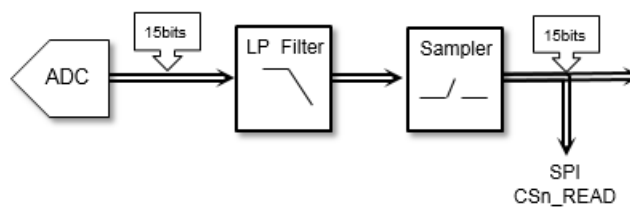
Figure 51. Auto-triggering timing diagram



5.13.2 Digital signal processing

The signal processing consists in a series of operations performed on the converted current information in the digital domain.

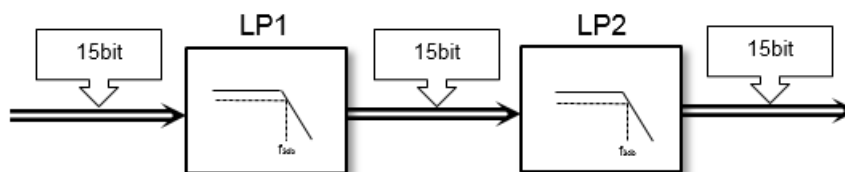
Figure 52. Digital signal processing simplified block diagram



5.13.2.1 Low-pass filtering

The first operation performed is a 2nd order low-pass filtering on the raw ADC data accomplished by two cascaded single pole filters with the same cut-off frequency.

Figure 53. Digital LP filtering simplified block diagram



The filter's cut-off frequency can be configured through SPI as follows (setting is common for the three phases):

Table 73. Current monitors LP filtering configuration bits

| CSM_LP_CFG2 | CSM_LP_CFG1 | CSM_LP_CFG0 | Description |
|-------------|-------------|-------------|------------------------|
| 0 | 0 | 0 | No filtering (Default) |
| 0 | 0 | 1 | 91 kHz |
| 0 | 1 | 0 | 37 kHz |
| 0 | 1 | 1 | 17 kHz |
| 1 | 0 | 0 | 8 kHz |
| 1 | 0 | 1 | 4 kHz |
| 1 | 1 | 0 | 2 kHz |
| 1 | 1 | 1 | 1 kHz |

5.13.2.2 Conversion sampling

Current monitor's DSP allows two kinds of data flow toward the SPI register (digital format) and to D/A (analog format):

- Free running;
- Track & Hold

Note: Conversion sampling affects NO A/D operation whatsoever. Conversion sampling logic only defines how SPI reg. and D/A output values have to be updated.

5.13.2.2.1 Free running

In Free Running mode the CS_n_READ SPI registers and the CS_{On} voltage are continuously updated as soon as A/D output words are available.

Free Running mode is enabled configuring signal CSM_SAMPLE_CFG = 000 in the register CH_n_CFG2.

Note: In the following timing diagrams, N-th A/D Out value corresponds to the SAR conversion value.

Figure 54. Free running sampling timing diagram - non-zero current + auto-triggering

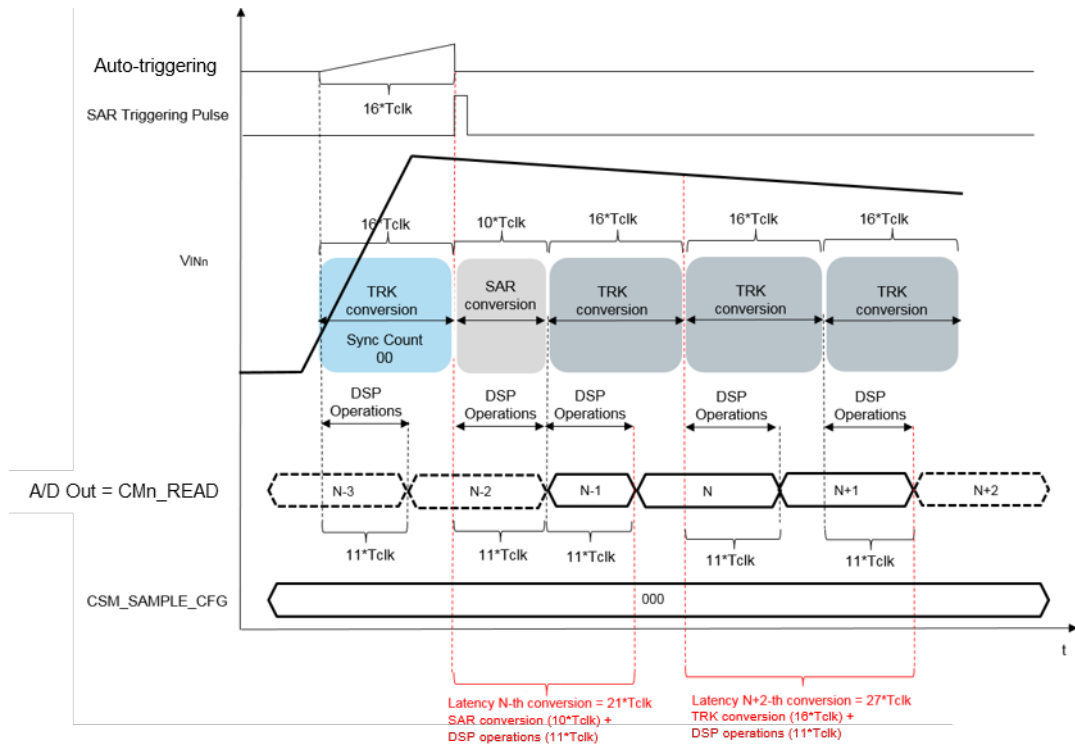


Figure 55. Free running sampling timing diagram - non-zero current + auto-triggering, latency to CSOn

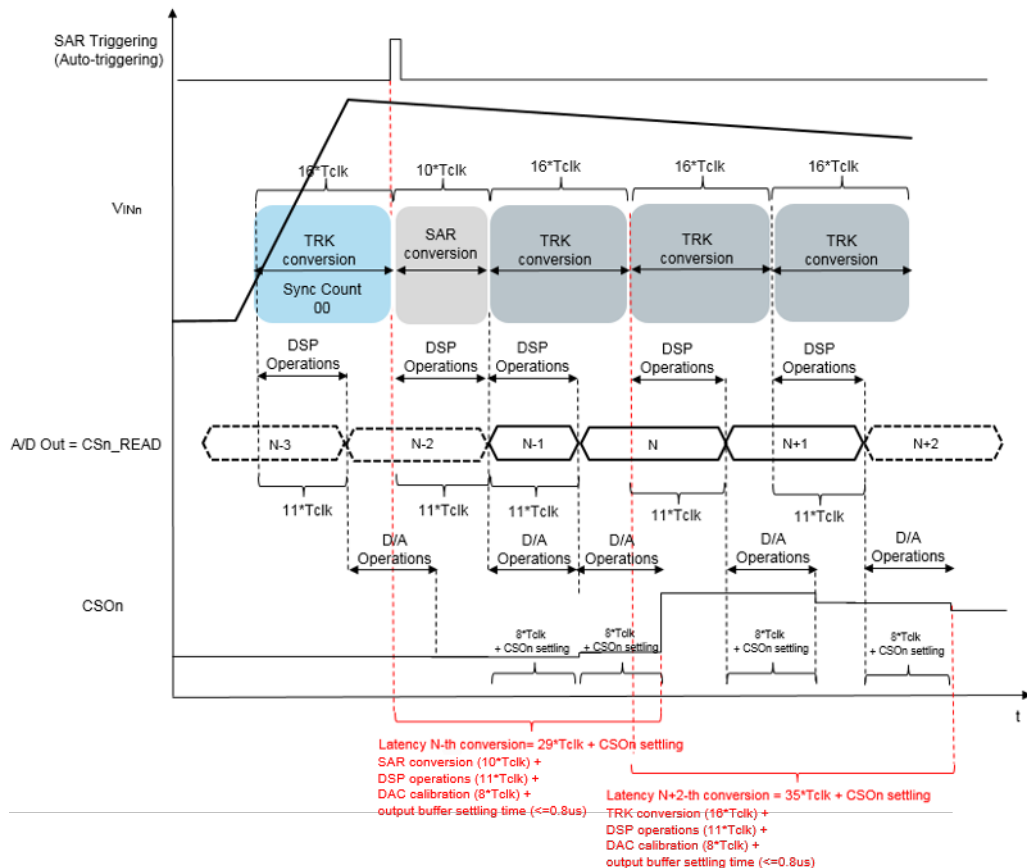


Figure 56. Free running sampling timing diagram - non-zero current + command edge-triggering

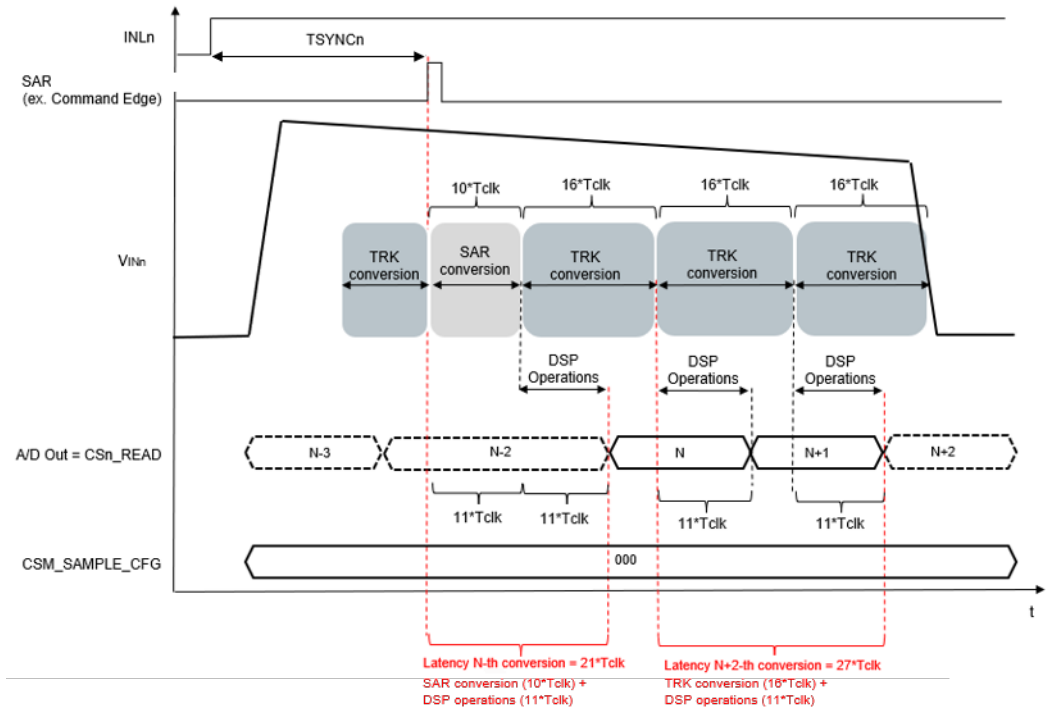


Figure 57. Free running sampling timing diagram - zero current (offset) + auto-triggering

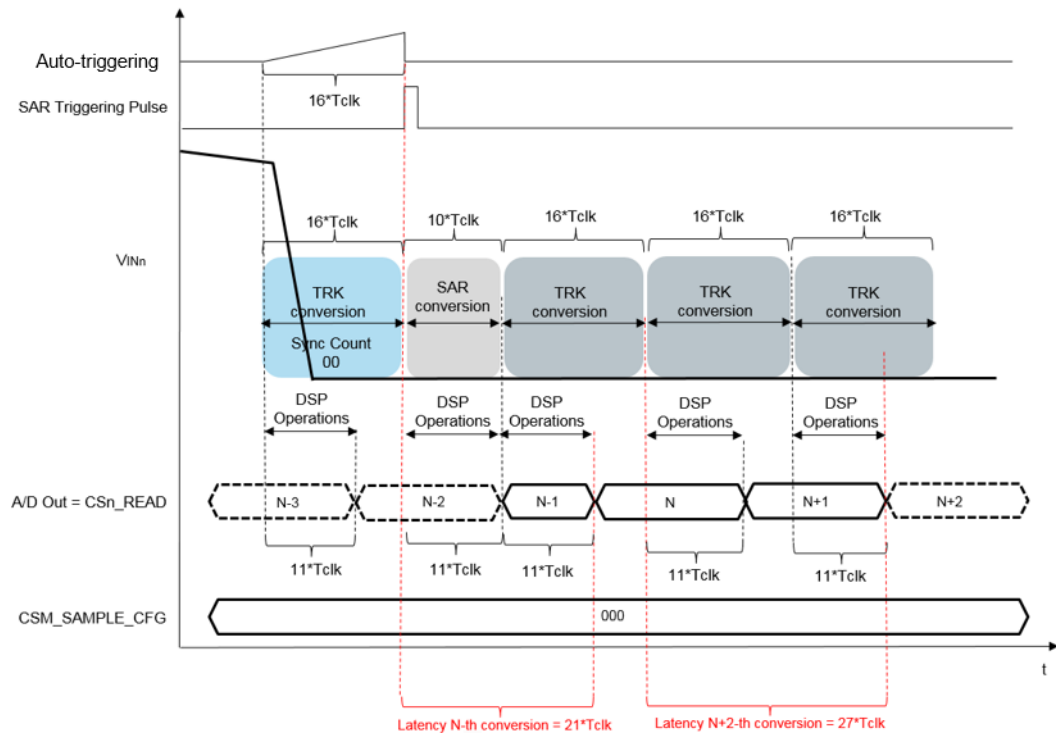
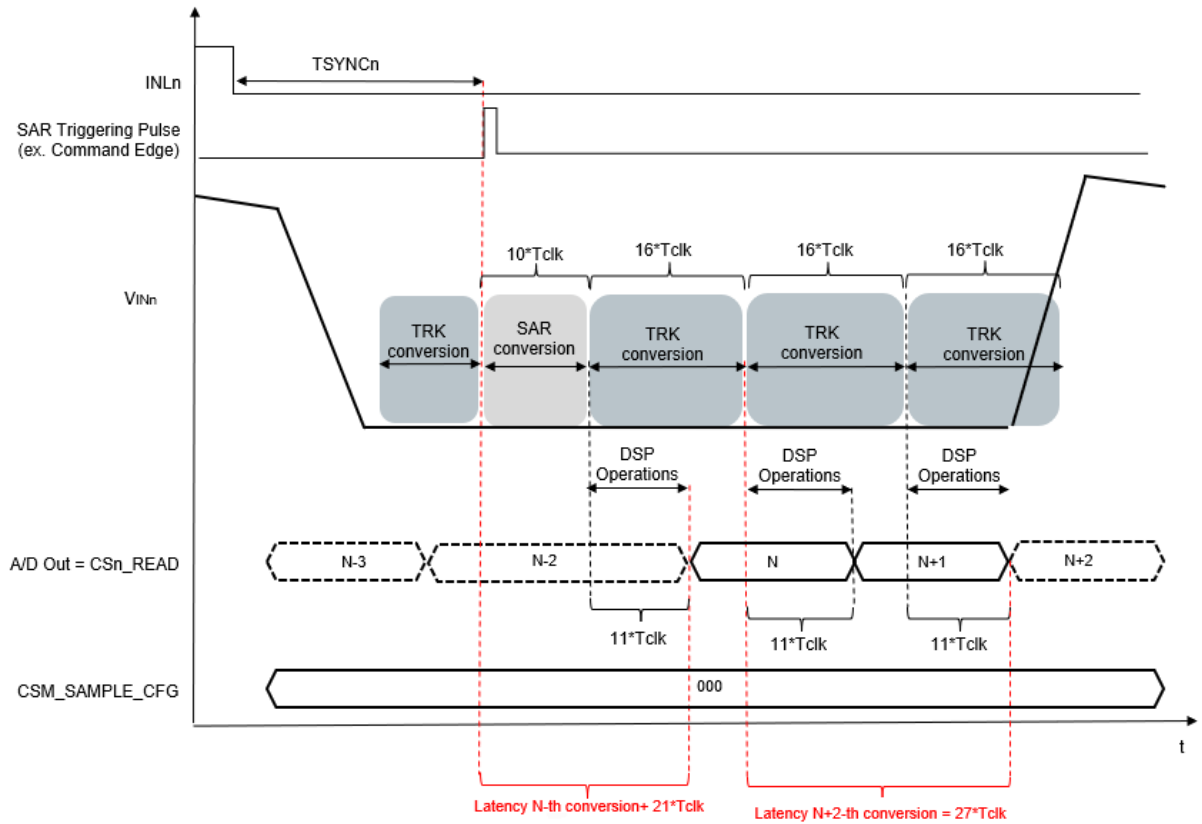


Figure 58. Free running sampling timing diagram - zero current (offset) + command edge-triggering


5.13.2.2.2 Track and hold

In Track and Hold mode the CMn_READ SPI registers and the $CSON$ voltage track the A/D output starting from the SAR Triggering Pulse and hold the n-th conversion specified in the CSM_SAMPLE_CFG register.

As a consequence, this kind of sampling method is useful along with a command edge triggering. It turns out that if no Command Edge is present (ex. $INLn$ rising/falling) the CMn_READ SPI registers and the $CSON$ voltage display the last written value.

All A/D output words [phase 1, 2, 3] are tracked and sampled at the same time, synchronously.

The n-th data conversion after the SAR triggering to be hold can be configured by means of the following bits:

Table 74. Current monitors sampling configuration bits

| $CSMn_SAMPLE_CFG3$ | $CSMn_SAMPLE_CFG1$ | $CSMn_SAMPLE_CFG0$ | Description |
|----------------------|----------------------|----------------------|---|
| 0 | 0 | 0 | Free running – No T&H (Default) |
| 0 | 0 | 1 | T&H 1st data conversion from triggering |
| 0 | 1 | 0 | T&H 2nd data conversion from triggering |
| 0 | 1 | 1 | T&H 3rd data conversion from triggering |
| 1 | 0 | 0 | T&H 4th data conversion from triggering |
| 1 | 0 | 1 | T&H 5th data conversion from triggering |
| 1 | 1 | 0 | T&H 6th data conversion from triggering |
| 1 | 1 | 1 | T&H 7th data conversion from triggering |

Note: CSM_SAMPLE_CFG and CSM_SSPV_PH_CFG configurations can be separately configured with no internal gating.

This way all the following configurations are allowed to take place in principle:

1. Auto-Triggering only (NO Command Edge) + Free Running
2. Auto-Triggering only (NO Command Edge) + T&H
3. Command Edge Triggering + Free Running
4. Command Edge Triggering + T&H

In scenario 2) CMn_READ and CSOn value won't be updated and the value displayed reflects the last valid value or the default non valid value as ever been captured.

This possibility in case not specifically needed by application shall be avoided by the application SW itself.

Note: In the following timing diagrams, N-th A/D Out value corresponds to the SAR conversion value.

Figure 59. T&H sampling timing diagram - non-zero current + auto-triggering

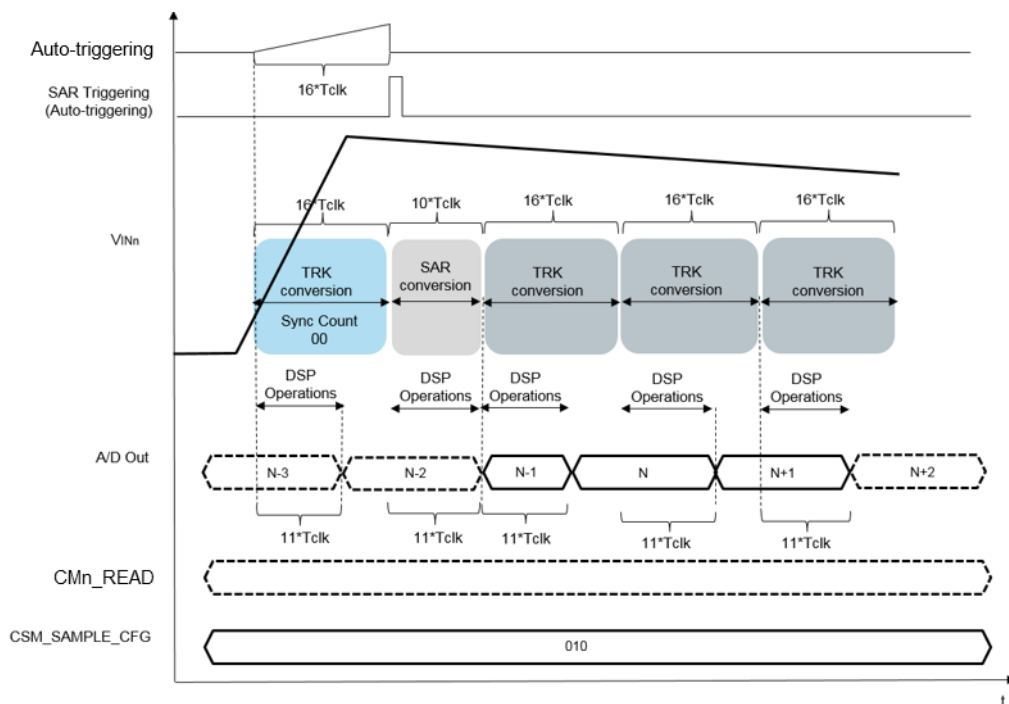


Figure 60. T&H sampling timing diagram - zero current (offset) + auto-triggering

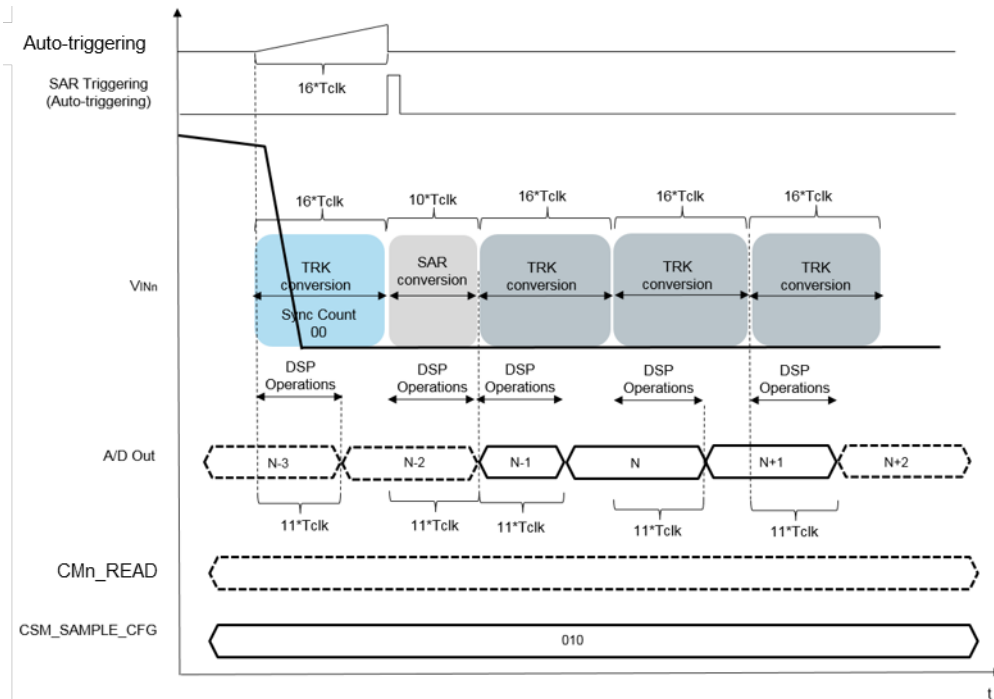


Figure 61. T&H sampling timing diagram - non-zero current + command edge-triggering

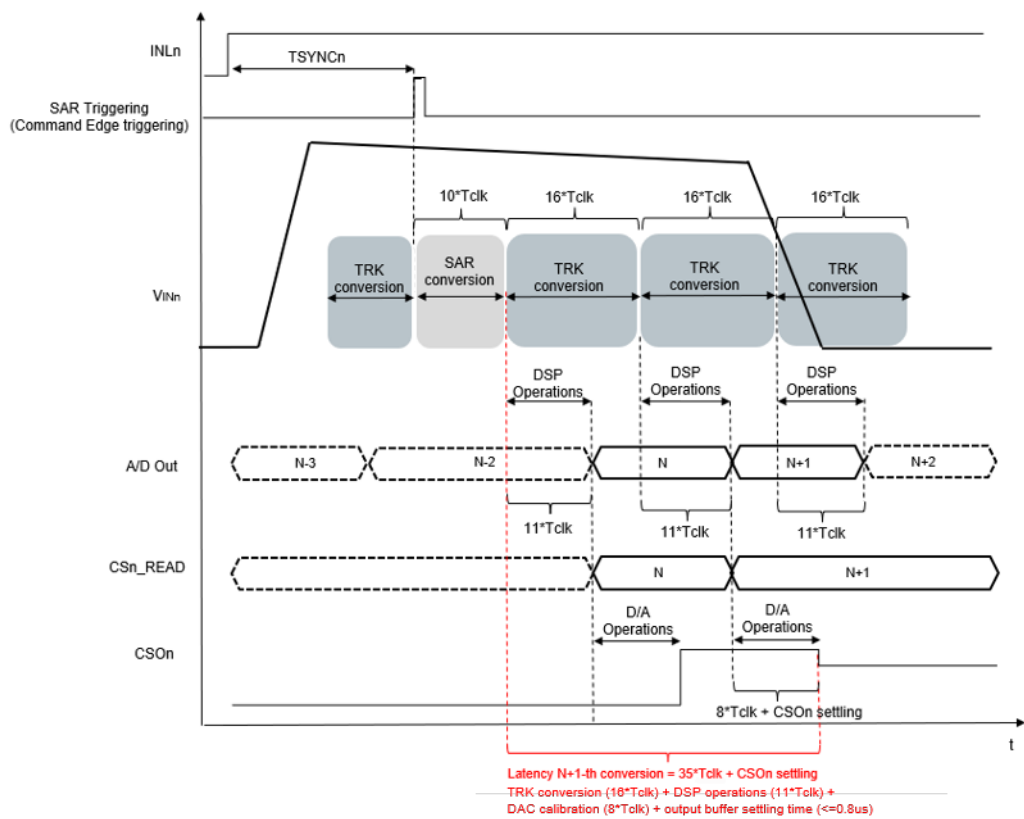
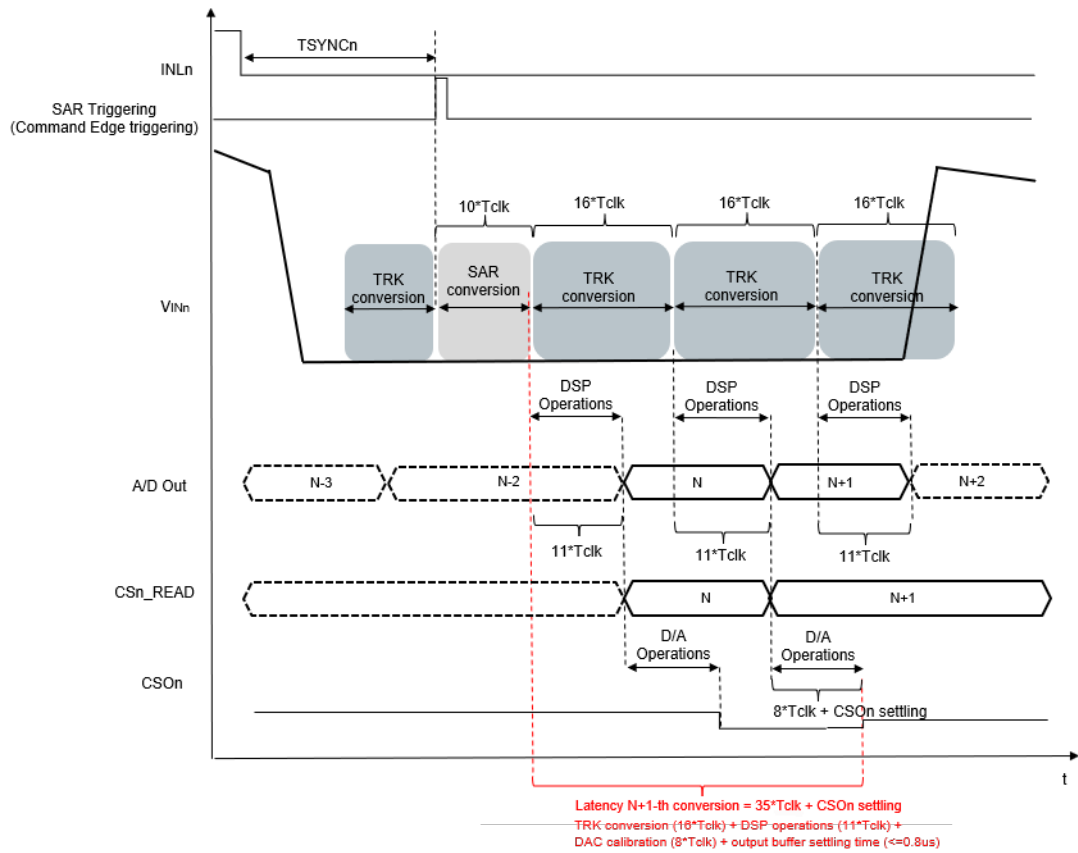


Figure 62. T&H sampling timing diagram - zero current (offset) + command edge-triggering



5.13.2.3 Digital format current information

The current measurement is available in digital format right after the T&H block and can be read through a dedicated SPI signal (CMn_READ in CHn_STATUS2 register).

Current Measurement reconstruction formula

Internal conversion data read-out via CMn_READ registers:

$$I_{LOAD}^{R_{shunt}} = \Delta_{CM_in_LSB_15bit} \times D_{CMn_READ} \quad (17)$$

Where: D_{CMn_READ} is the digital word stored in CMn_READ and $\Delta_{CM_in_LSB_15bit}$ is the input ADC quantization step re-defined as follows:

$$\Delta_{CM_in_LSB_15bit} = \frac{CM \text{ input ADC LSB}}{2^4} \quad (18)$$

Table 75. Digital format current information LSB

| VCM_MAX | $\Delta_{CM_in_LSB_15bit}$ |
|---------|-------------------------------|
| ±7 mV | 0.628 μV |
| ±18 mV | 1.256 μV |
| ±36 mV | 2.517 μV |
| ±90 mV | 6.293 μV |
| ±160 mV | 11.329 μV |
| ±300 mV | 20.141 μV |

D_{CMn_READ} coding in two's complement.

Example:

$D_{CMn_READ} = 101100011110101$ (binary) $\rightarrow -9995$ (decimal)

$CS_INRANGE_CFG = 011$ (CM input ADC range +/-90 mV)

$I_{LOAD} R_{SHUNT} = -9995 * 6.293 \mu V = -62.898$ mV

Latency associated to digital format current information update (SPI) in auto-triggering mode can be retrieved in the following table.

Table 76. Current monitors A/D auto-triggering latency

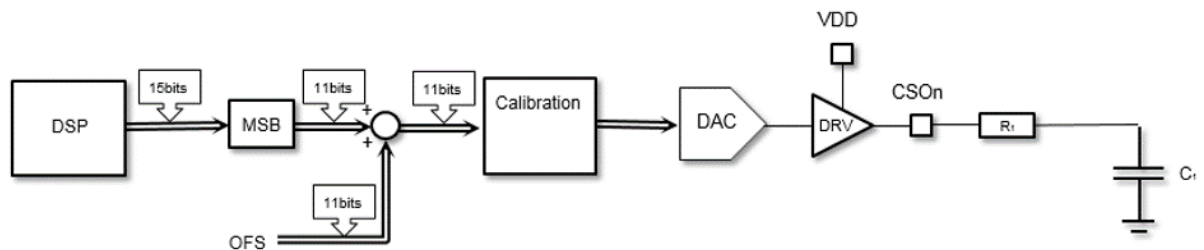
| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|---------------|------------------|-----|-----|-----|------|--|
| CM_in_latency | CM Input latency | 31 | - | 37 | Tclk | Application information ⁽¹⁾ |
| | | 39 | | 45 | | |
| | | 47 | | 53 | | |
| | | 55 | | 61 | | |

1. $CSMn_SYNC_COUNT_CFG1$ (16/24/32/40 Tclk) + SAR (10 Tclk) + DSP (5 to 11 Tclk).

5.13.3 D/A conversion

After DSP operations digital conversion is forwarded to an analog output channel which provides the processed current information to the analog domain.

Figure 63. D/A conversion simplified block diagram



In order to better fit dynamic range and maximize the output S/N with respect to the externally connected microcontroller A/D, two successive digital operations are performed.

First is the truncation from signed 15 bits to signed 11 bits.

The current measurement coded in a signed 15-bit word is firstly converted to a signed 11-bit word by taking the 11MSB.

Second is Shift and Rescale (sign removal and offset adding).

From the resulting processed word the 11MSB without sign are taken and a fixed selectable offset OFS is added (shift).

The shift amount for the specific channel can be configured by means of dedicated SPI bits in order to adjust the current monitor output range to the μC ADC input range as follows:

Table 77. Current monitors output offset configuration bits

| CSMn_OFS1 | CSMn_OFS0 | Description |
|-----------|-----------|-----------------------|
| 0 | 0 | 0LSB DAC |
| 0 | 1 | 90LSB DAC |
| 1 | 0 | 1024LSB DAC |
| 1 | 1 | 1024LSB DAC (Default) |

- Note:
- 00 and 01 configurations are intended to be used when the current to be read is only positive (DC-LINK configuration)
 - 10 and 11 configurations should be used when the current to be read is either positive or negative (Single Leg)

The 11-bits unsigned word feeds a cascaded of a 10-bit resistive string DAC and a Voltage Buffer that converts the digital code into the corresponding analog signal referred to the full scale voltage.

DRV gain can be configured by means of dedicated SPI bits in order to adjust the current monitor output range to the μC ADC input range as follows:

Table 78. Current monitors output gain configuration

| CSM_OUT_RANGE_CFG | Description |
|-------------------|------------------------|
| 0 | VCSO = 3.3 V (Default) |
| 1 | VCSO = 5 V |

To ensure output signal stability, a RC low-pass filter is recommended on CSOn pins; refer to Section 6 Application circuit and the related Section 6.3 Bill of materials for details.

Table 79. Current monitor's analog output characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|--|---------------------------------|--|-------------|----------------|-------------|---------------|-------------------------|
| Current Monitor Analog Output | | | | | | | |
| CM_out_range_max | CSOn output range max | Iload = 250 μA | - | - | 0.11 | V | - |
| CM_out_range_min | CSOn output range min | Iload = -250 μA CSMn_OUT_RANGE_CFG = 1 CSMn_OUT_RANGE_CFG = 0 | 4.8 3.28 | - | VDD 3.32 | V | - |
| Current Monitor Analog Output Resolution | | | | | | | |
| CM_out_dac_res | CM DAC resolution | - | - | 11 | - | bits | Design Information |
| CM_out_dac_lsb | CM DAC LSB | - | - | 2.441 1.611 | - | mV | Design Information |
| Current Monitor Analog Output Dynamic Characteristics | | | | | | | |
| CM_out_dac_data_rate | CM DAC sample rate | - | - | 1.25 | - | MHz | Application information |
| CM_out_dac_pos_st1 | CM DAC positive settling time 1 | 23 to 1023 LSB transition RLP = 1 k Ω CLP = 270 pF | - | - | 0.8 | μs | - |
| CM_out_dac_pos_st2 | CM DAC positive settling time 2 | 1023 to 2048 LSB Transition RLP = 1 k Ω CLP = 270 pF | - | - | 0.8 | μs | - |
| CM_out_dac_neg_st1 | CM DAC negative settling time 1 | 2048 to 1023 LSB transition RLP = 1 k Ω CLP = 270 pF | - | - | 0.8 | μs | - |
| CM_out_dac_neg_st2 | CM DAC negative settling time 2 | 1023 to 23 LSB Transition RLP = 1 k Ω CLP = 270 pF | - | - | 0.8 | μs | - |

5.13.3.1 Analog format current information

Current Measurement reconstruction formula at CSO_n pin is the following:

$$I_{LOAD}R_{shunt} = \left(\frac{V_{CSO_n}}{\Delta_{CM_out_LSB}} - OFS \right) \Delta_{CM_in_LSB} \quad (19)$$

Where: V_{CSO_n} is the voltage at pin CSO_n, OFS is the selected shift value, R_{SHUNT} is the shunt resistance value, $\Delta_{CM_in_LSB}$ is the input ADC quantization step, defined in Table 75, and $\Delta_{CM_out_LSB}$ is D/A quantization step, available in Table 79 (parameter name: T CM_out_dac_lsb).

Example:

- $V_{CSO_n} = 1\text{ V}$
- $CSMn_OFS = 1024\text{LSB}$
- $CSM_OUT_RANGE_CFG = 0$
- $CSM_OUT_RANGE_CFG = 0$
- $CS_INRANGE_CFG = 011$ (CM input ADC range +/-90 mV)
- $I_{LOAD} \cdot R_{SHUNT} = (1/1.611\text{ mV} - 1024) \cdot 100.7\text{ }\mu\text{V} = -40.609\text{ mV}$

Latency associated to analog format current information update in auto-triggering mode can be retrieved in the following table.

Table 80. Current monitors A/D - D/A auto-triggering latency

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|------------|------------|-----|-----|-----|------|--|
| CM_latency | CM latency | 33 | - | 45 | Tclk | Application information ⁽¹⁾ |
| | | 41 | | | | |
| | | 49 | | | | |
| | | 57 | | | | |

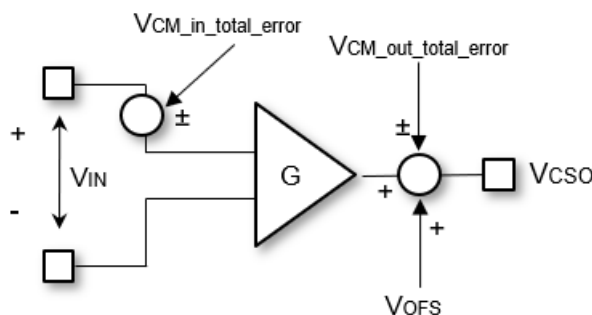
1. $CSMn_SYNC_COUNT_CFG1$ (16/24/32/40 Tclk) + SAR (10 Tclk) + DSP (7 to 19 Tclk)

Note: Please note that values indicated in Table 80 refers to ADC & DSP section only. CSO buffer settling time should be added to retrieve the full chain settling time at CSOn.

5.13.4 Current monitor A/D - D/A chain

When Current Measurement is evaluated at CSOn pins, the full A/D-D/A chain is exploited and the structure can be assimilated to a voltage amplifying stage, which can be represented as in the following picture, and the corresponding Input/Output transfer function:

Figure 64. A/D-D/A chain accuracy block diagram



$$V_{CSO} = V_{IN}G \pm V_{CM_in_total_error}G + V_{OFS} \pm V_{CM_out_total_error} \quad (20)$$

CSM chain gain values are summarized in the following table.

Table 81. CSM gain

| CSM input range FULL SCALE | GAIN output range: 0-5V | GAIN output range: 0-3.3V |
|-------------------------------|----------------------------|------------------------------|
| ±7 mV | 242.8856 | 160.2985 |
| ±18 mV | 121.3824 | 80.1094 |
| ±36 mV | 60.60079 | 39.99503 |
| ±90 mV | 24.24032 | 15.99801 |
| ±160 mV | 13.4661 | 8.887295 |
| ±300 mV | 7.574629 | 4.999069 |

Gain is calculated as the ratio between CSO output range (either 3.3 V or 5 V) and the input Full Scale range. Values in Table 81 are valid only in case OFS = 1024 lsb. OFS = 0 lsb and OFS = 90 lsb have to be used in case of DC-link configuration; in this case input voltage can be only positive and gain values of Table 81 must be multiplied by 2.

Total error:

The CM A/D – D/A Chain total error contribution is given by:

Table 82. Current monitor A/D - D/A total error

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|---------------------------------|-----------------|----------------------------------|-----|----------------------------|------|---|
| Current Monitor Accuracy | | | | | | |
| CM_gain_err | CM Gain Error | -2 | - | 2 | % | (1) All input ranges |
| CM_offset_err | CM Offset Error | -2 -2 -2 -2 -3 -6 | - | 2 2 2 2 3 6 | mV | (1) Each value refers to the corresponding CM differential voltage input range |

1. Ex.

- $V_{in} = I_{Sn+} - I_{Sn-} = -70 \text{ mV}$
- $CM_{in_range_diff} = \pm 90 \text{ mV}$
- $CM_{out_range} = 3.3 \text{ V}$
- $CSM_OFS = 1024$
- $VOFS = 1024 * 1.611 \text{ mV} = 1.65 \text{ V}$
- $G = 15.99801$
- $V_{CM_total_error} = \pm 2 \text{ mV} \pm (2\% * 70 \text{ mV}) = \pm 2 \text{ mV} \pm 1.4 \text{ mV} = \pm 3.4 \text{ mV}$
- $V_{out} (ideal) = 1.65 \text{ V} - 70 \text{ mV} * 15.99801 = 530 \text{ mV}$
- $V_{out} (minimum) = V_{out} (ideal) - (3.40 \text{ mV} * 15.99801) = 475.60 \text{ mV}$
- $V_{out} (maximum) = V_{out} (ideal) + (3.40 \text{ mV} * 15.99801) = 584.39 \text{ mV}$

Noise Performance
Table 83. Current monitor chain noise performance

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|----------------------|------------------------------------|-----|-------------------|-----|----------|--|
| CM_noise_performance | CM integrated output noise voltage | - | 9.7 4.5 2.6 | - | mV (RMS) | Application information ⁽¹⁾ |

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|--------|-----------|-----|-----|-----|------|-------|
| | | | 1.4 | | | |
| | | | 1.2 | | | |
| | | | 1.2 | | | |

1. Measurement setup: $T_j = 25^\circ\text{C}$ $I_{S+n} = I_{S-n}$, $R_{LP} = 1\text{ k}\Omega$; $CLP = 270\text{ pF}$; $VOFS = 2.5\text{ V}$. Measured after low pass filter.

5.14 Off State Diagnosis (OFD)

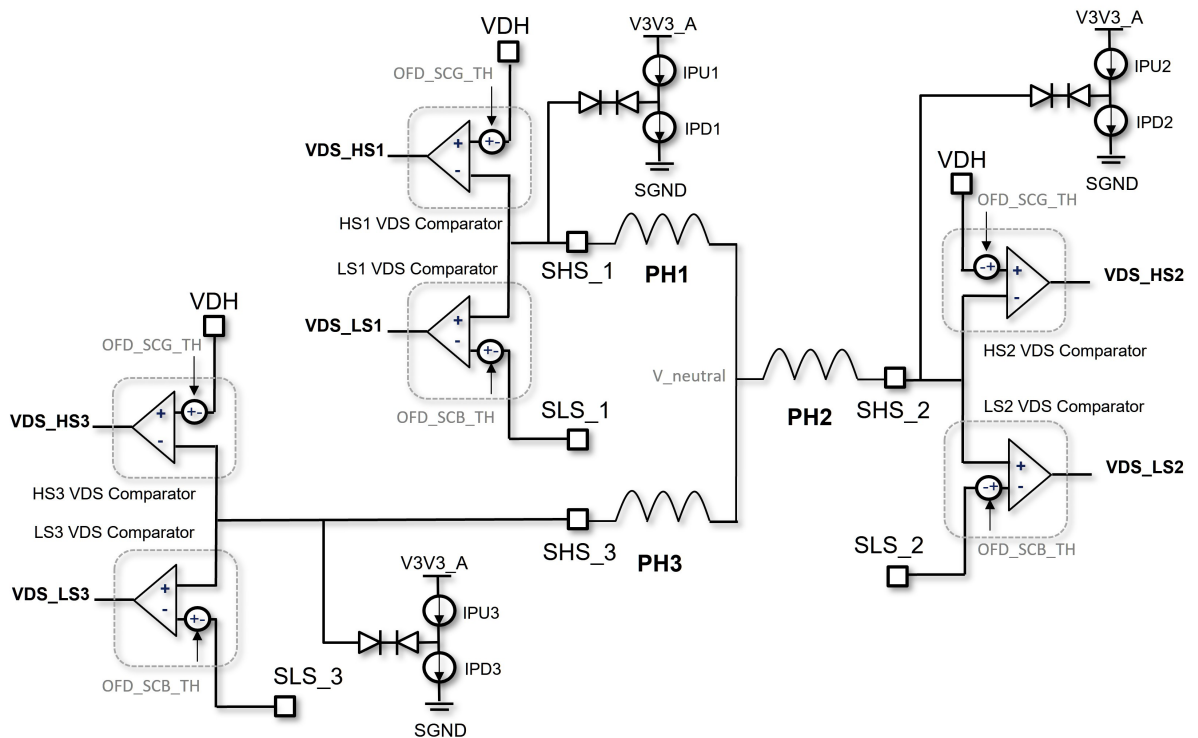
L9908 implements a monitoring unit to detect failure condition affecting the load during the half bridges tristate condition ($V_{GHn} - V_{SHn} = 0\text{ V}$ and $V_{GLn} - V_{SLn} = 0\text{ V}$).

Load Failure Mode Detection:

- Open load at one of the SHS_n terminals;
- Short-circuit to ground at one or multiple SHS_n terminals;
- Short-circuit to battery at one or multiple SHS_n terminals.

Each error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

Figure 65. OFF State Diagnosis simplified block diagram



The off state diagnosis unit is composed by a multiple force stage and a multiple monitor stage.

The force stage has the purpose of driving the state of each SHS_n terminal into a predetermined voltage condition, any deviation from this condition is then detected by the monitor stage and interpreted as a faulty condition.

Force stage is composed by a protected controlled pull-up/pull-down current source for each phase respectively towards V3V3_A and SGND.

Monitor stage is composed by the LS VDS and the HS VDS comparators which compare the n-th phase voltage with respectively OFD_SCB_TH and OFD_SCG_TH fixed thresholds.

The n-th phase OFD unit can be enabled/disabled by dedicated SPI bits as follows:

Table 84. OFD enable bits

| OFDn_EN1 | OFDn_EN0 | Description |
|----------|----------|---|
| 0 | 0 | Off State Diagnosis disabled (Default) |
| 0 | 1 | Pull-up current enabled, Pull-down current disabled |
| 1 | 0 | Pull-down current enabled, Pull-up current disabled |
| 1 | 1 | Off State Diagnosis disabled |

The OFD is automatically enabled when OFD_EN bit is set and INLn/INHn = 0 [n = 1,2,3]. Once enabled, the OFD circuit is stopped as soon as a 0 → 1 transition of INHn/INLn is detected.

Depending on the external load condition, the OFD configuration and detection shall follow the next table:

Table 85. OFD fault detection table

| Condition | OFD_EN[1:0] | Error Flag | Description |
|-----------------------------------|-------------------------------------|---|---|
| 3-Phase OFD [Three phase load] | OFD1 = 10 OFD2 = 01 OFD3 = 10 | HS2_OFD = X ⁽¹⁾ LS1_OFD = 0 LS2_OFD = 0 LS3_OFD = 0 | Short to ground on one or multiple motor phase |
| | | HS2_OFD = 0 LS1_OFD = 1 LS2_OFD = 1 LS3_OFD = 1 | Short to battery on one or multiple motor phase |
| | | HS2_OFD = X ⁽¹⁾ LS1_OFD = 0 LS2_OFD = 1 LS3_OFD = 1 | Open connection on motor phase 1 (SHS_1) |
| | | HS2_OFD = X ⁽¹⁾ LS1_OFD = 0 LS2_OFD = 1 LS3_OFD = 0 | Open connection on motor phase 2 (SHS_2) |
| | | HS2_OFD = X ⁽¹⁾ LS1_OFD = 1 LS2_OFD = 1 LS3_OFD = 0 | Open connection on motor phase 3 (SHS_3) |
| | | HS2_OFD = 1 LS1_OFD = 1 LS2_OFD = 1 LS3_OFD = 1 | No Fault |

1. X = don't care.

Note:

- The OFD circuit can detect a SCB or SCG condition affecting the three phases in general, due to the low DC resistance of the motor it cannot identify at which phase the failure is present.
- Correct functionality of OFD is based on a current mismatch between pull-up and pull-down current. In case of additional external pull-up/down contribution the following inequation must be satisfied:

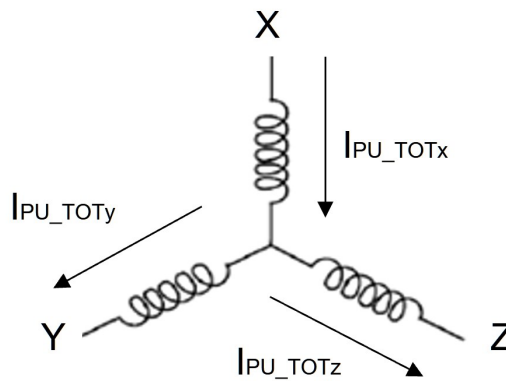
$$I_{PU_TOTx} > I_{PD_TOT_PHy} + I_{PD_TOT_PHz} \quad (21)$$

Where:

I_{pu_totx} is the equivalent pull-up current injected into the phase x (assuming phase x being configured as OFD_EN = 01)

I_{pd_toty} and I_{pd_totz} are the equivalent pull-down currents injected respectively into the phase y and z (assuming phase y and z being configured as OFD_EN = 10)

Figure 66. OFD currents in motor phases



Blanking and Filtering

To avoid false error detections during the diagnosis settling time and to increase noise robustness, the OSD implements a two-step digital filtering: an Up/Down counter of length equal to T_{ofd_flt} on the comparator's output filters out the high frequency noise while a blanking time masks the filters output by a programmable delay time T_{ofd_blank} .

Figure 67. OFD enabling and masking time start - IPU example

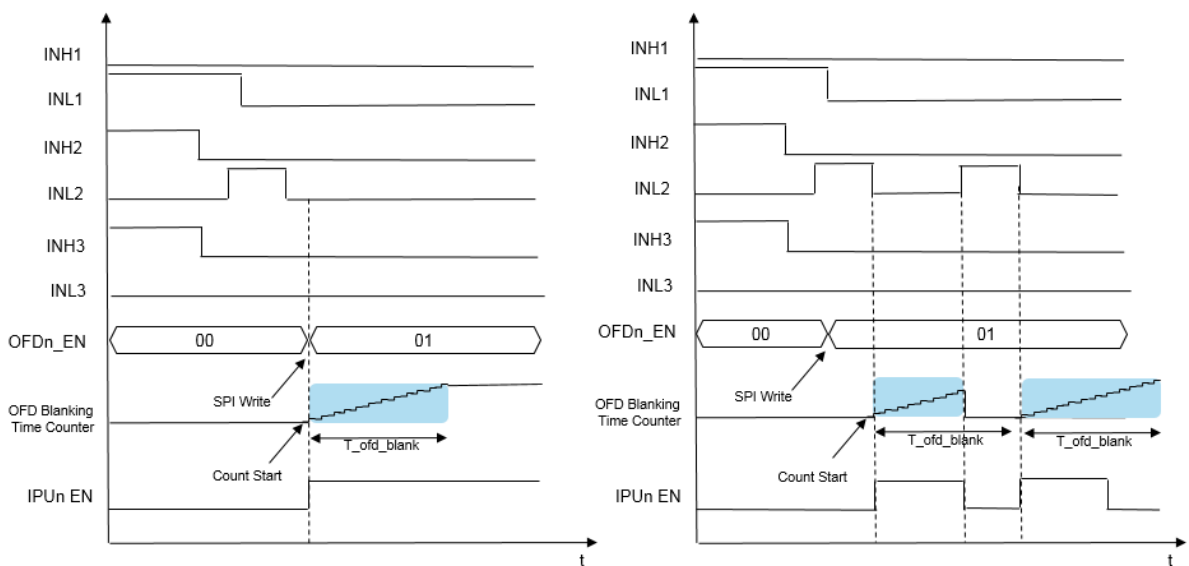


Figure 68. OFD Masking and deglitch filtering - LSn_OFD Example

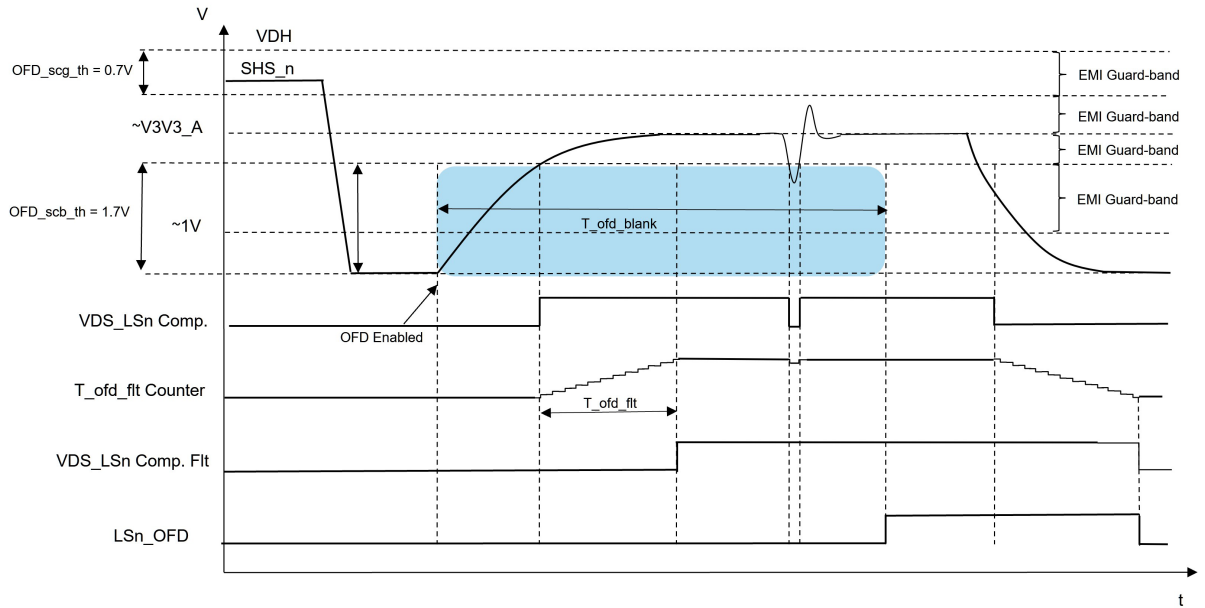
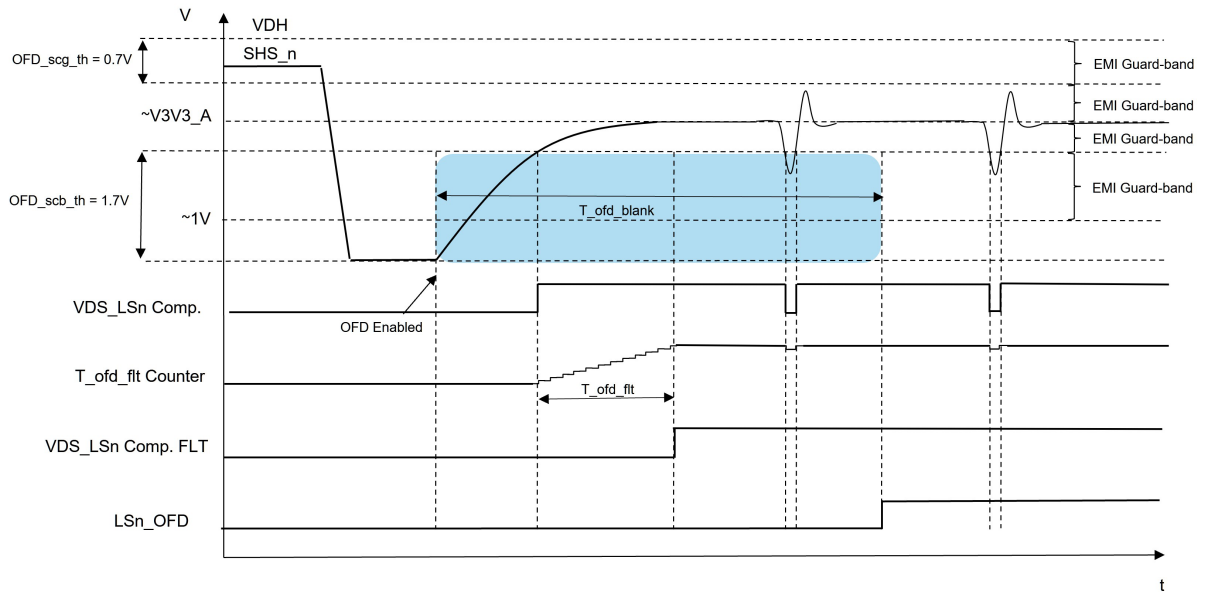


Figure 69. OFD Masking and deglitch filtering - LSn_OFD Example with multiple glitches



The T_{ofd_blank} can be configured by dedicated SPI bits as follows:

Table 86. OFD blanking time configuration bits

| OFD_BLANK1 | OFD_BLANK0 | Description |
|------------|------------|---|
| 0 | 0 | $T_{ofd_blank} = 10\text{ ms}$ |
| 0 | 1 | $T_{ofd_blank} = 25\text{ ms}$ |
| 1 | 0 | $T_{ofd_blank} = 50\text{ ms}$ (Default) |
| 1 | 1 | $T_{ofd_blank} = 100\text{ ms}$ |

Note: The application software must configure T_{ofd_blank} to ensure that the motor is not running and the phases are not energized. For some applications the maximum available T_{ofd_blank} configuration could be too short, the application SW then shall enable the OFD circuit with an additional delay after disabling the bridge drivers.

Table 87. OFD electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-----------------|--|---------------------------------|------|-----------|-----|------|--------------------------------|
| OFD_rvef | OFD phase reference voltage in with no fault | OFDn_EN = 01 OFDi,j_EN = 10 | 2 | 2.7 | 3.1 | V | - |
| OFD_vpd_ol | OFD open load voltage in pd mode | OFDn_EN = 10 SHS_n = No Load | - | - | 0.9 | V | - |
| OFD_ipu | OFD pull up current capability | OFDn_EN = 01 | 2.25 | - | 3.3 | mA | - |
| OFD_ipd | OFD pull down current capability | OFDn_EN = 10 | 0.6 | 0.75 | 0.9 | mA | It includes ILEAK contribution |
| OFD_scb_th | OFD_SCB detection threshold | - | - | SLS_n+1.7 | - | V | Not subject to production test |
| OFD_scg_th | OFD_SCG detection threshold | - | - | VDH-0.7 | - | V | Not subject to production test |
| T_ofdflt | OFD Fault detection filter time | - | 85 | 100 | 115 | µs | Digital filter |
| T_ofd_blank_acc | OFD Blanking Time accuracy | CLK_SSM_EN = 0 | -15 | - | 15 | % | - |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.15 On State Diagnosis (OND)

L9908 implements a monitoring unit to detect failure condition affecting the load during the half bridges ON state by monitoring the voltage drain-source drop across the Ext. FET.

The ON state diagnosis unit is composed by a dedicated VDS comparator for each HS and LS Ext. FET that constantly monitors the voltage drop during FET's ON state.

ON State Load Failure Mode Detection:

- Short-circuit to ground at one SHS_n terminals → HS_n_STG flag is set to 1
- Short-circuit to battery at one SHS_n terminals → LS_n_STB flag is set to 1

The ON state diagnosis can be disabled by a dedicated SPI bit as follows:

Table 88. OND enable bits

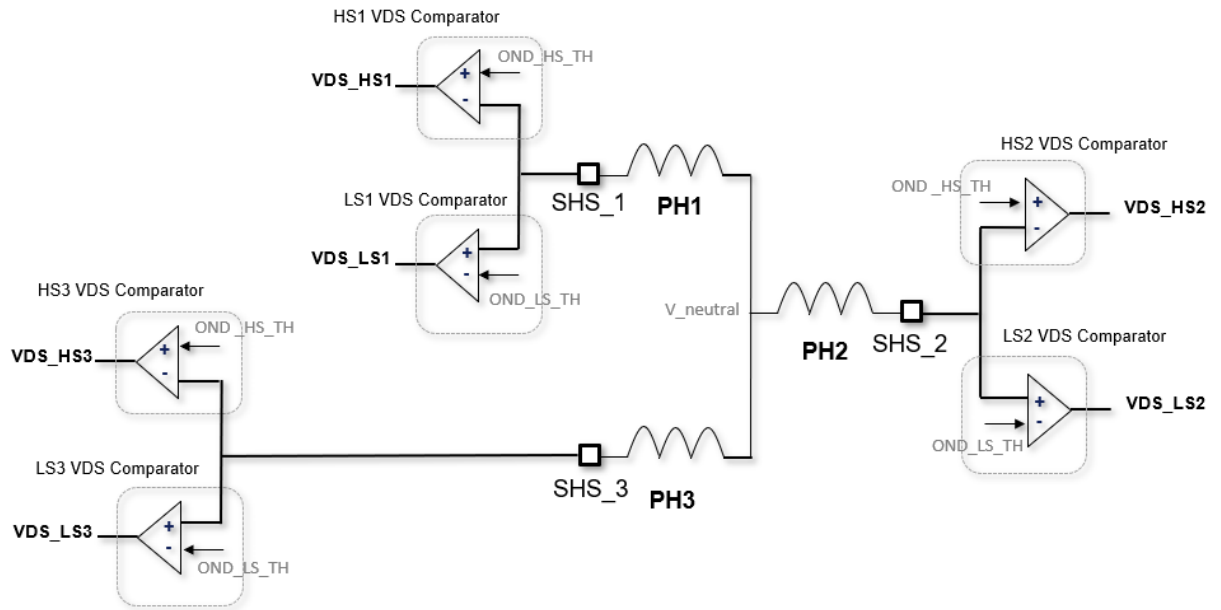
| ONDn_DIS | Description |
|----------|--|
| 0 | ON State diagnosis enabled on n-th HS and LS (Default) |
| 1 | ON State diagnosis disabled on n-th HS and LS |

When the OND monitoring is disabled while having the fault flag set, the flag will not be cleared until SPI read.

If $VDH-SHS_n \geq V_{ond_hs_th}$ occurs for an interval longer than T_{ond_flt} filter time, the HS_n_STG flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

If $SHS_n-SLS_n \geq V_{ond_ls_th}$ occurs for an interval longer than T_{ond_flt} filter time, the LS_n_STB flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

Figure 70. ON State Diagnosis simplified block diagram



Threshold configuration

The reference thresholds for the OND unit V_{ond_th} are generated through two 6-bit Current Steering DAC, one for HS and one for LS FETs.

Diagnosis thresholds can be configured through dedicated SPI bits as follows:

$$V_{OND_TH_HS} = \Delta_{LSB} \times VDS_HS_TH[5:0] \tag{22}$$

$$V_{OND_TH_LS} = \Delta_{LSB} \times VDS_LS_TH[5:0] \tag{23}$$

Where: Δ_{LSB} is the minimum voltage step and $VDS_HS_TH/VDS_LS_TH [5:0]$ in the register GEN_CFG2 there are the dedicated SPI configuration bits.

Default value is $VDS_HS_TH = VDS_LS_TH = 0x00$. The default code equals the first non-zero code 0x01 which corresponds to a $V_{ond_hs_th} = 1LSB = 27\text{ mV}$

Blanking and Filtering

The OND fault detection is based on the correlation between V_{ds} voltage with the current conducted through ohm's law; it turns out that a correct detection can be performed only when Ext. FET is in full R_{dsON} mode.

In order to prevent spurious short circuit detections due to an internal circuit voltage compression, the n-th OND monitor circuit is masked by the VDH UV diagnosis assertion. During a VDH UV condition OND fault detection is always prevented.

In order to prevent spurious short circuit detections due to a non-linear operation region, the n-th OND monitor circuit is masked according to the internal n-th gate drive signal:

- masking is removed after a programmable blanking time T_{ond_blank} from gate drive signal rising edge;
- masking is re-activated soon after gate drive signal falling edge.

The T_{ond_blank} can be configured by dedicated SPI bits as follows:

Table 89. OND blanking time configuration bits

| OND_BLANK2 | OND_BLANK1 | OND_BLANK0 | Description |
|------------|------------|------------|---|
| 0 | 0 | 0 | $T_{ond_blank} = 0.7\ \mu\text{s}$ |
| 0 | 0 | 1 | $T_{ond_blank} = 1\ \mu\text{s}$ |
| 0 | 1 | 0 | $T_{ond_blank} = 1.5\ \mu\text{s}$ (Default) |
| 0 | 1 | 1 | $T_{ond_blank} = 2\ \mu\text{s}$ |
| 1 | 0 | 0 | $T_{ond_blank} = 2.5\ \mu\text{s}$ |

| OND_BLANK2 | OND_BLANK1 | OND_BLANK0 | Description |
|------------|------------|------------|------------------------------|
| 1 | 0 | 1 | $T_{ond_blank} = 3.5 \mu s$ |
| 1 | 1 | 0 | $T_{ond_blank} = 5 \mu s$ |
| 1 | 1 | 1 | $T_{ond_blank} = 8 \mu s$ |

Note: The PWM ON time must be longer than T_{ond_blank} , else way the short circuit condition cannot be detected. In order to remove glitches and increase the detection capability of the system also at low Duty Cycles a cascaded filtering is introduced. Filtering action is developed by a digital up/down counter, incrementing the count at fault present and decrementing it at fault absent cumulating detections all over PWM cycles. The T_{ond_flt} can be configured by dedicated SPI bits as follows:

Table 90. OND filtering time configuration bits

| OND_FLT1 | OND_FLT0 | Description |
|----------|----------|------------------------------------|
| 0 | 0 | $T_{ond_flt} = 1 \mu s$ |
| 0 | 1 | $T_{ond_flt} = 2.5 \mu s$ |
| 1 | 0 | $T_{ond_flt} = 4 \mu s$ (Default) |
| 1 | 1 | $T_{ond_flt} = 8 \mu s$ |

Figure 71. OND blanking and filtering (VDS_LSn example), multiple fault

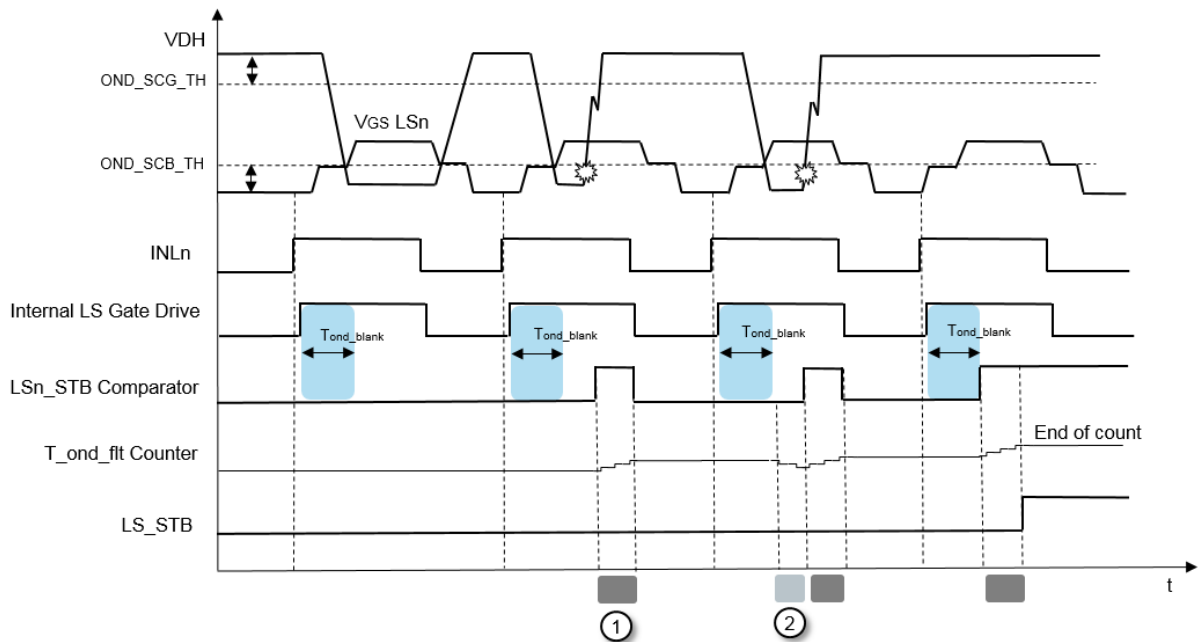
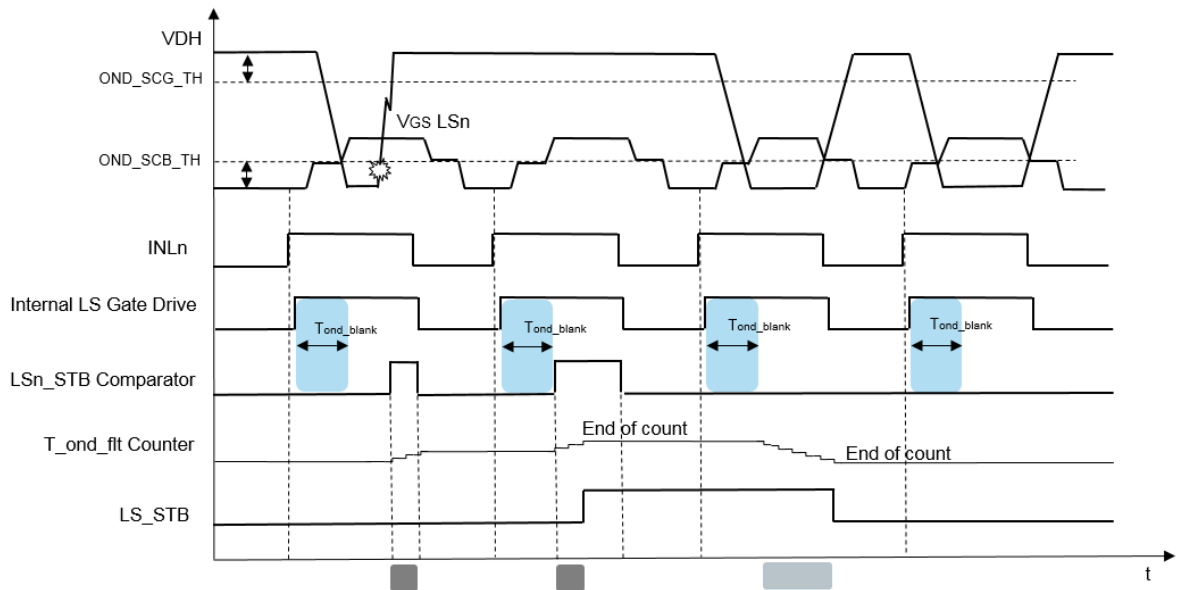


Figure 72. OND blanking and filtering (VDS_LSn example), single fault



Where:

1. LSn gate drive rising edge → T_ond_blank is elapsed comparator output masking is released; VSLn-VSHn > VDS_ond_th → LSn_STB comparator output is set to 1; T_ond_ft counter +1; LSn gate drive falling edge → comparator output masking is enabled → T_ond_ft counter freeze.
2. LSn gate drive rising edge → T_ond_blank is elapsed comparator output masking is released; VSLn-VSHn < VDS_ond_th → LSn_STB comparator output is set to 0; T_ond_ft counter -1; LSn gate drive falling edge → comparator output masking is enabled → T_ond_ft counter freeze.

The correct operation OND stage is safety relevant and then a self-check procedure is implemented.

Table 91. OND electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-------------|--------------------------------------|--|------|-----|-----|------|--------------------------------|
| OND_th_lsb | VDS monitoring threshold step | - | - | 27 | - | mV | Not subject to production test |
| OND_th_acc1 | VDS monitoring thresholds accuracy 1 | 0.594 V < VDH SHS_n < 1.7 V 0.594 V < SHS_n- SLS_n < 1.7 V | -4.5 | - | 4.5 | % | 16x < VDS_HS/LH_TH < 3Fx |
| OND_th_acc2 | VDS monitoring thresholds accuracy 2 | 0.324 V < VDH- SHS_n < 0.594 V 0.324 V < SHS_n- SLS_n < 0.594 V | -6 | - | 6 | % | Cx < VDS_HS/LH_TH < 16x |
| OND_th_acc3 | VDS monitoring thresholds accuracy 3 | 0.162 V < VDH- SHS_n < 0.324 V 0.162 V < SHS_n- SLS_n < 0.324 V | -10 | - | 10 | % | 6x < VDS_HS/LH_TH < Cx |
| OND_th_acc4 | VDS monitoring thresholds accuracy 4 | 0.081 V < VDH- SHS_n < 0.162 V 0.081 V < SHS_n- SLS_n < 0.162 V | -15 | - | 15 | % | 4x < VDS_HS/LH_TH < 6x |

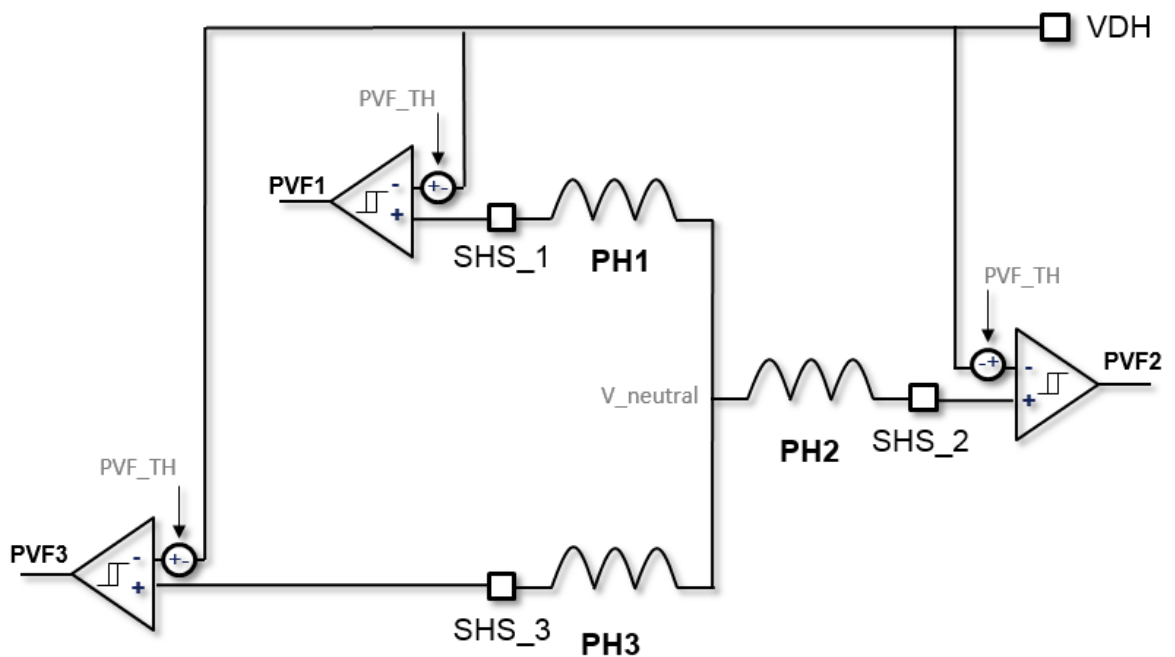
| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|-----------------|--------------------------------------|--|-----|-----|-----|------|------------------------|
| OND_th_acc5 | VDS monitoring thresholds accuracy 5 | VDH-SHS_n ≤ 0.081 V SHS_n-SLS_n ≤ 0.081 V | -12 | - | 12 | mV | 0x < VDS_HS/LH_TH < 3x |
| T_ond_fit_acc | OND Filtering Time accuracy | CLK_SSM_EN = 0 | -15 | - | 15 | % | - |
| T_ond_blank_acc | OND Blanking Time accuracy | CLK_SSM_EN = 0 | -15 | - | 15 | % | - |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.16 Phase Voltage Feedback (PVF)

L9908 implements three symmetric hysteretic comparators to monitor the level each motor phase voltage. This function allows a real time feedback on half bridges behavior in terms of phase voltage level and transition timing and actual phase's duty cycle.

Figure 73. Off State Diagnosis block diagram



Each phase voltage comparator converts the output phase voltage into a digital signal by comparing it against a threshold proportional to VDH voltage so that:

$VDH-SHS_n \geq PVFn_th_h$: PVFn is set to 1.

$VDH-SHS_n \leq PVFn_th_l$: PVFn is set to 0.

PVFn_th_h and PVFn_th_l are referred to as a specific percentage of the VDH voltage and can be configured by PVF_TH_CFG bits in the register GEN_CFG4, as follows:

Table 92. PVF threshold selection bits

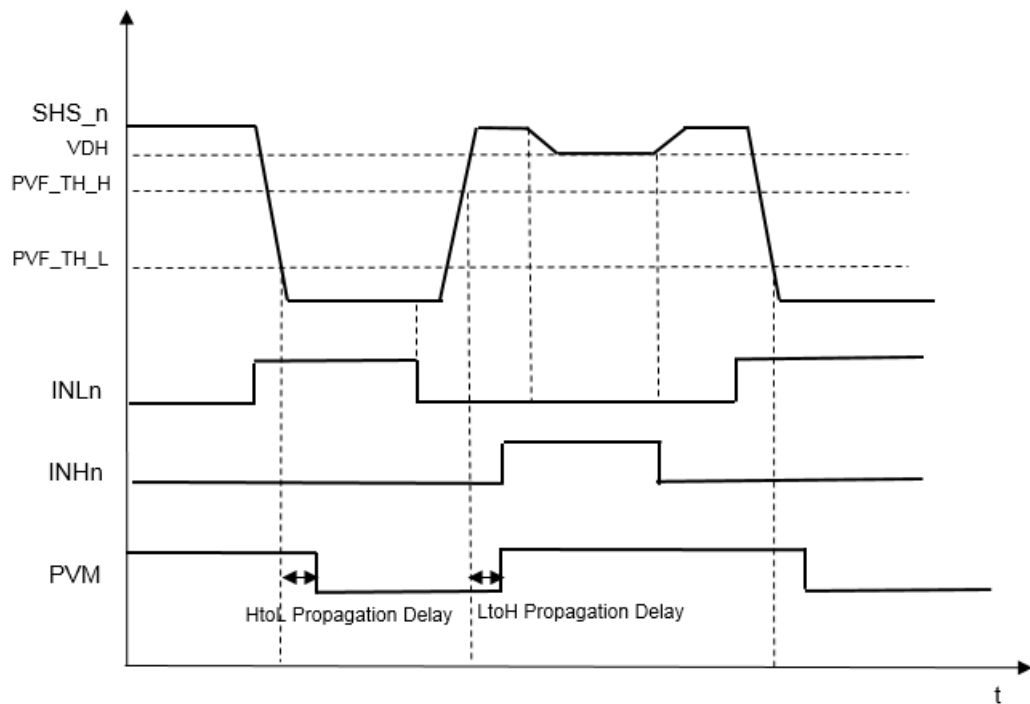
| PVF_TH_CFG | Description |
|------------|--|
| 0 | VPVF_TH_H = VDH*0.75 (Default) VPVF_TH_L = VDH*0.25 |

| PVF_TH_CFG | Description |
|------------|--|
| 1 | $VPVF_TH_H = VDH * 0.6$ $VPVF_TH_L = VDH * 0.4$ |

Table 93. PVF electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|--------------------------|--|------|-----|-----|------|-------|
| PPVF_th_acc | PVF thresholds accuracy | -6.5 | - | 6.5 | % | - |
| PPVF_th_match | PVF thresholds matching | -8 | - | 8 | % | - |
| PPVF_htol_dly | PVF high to low propagation delay | - | - | 200 | ns | - |
| PPVF_ltoh_dly | PVF low to high propagation delay | - | - | 200 | ns | - |
| PPVF_dly_match | PVF propagation delay matching (phase vs. phase) | - | 10 | 30 | ns | - |
| PPVF_htol_ltoh_dly_match | PVF propagation delay matching (single phase - rise to fall) | - | 20 | 35 | ns | - |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Figure 74. Phase voltage feedback behavior


The state of PVF comparators is echoed into dedicated SPI readable registers PVFn_ECHO, in the register GEN_STATUS3.

To save pin-count the phase comparator outputs are multiplexed to one single output pin CSO3/PVM.

The selection of which phase comparators output can be configured by means of a dedicated SPI bit set as follows:

Table 94. PVF output redirection selection bit

| PVF_OUT_CFG0 | PVF_OUT_CFG0 | Description |
|--------------|--------------|--|
| 0 | 0 | PVF1 xor PVF2 xor PVF3 is output (Default) |
| 0 | 1 | PVF1 is output |
| 1 | 0 | PVF2 is output |
| 1 | 1 | PVF3 is output |

5.16.1 CSO3 - PVF multiplexing

For pin saving purpose PVF and CSO3 outputs are multiplexed on the same pin and can be selected by CSO3_DIS bit in the register SAFETY_RELEVANT2:

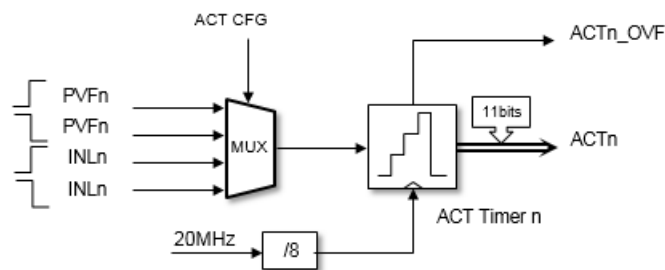
Table 95. CSO3-PVFn output multiplexing selection bits

| CSO3_DIS | Description |
|----------|--|
| 0 | CSO3/PVM pin used a CM3 output (Default) |
| 1 | CSO3/PVM pin used a PVFn output |

5.17 Actuation Timers (ACT)

L9908 implements an additional built-in feature which measures cycle by cycle the on or the off time windows applied to each phase either on INLn or on PVFn signals. This feature is performed by three dedicated 11-bit accumulators which count the number of clock cycles (CLK/8) fitting the time window.

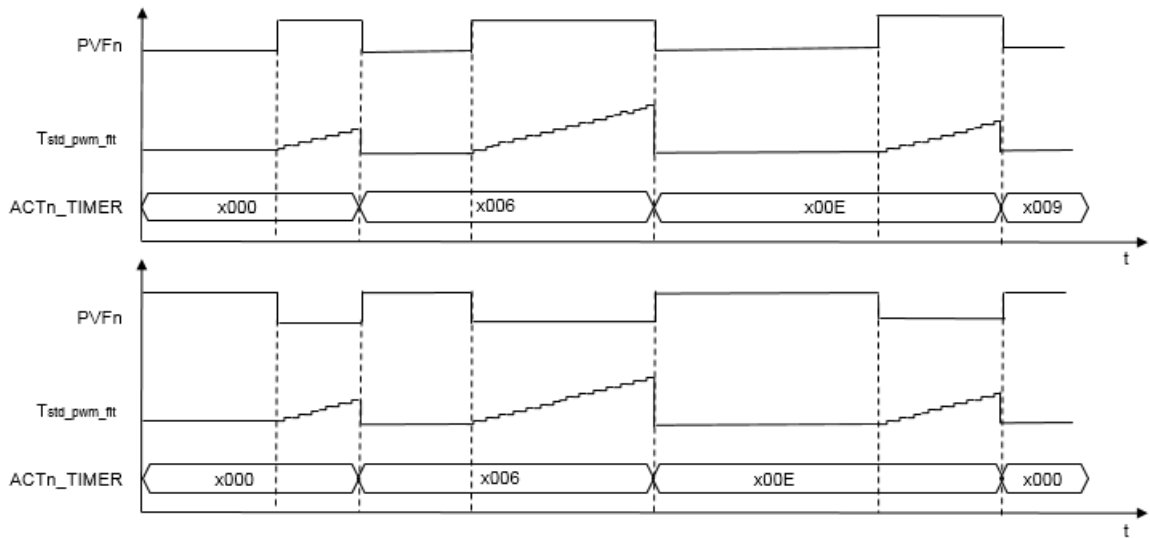
Figure 75. Actuation Timer simplified block diagram



To allow the maximum flexibility against the time window to be measured, either positive or negative, timers can be configured by a proper SPI bit set to be run in negative or positive polarity so that the time is triggered respectively by the falling or the rising of the reference signal and stopped by the opposite edge.

Table 96. Actuation Timers configuration bits

| ACT_CFG1 | ACT_CFG0 | Description |
|----------|----------|---------------------------------|
| 0 | 0 | PVF Negative Polarity (Default) |
| 0 | 1 | PVF Positive Polarity |
| 1 | 0 | INL Negative Polarity |
| 1 | 1 | INL Positive Polarity |

Figure 76. Actuation Timers timing diagram on ACT (positive & negative polarity)


The content of the count is stored into a dedicated 11bit SPI read-only register ACTn.

Reconstruction formula:

$$T_{ON - OFF} = \Delta_{ACT_LSB} \times D_{ACTn} \tag{24}$$

Where: D_{ACTn} is the digital word stored in ACTn and Δ_{ACT_LSB} is the ACT counter quantization step.

Example:

$D_{ACTn} = 10001010101$ (binary) à 1109 (decimal)

$ACT_CFG = 01$

$TON_PVF = 1109 * 0.4 \mu s = 443.6 \mu s \pm 50 ns$

In case the measured time window will exceed the maximum count allowed the counter overflow is flagged by setting to '1' a dedicated SPI read-only register ACTn_OVF.

Note: when ACT overflow condition is reached on n-th counter the ACTn value keeps the full-scale value until another counting window is started or the disabling of ACT function.

The ACT function can be enabled according to the following SPI bits:

Table 97. Actuation Timers enable bits

| ACT_EN | Description |
|--------|------------------------|
| 0 | ACT Disabled (Default) |
| 1 | ACT Enabled |

Table 98. Actuation Timers electrical characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit | Notes |
|------------|----------------|----------------|-----|-----|-----|---------|--------------------------------|
| ACT_res | ACT resolution | - | - | 11 | - | bits | Not subject to production test |
| ACT_lsb | ACT LSB | - | - | 0.4 | - | μs | Not subject to production test |
| ACT_in_acc | ACT accuracy | CLK_SSM_EN = 0 | -50 | - | 50 | μs | Not subject to production test |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

Note: Internal counter is a 14-bit counter with LSB equal to 50 ns. ACT readout and TSYNC configuration however are available only through the internal counter 11MSB.

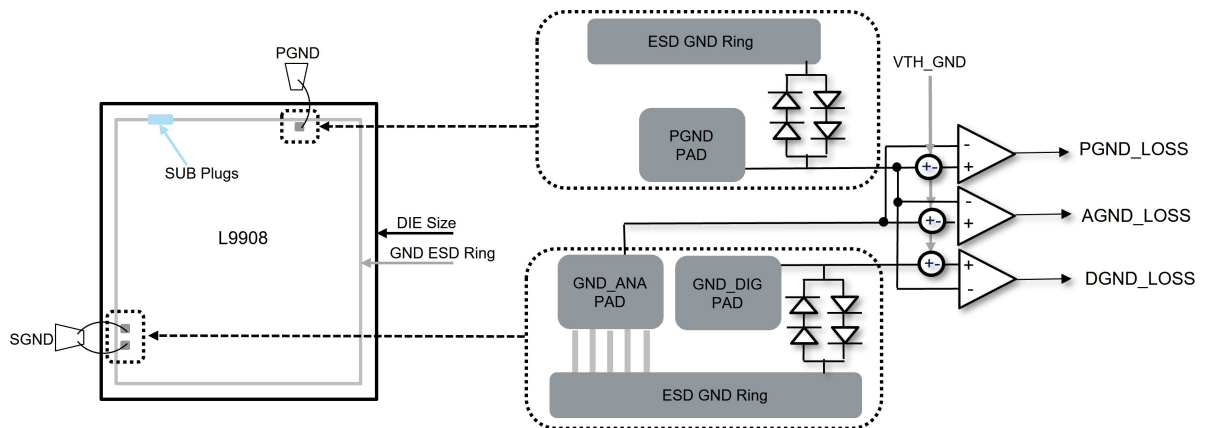
5.18 Ground Loss Monitor (GLM)

L9908 implements two ground reference pins, a Power Ground (PGND) dedicated as reference for the noisy, high power gate supply circuitry (CP1, CP2) and a Signal Ground (SGND) dedicated to the low power internal analog/digital circuitry.

For EMI robustness the GND pin is internally split in two GND reference PADS: GND_ANA (ground reference for analog circuitry supplied from V3V3_ANA) and GND_DIG (ground reference for digital circuitry supplied by V3V3_DIG), GND_ANA is connected to the ESD GND ring by means of a direct metal connection and bias the substrate through SUB Plugs placed all around IC border.

GND_ANA and PGND are connected to the ESD GND by means of a standard ESD protection for ground pins composed by a double couple of anti-parallel LV diodes.

Figure 77. Ground pins inter-connection



L9908 implements a monitoring unit to detect disconnection affecting ground references.

If $V_{PGND} - V_{GND_ANA} \geq V_{TH_GND}$ occurs for an interval longer than $T_{glm_loss_flt}$ filtering time, the PGND_LOSS flag is set.

If $V_{GND_DIG} - V_{GND_ANA} \geq V_{TH_GND}$ occurs for an interval longer than $T_{glm_loss_flt}$ filtering time, the DGND_LOSS flag is set.

If $V_{GND_DIG} - V_{PGND} \geq V_{TH_GND}$ occurs for an interval longer than $T_{glm_loss_flt}$ filtering time, the AGND_LOSS flag is set.

The correct operation Ground Loss Monitor stage is safety relevant and then a self-check procedure is implemented.

Table 99. GLM electrical characteristics

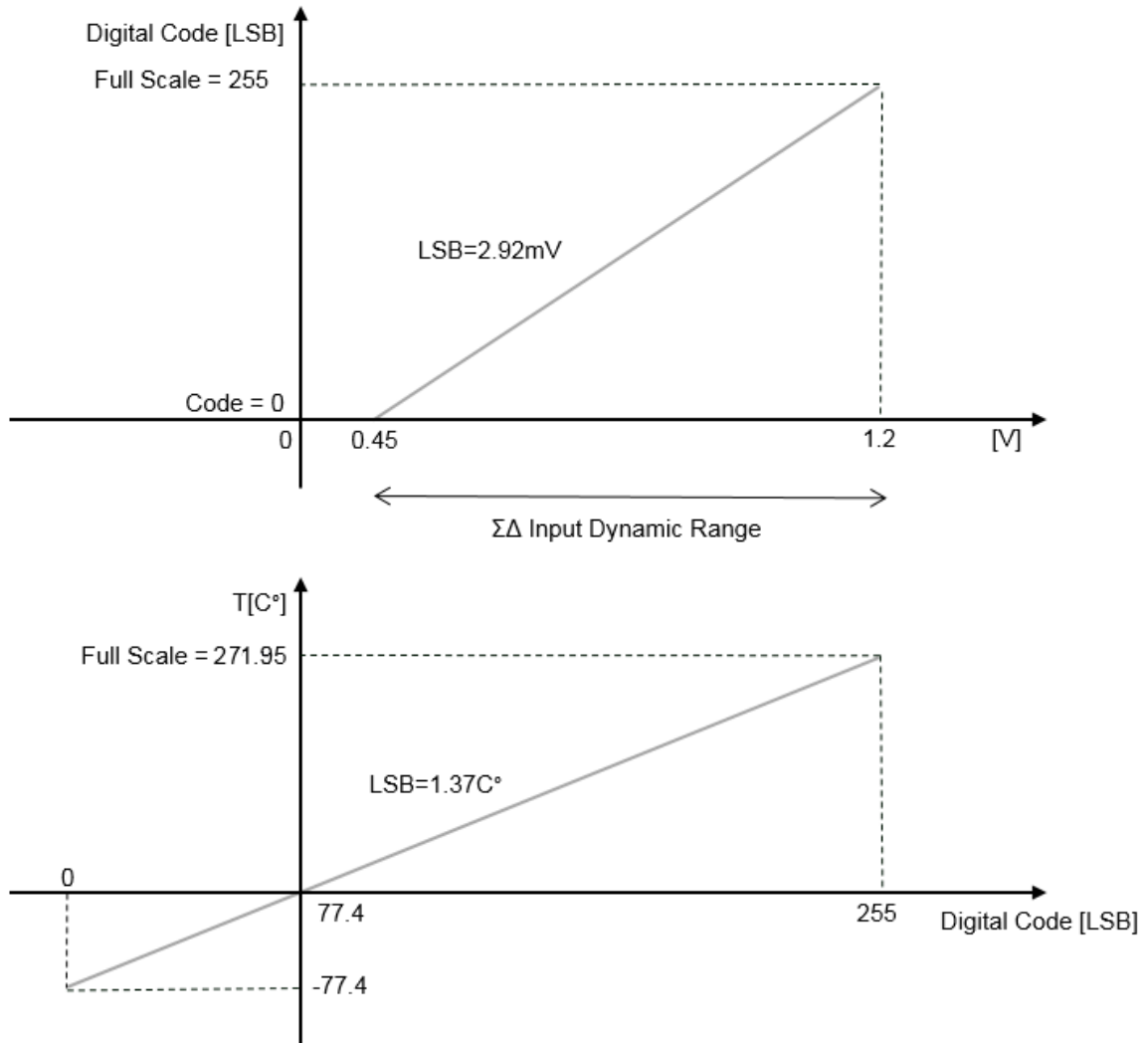
| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|----------------|---------------------------------|------|------|------|------|----------------|
| GLM_th | GLM detection threshold VTH_GND | 0.24 | 0.4 | 0.55 | V | - |
| T_glm_loss_flt | GLM filter time | 1 | 1.25 | 1.5 | ms | Digital Filter |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.19 Temperature Monitor (OTM)

L9908 implements a monitoring unit of the average junction temperature able to detect excessive over-heating conditions affecting the device.

Figure 78. Temperature monitor ADC characteristics



The temperature measurement data are stored in a dedicated register and can be retrieved by SPI readout of TEMP_READ in the register GEN_TEMP_STATUS.

The temperature can be retrieved by the following formula:

$$T_j [^{\circ}C] = (1.37^{\circ}C \times D_{TEMP_READ}) - 77.4^{\circ}C \quad (25)$$

Where: DTEMP_READ is the digital word stored in TEMP_READ.

The digitized temperature information is compared by two hysteresis comparators with selectable threshold based on the following scheme:

If $DTEMP \geq DTEMP_WR_TH$ occurs for an interval longer than $T_{otm_wr_flt}$ filtering time, the OTM_WR flag is set. The error flag remains set until the failure condition is removed.

If $DTEMP \geq DTEMP_SD_TH$ (= 185deg.) occurs for an interval longer than $T_{otm_sd_flt}$ filtering time, the OTM_SD flag is set. The error flag remains set until the failure condition is removed and the flag is cleared by the SPI command.

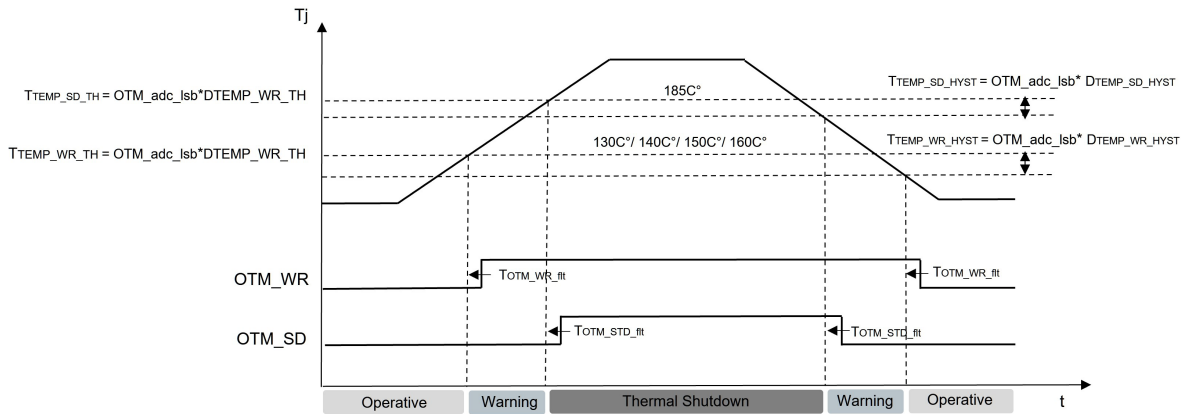
The thermal Warning threshold can be configured by the following SPI bit sets:

Table 100. Thermal warning configuration bits

| TWN_CFG1 | TWN_CFG0 | Description |
|----------|----------|-------------|
| 0 | 0 | 130 deg. |

| TWN_CFG1 | TWN_CFG0 | Description |
|----------|----------|--------------------|
| 0 | 1 | 140 deg. (Default) |
| 1 | 0 | 150 deg. |
| 1 | 1 | 160 deg. |

Figure 79. Junction temperature ranges



Temperature Range: Parametrical/Functional Range

L9908 is in NORMAL mode: Gate Driver Supply is active, Half Bridge Gate Drivers stage is enabled, monitoring units are enabled and SPI registers are out of reset. No damage affects L9908 and no wrong operation takes place. All static and dynamic parameters stay within specification limits.

Temperature Range: Critical OT Range

L9908 is set into SAFE- OFF mode: Gate Driver Supply is disabled, Half Bridge Gate Drivers stage is disabled. No damage affects L9908 and no wrong operation takes place. Static and dynamic parameters may deviate from specification limits.

Exposure to critical OT conditions for extended periods may affect device reliability.

Table 101. OTM electrical characteristics

| Symbol | Parameter | Min | Typ | Max | Unit | Notes |
|-----------------|------------------------------------|-----|------|------|------|--------------------------------|
| OTM_th | OTM detection threshold hysteresis | 5 | 10 | 15 | °C | Not subject to production test |
| T_otm_wr_fit | Thermal Warning filter time | 10 | 20 | 30 | µs | Digital Filter |
| T_otm_sd_fit | Thermal Shutdown filter time | 7 | 13 | 17.5 | µs | Digital Filter |
| OTM_readout_res | OTM Readout Resolution | - | 8 | - | - | Not subject to production test |
| OTM_readout_lsb | OTM Readout LSB | - | 1.37 | - | °C | Not subject to production test |
| OTM_acc | OTM ADC conversion accuracy | -5 | - | 5 | °C | Temperature Read out accuracy |
| OTM-sr | OTM ADC sample rate | - | - | 1 | kHz | Not subject to production test |
| T_otm_start_up | OTM ADC start up time | - | - | 3 | ms | Not subject to production test |

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in Table 5 unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.20 Serial Peripheral Interface (SPI)

L9908 implements a standard 4-pin Serial Peripheral Interface (SPI) to access both IC configuration and diagnosis/status registers up to 10 MHz Baud Rate (up/down-stream).

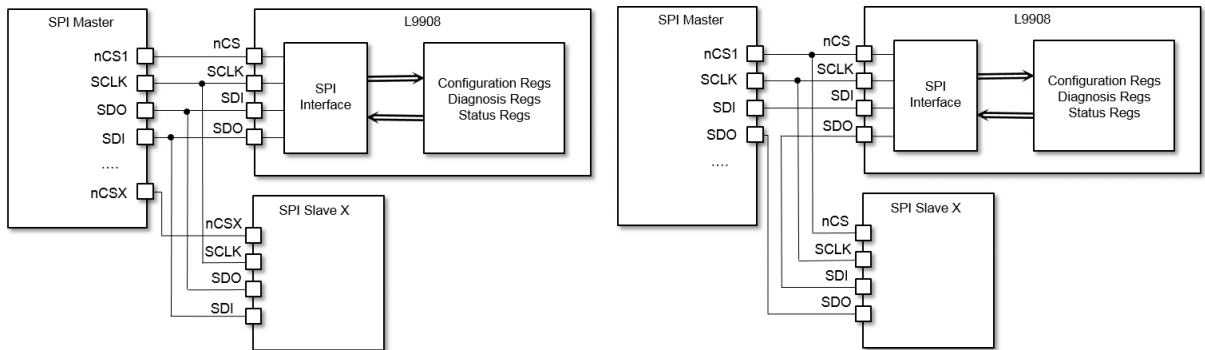
5.20.1 Protocol description

L9908 implement a SPI-slave interface based on a 32-bit protocol.

This slave interface then always requires a SPI-master device (ex. uC) which is responsible to generate the selection and the synchronization signals (NCS, SCLK) necessary to the data transmission.

The interface supports star mode connections along with other SPI-slave devices while it does not support daisy-chain mode connections (input data aren't transmitted directly to output port).

Figure 80. SPI connection modes "a" star connection (supported) "b" daisy-chain connection (not supported)



The data exchange has an out-of-frame structure: each MISO output frame is related to the previously transmitted MOSI frame.

SPI-master can directly verify if the previous frame has been received and processed correctly.

NCS pin (chip select) is used by the SPI-master to enable/disable the data communication. Communication starts with the NCS falling edge while is stopped with the NCS rising edge. As long as NCS is high any transition at the SCLK and SDI pins (including glitches) is ignored and SDO is forced into a high impedance state.

SCLK pin (Synchronous Serial Clock) is used by the SPI-master to synchronize the data communication. Each correct communication shall contain 32 SCLK pulses.

At each SCLK rising edge SDI and SDO data are updated respectively by SPI-master and L9908 (shift), at each SCLK falling edge SDI and SDO data are sampled respectively by L9908 and SPI-master (capture). SCLK has to be low during NCS transition.

SDI pin (Serial Data Input) is used by the SPI-master to deliver the 32-bit input frame to L9908. In MOSI communication the first bit expected is MSB while the last is LSB.

SDO pin (Serial Data Output) is used by L9908 to transmit the 32-bit data output. In MISO communication the first bit transmitted is MSB while the last is LSB.

Figure 81. SPI timing diagram

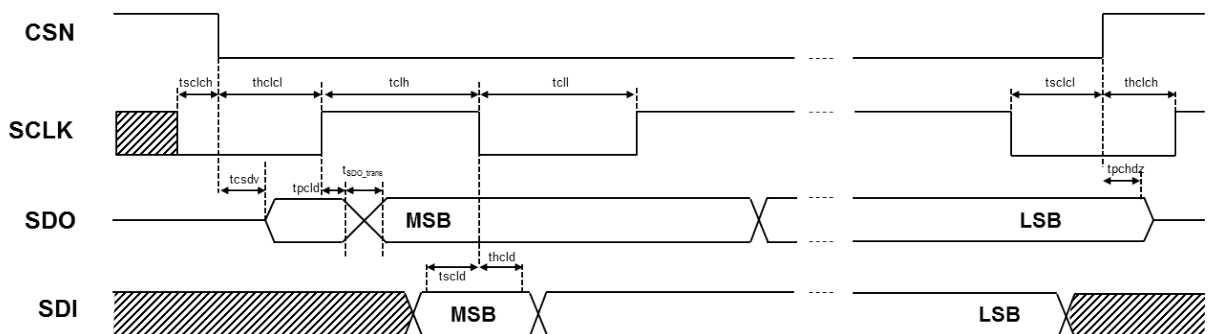


Table 102. SPI timing characteristics

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|----------|--------------------|-------------------------------|-----|-----|------|------|
| SPI_fclk | Transfer Frequency | 50% duty cycle ⁽¹⁾ | - | 10 | 10.2 | MHz |

| Symbol | Parameter | Test Condition | Min | Typ | Max | Unit |
|---------------------|--|---|-----|-----|-----|------|
| SPI_tpclدtsdo_trans | Propagation delay | SCLK to data at SDO is valid Cload_max = 200 pF Including parasitics | - | - | 100 | ns |
| SPI_tcsdv | NCS=LOW to data at SDO active | Cload_max = 200 pF Including parasitics | - | - | 200 | ns |
| SPI_tpchdz | NCS L/H to SDO at high impedance | Cload_max = 200 pF Including parasitics | - | - | 200 | ns |
| SPI_tscclh | SCLK before NCS low | (2) | 50 | - | - | ns |
| SPI_thclcl | SCLK change L/H after NCS=LOW | (2) | 130 | - | - | ns |
| SPI_tscclcl | SCLK low before NCS high | (2) | 50 | - | - | ns |
| SPI_thclch | SCLK high after NCS high | (2) | 50 | - | - | ns |
| SPI_tscclcl | SDI input setup time | (2) | 20 | - | - | ns |
| SPI_thclcl | SDI input hold time | (2) | - | - | 20 | ns |
| SPI_tonNCS | NCS min. high time | (2) | 650 | - | - | ns |
| SPI_tclh | Minimum Time SCLK=HIGH | (2) | 45 | - | - | ns |
| SPI_tcll | Minimum Time SCLK=LOW | (2) | 45 | - | - | ns |
| SPI_Cin | Input pin capacitance | (2) | - | - | 30 | pF |
| SPI_Cout_hiz | MISO output pin capacitance in tri-state | (2) | - | - | 50 | pF |

1. SPI max frequency may be less depending on the total capacitive load or MCU timing requirements.
2. Not subject to production test, guaranteed by design.

Note: All parameters are guaranteed, and tested, in the voltage ranges reported above in [Table 5](#) unless otherwise specified. Where not specified the parametrical operating range equals the functional operating range.

5.20.2 Frame description

The 32-bit SPI frames content is divided as follows:

Table 103. MOSI - SPI frame description

| Bit | 31 | 30-23 | 22 | 21 | 20-5 | 4-0 |
|------|-----|---------|--------|----|------------|-----|
| MOSI | R/W | ADDRESS | RSV/TM | FC | DATA WRITE | CRC |

MOSI Stream:

[31] R/W Flag. Selects if the current operation is a read (0) operation or write (1) operation.

[30-23] SPI register address

[22] Test Mode Flag

[21] Frame Counter

[20-5] Data Write

[4-0] CRC checksum generated by SPI-master

Table 104. MISO - SPI frame description

| Bit | 31 | 30-29 | 28-21 | 20-5 | 4-0 |
|------|---------|--------|------------|-----------|-----|
| MISO | SPI ERR | IC ERR | ADDRESS FB | DATA READ | CRC |

MISO Stream:

[31] SPI Error Flag. Provide information related to the previous stream.

[30-29] IC Error Flag. Provide information related to IC high level error.

[28-21] SPI register address feedback. Last received valid frame address feedback.

[20-5] Data Read. Data contents of SPI register addressed by last received valid frame.

[4-0] CRC checksum generated by SPI-slave

5.20.2.1 Write-Read operations

1st Frame: Write Access to R/W Register X

As the NCS rising edge is detected, if it is valid, the command is processed and the R/W register X is updated with data Y. After the register X is updated correctly the output buffer is updated as well.

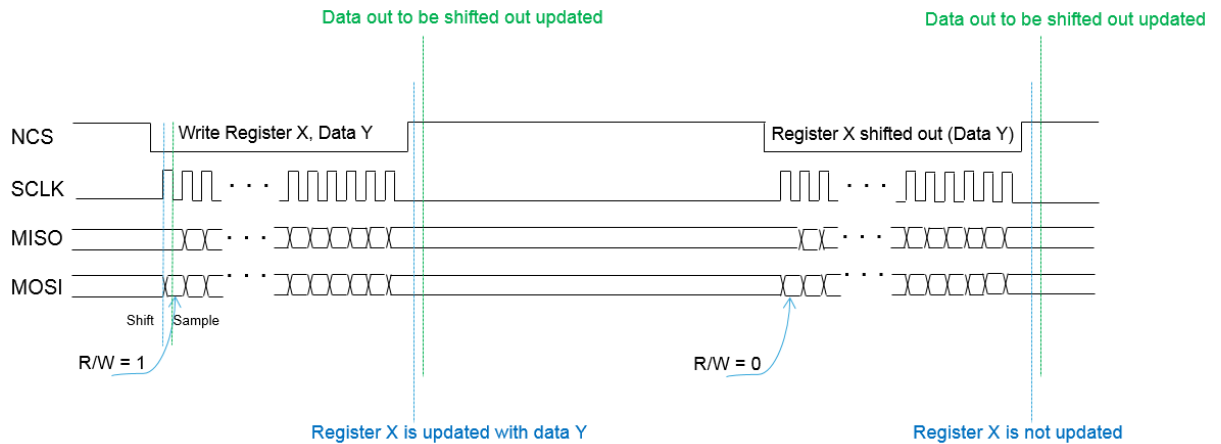
2nd Frame: Read Access

As the NCS falling edge is detected, the register X with data Y is started being shifted out on MISO bus. The X register data remains unchanged as R/W bit is zero, the following MISO frame will be updated with the same data.

The first SPI frame after an internal reset (i.e. INT_RST) will have a fixed content:

- IC_ERR and SPI_ERR flag all 0
- Address Feedback all = 0
- Data all = 0

Figure 82. SPI Write-Read operation



5.20.2.2 Read-Read operations

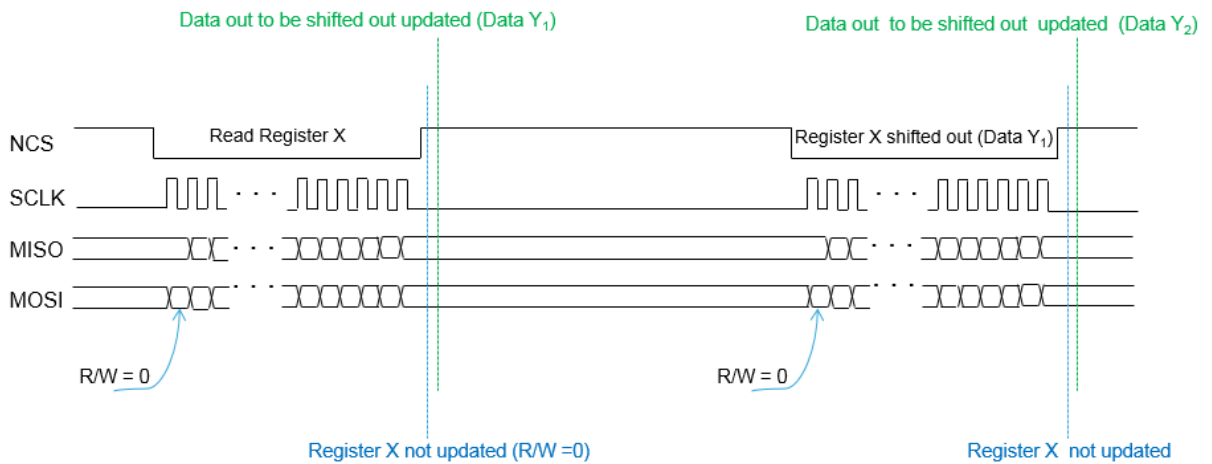
1st Frame: Read Access to Register X

As the NCS rising edge is detected, if it is valid, the command is processed but the R/W register X register data remains unchanged as R/W bit is zero and the output buffer is updated with data Y1.

2nd Frame: Read Access to Register X

As the NCS falling edge is detected, the register X with data Y1 is started being shifted out on MISO bus. The X register data remains unchanged as R/W bit is zero, the following MISO frame will be updated with the data Y2.

Figure 83. SPI Read-Read operation



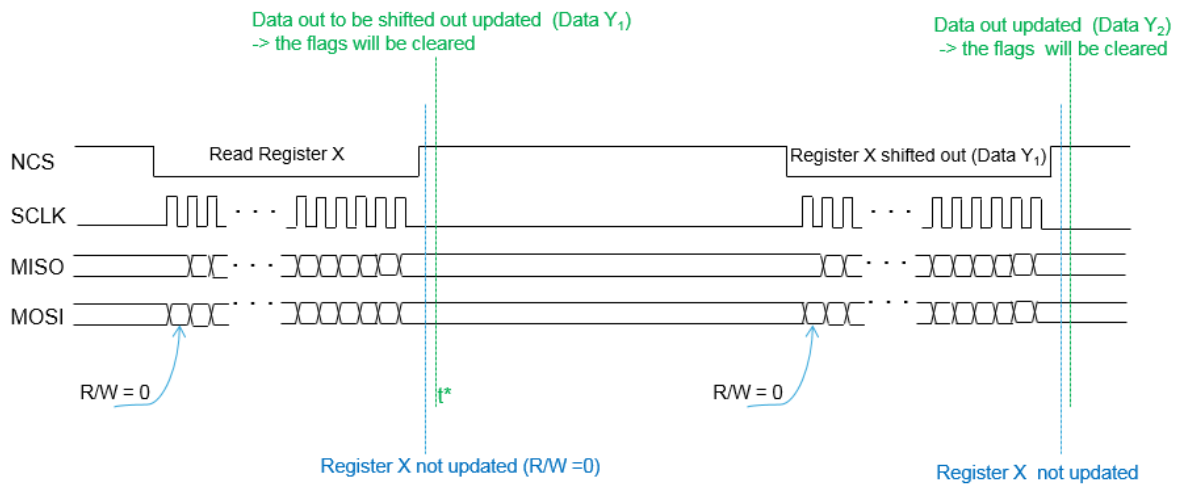
5.20.2.3 Clear on Read Operations

1st Frame: Read Access to Register X

As the NCS rising edge is detected, if it is valid, the command is processed but the R/W register X register data remains unchanged as R/W bit is zero and the output buffer is updated with data Y1. After the output buffer is updated correctly the X register flags are cleared.

2nd Frame: Read Access to Register X As NCS falling edge is detected, the register X with data Y1 is started being shifted out on MISO bus.

Figure 84. SPI Clear on Read operation



5.20.3 Frame monitoring

Correct SPI communication is safety relevant and then the following safety mechanism is implemented.

Cyclic Redundancy Check (CRC)

MISO/MOSI SPI data are protected with a 5-bit CRC using the following polynomial expression:

$$G(x) = x^5 + x^2 + 1 \tag{26}$$

The initial value to be used is 11111 (0x1F).

CRC is calculated over bit 5-31 except bit 21 (Hamming distance of 3 over 26 bit data), MSB First.

Example:

Read register 0x4A command (data = 0)

Frame: [0 0100:1010 0 0 0000:0000:0000:0000 10001] (0x25000011)

Frame: [0 0100:1010 0 1 0000:0000:0000:0000 10001] (0x25200011)

CRC is 10001 independently on FC value.

Write 0xABCD to register 0xC7 command

Frame: [1 1100:0111 0 0 1010:1011:1100:1101 11000] (0xE39579B8)

Frame: [1 1100:0111 0 1 1010:1011:1100:1101 11000] (0xE3B579B8)

CRC is 11000b independently on FC value.

Frame Counter Check (FC)

A 1-bit frame counter is transmitted by the SPI-master within every MOSI frame to support the detection of failures in the communication channel (ex. corrupted or missing frames). The initial value to be used is 0.

Clock Counter Check

L9908 implements two separate clock counters for the rising and the falling edges of SCLK clock to check the length of the MOSI frame to be equal to 32. The clock counters reset is generated from the detection of a rising edge of NCS.

5.20.4 Error handling

In case of an error either regarding the SPI word length (clock counter), frame counter bit value (FC) or wrong CRC check, the SPI_ERR bit is set to '1' and the frame is ignored by L9908. The SPI error bit always refers to the previous SPI frame.

The register SPI_CMM_FAULT contains specific bits indicating which SPI fault occurred on the previous frame. After reading, register value will be reset. Refer to the next section for details.

5.20.5 Register description

Legenda:

Safety Description:

- NSR = Non-safety Relevant Register
- SLR = Safety Latent Register
- SSR = Safety Relevant Register

Operation Type:

- RW = Read/Write
- RO = Read Only
- CR = Clear on Read

Reset Source:

- A = INT_RST
- B = INT_RST || CFG_RST
- D = INT_RST (excluded CLK1_TIMEOUT)

Table 105. CHIPID

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CHIPID | 0x0 | UNUSED_9 | RO | 15 | 1 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| NSR | | UNUSED_8 | RO | 14 | 1 | 0x0 | B |
| | | UNUSED_7 | RO | 13 | 1 | 0x0 | B |
| | | UNUSED_6 | RO | 12 | 1 | 0x0 | B |
| | | UNUSED_5 | RO | 11 | 1 | 0x0 | B |
| | | UNUSED_4 | RO | 10 | 1 | 0x0 | B |
| | | UNUSED_3 | RO | 9 | 1 | 0x0 | B |
| | | UNUSED_2 | RO | 8 | 1 | 0x0 | B |
| | | UNUSED_1 | RO | 7 | 1 | 0x0 | B |
| | | UNUSED_0 | RO | 6 | 1 | 0x0 | B |
| | | METAL_ID | RO | 3 | 3 | 0x0 | B |
| | | SILICON_ID | RO | 0 | 3 | 0x1 | B |

Table 106. GEN_CFG1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| GEN_CFG1 | 0x2 | WDT_EN 0: Watchdog disabled (Default) 1: Watchdog enabled | RW | 15 | 1 | 0x0 | B |
| SLR | | CLK_SSM_EN 0: Clock SSM Disabled (Default) 1: Clock SSM Enabled | RW | 14 | 1 | 0x0 | B |
| | | CSM_OUT_RANGE_CFG | RW | 13 | 1 | 0x0 | B |
| | | CSM_SSPV_PH_CFG 00: No synchronization 01: TSYNC based on Phase 1 (Default) 10: TSYNC based on Phase 2 11: TSYNC based on Phase 3 | RW | 11 | 2 | 0x01 | B |
| | | CSM_LP_CFG 000: No filtering (Default) 001: 91kHz 010: 37kHz 011: 17kHz 100: 8kHz 101: 4kHz 110: 2kHz 111: 1kHz | RW | 8 | 3 | 0x0 | B |
| | | DTP_CFG 000: 0us - DTP Disabled 001: 0.25us 010: 0.35us 011: 0.5us 100: 1us - Default 101: 1.5us | RW | 5 | 3 | 0x2 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| SLR | | 110: 2us 111: 4us | | | | | |
| | | SR_CRC_FAIL_REDIRECT_CFG | RW | 4 | 1 | 0x0 | B |
| | | VBP_OV_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 3 | 1 | 0x0 | B |
| | | VBP_UV_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 2 | 1 | 0x0 | B |
| | | VDH_OV_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 1 | 1 | 0x0 | B |
| | | VDH_UV_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 0 | 1 | 0x0 | B |

Table 107. GEN_CFG2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| GEN_CFG2 | 0x3 | ACT_CFG 00: PVF Negative Polarity (Default) 01: PVF Positive Polarity 10: INL Negative Polarity 11: INL Positive Polarity | RW | 14 | 2 | 0x0 | B |
| SLR | | OFD_BLANK 00: T_ofd_blank = 10ms 01: T_ofd_blank = 25ms 10: T_ofd_blank = 50ms (Default) 11: T_ofd_blank = 100ms | RW | 12 | 2 | 0x2 | B |
| | | VDS_HS_TH | RW | 6 | 6 | 0x0 | B |
| | | VDS_LS_TH | RW | 0 | 6 | 0x0 | B |

Table 108. GE_CFG3

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| GEN_CFG3 | 0x4 | TWN_CFG 00: 130deg. 01: 140deg. (Default) 10: 150deg. 11: 160deg. | RW | 14 | 2 | 0x1 | B |
| SLR | | STP3_VGS_DIS 0: Shoot-through protection on FET Vgs enabled (Default) | RW | 13 | 1 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset | |
|--|---------|--|------|------------|-----------|-------------|-------|--|
| SLR | | 1: Shoot-through protection on FET Vgs disabled | | | | | | |
| | | STP2_VGS_DIS | RW | 12 | 1 | 0x0 | B | |
| | | 0: Shoot-through protection on FET Vgs enabled (Default) | | | | | | |
| | | 1: Shoot-through protection on FET Vgs disabled | | | | | | |
| | | STP1_VGS_DIS | RW | 11 | 1 | 0x0 | B | |
| | | 0: Shoot-through protection on FET Vgs enabled (Default) | | | | | | |
| | | 1: Shoot-through protection on FET Vgs disabled | | | | | | |
| | | STP3_PWM_DIS | RW | 10 | 1 | 0x0 | B | |
| | | 0: Shoot-through protection on PWM input enabled (Default) | | | | | | |
| | | 1: Shoot-through protection on PWM input disabled | | | | | | |
| | | STP2_PWM_DIS | RW | 9 | 1 | 0x0 | B | |
| | | 0: Shoot-through protection on PWM input enabled (Default) | | | | | | |
| | | 1: Shoot-through protection on PWM input disabled | | | | | | |
| STP1_PWM_DIS | RW | 8 | 1 | 0x0 | B | | | |
| 0: Shoot-through protection on PWM input enabled (Default) | | | | | | | | |
| 1: Shoot-through protection on PWM input disabled | | | | | | | | |
| UNUSED_0 | RW | | | 6 | 2 | 0x0 | B | |
| BT1_DIS | RW | | | 5 | 1 | 0x0 | B | |
| 0: Bootstrap Limiter 1 Enabled (Default) | | | | | | | | |
| 1: Bootstrap Limiter 1 Disabled | | | | | | | | |
| OND_FLT | RW | | | 3 | 2 | 0x2 | B | |
| 00: T_ond_ft = 1 μs | | | | | | | | |
| 01: T_ond_ft = 2.5 μs | | | | | | | | |
| 10: T_ond_ft = 4 μs (Default) | | | | | | | | |
| 11: T_ond_ft = 8 μs | | | | | | | | |
| OND_BLANK | RW | | | 0 | 3 | 0x2 | B | |
| 000: T_ond_blank = 0.7u | | | | | | | | |
| 001: T_ond_blank = 1 μs | | | | | | | | |
| 010: T_ond_blank = 1.5 μs (Default) | | | | | | | | |
| 011: T_ond_blank = 2 μs | | | | | | | | |
| 100: T_ond_blank = 2.5 μs | | | | | | | | |
| 101: T_ond_blank = 3.5 μs | | | | | | | | |
| 110: T_ond_blank = 5 μs | | | | | | | | |
| 111: T_ond_blank = 8 μs | | | | | | | | |

Table 109. GEN_CFG4

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|-------------|------|------------|-----------|-------------|-------|
| GEN_CFG4 | 0x5 | PVF_OUT_CFG | RW | 14 | 2 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|--|------|------------|-----------|-------------|-------|
| | | 00: PVF1 xor PVF2 xor PVF3 is output (Default) 01: PVF1 is output 10: PVF2 is output 11: PVF3 is output | | | | | |
| SLR | | PVF_TH_CFG 0: VPVF_TH_H = VDH*0.75 (Default) VPVF_TH_L = VDH*0.25 1: VPVF_TH_H = VDH*0.6 VPVF_TH_L = VDH*0.4 | RW | 13 | 1 | 0x0 | B |
| | | UNUSED_0 | RW | 12 | 1 | 0x0 | B |
| | | DRV_HIZ 0: Pre-drivers in NO high impedance 1: Pre-drivers in high impedance (Default) | RW | 11 | 1 | 0x1 | B |
| | | SELF_TEST_CFG4 0: OND LS Self-Test Not Active 1: OND LS Self-Test Active (Default) SELF_TEST_CFG3 0: OND HS Self-Test Not Active 1: OND HS Self-Test Active (Default) SELF_TEST_CFG2 0: Supply Monitors Self-Test Not Active 1: Supply Monitors Self-Test Active (Default) SELF_TEST_CFG1 0: SW Off Path Self-Test Not Active 1: SW Off Path Self-Test Active (Default) SELF_TEST_CFG0 0: Clock Monitor Self-Test Not Active 1: Clock Monitor Self-Test Active (Default) | RW | 6 | 5 | 0x1F | B |
| | | HB3_ACK | RW | 5 | 1 | 0x1 | B |
| | | HB2_ACK | RW | 4 | 1 | 0x1 | B |
| | | HB1_ACK | RW | 3 | 1 | 0x1 | B |
| | | HB3_DIS 0: 3rd HS/LS drivers is enabled (Default) 1: 3rd HS/LS drivers is disabled | RW | 2 | 1 | 0x0 | B |
| | | HB2_DIS 0: 2nd HS/LS drivers is enabled (Default) 1: 2nd HS/LS drivers is disabled | RW | 1 | 1 | 0x0 | B |
| | | HB1_DIS 0: 1st HS/LS drivers is enabled (Default) 1: 1st HS/LS drivers is disabled | RW | 0 | 1 | 0x0 | B |

Table 110. GEN_STATUS1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------------|------|------------|-----------|-------------|-------|
| GEN_STATUS1 | 0x6 | AGND_LOSS | CR | 15 | 1 | 0x0 | A |
| NSR | | DGND_LOSS | CR | 14 | 1 | 0x0 | A |
| | | PGND_LOSS | CR | 13 | 1 | 0x0 | A |
| | | NVM_CRC_FAIL | RO | 12 | 1 | 0x0 | A |
| | | VDD_OV | CR | 11 | 1 | 0x0 | A |
| | | SELF_TEST_STATUS | RO | 9 | 2 | 0x0 | D |
| | | SR_CRC_FAIL | CR | 8 | 1 | 0x0 | A |
| | | CLK2_ERR | CR | 7 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 6 | 1 | 0x0 | A |
| | | CLK1_ERR | CR | 5 | 1 | 0x0 | A |
| | | CLK2_TIMEOUT | CR | 4 | 1 | 0x0 | A |
| | | CLK1_TIMEOUT | CR | 3 | 1 | 0x0 | D |
| | | SAFE_STATE | RO | 2 | 1 | 0x1 | A |
| | | CFG_RST | CR | 1 | 1 | 0x1 | B |
| | | INT_RST | CR | 0 | 1 | 0x1 | A |

Table 111. GEN_STATUS2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| GEN_STATUS2 | 0x7 | INL3_ECHO | RO | 15 | 1 | 0x0 | A |
| NSR | | INL2_ECHO | RO | 14 | 1 | 0x0 | A |
| | | INL1_ECHO | RO | 13 | 1 | 0x0 | A |
| | | INH3_ECHO | RO | 12 | 1 | 0x0 | A |
| | | INH2_ECHO | RO | 11 | 1 | 0x0 | A |
| | | INH1_ECHO | RO | 10 | 1 | 0x0 | A |
| | | NDIS_ECHO | RO | 9 | 1 | 0x1 | A |
| | | EN_BR_ECHO | RO | 8 | 1 | 0x0 | A |
| | | VBP_OV | CR | 7 | 1 | 0x0 | A |
| | | VBP_UV | CR | 6 | 1 | 0x0 | A |
| | | VDH_OV | CR | 5 | 1 | 0x0 | A |
| | | VDH_UV | CR | 4 | 1 | 0x0 | A |
| | | VCP_OV | CR | 3 | 1 | 0x0 | A |
| | | VCP_UV | CR | 2 | 1 | 0x0 | A |
| | | VPRE_OV | CR | 1 | 1 | 0x0 | A |
| | | VPRE_UV | CR | 0 | 1 | 0x0 | A |

Table 112. GEN_STATUS3

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| GEN_STATUS3 | 0x8 | UNUSED_4 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_3 | RO | 14 | 1 | 0x0 | A |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset | |
|---------------------|---------|--------------------|------|------------|-----------|-------------|-------|--|
| NSR | | CP2_EN_ECHO | RO | 13 | 1 | 0x1 | A | |
| | | CP1_EN_ECHO | RO | 12 | 1 | 0x1 | A | |
| | | HB3_EN_ECHO | RO | 11 | 1 | 0x1 | A | |
| | | HB2_EN_ECHO | RO | 10 | 1 | 0x1 | A | |
| | | HB1_EN_ECHO | RO | 9 | 1 | 0x1 | A | |
| | | UNUSED_0 | RO | 6 | 3 | 0x0 | A | |
| | | OPERATION_MODE | | | | | | |
| | | 000: RESET Mode | | | | | | |
| | | 001: NVM Read Mode | | | | | | |
| | | 010: SAFE OFF Mode | | | | | | |
| | | 011: NORMAL Mode | | | | | | |
| 100: CFG Mode | | | | | | | | |
| 101: SELF TEST Mode | | | | | | | | |
| 110: RESET Mode | | | | | | | | |
| 111: RESET Mode | | | | | | | | |
| | | PVF3_ECHO | RO | 2 | 1 | 0x0 | A | |
| | | PVF2_ECHO | RO | 1 | 1 | 0x0 | A | |
| | | PVF1_ECHO | RO | 0 | 1 | 0x0 | A | |

Table 113. GEN_TEMP_STATUS

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|-----------------|---------|------------|------|------------|-----------|-------------|-------|
| GEN_TEMP_STATUS | 0x9 | UNUSED_5 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_4 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_3 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 12 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 11 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 10 | 1 | 0x0 | A |
| | | OTM_SD | CR | 9 | 1 | 0x0 | A |
| | | OTM_WR | CR | 8 | 1 | 0x0 | A |
| | | TEMP_READ | RO | 0 | 8 | 0x0 | A |

Table 114. SW_RESET

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| SW_RESET | 0xA | UNUSED_7 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_6 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_5 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_4 | RO | 12 | 1 | 0x0 | A |
| | | UNUSED_3 | RO | 11 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 10 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 9 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 8 | 1 | 0x0 | A |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| NSR | | SW_RESET_KEY 0xCC: SW Reset Activation | RW | 0 | 8 | 0x0 | A |

Table 115. WDT_CFG_CMD

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| WDT_CFG_CMD | 0xB | UNUSED_2 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_1 | RO | 14 | 1 | 0x0 | A |
| | | WDT_RESET 00: NO Reset 01: NO Reset (Default) 10: Reset 11: NO Reset | RW | 12 | 2 | 0x1 | A |
| | | WDT_FAIL_COUNT_CFG 00: 1 01: 1 10: 2 11: 3 (Default) | RW | 10 | 2 | 0x3 | A |
| | | WDT_OVF_CFG 00: 11.26 ms 01: 22.52 ms (Default) 10: 45.04 ms 11: 90.11 ms | RW | 8 | 2 | 0x1 | A |
| | | WDT_GRAY | RO | 4 | 4 | 0x0 | A |
| | | WDT_BINARY | RW | 0 | 4 | 0x0 | A |

Table 116. WDT_STATUS

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|-----------------------|------|------------|-----------|-------------|-------|
| WDT_STATUS | 0xC | UNUSED_4 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_3 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 12 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 11 | 1 | 0x0 | A |
| | | WDT_FAIL_COUNT_STATUS | RO | 9 | 2 | 0x0 | A |
| | | WDT_OVF_STATUS | RO | 3 | 6 | 0x0 | A |
| | | WD_ON_STATUS | RO | 2 | 1 | 0x0 | A |
| | | WDT_DATA_FAIL | RO | 1 | 1 | 0x0 | A |
| | | WDT_OVF_FAIL | RO | 0 | 1 | 0x0 | A |

Table 117. BIST_KEY

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| BIST_KEY | 0xD | UNUSED_7 | RO | 15 | 1 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| NSR | | UNUSED_6 | RO | 14 | 1 | 0x0 | B |
| | | UNUSED_5 | RO | 13 | 1 | 0x0 | B |
| | | UNUSED_4 | RO | 12 | 1 | 0x0 | B |
| | | UNUSED_3 | RO | 11 | 1 | 0x0 | B |
| | | UNUSED_2 | RO | 10 | 1 | 0x0 | B |
| | | UNUSED_1 | RO | 9 | 1 | 0x0 | B |
| | | UNUSED_0 | RO | 8 | 1 | 0x0 | B |
| | | BIST_KEY 0x55 --> 0x33 SELF TEST Mode Access | RW | 0 | 8 | 0x0 | B |

Table 118. CFG_EN_UNLOCK

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|--|------|------------|-----------|-------------|-------|
| CFG_EN_UNLOCK | 0xE | UNUSED_7 | RO | 15 | 1 | 0x0 | B |
| NSR | | UNUSED_6 | RO | 14 | 1 | 0x0 | B |
| | | UNUSED_5 | RO | 13 | 1 | 0x0 | B |
| | | UNUSED_4 | RO | 12 | 1 | 0x0 | B |
| | | UNUSED_3 | RO | 11 | 1 | 0x0 | B |
| | | UNUSED_2 | RO | 10 | 1 | 0x0 | B |
| | | UNUSED_1 | RO | 9 | 1 | 0x0 | B |
| | | UNUSED_0 | RO | 8 | 1 | 0x0 | B |
| | | CFG_EN_UNLOCK 0x55 --> 0x33: CONFIG Mode Access 0xAA: CONFIG Mode Exit | RW | 0 | 8 | 0x0 | B |

Table 119. SAFETY_RELEVANT1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|------------------|---------|--|------|------------|-----------|-------------|-------|
| SAFETY_RELEVANT1 | 0x10 | FS_FLAG_CFG 0: Push-pull (Default) 1: Open-drain | RW | 15 | 1 | 0x0 | B |
| SSR | | UNUSED_0 | RW | 13 | 2 | 0x0 | B |
| | | VBP_OV_REACT_CFG 00: Full SW Off – disable all HB drivers and CPs, device is sent in SAFE-OFF mode (Default) 01: Reduced Operation Mode – disable failing HB only, device remains in NORMAL mode 10: Flag only – down-rate fault to simple warning, device remains in NORMAL mode 11: Flag only – down-rate fault to simple warning, device remains in NORMAL mode | RW | 11 | 2 | 0x0 | B |
| | | VBP_UV_REACT_CFG | RW | 9 | 2 | 0x0 | B |
| | | | | | | | |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------------|------|------------|-----------|-------------|-------|
| SSR | | VDH_OV_REACT_CFG | RW | 7 | 2 | 0x0 | B |
| | | VDH_UV_REACT_CFG | RW | 5 | 2 | 0x0 | B |
| | | CRC | RW | 0 | 5 | 0x17 | B |

Table 120. SAFETY_RELEVANT2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|------------------|---------|---|------|------------|-----------|-------------|-------|
| SAFETY_RELEVANT2 | 0x11 | CSO3_DIS 0: CSO3/PVM pin used a CM3 output (Default) 1: CSO3/PVM pin used a PVFn output | RW | 15 | 1 | 0x0 | B |
| SSR | | CS3_DIS 0: current monitor enabled (Default) 1: current monitor disabled | RW | 14 | 1 | 0x0 | B |
| | | CS2_DIS 0: current monitor enabled (Default) 1: current monitor disabled | RW | 13 | 1 | 0x0 | B |
| | | CS1_DIS 0: current monitor enabled (Default) 1: current monitor disabled | RW | 12 | 1 | 0x0 | B |
| | | VDH_FLT_CFG 00: 12.25 μ s (Defaults) 01: 25 μ s 10: 50 μ s 11: 100 μ s | RW | 10 | 2 | 0x0 | B |
| | | VDH_OV_CFG 000: 12 V Systems 1 001: 12 V Systems 2 010: 24 V Systems 1 011: 24 V Systems 2 100: 48 V Systems 1 101: 48 V Systems 2 110: 48 V Systems 3 111: 48 V Systems 4 (Defaults) | RW | 7 | 3 | 0x7 | B |
| | | VDH_UV_CFG 00: 12 V Systems (Defaults) 01: 24 V Systems 10: 48 V Systems 11: VDH UV Disabled | RW | 5 | 2 | 0x0 | B |
| | | CRC | RW | 0 | 5 | 0x17 | B |

Table 121. SAFETY_RELEVANT3

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|------------------|---------|---|------|------------|-----------|-------------|-------|
| SAFETY_RELEVANT3 | 0x12 | CP2_DIS 0: Charge Pump 2 Enabled (Default) 1: Charge Pump 2 Disabled | RW | 15 | 1 | 0x0 | B |
| | | CP1_DIS 0: Charge Pump 1 Enabled (Default) 1: Charge Pump 1 Disabled | RW | 14 | 1 | 0x0 | B |
| SSR | | UNUSED_2 | RW | 13 | 1 | 0x0 | B |
| | | UNUSED_1 | RW | 12 | 1 | 0x0 | B |
| | | UNUSED_0 | RW | 11 | 1 | 0x0 | B |
| | | VBP_FLT_CFG 00: 12.25 μ s (Defaults) 01: 25 μ s 10: 50 μ s 11: 100 μ s | RW | 9 | 2 | 0x0 | B |
| | | VBP_OV_CFG 00: 12 V Systems 1 01: 12 V Systems 2 10: 24 V Systems 1 11: 24 V Systems 2 (Defaults) | RW | 7 | 2 | 0x0 | B |
| | | VBP_UV_CFG 00: 12 V Systems (Defaults) 01: 24 V Systems 10: 48 V Systems 11: VBP UV Disabled | RW | 5 | 2 | 0x0 | B |
| | | CRC | RW | 0 | 5 | 0x17 | B |

Table 122. CH1_STATUS1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH1_STATUS1 | 0x20 | UNUSED_7 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_6 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_5 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_4 | RO | 12 | 1 | 0x0 | A |
| | | UNUSED_3 | RO | 11 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 10 | 1 | 0x0 | A |
| | | LS1_OFF | RO | 9 | 1 | 0x0 | A |
| | | HS1_OFF | RO | 8 | 1 | 0x0 | A |
| | | LS1_STB | CR | 7 | 1 | 0x0 | A |
| | | HS1_STG | CR | 6 | 1 | 0x0 | A |
| | | LS1_OFD | RO | 5 | 1 | 0x0 | A |
| | | HS1_OFD | RO | 4 | 1 | 0x0 | A |
| | | UNUSED_1 | CR | 3 | 1 | 0x0 | A |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| NSR | | STP_VGS_1 | CR | 2 | 1 | 0x0 | A |
| | | STP_PWM_1 | CR | 1 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 0 | 1 | 0x0 | A |

Table 123. CH1_STATUS2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH1_STATUS2 | 0x21 | UNUSED_0 | RO | 15 | 1 | 0x0 | A |
| NSR | | CM1_READ | RO | 0 | 15 | 0x0 | A |

Table 124. CH1_CFG1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| CH1_CFG1 | 0x22 | UNUSED_1 | RW | 11 | 5 | 0x0 | B |
| SLR | | OFD1_EN 00: Off State Diagnosis disabled (Default) 01: Pull-up current enabled, Pull-down current disabled 10: Pull-down current enabled, Pull-up current disabled 11: Off State Diagnosis disabled | RW | 9 | 2 | 0x0 | B |
| | | OND1_DIS 0: ON State diagnosis enabled on HS and LS (Default) 1: ON State diagnosis disabled on HS and LS | RW | 8 | 1 | 0x0 | B |
| | | LS1_STB_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 7 | 1 | 0x0 | B |
| | | HS1_STG_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 6 | 1 | 0x0 | B |
| | | UNUSED_0 | RO | 15 | 1 | 0x0 | A |
| | | STP_VGS_1_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 4 | 1 | 0x0 | B |
| | | STP1_VGS_CFG 00: 0.2 μ s (Defaults) 01: 0.5 μ s 10: 1 μ s 11: 1.5 μ s | RW | 2 | 2 | 0x0 | B |
| | | STP1_PWM_CFG 00: 0.2 μ s (Defaults) 01: 0.5 μ s 10: 1 μ s 11: 1.5 μ s | RW | 0 | 2 | 0x0 | B |

Table 125. CH1_CFG2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| CH1_CFG2 | 0x23 | UNUSED | RW | 11 | 5 | 0x0 | B |
| SLR | | CSM1_SYNC_COUNT_CFG 00: 16Tclk (Default) 01: 24Tclk 10: 32Tclk 11: 40Tclk | RW | 9 | 2 | 0x0 | B |
| | | UNUSED_0 | RW | 8 | 1 | 0x0 | B |
| | | CSM1_SAMPLE_CFG 000: Free running – No T&H (Default) 001: T&H 1st data conversion from triggering 010: T&H 2nd data conversion from triggering 011: T&H 3rd data conversion from triggering 100: T&H 4th data conversion from triggering 101: T&H 5th data conversion from triggering 110: T&H 6th data conversion from triggering 111: T&H 7th data conversion from triggering | RW | 5 | 3 | 0x0 | B |
| | | CSM1_IN_RANGE_CFG 000: VIN_MAX = ±7 mV 001: VIN_MAX = ±18 mV 010: VIN_MAX = ±36 mV 011: VIN_MAX = ±90 mV 100: VIN_MAX = ±160 mV 101: VIN_MAX = ±300 mV (Default) 110: Reserved 111: Reserved | RW | 2 | 3 | 0x5 | B |
| | | CSM1_OFS 00: 0LSB DAC 01: 90LSB DAC 10: 1024LSB DAC 11: 1024LSB DAC (Default) | RW | 0 | 2 | 0x3 | B |

Table 126. CH1_CFG3

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|--|------|------------|-----------|-------------|-------|
| CH1_CFG3 | 0x24 | UNUSED_3 | RW | 15 | 1 | 0x0 | B |
| NSR | | UNUSED_2 | RW | 14 | 1 | 0x0 | B |
| | | UNUSED_1 | RW | 13 | 1 | 0x0 | B |
| | | UNUSED_0 | RW | 12 | 1 | 0x0 | B |
| | | ACT1_EN 0: ACT Disabled (Default) 1: ACT Enabled | RW | 11 | 1 | 0x0 | B |
| | | TSYNC1_CFG | RW | 0 | 11 | 0x0 | B |

Table 127. CH1_SAFETY_RELEVANT

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------------|---------|---|------|------------|-----------|-------------|-------|
| CH1_SAFETY_RELEVANT | 0x25 | UNUSED_4 | RW | 15 | 1 | 0x0 | B |
| SRR | | UNUSED_3 | RW | 14 | 1 | 0x0 | B |
| | | UNUSED_2 | RW | 13 | 1 | 0x0 | B |
| | | STP_VGS_1_REACT_CFG | RW | 11 | 2 | 0x0 | B |
| | | 00: Full SW Off – disable all HB drivers and CPs, device is sent in SAFE-OFF mode (Default) | | | | | |
| | | 01: Reduced Operation Mode – disable failing HB only, device is remain in NORMAL mode | | | | | |
| | | 10: Flag only – down-rate fault to simple warning, device is remain in NORMAL mode | | | | | |
| | | 11: Flag only – down-rate fault to simple warning, device is remain in NORMAL mode | | | | | |
| | | UNUSED_1 | RW | 10 | 1 | 0x0 | B |
| | | UNUSED_0 | RW | 9 | 1 | 0x0 | B |
| | | LS1_STB_REACT_CFG | RW | 7 | 2 | 0x0 | B |
| HS1_STG_REACT_CFG | RW | 5 | 2 | 0x0 | B | | |
| CRC | RW | 0 | 5 | 0x17 | B | | |

Table 128. CH1_ACT

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH1_ACT | 0x26 | UNUSED_3 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_2 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 12 | 1 | 0x0 | A |
| | | ACT1_OVF | RO | 11 | 1 | 0x0 | A |
| | | ACT1 | RO | 0 | 11 | 0x0 | A |

Table 129. CH2_STATUS1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH2_STATUS1 | 0x28 | UNUSED_7 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_6 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_5 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_4 | RO | 12 | 1 | 0x0 | A |
| | | UNUSED_3 | RO | 11 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 10 | 1 | 0x0 | A |
| | | LS2_OFF | RO | 9 | 1 | 0x0 | A |
| | | HS2_OFF | RO | 8 | 1 | 0x0 | A |
| | | LS2_STB | CR | 7 | 1 | 0x0 | A |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| NSR | | HS2_STG | CR | 6 | 1 | 0x0 | A |
| | | LS2_OFD | RO | 5 | 1 | 0x0 | A |
| | | HS2_OFD | RO | 4 | 1 | 0x0 | A |
| | | UNUSED_1 | CR | 3 | 1 | 0x0 | A |
| | | STP_VGS_2 | CR | 2 | 1 | 0x0 | A |
| | | STP_PWM_2 | CR | 1 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 0 | 1 | 0x0 | A |

Table 130. CH2_STATUS2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH2_STATUS2 | 0x29 | UNUSED_0 | RO | 15 | 1 | 0x0 | A |
| NSR | | CM2_READ | RO | 0 | 15 | 0x0 | A |

Table 131. CH2_CFG1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| CH2_CFG1 | 0x2A | UNUSED_1 | RW | 11 | 5 | 0x0 | B |
| SLR | | OFD2_EN 00: Off State Diagnosis disabled (Default) 01: Pull-up current enabled, Pull-down current disabled 10: Pull-down current enabled, Pull-up current disabled 11: Off State Diagnosis disabled | RW | 9 | 2 | 0x0 | B |
| | | OND2_DIS 0: ON State diagnosis enabled on HS and LS (Default) 1: ON State diagnosis disabled on HS and LS | RW | 8 | 1 | 0x0 | B |
| | | LS2_STB_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 7 | 1 | 0x0 | B |
| | | HS2_STG_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 6 | 1 | 0x0 | B |
| | | UNUSED_0 | RO | 15 | 1 | 0x0 | A |
| | | STP_VGS_2_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 4 | 1 | 0x0 | B |
| | | STP2_VGS_CFG 00: 0.2 μ s (Defaults) 01: 0.5 μ s 10: 1 μ s 11: 1.5 μ s | RW | 2 | 2 | 0x0 | B |
| | | STP2_PWM_CFG 00: 0.2 μ s (Defaults) | RW | 0 | 2 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| SLR | | 01: 0.5 μ s 10: 1 μ s 11: 1.5 μ s | | | | | |

Table 132. CH2_CFG2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| CH2_CFG2 | 0x2B | UNUSED | RW | 11 | 5 | 0x0 | B |
| SLR | | CSM2_SYNC_COUNT_CFG 00: 16Tclk (Default) 01: 24Tclk 10: 32Tclk 11: 40Tclk | RW | 9 | 2 | 0x0 | B |
| | | UNUSED_0 | RW | 8 | 1 | 0x0 | B |
| | | CSM2_SAMPLE_CFG 000: Free running – No T&H (Default) 001: T&H 1st data conversion from triggering 010: T&H 2nd data conversion from triggering 011: T&H 3rd data conversion from triggering 100: T&H 4th data conversion from triggering 101: T&H 5th data conversion from triggering 110: T&H 6th data conversion from triggering 111: T&H 7th data conversion from triggering | RW | 5 | 3 | 0x0 | B |
| | | CSM2_IN_RANGE_CFG 000: VIN_MAX = \pm 7mV 001: VIN_MAX = \pm 18 mV 010: VIN_MAX = \pm 36 mV 011: VIN_MAX = \pm 90 mV 100: VIN_MAX = \pm 160 mV 101: VIN_MAX = \pm 300 mV (Default) 110: Reserved 111: Reserved | RW | 2 | 3 | 0x5 | B |
| | | CSM2_OFS 00: 0LSB DAC 01: 90LSB DAC 10: 1024LSB DAC 11: 1024LSB DAC (Default) | RW | 0 | 2 | 0x3 | B |

Table 133. CH2_CFG3

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH2_CFG3 | 0x2C | UNUSED_3 | RW | 15 | 1 | 0x0 | B |
| NSR | | UNUSED_2 | RW | 14 | 1 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|--|------|------------|-----------|-------------|-------|
| NSR | | UNUSED_1 | RW | 13 | 1 | 0x0 | B |
| | | UNUSED_0 | RW | 12 | 1 | 0x0 | B |
| | | ACT2_EN 0: ACT Disabled (Default) 1: ACT Enabled | RW | 11 | 1 | 0x0 | B |
| | | TSYNC2_CFG | RW | 0 | 11 | 0x0 | B |

Table 134. CH2_SAFETY_RELEVANT

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------------|---------|---|------|------------|-----------|-------------|-------|
| CH2_SAFETY_RELEVANT | 0x2D | UNUSED_4 | RW | 15 | 1 | 0x0 | B |
| SRR | | UNUSED_3 | RW | 14 | 1 | 0x0 | B |
| | | UNUSED_2 | RW | 13 | 1 | 0x0 | B |
| | | STP_VGS_2_REACT_CFG 00: Full SW Off – disable all HB drivers and CPs, device is sent in SAFE-OFF mode (Default) 01: Reduced Operation Mode – disable failing HB only, device remains in NORMAL mode 10: Flag only – down-rate fault to simple warning, device remains in NORMAL mode 11: Flag only – down-rate fault to simple warning, device remains in NORMAL mode | RW | 11 | 2 | 0x0 | B |
| | | UNUSED_1 | RW | 10 | 1 | 0x0 | B |
| | | UNUSED_0 | RW | 9 | 1 | 0x0 | B |
| | | LS2_STB_REACT_CFG | RW | 7 | 2 | 0x0 | B |
| | | HS2_STG_REACT_CFG | RW | 5 | 2 | 0x0 | B |
| | | CRC | RW | 0 | 5 | 0x17 | B |

Table 135. CH2_ACT

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH2_ACT | 0x2E | UNUSED_3 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_2 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 12 | 1 | 0x0 | A |
| | | ACT2_OVF | RO | 11 | 1 | 0x0 | A |
| | | ACT2 | RO | 0 | 11 | 0x0 | A |

Table 136. CH3_STATUS1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH3_STATUS1 | 0x30 | UNUSED_7 | RO | 15 | 1 | 0x0 | A |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| NSR | | UNUSED_6 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_5 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_4 | RO | 12 | 1 | 0x0 | A |
| | | UNUSED_3 | RO | 11 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 10 | 1 | 0x0 | A |
| | | LS3_OFF | RO | 9 | 1 | 0x0 | A |
| | | HS3_OFF | RO | 8 | 1 | 0x0 | A |
| | | LS3_STB | CR | 7 | 1 | 0x0 | A |
| | | HS3_STG | CR | 6 | 1 | 0x0 | A |
| | | LS3_OFD | RO | 5 | 1 | 0x0 | A |
| | | HS3_OFD | RO | 4 | 1 | 0x0 | A |
| | | UNUSED_1 | CR | 3 | 1 | 0x0 | A |
| | | STP_VGS_3 | CR | 2 | 1 | 0x0 | A |
| | | STP_PWM_3 | CR | 1 | 1 | 0x0 | A |
| UNUSED_0 | RO | 0 | 1 | 0x0 | A | | |

Table 137. CH3_STATUS2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH3_STATUS2 | 0x31 | UNUSED_0 | RO | 15 | 1 | 0x0 | A |
| NSR | | CM3_READ | RO | 0 | 15 | 0x0 | A |

Table 138. CH3_CFG1

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| CH3_CFG1 | 0x32 | UNUSED_1 | RW | 11 | 5 | 0x0 | B |
| SLR | | OFD3_EN 00: Off State Diagnosis disabled (Default) 01: Pull-up current enabled, Pull-down current disabled 10: Pull-down current enabled, Pull-up current disabled 11: Off State Diagnosis disabled | RW | 9 | 2 | 0x0 | B |
| | | OND3_DIS 0: ON State diagnosis enabled on HS and LS (Default) 1: ON State diagnosis disabled on HS and LS | RW | 8 | 1 | 0x0 | B |
| | | LS3_STB_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 7 | 1 | 0x0 | B |
| | | HS3_STG_REDIRECT_CFG 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | RW | 6 | 1 | 0x0 | B |
| | | UNUSED_0 | RO | 15 | 1 | 0x0 | A |
| | | STP_VGS_3_REDIRECT_CFG | RW | 4 | 1 | 0x0 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| SLR | | 0: Fault redirected on FS_FLAG/IC ERR (Default) 1: Fault redirection masked | | | | | |
| | | STP3_VGS_CFG 00: 0.2 μ s (Defaults) 01: 0.5 μ s 10: 1 μ s 11: 1.5 μ s | RW | 2 | 2 | 0x0 | B |
| | | STP3_PWM_CFG 00: 0.2 μ s (Defaults) 01: 0.5 μ s 10: 1 μ s 11: 1.5 μ s | RW | 0 | 2 | 0x0 | B |

Table 139. CH3_CFG2

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---|------|------------|-----------|-------------|-------|
| CH3_CFG2 | 0x33 | UNUSED | RW | 11 | 5 | 0x0 | B |
| SLR | | CSM3_SYNC_COUNT_CFG 00: 16Tclk (Default) 01: 24Tclk 10: 32Tclk 11: 40Tclk | RW | 9 | 2 | 0x0 | B |
| | | UNUSED_0 | RW | 8 | 1 | 0x0 | B |
| | | CSM3_SAMPLE_CFG 000: Free running – No T&H (Default) 001: T&H 1st data conversion from triggering 010: T&H 2nd data conversion from triggering 011: T&H 3rd data conversion from triggering 100: T&H 4th data conversion from triggering 101: T&H 5th data conversion from triggering 110: T&H 6th data conversion from triggering 111: T&H 7th data conversion from triggering | RW | 5 | 3 | 0x0 | B |
| | | CSM3_IN_RANGE_CFG 000: VIN_MAX = \pm 7 mV 001: VIN_MAX = \pm 18 mV 010: VIN_MAX = \pm 36 mV 011: VIN_MAX = \pm 90 mV 100: VIN_MAX = \pm 160 mV 101: VIN_MAX = \pm 300 mV (Default) 110: Reserved 111: Reserved | RW | 2 | 3 | 0x5 | B |
| | | CSM3_OFS 00: 0LSB DAC | RW | 0 | 2 | 0x3 | B |

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|---------------------------|------|------------|-----------|-------------|-------|
| SLR | | 01: 90LSB DAC | | | | | |
| | | 10: 1024LSB DAC | | | | | |
| | | 11: 1024LSB DAC (Default) | | | | | |
| | | 0 | 0 | 0 | 0 | 0 | 0 |

Table 140. CH3_CFG3

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset | |
|---------------|---------|---------------------------|------|------------|-----------|-------------|-------|--|
| CH3_CFG3 | 0x34 | UNUSED_3 | RW | 15 | 1 | 0x0 | B | |
| NSR | | UNUSED_2 | RW | 14 | 1 | 0x0 | B | |
| | | UNUSED_1 | RW | 13 | 1 | 0x0 | B | |
| | | UNUSED_0 | RW | 12 | 1 | 0x0 | B | |
| | | ACT3_EN | | | | | | |
| | | 0: ACT Disabled (Default) | RW | 11 | 1 | 0x0 | B | |
| | | 1: ACT Enabled | | | | | | |
| | | TSYNC3_CFG | RW | 0 | 11 | 0x0 | B | |

Table 141. CH3_SAFETY_RELEVANT

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset | |
|---------------------|---------|---|------|------------|-----------|-------------|-------|--|
| CH3_SAFETY_RELEVANT | 0x35 | UNUSED_4 | RW | 15 | 1 | 0x0 | B | |
| SRR | | UNUSED_3 | RW | 14 | 1 | 0x0 | B | |
| | | UNUSED_2 | RW | 13 | 1 | 0x0 | B | |
| | | STP_VGS_3_REACT_CFG | | | | | | |
| | | 00: Full SW Off – disable all HB drivers and CPs, device is sent in SAFE-OFF mode (Default) | | | | | | |
| | | 01: Reduced Operation Mode – disable failing HB only, device remains in NORMAL mode | RW | 11 | 2 | 0x0 | B | |
| | | 10: Flag only – down-rate fault to simple warning, device remains in NORMAL mode | | | | | | |
| | | 11: Flag only – down-rate fault to simple warning, device remains in NORMAL mode | | | | | | |
| | | UNUSED_1 | RW | 10 | 1 | 0x0 | B | |
| | | UNUSED_0 | RW | 9 | 1 | 0x0 | B | |
| | | LS3_STB_REACT_CFG | RW | 7 | 2 | 0x0 | B | |
| HS3_STG_REACT_CFG | RW | 5 | 2 | 0x0 | B | | | |
| | | CRC | RW | 0 | 5 | 0x17 | B | |

Table 142. CH3_ACT

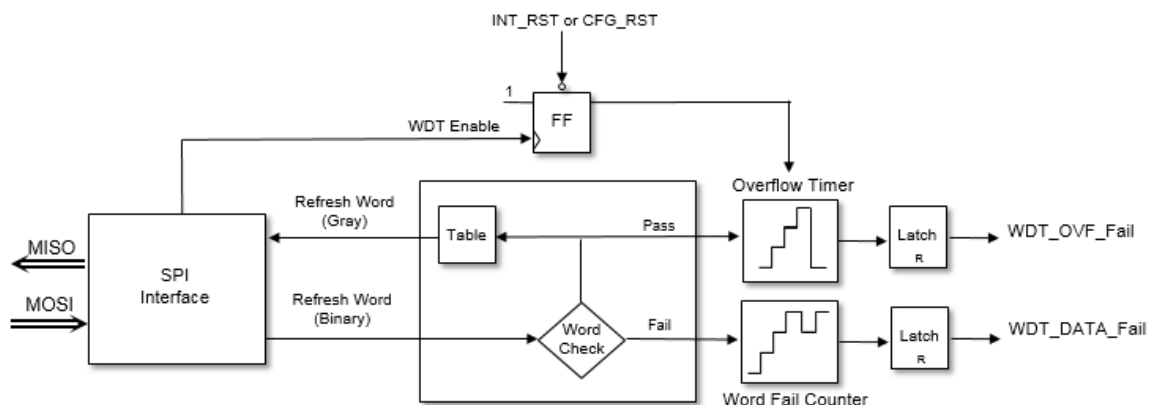
| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|------------|------|------------|-----------|-------------|-------|
| CH3_ACT | 0x36 | UNUSED_3 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_2 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 13 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 12 | 1 | 0x0 | A |
| | | ACT3_OVF | RO | 11 | 1 | 0x0 | A |
| | | ACT3 | RO | 0 | 11 | 0x0 | A |

Table 143. SPI_CMM_FAULT

| Register Name | Address | Field Name | Type | Bit Offset | Bit Width | Reset Value | Reset |
|---------------|---------|--|------|------------|-----------|-------------|-------|
| SPI_CMM_FAULT | 0xFD | UNUSED_11 | RO | 15 | 1 | 0x0 | A |
| NSR | | UNUSED_10 | RO | 14 | 1 | 0x0 | A |
| | | UNUSED_9 | RO | 13 | 1 | 0x0 | A |
| | | FCNTERR Wrong Frame Counter bit | CR | 12 | 1 | 0x0 | A |
| | | CRCERR Wrong CRC check value | CR | 11 | 1 | 0x0 | A |
| | | SHORTERR Previous SPI frame length<32 bit | CR | 10 | 1 | 0x0 | A |
| | | LONGERR Previous SPI frame length>32 bit | CR | 9 | 1 | 0x0 | A |
| | | UNUSED_8 | RO | 8 | 1 | 0x0 | A |
| | | UNUSED_7 | RO | 7 | 1 | 0x0 | A |
| | | UNUSED_6 | RO | 6 | 1 | 0x0 | A |
| | | UNUSED_5 | RO | 5 | 1 | 0x0 | A |
| | | UNUSED_4 | RO | 4 | 1 | 0x0 | A |
| | | UNUSED_3 | RO | 3 | 1 | 0x0 | A |
| | | UNUSED_2 | RO | 2 | 1 | 0x0 | A |
| | | UNUSED_1 | RO | 1 | 1 | 0x0 | A |
| | | UNUSED_0 | RO | 0 | 1 | 0x0 | A |

5.21 Window Watchdog Timer (WTD)

L9908 implements a watchdog timer function to ensure a safe SPI communication with μ C in case of corrupted or lost SPI communication.

Figure 85. Watchdog Timer simplified block diagram


Watchdog timer function can be enabled by the SPI signal WDT_EN in the register GEN_CFG1:

Table 144. Watchdog enable bit

| WDT_EN | Description |
|--------|-----------------------------|
| 0 | Watchdog disabled (Default) |
| 1 | Watchdog enabled |

Once enabled, WDT_EN can be reset to disable only by INT_RST = 0 or CFG_RST = 0.

Activation status of WDT is also stored in the SPI read only register WD_ON_STATUS: WD_ON_STATUS = 0 WDT is not active, WD_ON_STATUS = 1 WDT is active.

As soon as the watchdog is enabled the overflow counter is started thus defining the available refresh window Twdt_ovf which length is defined by the SPI register WDT_OVF_CFG.

Table 145. Watchdog configuration table for WDT overflow timer

| WDT_OVF_CFG1 | WDT_OVF_CFG0 | Description |
|--------------|--------------|--------------------|
| 0 | 0 | 11.26 ms |
| 0 | 1 | 22.52 ms (Default) |
| 1 | 0 | 45.04 ms |
| 1 | 1 | 90.11 ms |

The WDT overflow counter status can be accessed through the dedicated SPI read only register WDT_OVF_STATUS.

The counter value in seconds can be retrieved by the following reconstruction formula:

$$T_{WDT_OVF_STATUS} = \Delta_{WDT_OVF_LSB} \times D_{WDT_OVF_STATUS} \quad (27)$$

Where: D_{WDT_OVF} is the digital word stored in WDT_OVF_STATUS and $\Delta_{WDT_OVF_LSB}$ is the counter LSB as defined in Table 146.

Table 146. WDT overflow timer LSB

| WDT_OVF_CFG | Description |
|-------------|---------------------|
| 00 | 0.2048 ms |
| 01 | 0.4096 ms (Default) |
| 10 | 0.8192 ms |

| WDT_OVF_CFG | Description |
|-------------|-------------|
| 11 | 1.6384 ms |

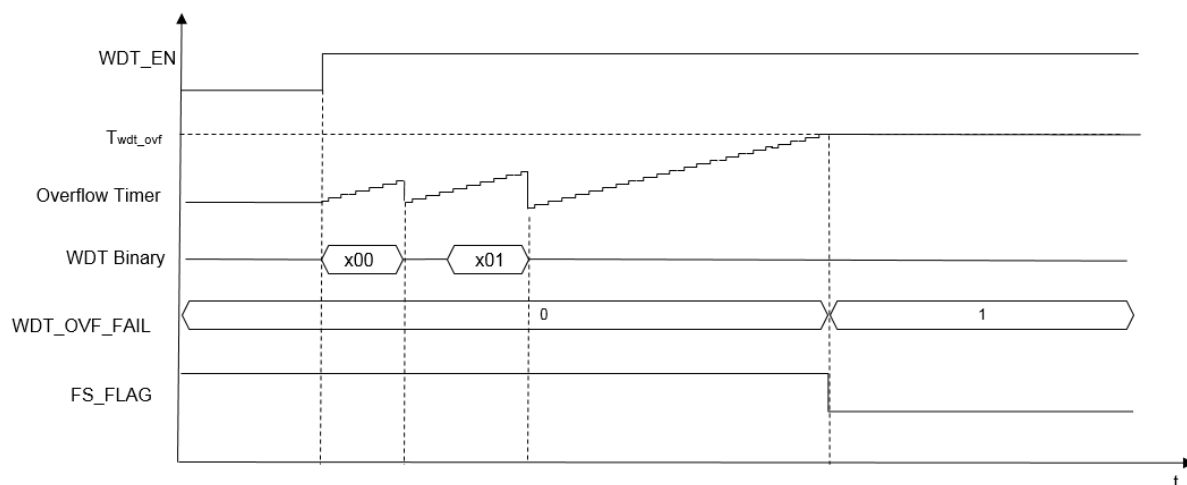
Reprogramming of WDT_OVF_CFG configuration is possible only while WDT_EN = 0

Table 147. WDT overflow counter accuracy

| Symbol | Parameter | Min | Typ | Max | Unit |
|-------------|-------------------------------|-----|-----|-----|------|
| WDT_ovf_acc | WDT overflow counter accuracy | -10 | - | 10 | % |

Within this window the watchdog expects a refresh pulse to reset the overflow counter and restart a new window: if refresh is missed before the overflow counter is elapsed the error flag WDT_OVF_Fail is set and L9908 is sent to safe state. The flag remains set until the WDT is reset by the SPI command or re-enabled after a power-on sequence.

Figure 86. WDT Operation – Overflow timer failure



The refresh of the overflow counter has to be performed by the uC through a dedicated SPI frame including the 4-bit watchdog refresh command. The watchdog circuitry compares the received watchdog refresh command with an internal look-up table and answers with a corresponding 4-bit Gray code in the next SPI MISO frame.

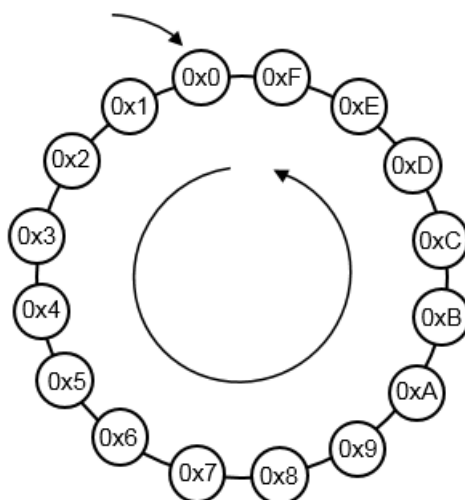
Table 148. Watchdog Binary to Gray answer conversion

| Binary (μC) → Gray (L9908) | Binary → (μC) → Gray (L9908) | Binary (μC) → Gray (L9908) | Binary (μC) → Gray (L9908) |
|----------------------------|------------------------------|----------------------------|----------------------------|
| 0x0 (0000) → 0x0 (0000) | 0x4 (0100) → 0x6 (0110) | 0x8 (1000) → 0xC (1100) | 0xC (1100) → 0xA (1010) |
| 0x1 (0001) → 0x1 (0001) | 0x5 (0101) → 0x7 (0111) | 0x9 (1001) → 0xD (1101) | 0xD (1101) → 0xB (1011) |
| 0x2 (0010) → 0x3 (0011) | 0x6 (0110) → 0x5 (0101) | 0xA (1010) → 0xF (1111) | 0xE (1110) → 0x9 (1001) |
| 0x3 (0011) → 0x2 (0010) | 0x7 (0111) → 0x4 (0100) | 0xB (1011) → 0xE (1110) | 0xF (1111) → 0x8 (1000) |

The expected watchdog command order starts with number 0x0 (0000) and is incremented by 1 at each refresh window if the command is correctly interpreted and no failure is detected.

Once command number 0xF (1111) is reached the sequence restarts with number 0x0 (0000).

Figure 87. Watchdog command order sequence



In case of a wrong WDT data command (command different from the expected sequence order), the watchdog word fail counter is incremented by 1. With the next valid watchdog data command the fail counter is decreased by 1. If the failure counter reaches the failure limit defined in the SPI register WDT_FAIL_COUNT_CFG the watchdog fail flag WDT_DATA_fail is set and L9908 is sent to safe state.

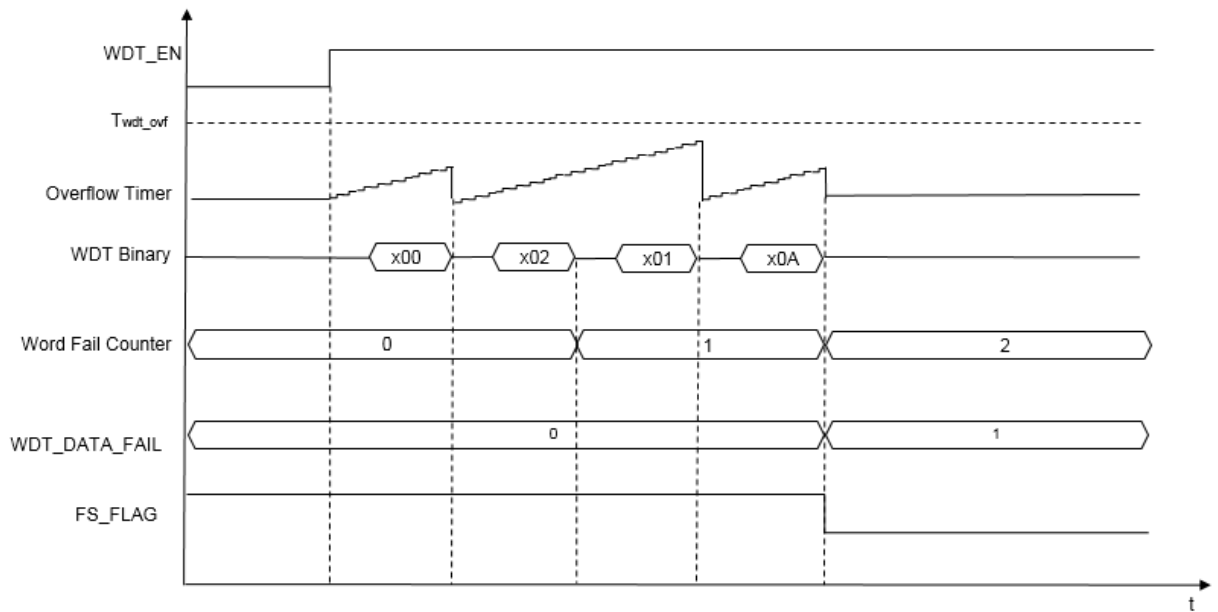
The fail counter limit can be programmed by the following SPI bit set:

Table 149. Watchdog configuration table for WDT data fail counter

| WDT_FAIL_COUNT_CFG1 | WDT_FAIL_COUNT_CFG0 | Description |
|---------------------|---------------------|-------------|
| 0 | 0 | 1 |
| 0 | 1 | 1 |
| 1 | 0 | 2 |
| 1 | 1 | 3 (Default) |

The information about the number of encountered WDT data failures is stored in the dedicated SPI register WDT_FAIL_COUNT_STATUS.

Figure 88. WDT Operation – Word sequence failure



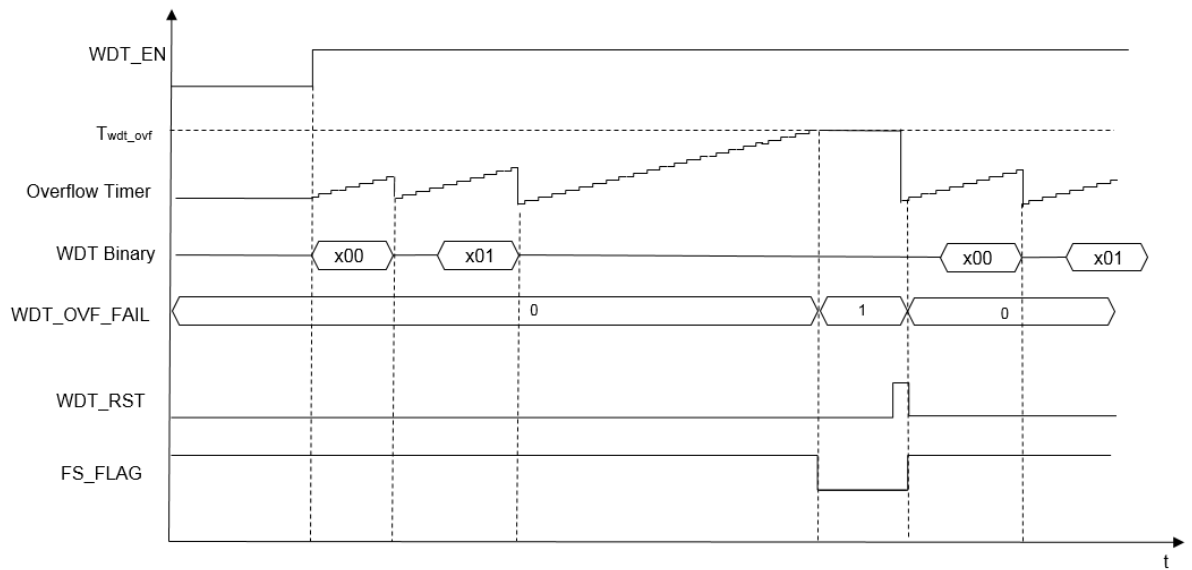
In case of failure ($WDT_OVF_fail = 1$ or $WDT_DATA_fail = 1$) the WDT can be reset by setting to 10 the SPI register command WDT_RESET .

Table 150. Watchdog RESET bits

| WDT_RST1 | WDT_RST0 | Description |
|----------|----------|--------------------|
| 0 | 0 | NO Reset |
| 0 | 1 | NO Reset (Default) |
| 1 | 0 | Reset |
| 1 | 1 | NO Reset |

Note: This command is processed by the logic only if a failure is detected ($WDT_OVF_fail = 1$ or $WDT_DATA_fail = 1$). The WDT_RESET doesn't reset the WDT_EN bit but only the error flag: μC needs to refresh the WDT properly afterwards.

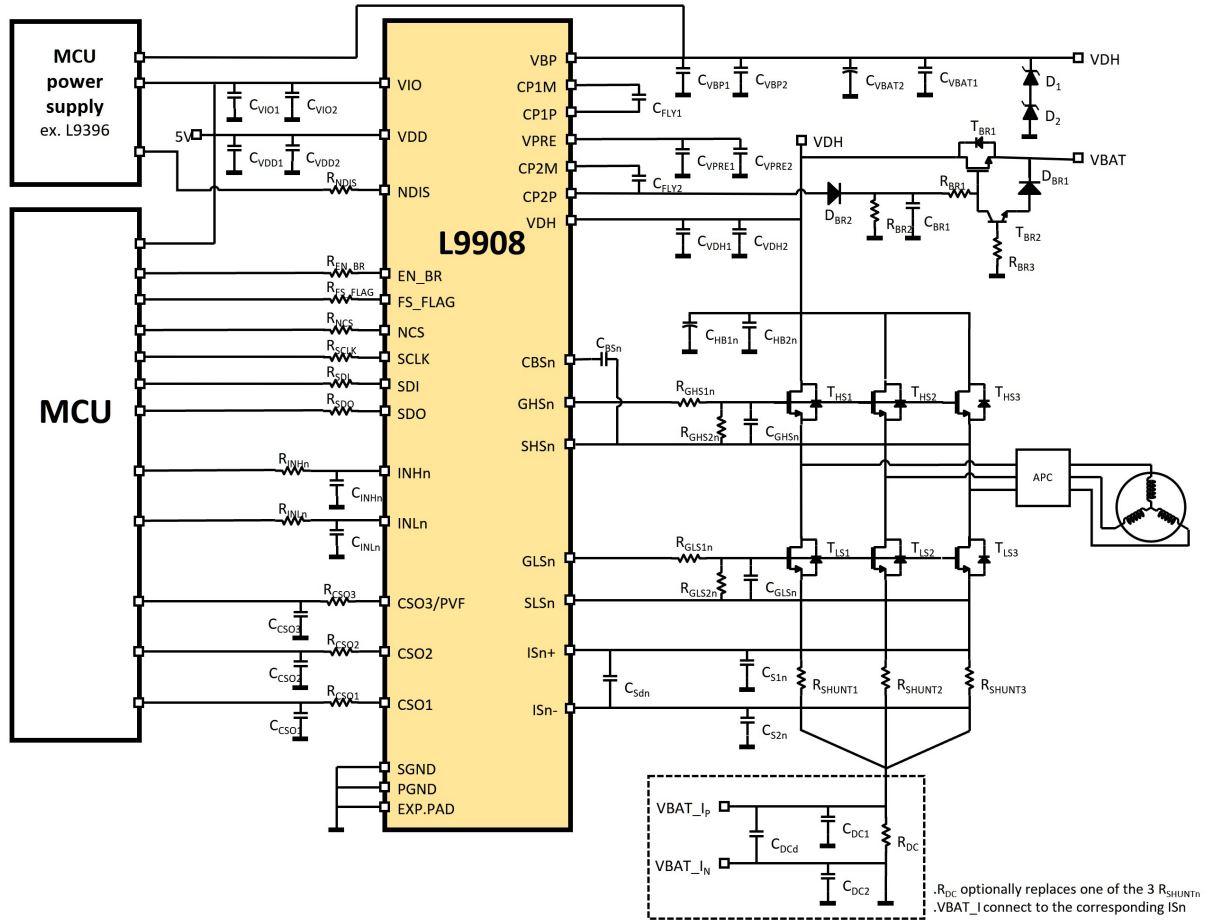
Figure 89. WDT Operation – WDT Reset after overflow timer failure



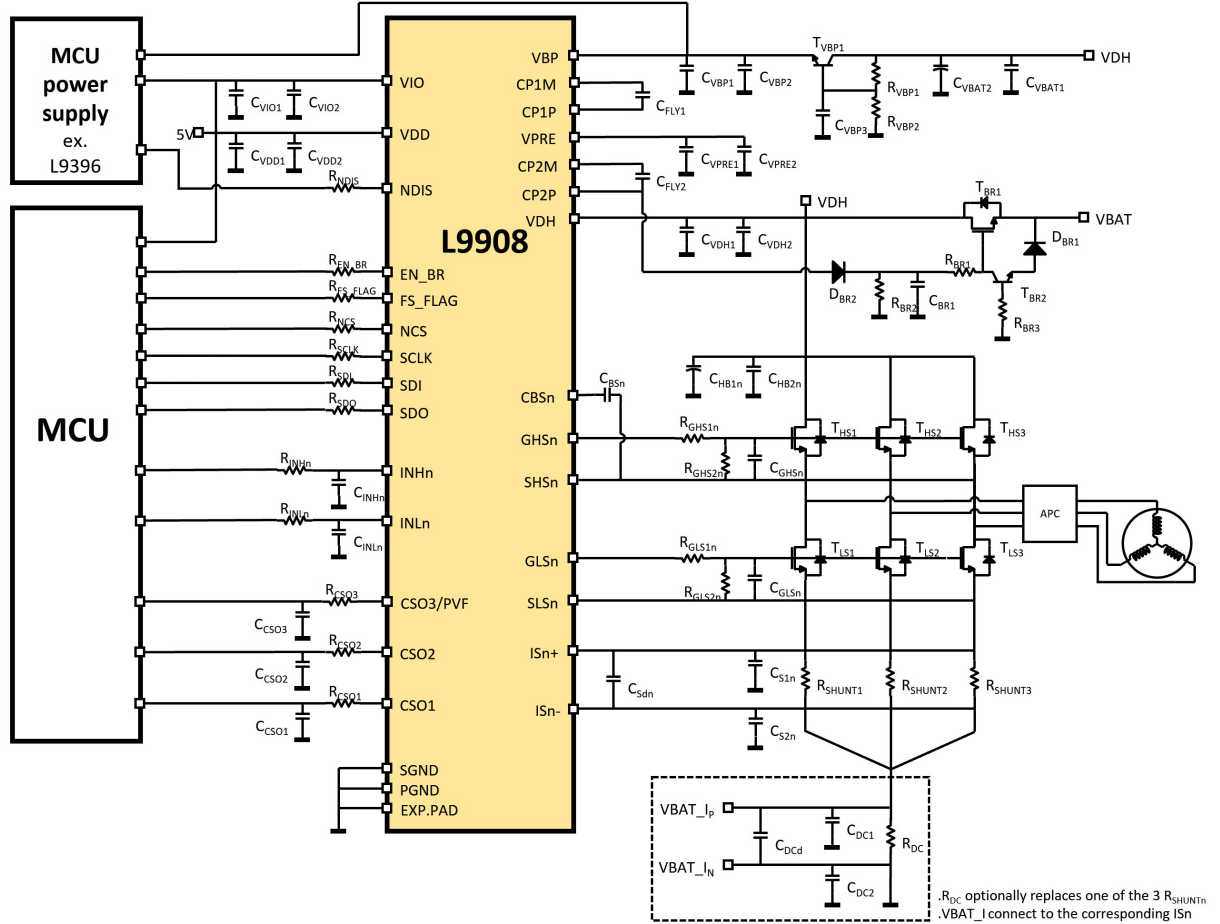
6 Application circuit

6.1 12 V/24 V systems

Figure 90. Application circuit, 12 V/24 V systems



6.2 48 V systems

Figure 91. Application circuit, 48 V systems


6.3 Bill of materials

The following table summarizes the suggested BOM for both systems shown on Figure 90 and Figure 91.

Table 151. Application circuit - BOM

| Component | Min | Typ | Max | Unit | Minimum requirement | | | Comment |
|------------|-----|-----|-----|---------|---------------------|--------------|--------------|---|
| | | | | | 12 V systems | 24 V systems | 48 V systems | |
| C_{BR1} | - | 390 | - | nF | 50 V | | 100 V | - |
| C_{BSn} | - | 1 | - | μ F | | 25 V | | - |
| C_{CSO1} | - | 220 | - | pF | | 6.3 V | | With $R_{CSO1,2,3}$, is mandatory for CSO signal stability |
| C_{CSO2} | - | 220 | - | pF | | 6.3 V | | |
| C_{CSO3} | - | 220 | - | pF | | 6.3 V | | |
| C_{DC1} | - | 10 | - | nF | | 6.3 V | | Max tolerance $\pm 5\%$ to be mounted close to R_{DC} |
| C_{DC2} | - | 10 | - | nF | | 6.3 V | | Max tolerance $\pm 5\%$ to be mounted close to R_{DC} |
| C_{DCd} | - | 220 | - | nF | | 6.3 V | | To be mounted close to pin |

| Component | Min | Typ | Max | Unit | Minimum requirement | | | Comment |
|--------------------|-----|-----|-----|------|---------------------|--------------|--------------|--|
| | | | | | 12 V systems | 24 V systems | 48 V systems | |
| C _{FLY1} | - | 1 | - | μF | 50 V | 100 V | | - |
| C _{FLY2} | - | 1 | - | μF | 50 V | 100 V | | - |
| C _{GHSn} | - | - | - | | 16 V | | | Optional |
| C _{GLSn} | - | - | - | | 16 V | | | Optional |
| C _{HB1n} | - | 100 | - | nF | 50 V | 100 V | | - |
| C _{HB2n} | - | 220 | - | μF | 50 V | 100 V | | - |
| C _{INHn} | - | 10 | - | pF | 6.3 V | | | Optional |
| C _{INLn} | - | 10 | - | pF | 6.3 V | | | Optional |
| C _{S1n} | - | 10 | - | nF | 6.3 V | | | Max tolerance ±5% to be mounted close to R _{SHUNTn} |
| C _{S2n} | - | 10 | - | nF | 6.3 V | | | Max tolerance ±5% to be mounted close to R _{SHUNTn} |
| C _{Sdn} | - | 220 | - | nF | 6.3 V | | | To be mounted close to pin |
| C _{VBAT1} | - | 100 | - | nF | 50 V | 100 V | | - |
| C _{VBAT2} | - | 10 | - | μF | 50 V | 100 V | | - |
| C _{VBP1} | - | 1 | - | μF | 50 V | 100 V | 16 V | - |
| C _{VBP2} | - | 100 | - | nF | 50 V | 100 V | 16 V | To be mounted close to pin |
| C _{VBP3} | - | 100 | - | nF | n.a. | | 50 V | - |
| C _{VDD1} | - | 1 | - | μF | 6.3 V | | | - |
| C _{VDD2} | - | 100 | - | nF | 6.3 V | | | To be mounted close to pin |
| C _{VDH1} | - | 100 | - | nF | 50 V | 100 V | | To be mounted close to pin |
| C _{VDH2} | - | 1 | - | μF | 50 V | 100 V | | - |
| C _{VIO1} | - | 1 | - | μF | 6.3 V | | | - |
| C _{VIO2} | - | 100 | - | nF | 6.3 V | | | To be mounted close to pin |
| C _{VPRE1} | - | 4.7 | 6.8 | μF | 16 V | | | Max tolerance ±20% |
| C _{VPRE1} | - | 4.7 | 6.8 | μF | n.a. | 16 V | | Max tolerance ±20% |
| C _{VPRE2} | - | 100 | - | nF | 16 V | | | To be mounted close to pin |
| D ₁ | - | - | - | | SMA6T39AY | SMA6T56AY | n.a. | - |
| D ₂ | - | - | - | | Short | SMA6T6V7AY | | - |
| D _{BR1} | - | - | - | - | STPS3L60 | | | - |
| D _{BR2} | - | - | - | - | STPS0520Z | | | - |
| R _{VBP1} | - | 22 | - | kΩ | - | | | - |
| R _{VBP2} | - | 22 | - | kΩ | - | | | - |
| R _{BR1} | - | 1 | - | kΩ | - | | | - |
| R _{BR2} | - | 39 | - | kΩ | - | | | - |
| R _{BR3} | - | 22 | - | kΩ | - | | | - |
| R _{CSO1} | - | 1 | - | kΩ | - | | | With C _{CSO1,2,3} , is mandatory for CSO signal stability |
| R _{CSO2} | - | 1 | - | kΩ | - | | | |

| Component | Min | Typ | Max | Unit | Minimum requirement | | | Comment |
|----------------------|-----|-----|-----|------|---------------------|---------------|--------------|--|
| | | | | | 12 V systems | 24 V systems | 48 V systems | |
| R _{CSO3} | - | 1 | - | kΩ | - | | | With C _{CSO1,2,3} , is mandatory for CSO signal stability |
| R _{DC} | - | 4 | - | mΩ | WSL10204L000FEA | | | - |
| R _{EN_BR} | - | 100 | - | Ω | - | | | Optional |
| R _{FS_FLAG} | - | 100 | - | Ω | - | | | Optional |
| R _{GHS1n} | - | 47 | - | Ω | - | | | - |
| R _{GHS2n} | - | 100 | - | kΩ | - | | | - |
| R _{GLS1n} | - | 47 | - | Ω | - | | | - |
| R _{GLS2n} | - | 100 | - | kΩ | - | | | - |
| R _{INHn} | - | 100 | - | Ω | - | | | Optional |
| R _{INLn} | - | 100 | - | Ω | - | | | Optional |
| R _{NCS} | - | 100 | - | Ω | - | | | Optional |
| R _{NDIS} | - | 100 | - | Ω | - | | | Optional |
| R _{SCLK} | - | 100 | - | Ω | - | | | Optional |
| R _{SDI} | - | 100 | - | Ω | - | | | Optional |
| R _{SDO} | - | 100 | - | Ω | - | | | Optional |
| R _{SHUNTn} | - | 4 | - | mΩ | WSL10204L000FEA | | | - |
| T _{BR1} | - | - | - | - | STL225N6F7AG | STH275N8F7 | | - |
| T _{BR2} | - | - | - | - | BCP56-16 | | | - |
| T _{VBP1} | - | - | - | - | BCP56-16 | | | - |
| T _{HSn} | - | - | - | - | STL225N6F7AG | STD105N10F7AG | | - |
| T _{LSn} | - | - | - | - | STL225N6F7AG | STD105N10F7AG | | - |

6.4 Layout guidelines

The following layout guidelines apply to any of the above shown application circuits.

- Three separated bulk capacitors CHB1 should be used - one per half bridge.
- Three separated ceramic capacitors CHB2 should be used - one per half bridge.
- Each of the 3 bulk capacitors CHB1 and each of the 3 ceramic capacitors CHB2 should be assigned to one of the half bridges and should be placed very close to it.
- The components within one half bridge should be placed close to each other to reduce stray inductance to a minimum: high-side MOSFET, low-side MOSFET, bulk capacitor CHB1, ceramic capacitor CHB2 and the shunt resistor RSHUNT form a loop that should be as small and tight as possible. The traces should be short and wide.
- The three half bridges can be separated; however, when there is one common GND referenced shunt resistor (RDC) for the three half bridges the sources of all low-side MOSFETs should be close to each other and close to the common shunt resistor.
- Additional R-C snubber circuits can be placed to attenuate/suppress oscillations during switching of the MOSFETs, there may be one or two snubber circuits per half bridge and components must be low inductive in terms of routing and packaging (ceramic capacitors).
- The exposed pad on the backside of the package shall be connected to GND.

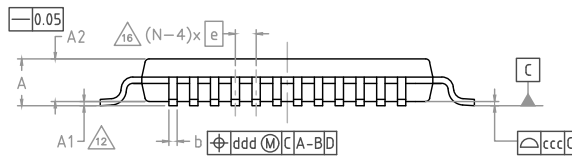
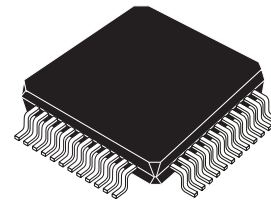
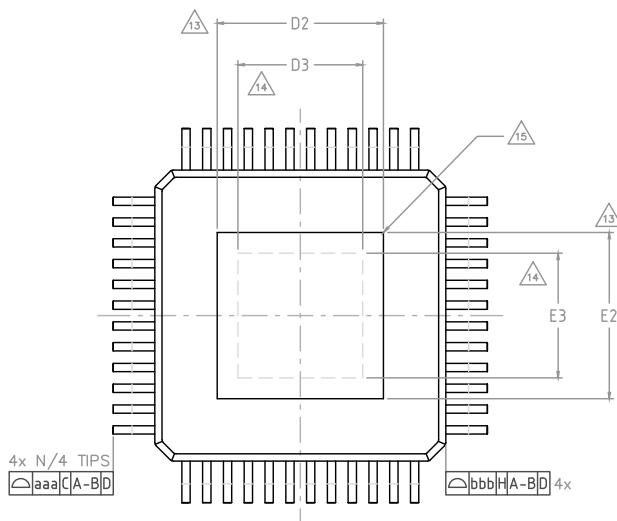
7 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

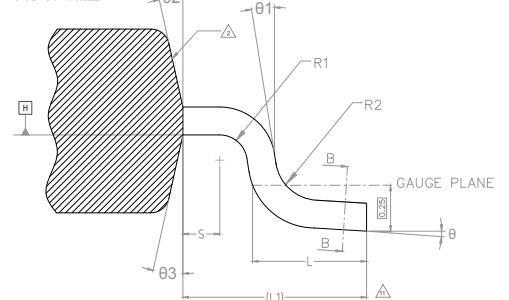
7.1 TQFP48 (7x7x1 mm exp. pad down) package information

Figure 92. TQFP48 (7x7x1 mm exp. pad down) package outline

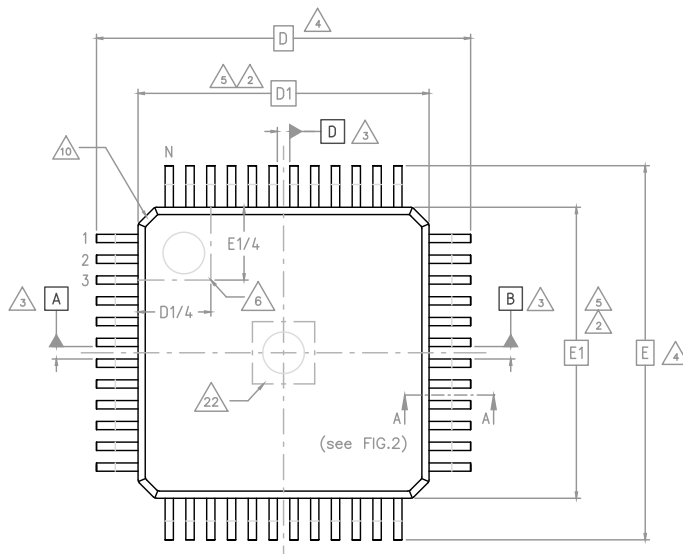
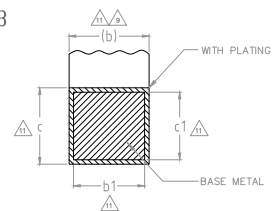
BOTTOM VIEW



SECTION A-A NOT TO SCALE



SECTION B-B NOT TO SCALE

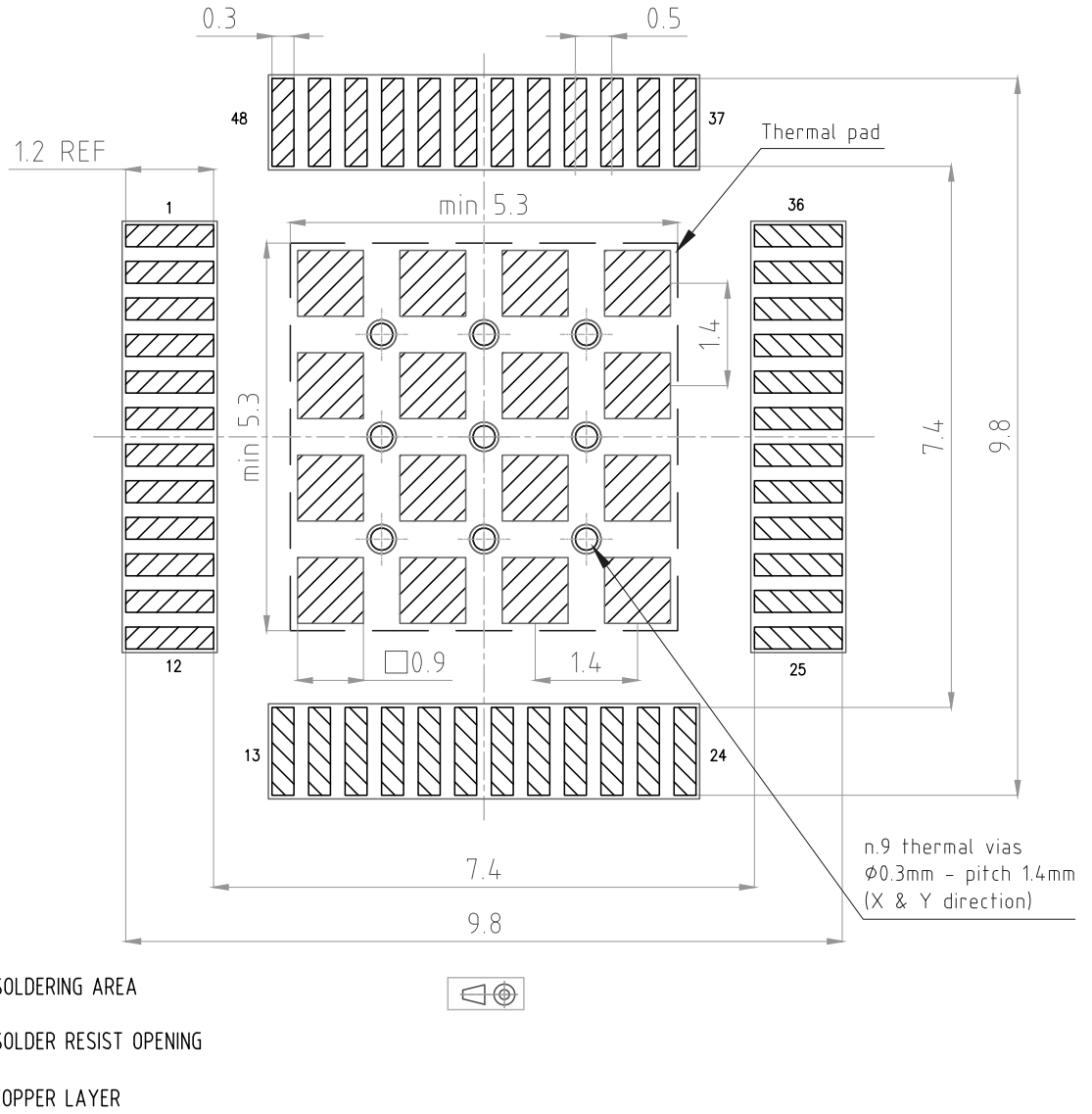


TOP VIEW



Table 152. TQFP48 (7x7x1 mm exp. pad down) package mechanical data

| Symbol | Dimensions in mm | | |
|---------------------------------------|------------------|------|------|
| | Min. | Typ. | Max. |
| e | 0° | 3.5° | 7° |
| e1 | 0° | - | - |
| e2 | 10° | 12° | 12° |
| e3 | 10° | 12° | 12° |
| A | - | - | 1.20 |
| A1 | 0.05 | - | 0.15 |
| A2 | 0.95 | 1.00 | 1.05 |
| b | 0.17 | 0.22 | 0.27 |
| c | 0.09 | - | 0.20 |
| D | 9.00 | | |
| D1 | 7.00 | | |
| D2 | - | - | 5.51 |
| D3 | 3.70 | - | - |
| e | - | 0.50 | - |
| E | 9.00 | | |
| E1 | 7.00 | | |
| E2 | - | - | 5.51 |
| E3 | 3.70 | - | - |
| L | 0.45 | 0.60 | 0.75 |
| L1 | 1.00 | | |
| N | 48 | | |
| R1 | 0.08 | - | - |
| R2 | 0.08 | - | 0.2 |
| S | 0.2 | - | - |
| Tolerance of form and position | | | |
| aaa | - | 0.20 | - |
| bbb | - | 0.20 | - |
| ccc | - | 0.08 | - |
| ddd | - | 0.08 | - |

7.2 TQFP48 (7x7x1 mm exp. pad down) PCB landpattern
Figure 93. Suggested PCB landpattern


Revision history

Table 153. Document revision history

| Date | Version | Changes |
|-------------|---------|--|
| 16-Nov-2020 | 1 | Initial release. |
| 03-Mar-2021 | 2 | <p>Updated:</p> <ul style="list-style-type: none"> • Section 5.9 Internal clock; • Section 5.13.1 A/D conversion; • Section 5.13.2.3 Digital format current information • Section 5.13.3.1 Analog format current information; • Section 5.13.4 Current monitor A/D - D/A chain; • Table 12. VDD monitor electrical characteristics; • Table 36. Clock spread spectrum electrical characteristics; • Table 42. Motor battery monitor electrical characteristics; • Table 44. Pre-regulation stage electrical characteristics; • Table 48. VBP monitor electrical characteristics; • Table 51. Charge pump 2 electrical characteristics; • Table 53. Bootstrap Limiter 1 electrical characteristics; • Table 54. VCP Monitor electrical characteristics; • Table 70. Current Monitor Input characteristics; • Table 79. Current monitor's analog output characteristics • Table 87. OFD electrical characteristics; • Table 91. OND electrical characteristics; • Table 93. PVF electrical characteristics. <p>Removed "Restricted" watermark.</p> |
| 28-Mar-2022 | 3 | <p>Added Section 7.2 TQFP48 (7x7x1 mm exp. pad down) PCB landpattern.</p> <p>Updated:</p> <ul style="list-style-type: none"> • Section 5.11.4 Supply distribution stage; • Section 5.12 Half bridges gate drivers; • Section 5.12.3 Shoot-Through Protection (STP); • Section 5.13.1 A/D conversion; • Section 6.3 Bill of materials; • Table 9. Quiescent current consumption in reset mode; • Table 10. Mean current consumptions in normal mode; • Table 44. Pre-regulation stage electrical characteristics; • Table 53. Bootstrap Limiter 1 electrical characteristics; • Table 54. VCP Monitor electrical characteristics; • Table 58. Pre-driver timings; • Table 60. VGS monitor electrical characteristics; • Table 76. Current monitors A/D auto-triggering latency; • Table 80. Current monitors A/D - D/A auto-triggering latency; • Table 93. PVF electrical characteristics; • Table 127. CH1_SAFETY_RELEVANT; • Table 152. TQFP48 (7x7x1 mm exp. pad down) package mechanical data; • Figure 7. Damage protected activation simplified structure; • Figure 10. Internal reset logic simplified block diagram; • Figure 23. Power-Up diagram; • Figure 26. Ext. FET gate supply simplified block diagram; • Figure 39. VGS Monitor operative ranges; • Figure 65. OFF State Diagnosis simplified block diagram; • Figure 66. OFD currents in motor phases; |

| Date | Version | Changes |
|------|---------|---|
| | | <ul style="list-style-type: none"> • Figure 68. OFD Masking and deglitch filtering - LSn_OFD Example; • Figure 69. OFD Masking and deglitch filtering - LSn_OFD Example with multiple glitches; • Figure 77. Ground pins inter-connection; • Figure 79. Junction temperature ranges; • Figure 90. Application circuit, 12 V/24 V systems; • Figure 91. Application circuit, 48 V systems. <p>Minor text changes in:</p> <ul style="list-style-type: none"> • Section 5.4 Configuration mode; • Section 5.6.4 Gate driver supply enable logic. |

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